Features

- High performance, low power Atmel® AVR® 8-bit Microcontroller
- Advanced RISC architecture
  - 131 powerful instructions - most single clock cycle execution
  - 32 × 8 general purpose working registers
  - Fully static operation
  - Up to eight MIPS throughput at 8MHz
- High endurance non-volatile memory segments
  - 16K/32Kbytes of in-system self-programmable flash (Atmel ATmega16HVB/32HVB)
  - 512/1Kbytes EEPROM
  - 1K/2Kbytes internal SRAM
  - Write/erase cycles 10,000 flash/100,000 EEPROM
  - Data retention: 20 years at 85°C/100 years at 25°C [1]
  - Optional boot code section with independent lock bits
    In-system programming by on-chip boot program
    True read-while-write operation
  - Programming lock for software security
- Battery management features
  - Two, three or four cells in series
  - High-current protection (charge and discharge)
  - Over-current protection (charge and discharge)
  - Short-circuit protection (discharge)
  - High-voltage outputs to drive N-channel charge/discharge FETs
  - Optional deep under voltage recovery mode - allowing 0-volt charging without external precharge FET
  - Optional high-voltage open drain output - allowing 0-volt charging with external precharge FET
  - Integrated cell balancing FETs
- Peripheral features
  - Two configurable 8-bit or 16-bit timers with separate prescaler, optional input capture (IC), compare mode and CTC
  - SPI - serial peripheral interface
  - 12-bit voltage ADC, six external and one internal ADC input
  - High resolution coulomb counter ADC for current measurements
  - TWI serial interface supporting SMBus implementation
  - Programmable watchdog timer
- Special microcontroller features
  - debugWIRE on-chip debug system
  - In-system programmable via SPI ports
  - Power-on reset
  - On-chip voltage regulator with short-circuit monitoring interface
  - External and Internal interrupt sources
  - Sleep modes: idle, ADC noise reduction, power-save, and power-off
- Additional secure authentication features available only under NDA
- Packages
  - 44-pin TSSOP
- Operating voltage: 4V -18V
- Maximum withstand voltage (high-voltage pins): 35V
- Temperature range: -40°C to 85°C
- Speed grade: 1MHz - 8MHz

Note: 1. See "Data retention" on page 8 for details.

8-bit AVR® Microcontroller with 16K/32Kbytes In-System Programmable Flash

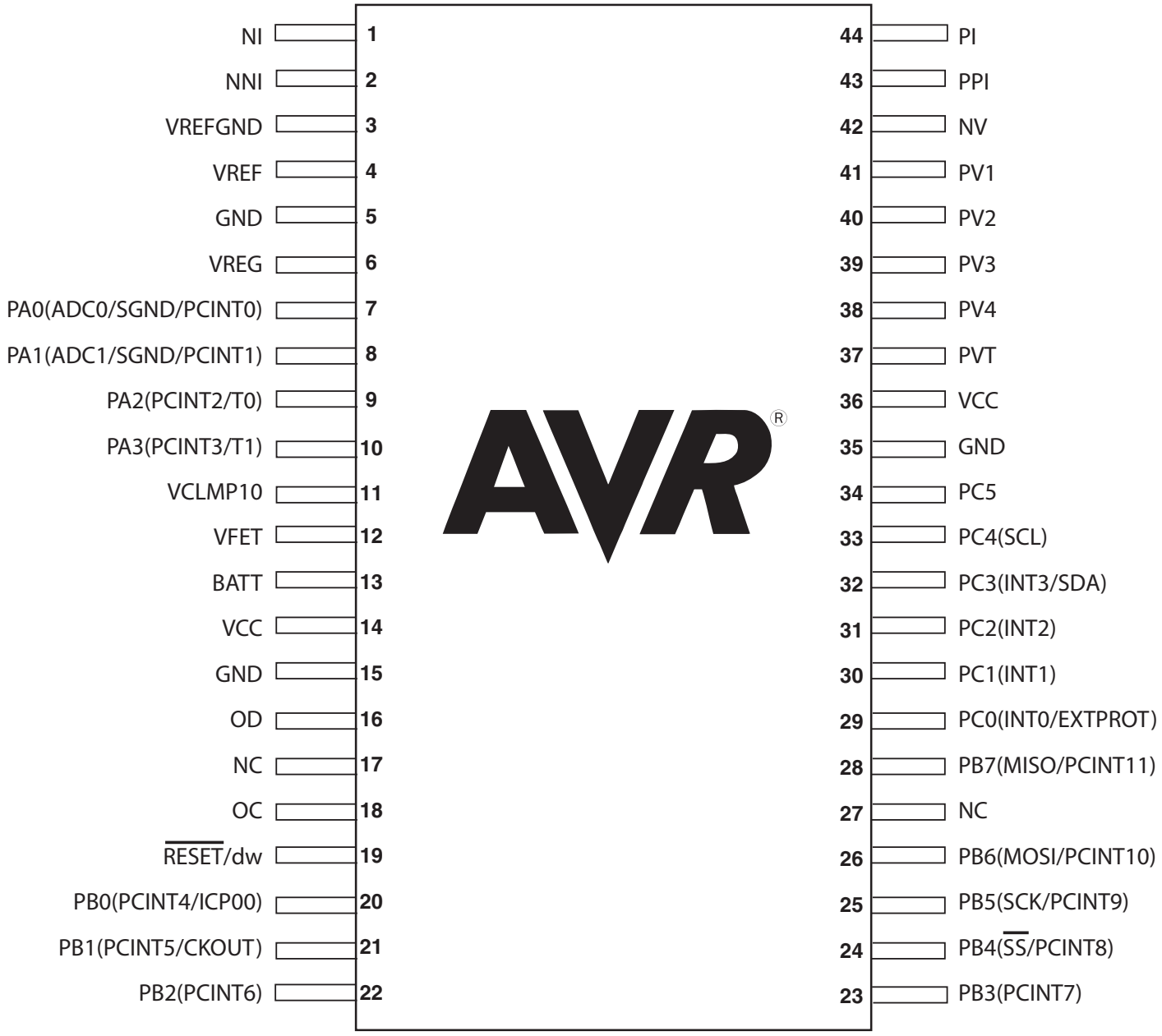
ATmega16HVB
ATmega32HVB

8042D–AVR–10/11

1. Pin configurations

1.1 TSSOP

Figure 1-1. TSSOP - pinout the Atmel ATmega16HVB/32HVB.



1.2 Pin descriptions

1.2.1 VFET

High voltage supply pin. This pin is used as supply for the internal voltage regulator, described in ”Voltage regulator” on page 129.

1.2.2 VCLMP10

Internal 10V clamping of VFET voltage for external decoupling.

1.2.3 VCC

Digital supply voltage. Normally connected to VREG.

1.2.4 VREG

Output from the internal voltage regulator. Used for external decoupling to ensure stable regulator operation. For details, see ”Voltage regulator” on page 129.

1.2.5 VREF

Internal voltage reference for external decoupling. For details, see ”Voltage reference and temperature sensor” on page 122.

1.2.6 VREFGND

Ground for decoupling of internal voltage reference. For details, see ”Voltage reference and temperature sensor” on page 122. Do not connect to GND or SGND on PCB.

1.2.7 GND

Ground.

1.2.8 Port A (PA3..PA0)

Port A serves as a low-voltage 4-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). As inputs, Port A pins that are externally pulled low will source current if the pull-up resistors are activated. The Port A pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port A also serves the functions of various special features of the Atmel ATmega16HVB/32HVB as listed in ”Alternate functions of Port A” on page 74.

1.2.9 Port B (PB7..PB0)

Port B is a low-voltage 8-bit bi-directional I/O port with internal pull-up resistors (selected for each bit). As inputs, Port B pins that are externally pulled low will source current if the pull-up resistors are activated. The Port B pins are tri-stated when a reset condition becomes active, even if the clock is not running.

Port B also serves the functions of various special features of the ATmega16HVB/32HVB as listed in ”Alternate functions of Port B” on page 75.

1.2.10 Port C (PC5)

Port C (PC5) is a high voltage Open Drain output port.

1.2.11 Port C (PC4..PC0)

Port C is a 5-bit high voltage Open Drain bi-directional I/O port.

1.2.12 OC/OD

High voltage output to drive Charge/Discharge FET. For details, see ”FET driver” on page 145.

1.2.13 PI/NI

Filtered positive/negative input from external current sense resistor, used to by the Coulomb Counter ADC to measure charge/discharge currents flowing in the battery pack. For details, see ”Coulomb counter – Dedicated fuel gauging Sigma-Delta ADC” on page 108.

1.2.14 PPI/NNI

Unfiltered positive/negative input from external current sense resistor, used by the battery protection circuit, for over-current and short-circuit detection. For details, see ”Battery protection” on page 132.

1.2.15 NV/PV1/PV2/PV3/PV4

NV, PV1, PV2, PV3, and PV4 are the inputs for battery cells one, two, three and four, used by the Voltage ADC to measure each cell voltage. For details, see ”Voltage ADC – 7-channel general purpose 12-bit Sigma-Delta ADC” on page 116.

1.2.16 PVT

Defines the source voltage level for the Charge FET driver. For details, see ”FET driver” on page 145.

1.2.17 BATT

Input for detecting when a charger is connected. Defines the source voltage level for the Discharge FET driver. For details, see ”FET driver” on page 145.

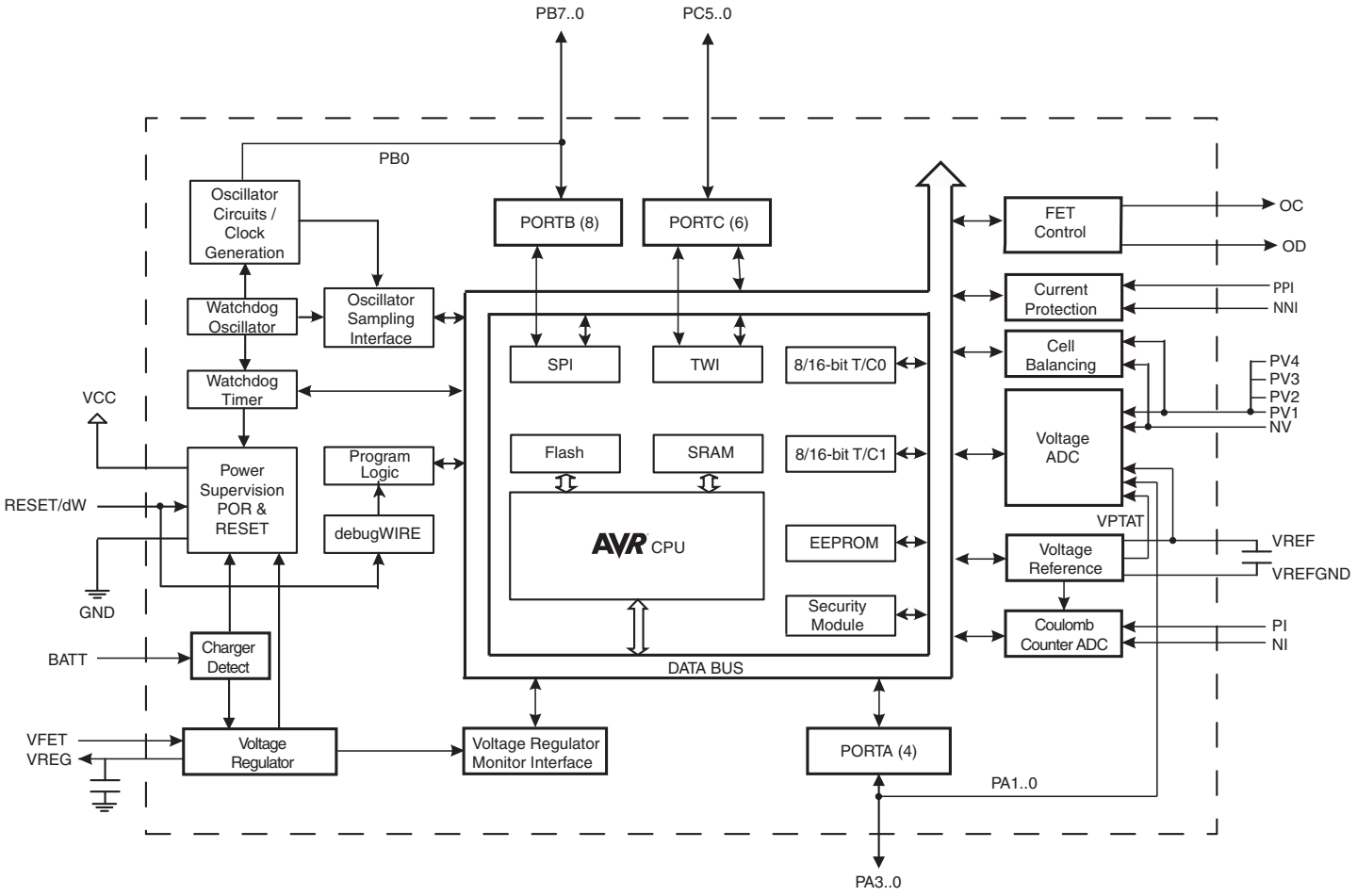
1.2.18 $\overline{\text{RESET}}$/dw

Reset input. A low level on this pin for longer than the minimum pulse length will generate a reset, even if the clock is not running. The minimum pulse length is given in Table 32-3 on page 227. Shorter pulses are not guaranteed to generate a reset. This pin is also used as debugWIRE communication pin.

2. Overview

The Atmel ATmega16HVB/32HVB is a monitoring and protection circuit for 3- and 4-cell Li-ion applications with focus on highest safety including safe authentication, low cost and high utilization of the cell energy. The device contains secure authentication features as well as autonomous battery protection during charging and discharging. The External Protection Input can be used to implement other battery protection mechanisms using external components, for example, protection against chargers with too high charge voltage can be easily implemented with a few low cost passive components. The feature set makes the ATmega16HVB/32HVB a key component in any system focusing on high security, battery protection, high system utilization and low cost.

Figure 2-1. Block diagram.



ATmega16HVB/32HVB provides the necessary redundancy on-chip to make sure that the battery is protected in critical failure modes. The chip is specifically designed to provide safety for the battery cells in case of pin shorting, loss of power (either caused by battery pack short or VCC short), illegal charger connection or software runaway. This makes ATmega16HVB/32HVB the ideal one-chip solution for applications with focus on high safety.

The ATmega16HVB/32HVB features an integrated voltage regulator that operates at a wide range of input voltages, 4 - 18 volts. This voltage is regulated to a constant supply voltage of

nominally 3.3 volts for the integrated logic and analog functions. The regulator capabilities, combined with an extremely low power consumption in the power saving modes, greatly enhances the cell energy utilization compared to existing solutions.

The chip utilizes the Atmel patented Deep Under-voltage Recovery (DUVR) mode that supports pre-charging of deeply discharged battery cells without using a separate Pre-charge FET. DUVR mode cannot be used in 2-cell applications. Optionally, Pre-charge FETs are supported for integration into many existing battery charging schemes.

The battery protection monitors the charge and discharge current to detect illegal conditions and protect the battery from these when required. A 12-bit Voltage ADC allows software to monitor each cell voltage individually with high accuracy. The ADC also provides one internal input channel to measure on-chip temperature and two input channels intended for external thermistors. An 18-bit ADC optimized for Coulomb Counting accumulates charge and discharge currents and reports accumulated current with high resolution and accuracy. It can also be used to provide instantaneous current measurements with 13-bit resolution. Integrated Cell Balancing FETs allow cell balancing algorithms to be implemented in software.

The MCU provides the following features: 16K/32Kbytes of In-System Programmable Flash with Read-While-Write capabilities, 512/1Kbytes EEPROM, 1K/2Kbytes SRAM. 32 general purpose working registers, 12 general purpose I/O lines, five general purpose high voltage open drain I/O lines, one general purpose super high voltage open drain output, debugWIRE for on-chip debugging and SPI for In-system Programming, a SM-Bus compliant TWI module, two flexible Timer/Counters with Input Capture and compare modes.

Internal and external interrupts, a 12-bit Sigma Delta ADC for voltage and temperature measurements, a high resolution Sigma Delta ADC for Coulomb Counting and instantaneous current measurements, integrated cell balancing FETs, Additional Secure Authentication Features, an autonomous Battery Protection module, a programmable Watchdog Timer with internal Oscillator, and software selectable power saving modes.

The AVR core combines a rich instruction set with 32 general purpose working registers. All the 32 registers are directly connected to the Arithmetic Logic Unit (ALU), allowing two independent registers to be accessed in one single instruction executed in one clock cycle. The resulting architecture is more code efficient while achieving throughputs up to ten times faster than conventional CISC microcontrollers.

The device is manufactured using the Atmel high voltage high density non-volatile memory technology. The On-chip ISP Flash allows the program memory to be reprogrammed In-System, through an SPI serial interface, by a conventional non-volatile memory programmer or by an On-chip Boot program running on the AVR core. The Boot program can use any interface to download the application program in the Application Flash memory. Software in the Boot Flash section will continue to run while the Application Flash section is updated, providing true Read-While-Write operation. By combining an 8-bit RISC CPU with In-System Self-Programmable-Flash and highly accurate analog front-end in a monolithic chip.

The Atmel ATmega16HVB/32HVB is a powerful microcontroller that provides a highly flexible and cost effective solution. It is part of the AVR Battery Management family that provides secure authentication, highly accurate monitoring and autonomous protection for Lithium-ion battery cells.

The ATmega16HVB/32HVB AVR is supported with a full suite of program and system development tools including: C Compilers, Macro Assemblers, Program Debugger/Simulators, and On-chip Debugger.

2.1 Comparison between the Atmel ATmega16HVB and the Atmel ATmega32HVB

The ATmega16HVB and the ATmega32HVB differ only in memory size for flash, EEPROM and internal SRAM. Table 2-1 summarizes the different configuration for the two devices.

Table 2-1. Configuration summary.

Device	Flash	EEPROM	SRAM
ATmega16HVB	16K	512	1K
ATmega32HVB	32K	1K	2K

3. Disclaimer

All parameters contained in this datasheet are preliminary and based on characterization of the Atmel ATmega16/32HVB.

4. Resources

A comprehensive set of development tools, application notes and datasheets are available for download on http://www.atmel.com/avr.

5. About code examples

This documentation contains simple code examples that briefly show how to use various parts of the device. These code examples assume that the part specific header file is included before compilation. Be aware that not all C compiler vendors include bit definitions in the header files and interrupt handling in C is compiler dependent. Please confirm with the C compiler documentation for more details.

For I/O registers located in extended I/O map, “IN”, “OUT”, “SBIS”, “SBIC”, “CBI”, and “SBI” instructions must be replaced with instructions that allow access to extended I/O. Typically “LDS” and “STS” combined with “SBRS”, “SBRC”, “SBR”, and “CBR”.

6. Data retention

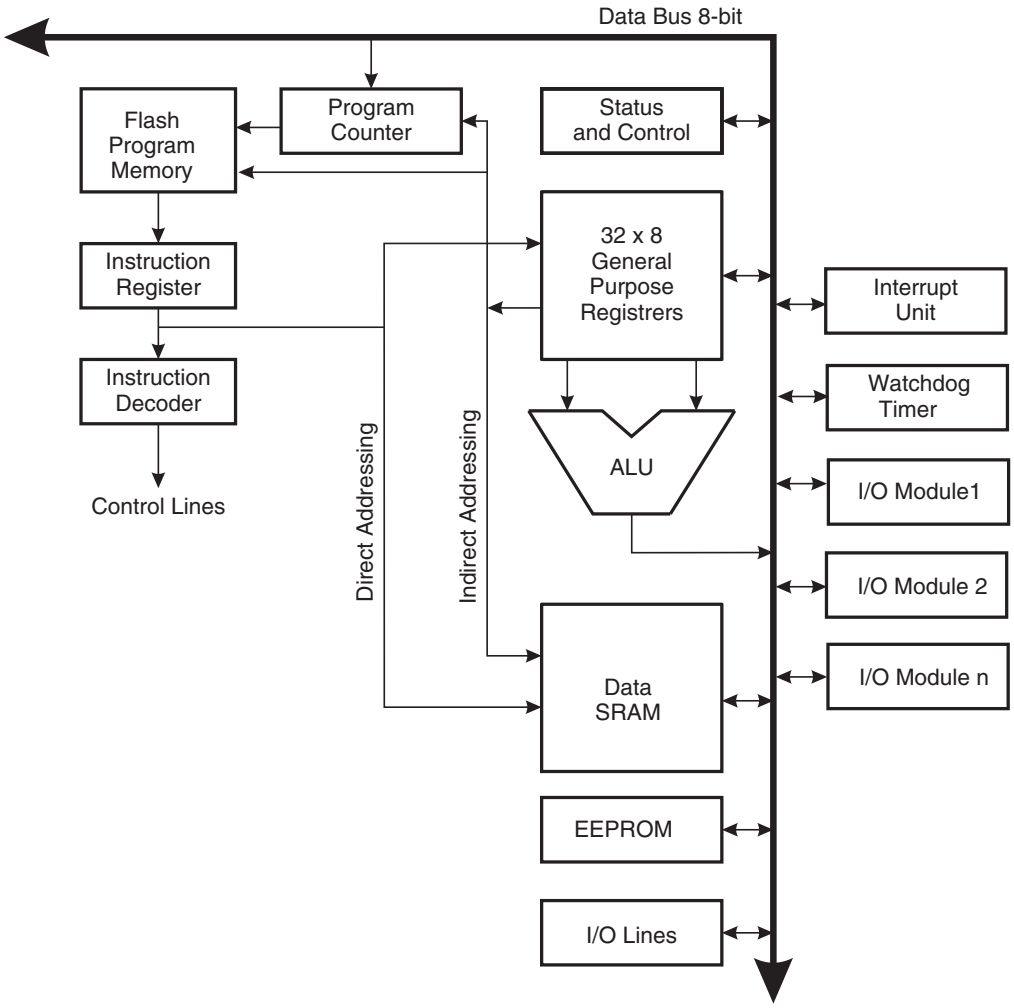
Reliability Qualification results show that the projected data retention failure rate is much less than one PPM over 20 years at 85°C or 100 years at 25°C.

7. AVR CPU core

7.1 Overview

This section discusses the Atmel AVR core architecture in general. The main function of the CPU core is to ensure correct program execution. The CPU must therefore be able to access memories, perform calculations, control peripherals, and handle interrupts.

Figure 7-1. Block diagram of the AVR architecture.



In order to maximize performance and parallelism, the AVR uses a Harvard architecture – with separate memories and buses for program and data. Instructions in the program memory are executed with a single level pipelining. While one instruction is being executed, the next instruction is pre-fetched from the program memory. This concept enables instructions to be executed in every clock cycle. The program memory is In-System Reprogrammable Flash memory.

The fast-access Register File contains 32 × 8-bit general purpose working registers with a single clock cycle access time. This allows single-cycle Arithmetic Logic Unit (ALU) operation. In a typ-

ical ALU operation, two operands are output from the Register File, the operation is executed, and the result is stored back in the Register File – in one clock cycle.

Six of the 32 registers can be used as three 16-bit indirect address register pointers for Data Space addressing – enabling efficient address calculations. One of the these address pointers can also be used as an address pointer for look up tables in Flash program memory. These added function registers are the 16-bit X-register, Y-register, and Z-register, described later in this section.

The ALU supports arithmetic and logic operations between registers or between a constant and a register. Single register operations can also be executed in the ALU. After an arithmetic operation, the Status Register is updated to reflect information about the result of the operation.

Program flow is provided by conditional and unconditional jump and call instructions, able to directly address the whole address space. Most AVR instructions have a single 16-bit word format. Every program memory address contains a 16-bit or 32-bit instruction.

During interrupts and subroutine calls, the return address Program Counter (PC) is stored on the Stack. The Stack is effectively allocated in the general data SRAM, and consequently the Stack size is only limited by the total SRAM size and the usage of the SRAM. All user programs must initialize the SP in the Reset routine (before subroutines or interrupts are executed). The Stack Pointer (SP) is read/write accessible in the I/O space. The data SRAM can easily be accessed through the five different addressing modes supported in the AVR architecture.

The memory spaces in the AVR architecture are all linear and regular memory maps.

A flexible interrupt module has its control registers in the I/O space with an additional Global Interrupt Enable bit in the Status Register. All interrupts have a separate Interrupt Vector in the Interrupt Vector table. The interrupts have priority in accordance with their Interrupt Vector position. The lower the Interrupt Vector address, the higher the priority.

The I/O memory space contains 64 addresses for CPU peripheral functions as Control Registers, SPI, and other I/O functions. The I/O Memory can be accessed directly, or as the Data Space locations following those of the Register File, 0x20 - 0x5F. In addition, the Atmel ATmega16HVB/32HVB has Extended I/O space from 0x60 - 0xFF in SRAM where only the ST/STS/STD and LD/LDS/LDD instructions can be used.

7.2 ALU – Arithmetic Logic Unit

The high-performance AVR ALU operates in direct connection with all the 32 general purpose working registers. Within a single clock cycle, arithmetic operations between general purpose registers or between a register and an immediate are executed. The ALU operations are divided into three main categories – arithmetic, logical, and bit-functions. Some implementations of the architecture also provide a powerful multiplier supporting both signed/unsigned multiplication and fractional format. See ”Instruction set summary” on page 259 for a detailed description.

7.3 Status Register

The Status Register contains information about the result of the most recently executed arithmetic instruction. This information can be used for altering program flow in order to perform conditional operations. Note that the Status Register is updated after all ALU operations, as specified in the Instruction Set Reference. This will in many cases remove the need for using the dedicated compare instructions, resulting in faster and more compact code.

The Status Register is not automatically stored when entering an interrupt routine and restored when returning from an interrupt. This must be handled by software.

7.3.1 SREG – AVR Status Register

Bit	7	6	5	4	3	2	1	0	
0x3F (0x5F)	I	T	H	S	V	N	Z	C	SREG
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7 – I: Global Interrupt Enable**

The Global Interrupt Enable bit must be set for the interrupts to be enabled. The individual interrupt enable control is then performed in separate control registers. If the Global Interrupt Enable Register is cleared, none of the interrupts are enabled independent of the individual interrupt enable settings. The I-bit is cleared by hardware after an interrupt has occurred, and is set by the RETI instruction to enable subsequent interrupts. The I-bit can also be set and cleared by the application with the SEI and CLI instructions, as described in the Instruction Set Reference.

- **Bit 6 – T: Bit Copy Storage**

The Bit Copy instructions BLD (Bit LoaD) and BST (Bit STore) use the T-bit as source or destination for the operated bit. A bit from a register in the Register File can be copied into T by the BST instruction, and a bit in T can be copied into a bit in a register in the Register File by the BLD instruction.

- **Bit 5 – H: Half Carry Flag**

The Half Carry Flag H indicates a Half Carry in some arithmetic operations. Half Carry is useful in BCD arithmetic. See the “Instruction Set Description” for detailed information.

- **Bit 4 – S: Sign Bit, S = N ⊕ V**

The S-bit is always an exclusive or between the negative flag N and the Two’s Complement Overflow Flag V. See the “Instruction Set Description” for detailed information.

- **Bit 3 – V: Two’s Complement Overflow Flag**

The Two’s Complement Overflow Flag V supports two’s complement arithmetics. See the “Instruction Set Description” for detailed information.

- **Bit 2 – N: Negative Flag**

The Negative Flag N indicates a negative result in an arithmetic or logic operation. See the “Instruction Set Description” for detailed information.

- **Bit 1 – Z: Zero Flag**

The Zero Flag Z indicates a zero result in an arithmetic or logic operation. See the “Instruction Set Description” for detailed information.

- **Bit 0 – C: Carry Flag**

The Carry Flag C indicates a carry in an arithmetic or logic operation. See the “Instruction Set Description” for detailed information.

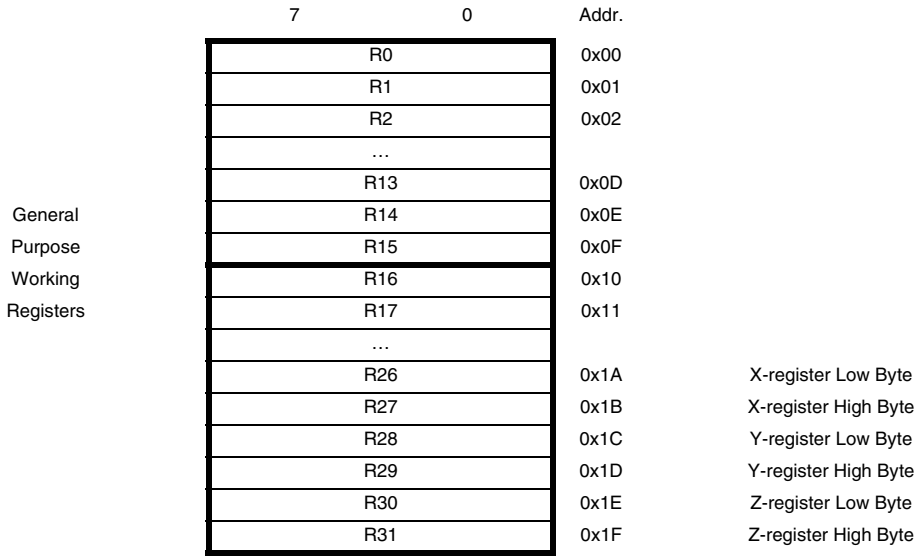
7.4 General purpose Register File

The Register File is optimized for the AVR Enhanced RISC instruction set. In order to achieve the required performance and flexibility, the following input/output schemes are supported by the Register File:

- One 8-bit output operand and one 8-bit result input
- Two 8-bit output operands and one 16-bit result input
- Two 8-bit output operands and one 16-bit result input
- One 16-bit output operand and one 16-bit result input

Figure 7-2 shows the structure of the 32 general purpose working registers in the CPU.

Figure 7-2. AVR CPU General Purpose Working Registers.



Most of the instructions operating on the Register File have direct access to all registers, and most of them are single cycle instructions.

As shown in Figure 7-2, each register is also assigned a data memory address, mapping them directly into the first 32 locations of the user Data Space. Although not being physically implemented as SRAM locations, this memory organization provides great flexibility in access of the registers, as the X-pointer, Y-pointer and Z-pointer registers can be set to index any register in the file.

7.4.1 The X-register, Y-register, and Z-register

The registers R26..R31 have some added functions to their general purpose usage. These registers are 16-bit address pointers for indirect addressing of the data space. The three indirect address registers X, Y, and Z are defined as described in Figure 7-3 on page 13.

Figure 7-3. The X-register, Y-register, and Z-registers.

In the different addressing modes these address registers have functions as fixed displacement, automatic increment, and automatic decrement (see the Instruction Set Reference for details).

7.5 Stack Pointer

The Stack is mainly used for storing temporary data, for storing local variables and for storing return addresses after interrupts and subroutine calls. The Stack Pointer Register always points to the top of the Stack. Note that the Stack is implemented as growing from higher memory locations to lower memory locations. This implies that a Stack PUSH command decreases the Stack Pointer.

The Stack Pointer points to the data SRAM Stack area where the Subroutine and Interrupt Stacks are located. This Stack space in the data SRAM must be defined by the program before any subroutine calls are executed or interrupts are enabled. The Stack Pointer must be set to point above 0x100. The Stack Pointer is decremented by one when data is pushed onto the Stack with the PUSH instruction, and it is decremented by two when the return address is pushed onto the Stack with subroutine call or interrupt. The Stack Pointer is incremented by one when data is popped from the Stack with the POP instruction, and it is incremented by two when data is popped from the Stack with return from subroutine RET or return from interrupt RETI.

The AVR Stack Pointer is implemented as two 8-bit registers in the I/O space. The number of bits actually used is implementation dependent. Note that the data space in some implementations of the AVR architecture is so small that only SPL is needed. In this case, the SPH Register will not be present.

7.5.1 SPH and SPL – Stack Pointer High and Stack Pointer Low

Bit	15	14	13	12	11	10	9	8	
0x3E (0x5E)	**SP15**	**SP14**	**SP13**	**SP12**	**SP11**	**SP10**	**SP9**	**SP8**	**SPH**
0x3D (0x5D)	**SP7**	**SP6**	**SP5**	**SP4**	**SP3**	**SP2**	**SP1**	**SP0**	**SPL**
	7	6	5	4	3	2	1	0	
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	RAM-END	RAM-END	RAM-END	RAM-END	RAM-END	RAM-END	RAM-END	RAM-END	
	RAM-END	RAM-END	RAM-END	RAM-END	RAM-END	RAM-END	RAM-END	RAM-END	

7.6 Instruction execution timing

This section describes the general access timing concepts for instruction execution. The Atmel AVR CPU is driven by the CPU clock clk_{CPU}, directly generated from the selected clock source for the chip. No internal clock division is used.

Figure 7-4 shows the parallel instruction fetches and instruction executions enabled by the Harvard architecture and the fast-access Register File concept. This is the basic pipelining concept to obtain up to one MIPS per MHz with the corresponding unique results for functions per cost, functions per clocks, and functions per power-unit.

Figure 7-4. The parallel instruction fetches and instruction executions.

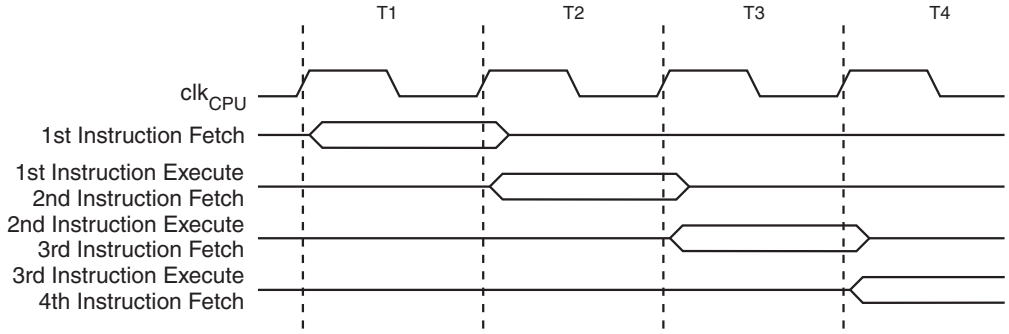
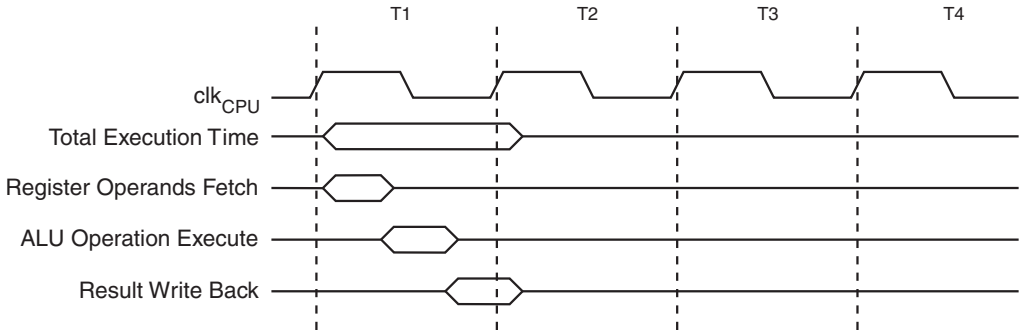


Figure 7-5 shows the internal timing concept for the Register File. In a single clock cycle an ALU operation using two register operands is executed, and the result is stored back to the destination register.

Figure 7-5. Single cycle ALU pperation.



7.7 Reset and interrupt handling

The AVR provides several different interrupt sources. These interrupts and the separate Reset Vector each have a separate program vector in the program memory space. All interrupts are assigned individual enable bits which must be written logic one together with the Global Interrupt Enable bit in the Status Register in order to enable the interrupt.

The lowest addresses in the program memory space are by default defined as the Reset and Interrupt Vectors. The complete list of vectors is shown in ”Interrupts” on page 52. The list also determines the priority levels of the different interrupts. The lower the address the higher is the priority level. RESET has the highest priority.

When an interrupt occurs, the Global Interrupt Enable I-bit is cleared and all interrupts are disabled. The user software can write logic one to the I-bit to enable nested interrupts. All enabled interrupts can then interrupt the current interrupt routine. The I-bit is automatically set when a Return from Interrupt instruction – RETI – is executed.

There are basically two types of interrupts. The first type is triggered by an event that sets the interrupt flag. For these interrupts, the Program Counter is vectored to the actual Interrupt Vector in order to execute the interrupt handling routine, and hardware clears the corresponding interrupt flag. Interrupt flags can also be cleared by writing a logic one to the flag bit position(s) to be cleared. If an interrupt condition occurs while the corresponding interrupt enable bit is cleared, the interrupt flag will be set and remembered until the interrupt is enabled, or the flag is cleared by software. Similarly, if one or more interrupt conditions occur while the Global Interrupt Enable bit is cleared, the corresponding interrupt flag(s) will be set and remembered until the Global Interrupt Enable bit is set, and will then be executed by order of priority.

The second type of interrupts will trigger as long as the interrupt condition is present. These interrupts do not necessarily have interrupt flags. If the interrupt condition disappears before the interrupt is enabled, the interrupt will not be triggered.

When the AVR exits from an interrupt, it will always return to the main program and execute one more instruction before any pending interrupt is served.

Note that the Status Register is not automatically stored when entering an interrupt routine, nor restored when returning from an interrupt routine. This must be handled by software.

When using the CLI instruction to disable interrupts, the interrupts will be immediately disabled. No interrupt will be executed after the CLI instruction, even if it occurs simultaneously with the CLI instruction. The following example shows how this can be used to avoid interrupts during the timed EEPROM write sequence.

Assembly code example

```
in  r16, SREG     ; store SREG value
cli    ; disable interrupts during timed sequence
sbi EECR, EEMPE   ; start EEPROM write
sbi EECR, EEPE
out SREG, r16     ; restore SREG value (I-bit)
```

C code example

```
char cSREG;
cSREG = SREG; /* store SREG value */
/* disable interrupts during timed sequence */
_CLI();
EECR |= (1<<EEMPE); /* start EEPROM write */
EECR |= (1<<EEPE);
SREG = cSREG; /* restore SREG value (I-bit) */
```

When using the SEI instruction to enable interrupts, the instruction following SEI will be executed before any pending interrupts, as shown in this example.

Assembly code example

```
sei  ; set Global Interrupt Enable
sleep; enter sleep, waiting for interrupt
; note: will enter sleep before any pending
; interrupt(s)
```

C code example

```
_SEI(); /* set Global Interrupt Enable */
_SLEEP(); /* enter sleep, waiting for interrupt */
/* note: will enter sleep before any pending interrupt(s) */
```

7.7.1 Interrupt response time

The interrupt execution response for all the enabled AVR interrupts is four clock cycles minimum. After four clock cycles the program vector address for the actual interrupt handling routine is executed. During this four clock cycle period, the Program Counter is pushed onto the Stack. The vector is normally a jump to the interrupt routine, and this jump takes three clock cycles. If an interrupt occurs during execution of a multi-cycle instruction, this instruction is completed before the interrupt is served. If an interrupt occurs when the MCU is in sleep mode, the interrupt execution response time is increased by four clock cycles. This increase comes in addition to the start-up time from the selected sleep mode.

A return from an interrupt handling routine takes four clock cycles. During these four clock cycles, the Program Counter (two bytes) is popped back from the Stack, the Stack Pointer is incremented by two, and the I-bit in SREG is set.

8. AVR memories

8.1 Overview

This section describes the different memories in the Atmel ATmega16HVB/32HVB. The AVR architecture has two main memory spaces, the Data Memory and the Program Memory space. In addition, the ATmega16HVB/32HVB features an EEPROM Memory for data storage. All three memory spaces are linear and regular.

8.2 In-system reprogrammable flash program memory

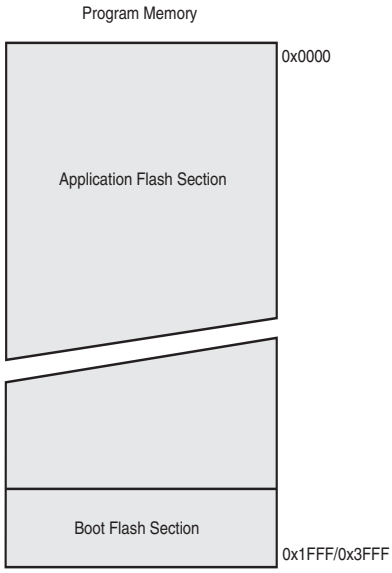
The ATmega16HVB/32HVB contains 16K/32Kbytes On-chip in-system reprogrammable flash memory for program storage. Since all AVR instructions are 16-bits or 32-bits wide, the Flash is organized as 8K/16K × 16.

The Flash memory has an endurance of at least 10,000 write/erase cycles. The ATmega16HVB/32HVB Program Counter (PC) is 13/14 bits wide, thus addressing the 8K/16K program memory locations. The operation of Boot Program section and associated Boot Lock bits for software protection are described in detail in ”Boot loader support – Read-while-write self-programming” on page 188. ”Memory programming” on page 204 contains a detailed description on Flash programming.

Constant tables can be allocated within the entire program memory address space (see the LPM – Load Program Memory instruction description).

Timing diagrams for instruction fetch and execution are presented in ”Instruction execution timing” on page 14.

Figure 8-1. Program memory map.



8.3 SRAM data memory

Figure 8-2 on page 18 shows how the ATmega16HVB/32HVB SRAM Memory is organized.

The Atmel ATmega16HVB/32HVB is a complex microcontroller with more peripheral units than can be supported within the 64 locations reserved in the Opcode for the IN and OUT instructions. For the Extended I/O space from 0x60 - 0xFF in SRAM, only the ST/STS/STD and LD/LDS/LDD instructions can be used.

The lower 1280/2304 data memory locations address both the Register File, the I/O memory, Extended I/O memory, and the internal data SRAM. The first 32 locations address the Register File, the next 64 location the standard I/O memory, then 160 locations of Extended I/O memory, and the next 1K/2K locations address the internal data SRAM.

The five different addressing modes for the data memory cover: Direct, Indirect with Displacement, Indirect, Indirect with Pre-decrement, and Indirect with Post-increment. In the Register File, registers R26 to R31 feature the indirect addressing pointer registers.

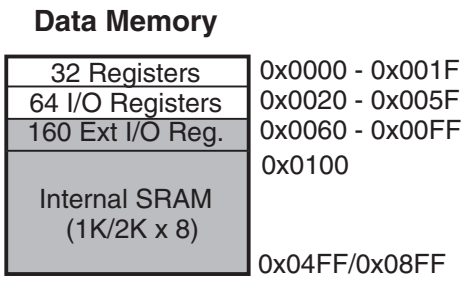
The direct addressing reaches the entire data space.

The Indirect with Displacement mode reaches 63 address locations from the base address given by the Y-register or the Z-register.

When using register indirect addressing modes with automatic pre-decrement and post-increment, the address registers X, Y, and Z are decremented or incremented.

The 32 general purpose working registers, 64 I/O Registers, 160 Extended I/O Registers, and the 1K/2Kbytes of internal data SRAM in the ATmega16HVB/32HVB are all accessible through all these addressing modes. The Register File is described in ”General purpose Register File” on page 12.

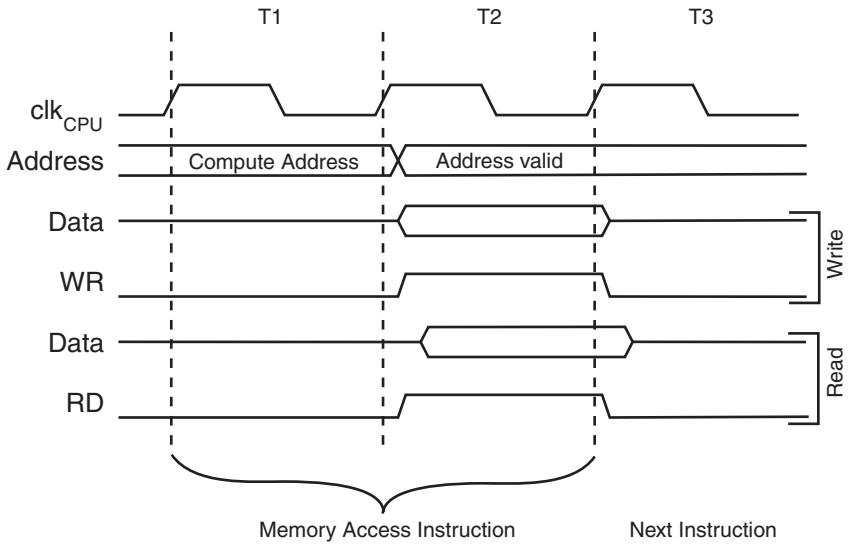
Figure 8-2. Data memory map.



8.3.1 Data memory access times

This section describes the general access timing concepts for internal memory access. The internal data SRAM access is performed in two clk_{CPU} cycles as described in Figure 8-3 on page 19.

Figure 8-3. On-chip data SRAM access cycles.



8.4 EEPROM data memory

The Atmel ATmega16HVB/32HVB contains 512/1Kbytes of data EEPROM memory. It is organized as a separate data space, in which single bytes can be read and written. The EEPROM has an endurance of at least 100,000 write/erase cycles. The access between the EEPROM and the CPU is described in the following, specifying the EEPROM Address Registers, the EEPROM Data Register, and the EEPROM Control Register.

For a detailed description of EEPROM programming, see page 207 and page 211 respectively.

8.4.1 EEPROM read/write access

The EEPROM Access Registers are accessible in the I/O space.

The write access time for the EEPROM is given in Table 8-1 on page 21. A self-timing function, however, lets the user software detect when the next byte can be written. If the user code contains instructions that write the EEPROM, some precautions must be taken.

In order to prevent unintentional EEPROM writes, a specific write procedure must be followed. Refer to ”EECR – The EEPROM control register” on page 21 for details on this.

When the EEPROM is read, the CPU is halted for four clock cycles before the next instruction is executed. When the EEPROM is written, the CPU is halted for two clock cycles before the next instruction is executed.

8.5 I/O memory

The I/O space definition of the ATmega16HVB/32HVB is shown in ”Register summary” on page 255.

All ATmega16HVB/32HVB I/Os and peripherals are placed in the I/O space. All I/O locations may be accessed by the LD/LDS/LDD and ST/STS/STD instructions, transferring data between the 32 general purpose working registers and the I/O space. I/O Registers within the address range 0x00 - 0x1F are directly bit-accessible using the SBI and CBI instructions. In these registers, the value of single bits can be checked by using the SBIS and SBIC instructions. Refer to ”Instruction set summary” on page 259 for more details. When using the I/O specific commands

IN and OUT, the I/O addresses 0x00 - 0x3F must be used. When addressing I/O Registers as data space using LD and ST instructions, 0x20 must be added to these addresses. The Atmel ATmega16HVB/32HVB is a complex microcontroller with more peripheral units than can be supported within the 64 location reserved in Opcode for the IN and OUT instructions. For the Extended I/O space from 0x60 - 0xFF in SRAM, only the ST/STS/STD and LD/LDS/LDD instructions can be used.

For compatibility with future devices, reserved bits should be written to zero if accessed. Reserved I/O memory addresses should never be written.

Some of the status flags are cleared by writing a logical one to them. Note that the CBI and SBI instructions will only operate on the specified bit, and can therefore be used on registers containing such status flags. The CBI and SBI instructions work with registers 0x00 to 0x1F only.

The I/O and peripherals control registers are explained in later sections.

8.5.1 General purpose I/O registers

The ATmega16HVB/32HVB contains three General Purpose I/O Registers. These registers can be used for storing any information, and they are particularly useful for storing global variables and Status Flags. General Purpose I/O Registers within the address range 0x00 - 0x1F are directly bit-accessible using the SBI, CBI, SBIS, and SBIC instructions.

8.6 Register description

8.6.1 EEARH and EEARL– The EEPROM Address Register High and Low

Bit	15	14	13	12	11	10	9	8	
0x22 (0x42)							**EEAR9**	**EEAR8**	**EEARH**
0x21 (0x41)	**EEAR7**	**EEAR6**	**EEAR5**	**EEAR4**	**EEAR3**	**EEAR2**	**EEAR1**	**EEAR0**	**EEARL**
Bit	7	6	5	4	3	2	1	0	
Read/Write	R	R	R	R	R	R	R/W	R/W	
	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	X	X	
	X	X	X	X	X	X	X	X	

- **Bits 15:10 – Reserved**

These bits are reserved bits in the ATmega16HVB/32HVB and will always read as zero.

- **Bits 9:0 – EEAR9:0: EEPROM address**

The EEPROM Address Registers – EEAR specify the EEPROM address in the 512/1Kbytes EEPROM space. The EEPROM data bytes are addressed linearly between 0 and 511/1023. The initial value of EEAR is undefined. A proper value must be written before the EEPROM may be accessed.

8.6.2 EEDR – The EEPROM data register

Bit	7	6	5	4	3	2	1	0	
0x20 (0x40)	**MSB**							**LSB**	**EEDR**
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:0 – EEDR[7:0]: EEPROM data**

For the EEPROM write operation, the EEDR Register contains the data to be written to the EEPROM in the address given by the EEAR Register. For the EEPROM read operation, the EEDR contains the data read out from the EEPROM at the address given by EEAR.

8.6.3 EECR – The EEPROM control register

Bit	7	6	5	4	3	2	1	0	
0x1F (0x3F)	–	–	EEPM1	EEPM0	EERIE	EEMPE	EEPE	EERE	EECR
Read/Write	R	R	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	X	X	0	0	X	0	

- **Bits 7:6 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB and will always read as zero.

- **Bits 5, 4 – EEPM1 and EEPM0: EEPROM programming mode bits**

The EEPROM Programming mode bit setting defines which programming action that will be triggered when writing EEPE. It is possible to program data in one atomic operation (erase the old value and program the new value) or to split the Erase and Write operations in two different operations. The Programming times for the different modes are shown in Table 8-1. While EEPE is set, any write to EEPMn will be ignored. During reset, the EEPMn bits will be reset to 0b00 unless the EEPROM is busy programming.

Table 8-1. EEPROM mode bits.

EEPM1	EEPM0	Typical programming time (1)	Operation
0	0	3.4ms	Erase and write in one operation (Atomic Operation)
0	1	1.8ms	Erase only
1	0	1.8ms	Write only
1	1	–	Reserved for future use

Note: 1. Actual timing depends on frequency of the Calibrated Fast RC Oscillator.

- **Bit 3 – EERIE: EEPROM Ready Interrupt enable**

Writing EERIE to one enables the EEPROM Ready Interrupt if the I bit in SREG is set. Writing EERIE to zero disables the interrupt. The EEPROM Ready interrupt generates a constant interrupt when EEPE is cleared.

- **Bit 2 – EEMPE: EEPROM Master Write enable**

The EEMPE bit determines whether setting EEPE to one causes the EEPROM to be written. When EEMPE is set, setting EEPE within four clock cycles will write data to the EEPROM at the selected address If EEMPE is zero, setting EEPE will have no effect. When EEMPE has been written to one by software, hardware clears the bit to zero after four clock cycles. See Bit 1 – EEPE: EEPROM Write enable for an EEPROM write procedure.

- **Bit 1 – EEPE: EEPROM Write enable**

The EEPROM Write Enable Signal EEPE is the write strobe to the EEPROM. When address and data are correctly set up, the EEPE bit must be written to one to write the value into the

EEPROM. The EEMPE bit must be written to one before a logical one is written to EEPE, otherwise no EEPROM write takes place. The following procedure should be followed when writing the EEPROM (the order of steps 2 and 3 is not essential):

1. Wait until EEPE becomes zero.
2. Write new EEPROM address to EEAR (optional).
3. Write new EEPROM data to EEDR (optional).
4. Write a logical one to the EEMPE bit while writing a zero to EEPE in EECR.
5. Within four clock cycles after setting EEMPE, write a logical one to EEPE.

Caution:

An interrupt between step 4 and step 5 will make the write cycle fail, since the EEPROM Master Write Enable will time-out. If an interrupt routine accessing the EEPROM is interrupting another EEPROM access, the EEAR or EEDR Register will be modified, causing the interrupted EEPROM access to fail. It is recommended to have the Global Interrupt Flag cleared during all the steps to avoid these problems.

When the write access time has elapsed, the EEPE bit is cleared by hardware. The user software can poll this bit and wait for a zero before writing the next byte. When EEPE has been set, the CPU is halted for two cycles before the next instruction is executed.

Caution:

A BOD reset during EEPROM write will invalidate the result of the ongoing operation.

- **Bit 0 – EERE: EEPROM Read enable**

The EEPROM Read Enable Signal EERE is the read strobe to the EEPROM. When the correct address is set up in the EEAR Register, the EERE bit must be written to a logic one to trigger the EEPROM read. The EEPROM read access takes one instruction, and the requested data is available immediately. When the EEPROM is read, the CPU is halted for four cycles before the next instruction is executed.

The user should poll the EEPE bit before starting the read operation. If a write operation is in progress, it is neither possible to read the EEPROM, nor to change the EEAR Register.

The calibrated Oscillator is used to time the EEPROM accesses and the programming time will therefore depend on the calibrated oscillator frequency. Table 8-2 lists the typical programming time for EEPROM access from the CPU.

Table 8-2. EEPROM programming time.

Symbol	Number of calibrated RC oscillator cycles	Typical programming time, f_{osc} = 8MHz
EEPROM write (from CPU)	27200	3.4ms

The following code examples show one assembly and one C function for writing to the EEPROM. The examples assume that interrupts are controlled (for example by disabling interrupts globally) so that no interrupts will occur during execution of these functions. The examples also assume that no Flash Boot Loader is present in the software. If such code is present, the EEPROM write function must also wait for any ongoing SPM command to finish.

Assembly code example

```
EEPROM_write:
  ; Wait for completion of previous write
  sbic EECR,EEPE
  rjmp EEPROM_write
  ; Set up address (r18:r17) in address register
  out  EEARH, r18
  out  EEARL, r17
  ; Write data (r16) to data register
  out  EEDR,r16
  ; Write logical one to EEMPE
  sbi  EECR,EEMPE
  ; Start eeprom write by setting EEPE
  sbi  EECR,EEPE
  ret
```

C code example

```
void EEPROM_write(unsigned int uiAddress, unsigned char ucData)
{
  /* Wait for completion of previous write */
  while(EECR & (1<<EEPE))
    ;
  /* Set up address and data registers */
  EEAR = uiAddress;
  EEDR = ucData;
  /* Write logical one to EEMPE */
  EECR |= (1<<EEMPE);
  /* Start eeprom write by setting EEPE */
  EECR |= (1<<EEPE);
}
```

The next code examples show assembly and C functions for reading the EEPROM. The examples assume that interrupts are controlled so that no interrupts will occur during execution of these functions.

Assembly code example

```
EEPROM_read:
  ; Wait for completion of previous write
  sbic EECR,EEPE
  rjmp EEPROM_read
  ; Set up address (r18:r17) in address register
  out  EEARH, r18
  out  EEARL, r17
  ; Start eeprom read by writing EERE
  sbi  EECR,EERE
  ; Read data from data register
  in   r16,EEDR
  ret
```

C code example

```
unsigned char EEPROM_read(unsigned int uiAddress)
{
  /* Wait for completion of previous write */
  while(EECR & (1<<EEPE))
    ;
  /* Set up address register */
  EEAR = uiAddress;
  /* Start eeprom read by writing EERE */
  EECR |= (1<<EERE);
  /* Return data from data register */
  return EEDR;
}
```

8.6.4 GPIOR2 – General purpose I/O Register 2

Bit	7	6	5	4	3	2	1	0	
0x2B (0x4B)	MSB							LSB	GPIOR2
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

8.6.5 GPIOR1 – General purpose I/O Register 1

Bit	7	6	5	4	3	2	1	0	
0x2A (0x4A)	MSB							LSB	GPIOR1
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

8.6.6 GPIOR0 – General purpose I/O Register 0

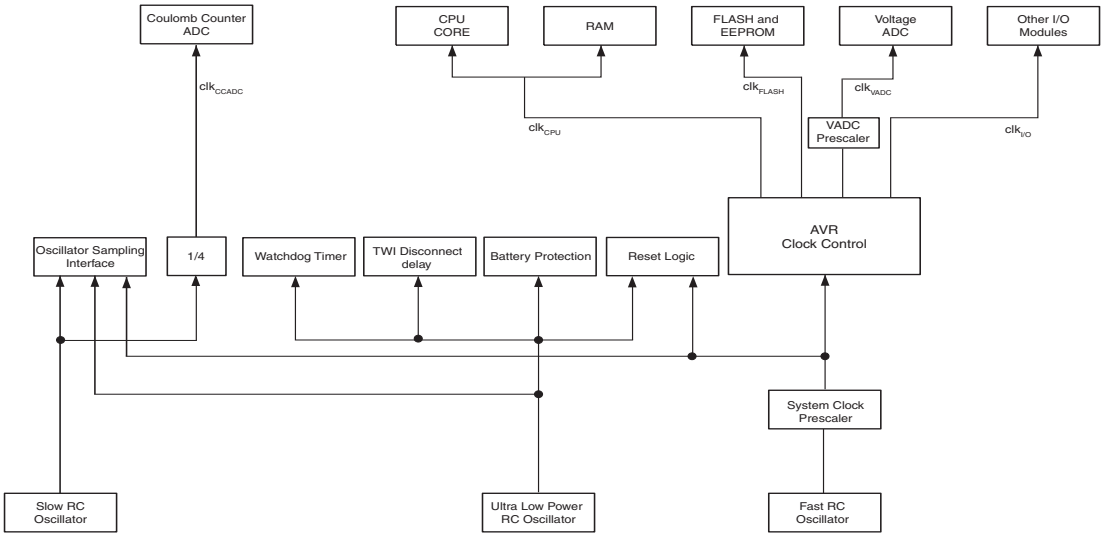
Bit	7	6	5	4	3	2	1	0	
0x1E (0x3E)	MSB							LSB	GPIOR0
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

9. System clock and clock options

9.1 Clock systems and their distribution

Figure 9-1 presents the principal clock systems in the AVR and their distribution. All of the clocks need not be active at a given time. In order to reduce power consumption, the clocks to modules not being used can be halted by using different sleep modes, as described in ”Power management and sleep modes” on page 35. The clock systems are detailed below.

Figure 9-1. Clock distribution.



9.1.1 CPU clock – clk_{CPU}

The CPU clock is routed to parts of the system concerned with operation of the AVR core. Examples of such modules are the General Purpose Register File, the Status Register and the data memory holding the Stack Pointer. Halting the CPU clock inhibits the core from performing general operations and calculations.

9.1.2 I/O clock – $clk_{I/O}$

The I/O clock is used by the majority of the I/O modules. The I/O clock is also used by the External Interrupt module, but note that some external interrupts are detected by asynchronous logic, allowing such interrupts to be detected even if the I/O clock is halted.

9.1.3 Flash clock – clk_{FLASH}

The Flash clock controls operation of the Flash interface. The Flash clock is usually active simultaneously with the CPU clock.

9.1.4 Voltage ADC clock – clk_{VADC}

The Voltage ADC is provided with a dedicated clock domain. The VADC clock is automatically prescaled relative to the System Clock Prescalers setting by the VADC Prescaler, giving a fixed VADC clock at 1MHz.

9.1.5 Coulomb counter ADC clock - clk_{CCADC}

The Coulomb Counter ADC is provided with a dedicated clock domain. This allows operating the Coulomb Counter ADC in low power modes like Power-save for continuous current measurements.

9.1.6 Watchdog timer and battery protection clock

The Watchdog Timer and Battery Protection are provided with a dedicated clock domain. This allows operation in all modes except Power-off. It also allows very low power operation by utilizing an Ultra Low Power RC Oscillator dedicated to this purpose.

9.2 Clock sources

The following section describes the clock sources available in the device. The clocks are input to the AVR clock generator, and routed to the appropriate modules.

The Atmel ATmega16HVB/32HVB has three on-board oscillators used to clock the internal logic. Table 9-1 shows the clock sources and their usage.

Table 9-1. Available clock sources.

Clock source	Usage
Calibrated fast RC oscillator	The clock source for the CPU, I/O, Flash, and Voltage ADC
Ultra low power RC oscillator	The clock source for the Watchdog Timer, Battery Protection, Bandgap Buffer Short Circuit Detector, and SMBus Connect/Disconnect
Slow RC oscillator	Used by the Coulomb Counter ADC and Oscillator Sampling Interface (OSI)

9.2.1 Calibrated Fast RC oscillator

The calibrated Fast RC Oscillator by default provides a 8.0MHz clock. The frequency is nominal value at 25°C. This clock will operate with no external components. During reset, hardware loads the calibration byte into the FOSCCAL Register and thereby automatically calibrates the Fast RC Oscillator. At 25°C, this calibration gives a frequency of 8MHz ±1%. The oscillator can be calibrated to any frequency in the range 7.3MHz - 8.1MHz by changing the FOSCCAL register. For more information on the pre-programmed calibration value, see the section ”Reading the signature row from software” on page 195. Note that the frequency of the system clock is given by the ”System clock prescaler” on page 28.

When this Oscillator is selected, start-up times are determined by the SUT Fuses as shown in Table 9-2.

Table 9-2. Start-up times for the calibrated Fast RC Oscillator clock selection.

SUT2:0	Start-up time from power-save	Additional delay from reset, typical values (2)
000	6 CK	14 CK + 4ms
001	6 CK	14 CK + 8ms
010	6 CK	14 CK + 16ms
011	6 CK	14 CK + 32ms
100	6 CK	14 CK + 64ms

Table 9-2. Start-up times for the calibrated Fast RC Oscillator clock selection. (Continued)

SUT2:0	Start-up time from power-save	Additional delay from reset, typical values (2)
101	6 CK	14 CK + 128ms
110	6 CK	14 CK + 256ms
111 (1)	6 CK	14 CK + 512ms

Notes: 1. The device is shipped with this option selected.
2. The actual value of the added, selectable 4ms - 512ms delay depends on the actual frequency of the "Ultra Low Power RC oscillator" . See Table 9-3 on page 28 and "Electrical characteristics" on page 225.

9.2.2 Slow RC oscillator

The Slow RC Oscillator provides a 131kHz clock (typical value, refer to section "Electrical characteristics" on page 225). This oscillator provides the clock for the CC-ADC module. It can also be used as a timing reference for run-time calibration of the Fast RC Oscillator and for accurately determining the actual ULP Oscillator frequency, refer to "OSI – Oscillator sampling interface" on page 29 for details.

To provide good accuracy when used as a timing reference, the Slow RC Oscillator has calibration bytes stored in the signature address space, refer to section "Reading the signature row from software" on page 195 for details. The actual clock period of the Slow RC Oscillator in µs as a function of temperature is given by:

$$\text{Slow RC period} = \frac{\text{Slow RC word - Slow RC temp prediction word} \cdot \frac{(T - T_{HOT})}{64}}{1024}$$

where T is the die temperature in Kelvin and T_{HOT} is the calibration temperature stored in the signature row. The die temperature can be found using the Voltage ADC, refer to section "Voltage ADC – 7-channel general purpose 12-bit Sigma-Delta ADC" on page 116 for details.

9.2.3 Ultra Low Power RC oscillator

The Ultra Low Power RC Oscillator (ULP Oscillator) provides a 128kHz clock (typical value, refer to section "Electrical characteristics" on page 225). This oscillator provides the clock for the Watchdog Timer and Battery Protection modules. The actual ULP Oscillator frequency depends on process variations and temperature, see "Electrical characteristics" on page 225. The Oscillator is automatically enabled in all operational modes. It is also enabled during reset. There are three alternative methods for determining the actual clock period of the ULP Oscillator:

1. To determine the accurate clock period as a function of die temperature, if needed by the application, the Oscillator Sampling Interface should be used. Refer to section "OSI – Oscillator sampling interface" on page 29 for details.
2. An alternative method to determine the accurate clock period as a function of die temperature, is to read calibration bytes from the signature address space and calculate the clock period as a function of die temperature, refer to section "Reading the signature row from software" on page 195 for details. The actual clock period of the ULP RC Oscillator in µs as a function of temperature is given by:

$$\text{ULP RC period} = \frac{\text{ULP RC word - ULP RC temp prediction word} \cdot \frac{(T - T_{HOT})}{64}}{1024}$$

where T is the die temperature in Kelvin and THOT is the calibration temperature stored in the Signature row. The die temperature can be found using the Voltage ADC, refer to section ”Voltage ADC – 7-channel general purpose 12-bit Sigma-Delta ADC” on page 116 for details.

3. To determine a fixed value for the actual clock period independent of the die temperature, for example to determine the best setting of the Battery Protection timing, use the calibration byte ULP_RC_FRQ stored in the signature address space, refer to section ”Reading the signature row from software” on page 195 for details.

9.3 Clock startup sequence

When the CPU wakes up from Power-save, the CPU clock source is used to time the start-up, ensuring a stable clock before instruction execution starts. When the CPU starts from reset, there is an additional delay allowing the voltage regulator to reach a stable level before commencing normal operation. The Ultra Low Power RC Oscillator is used for timing this real-time part of the start-up time. Start-up times are determined by the SUT Fuses as shown in Table 9-2 on page 26. The number of Ultra Low Power RC Oscillator cycles used for each time-out is shown in Table 9-3.

Table 9-3. Number of Ultra Low Power RC oscillator cycles.

Typical time-out (1)	Number of cycles
4ms	512
8ms	1K
16ms	2K
32ms	4K
64ms	8K
128ms	16K
256ms	32K
512ms	64K

Note: 1. The actual value depends on the actual clock period of the Ultra Low Power RC Oscillator, refer to ”Ultra Low Power RC oscillator” on page 27 for details.

9.4 Clock output

The CPU clock divided by two can be output to the PB1 pin. The CPU can enable the clock output function by setting the CKOE bit in the MCU Control Register. The clock will not run in any sleep modes.

9.5 System clock prescaler

The Atmel ATmega16HVB/32HVB has a System Clock Prescaler, used to prescale the Calibrated Fast RC Oscillator. The system clock can be divided by setting the ”CLKPR – Clock Prescale Register” on page 32, and this enables the user to decrease or increase the system clock frequency as the requirement for power consumption and processing power changes. This system clock will affect the clock frequency of the CPU and all synchronous peripherals. $clk_{I/O}$, clk_{CPU} and clk_{FLASH} are divided by a factor as shown in Table 9-4 on page 33.

When switching between prescaler settings, the System Clock Prescaler ensures that no glitches occurs in the clock system. It also ensures that no intermediate frequency is higher than

neither the clock frequency corresponding to the previous setting, nor the clock frequency corresponding to the new setting.

The ripple counter that implements the prescaler runs at the frequency of the undivided clock, and may be faster than the CPU's clock frequency. It is not possible to determine the state of the prescaler, and the exact time it takes to switch from one clock division to the other cannot be exactly predicted. From the time the CLKPS values are written, it takes between T1 + T2 and T1 + 2×T2 before the new clock frequency is active. In this interval, two active clock edges are produced. Here, T1 is the previous clock period, and T2 is the period corresponding to the new prescaler setting.

To avoid unintentional changes of clock frequency, a special write procedure must be followed to change the CLKPS bits:

1. Write the Clock Prescaler Change Enable (CLKPCE) bit to one and all other bits in CLKPR to zero.
2. Within four cycles, write the desired value to CLKPS while writing a zero to CLKPCE.

Interrupts must be disabled when changing prescaler setting to make sure the write procedure is not interrupted.

9.6 VADC clock prescaler

The VADC clock will be automatically prescaled relative to the System Clock Prescaler settings, see ”System clock prescaler” on page 28. Depending on the Clock Prescale Select bits, CLKPS1..0, the VADC clock, clk_{VADC}, will be prescaled by eight, four, two or one as shown in Table 9-5 on page 33.

9.7 OSI – Oscillator sampling interface

9.7.1 Features

- **Runtime selectable oscillator input (Slow RC or ULP RC oscillator)**
- **Seven bit prescaling of the selected oscillator**
- **Software read access to the phase of the prescaled clock**
- **Input capture trigger source for Timer/Counter0**

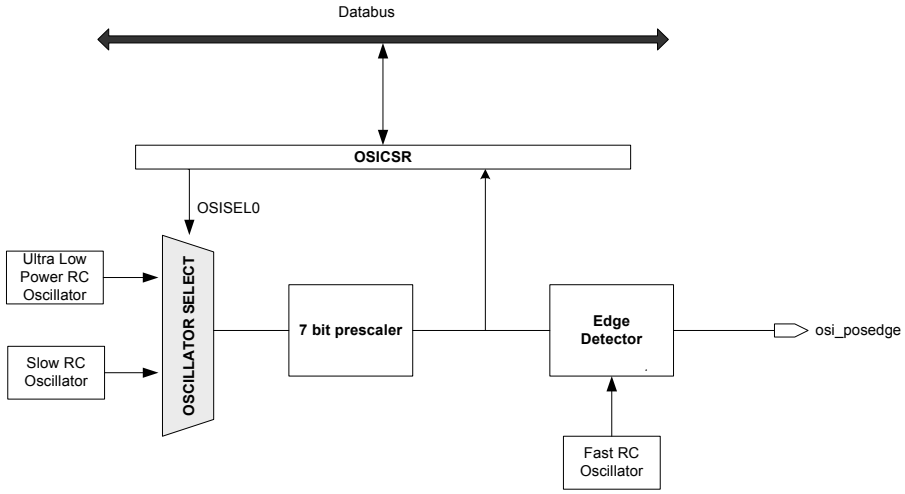
9.7.2 Overview

The Oscillator Sampling Interface (OSI) enables sampling of the Slow RC and Ultra Low Power RC (ULP) oscillators in Atmel ATmega16HVB/32HVB. OSI can be used to calibrate the Fast RC Oscillator runtime with high accuracy. OSI can also provide an accurate reference for compensating the ULP Oscillator frequency drift.

The prescaled oscillator phase can be continuously read by the CPU through the OSICSR register. In addition, the input capture function of Timer/Counter0 can be set up to trigger on the rising edge of the prescaled clock. This enables accurate measurements of the oscillator frequencies relative to the Fast RC Oscillator.

A simplified block diagram of the Oscillator Sampling Interface is shown in Figure 9-2 on page 30.

Figure 9-2. Oscillator sampling interface block diagram.



The osi_posedge signal pulses on each rising edge of the prescaled clock. This signal is not directly accessible by the CPU, but can be used to trigger the input capture function of Timer/Counter0. Using OSI in combination with the input capture function of Timer/Counter0 facilitates accurate measurement of the oscillator frequencies with a minimum of CPU calculation. Refer to ”Timer/Counter (T/C0,T/C1)” on page 82 for details on how to enable the Input Capture function.

9.7.3 Usage

The Slow RC oscillator represents a highly predictable and accurate clock source over the entire temperature range and provides an excellent reference for calibrating the Fast RC oscillator runtime. Typically, runtime calibration is needed to provide an accurate Fast RC frequency for asynchronous serial communication in the complete temperature range.

The Slow RC frequency at 85°C and the Slow RC temperature coefficient are stored in the signature row. These characteristics can be used to calculate the actual Slow RC clock period at a given temperature with high precision. Refer to ”Slow RC oscillator” on page 27 for details.

By measuring the number of CPU cycles of one or more prescaled Slow RC clock periods, the actual Fast RC oscillator clock period can be determined. The Fast RC clock period can then be adjusted by writing to the FOSCCAL register. The new Fast RC clock period after calibration should be verified by repeating the measurement and repeating the calibration if necessary. The Fast RC clock period as a function of the Slow RC clock period is given by:

$$T_{FastRC} = T_{SlowRC} \cdot \frac{128 \cdot n}{\text{number of CPU cycles in n prescaled Slow RC periods}}$$

where n is the number of prescaled Slow RC periods that is used in the measurement. Using more prescaled Slow RC periods decreases the measurement error, but increases the time consumed for calibration. Note that the Slow RC Oscillator needs very short time to stabilize after being enabled by the OSI module. Hence, the calibration algorithm may use the time between the first and second osi_posedge as time reference for calculations.

Another usage of OSI is determining the ULP frequency accurately. The ULP frequency at 85°C and the ULP temperature coefficient are stored in the signature row, allowing the ULP frequency to be calculated directly. However, the ULP frequency is less predictable over temperature than the Slow RC oscillator frequency, therefore a more accurate result can be obtained by calculating the ratio between the Slow RC and ULP oscillators. This is done by sampling both the ULP and Slow RC oscillators and comparing the results. When the ratio is known, the actual ULP frequency can be determined with high accuracy. The ULP RC clock period as a function of the Slow RC clock period is given by:

$$T_{ULPRC} = T_{SlowRC} \cdot \frac{\text{number of CPU cycles in n prescaled ULP RC periods}}{\text{number of CPU cycles in n prescaled Slow RC periods}}$$

where n is the number of prescaled ULP RC and Slow RC periods that is used in the measurement. Using more prescaled ULP RC and Slow RC periods decreases the measurement error, but increases the time consumed for calibration. Note that the FOSCCAL register must be kept at a constant value during this operation to ensure accurate results.

These clock period calculations should be performed again when there is a significant change in die temperature since the previous calculation. The die temperature can be found using the Voltage ADC, refer to section ”Voltage ADC – 7-channel general purpose 12-bit Sigma-Delta ADC” on page 116 for details.

9.8 Register description

9.8.1 FOSCCAL – Fast RC oscillator Calibration Register

Bit	7	6	5	4	3	2	1	0	
(0x66)	FCAL7	FCAL6	FCAL5	FCAL4	FCAL3	FCAL2	FCAL1	FCAL0	FOSCCAL
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	Device Specific Calibration Value								

- **Bits 7:0 – FCAL[7:0]: Fast RC Oscillator Calibration Value**

The Fast RC Oscillator Calibration Register is used to trim the Fast RC Oscillator to remove process variations from the oscillator frequency. The factory-calibrated value is automatically written to this register during chip reset, giving an oscillator frequency of approximately 8.0MHz at 25°C. The application software can write this register to change the oscillator frequency. The oscillator can be run-time calibrated to any frequency in the range 7.3MHz - 8.1MHz. Calibration outside that range is not guaranteed.

Note that this oscillator is used to time EEPROM and Flash write accesses, and these write times will be affected accordingly. If the EEPROM or Flash are written, do not calibrate to more than 8.1MHz. Otherwise, the EEPROM or Flash write may fail.

The FCAL[7:5] bits determine the range of operation for the oscillator. Setting these bits to 0b000 gives the lowest frequency range, setting this bit to 0b111 gives the highest frequency range. The frequency ranges are overlapping. A setting of for instance FOSCCAL = 0x1F gives a higher frequency than FOSCCAL = 0x20.

The FCAL[4:0] bits are used to tune the frequency within the selected range. A setting of 0x00 gives the lowest frequency in that range, and a setting of 0x1F gives the highest frequency in the range. Incrementing FCAL[4:0] by one will give a frequency increment of less than 1% in the frequency range 7.3MHz - 8.1MHz. With an accurate time reference, an oscillator accuracy of ±0.5% can be achieved after calibration. The frequency will drift with temperature, so run-time calibration will be required to maintain the accuracy. Refer to ”OSI – Oscillator sampling interface” on page 29 for details.

9.8.2 MCUCR – MCU Control Register

Bit	7	6	5	4	3	2	1	0	
0x35 (0x55)	---	–	CKOE	PUD	_	_	IVSEL	IVCE	MCUCR
Read/Write	R	R	R/W	R/W	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 5 – CKOE: Clock output**

When this bit is written to one, the CPU clock divided by 2 is output on the PB1 pin.

9.8.3 CLKPR – Clock Prescale Register

Bit	7	6	5	4	3	2	1	0	
(0x61)	CLKPCE	_	_	_	_	_	CLKPS1	CLKPS0	CLKPR
Read/Write	R/W	R	R	R	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	1	1	

- **Bit 7 – CLKPCE: Clock Prescaler change enable**

The CLKPCE bit must be written to logic one to enable change of the CLKPS bits. The CLKPCE bit is only updated when the other bits in CLKPR are simultaneously written to zero. CLKPCE is cleared by hardware four cycles after it is written or when CLKPS bits are written. Rewriting the CLKPCE bit within this time-out period does neither extend the time-out period, or clear the CLKPCE bit.

- **Bit 1:0 – CLKPS[1:0]: Clock Prescaler select Bit[1:0]**

These bits define the division factor between the selected clock source and the internal system clock. These bits can be written run-time to vary the clock frequency to suit the application requirements. As the divider divides the master clock input to the MCU, the speed of all synchronous peripherals is reduced when a division factor is used. The division factors are given in Table 9-4. Note that writing to the System Clock Prescaler Select bits will abort any ongoing VADC conversion.

The CKDIV8 Fuse (see Table 30-3 on page 205) determines the initial value of the CLKPS bits. If CKDIV8 is unprogrammed, the CLKPS bits will be reset to “00”. If CKDIV8 is programmed, CLKPS bits are reset to “11”, giving a division factor of eight at startup (default factory setting).

Note that any value can be written to the CLKPS bits, regardless of the CKDIV8 Fuse setting.

Table 9-4. System clock prescaler select.

CLKPS1	CLKPS0	Clock division factor
0	0	1
0	1	2
1	0	4
1	1	8

Table 9-5. VADC Clock prescaling [1].

CLKPS1	CLKPS0	VADC division factor
0	0	8
0	1	4
1	0	2
1	1	1

Note: 1. When changing Prescaler value, the VADC Prescaler will automatically change frequency of the VADC clock and abort any ongoing conversion.

9.8.4 OSICSR – Oscillator sampling interface control and Status Register

Bit	7	6	5	4	3	2	1	0	
0x17 (0x37)	–	–	–	OSISEL0	–	–	OSIST	OSIEN	OSICSR
Read/Write	R	R	R	R/W	R	R	R	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:5, 3:2 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB and will always read as zero.

- **Bit 4 – OSISEL0: Oscillator sampling interface select 0**

Table 9-6. OSISEL Bit Description.

OSISEL0	Oscillator source
0	ULP Oscillator
1	Slow RC Oscillator

- **Bit 1 – OSIST: Oscillator sampling interface status**

This bit continuously displays the phase of the prescaled clock. This bit can be polled by the CPU to determine the rising and falling edges of the prescaled clock.

- **Bit 0 – OSIEN: Oscillator sampling interface enable**

Setting this bit enables the Oscillator Sampling Interface. When this bit is cleared, the Oscillator Sampling Interface is disabled.

Notes: 1. The prescaler is reset each time the OSICSR register is written, and hence each time a new oscillator source is selected.

10. Power management and sleep modes

Sleep modes enable the application to shut down unused modules in the MCU, thereby saving power. The AVR provides various sleep modes allowing the user to tailor the power consumption to the application's requirements.

10.1 Sleep modes

Figure 9-1 on page 25 presents the different clock systems in the Atmel ATmega16HVB/32HVB, and their distribution. The figure is helpful in selecting an appropriate sleep mode. The different sleep modes and their wake up sources is summarized in Table 10-1, and Figure 10-1 on page 36 shows a sleep mode state diagram.

Table 10-1. Wake-up Sources for Sleep Modes.

Mode	Wake-up sources											
	Bandgap buffer short circuit detection	Wake-up on regular current	Battery protection interrupts	External interrupts	WDT	SPM/EEPROM ready	CC-ADC	V-ADC	Other I/O	Charger detect (1)(2)	SMBus address match and bus connect/disconnect	Voltage regulator warning
Idle	X	X	X	X	X	X	X	X	X	X	X	X
ADC noise reduction	X	X	X	X	X	X	X	X		X	X	X
Power-save	X	X	X	X	X		X			X	X	
Power-off										X		

Notes: 1. Discharge FET must be switched off for Charge Detect to be active.
2. When waking from Power-off the Charger Detect will generate a Power-on Reset (POR). From other sleep modes a charger detect interrupt will wake-up chip.

To enter any of the sleep modes, the SE bit in SMCR, see "SMCR – Sleep Mode Control Register" on page 39, must be written to logic one and a SLEEP instruction must be executed. The SM2..0 bits in the SMCR Register select which sleep mode will be activated by the SLEEP instruction. See Table 10-3 on page 40 for a summary.

If an enabled interrupt occurs while the MCU is in a sleep mode, the MCU wakes up. The MCU is then halted for four cycles in addition to the start-up time, executes the interrupt routine, and resumes execution from the instruction following SLEEP. The contents of the register file and SRAM are unaltered when the device wakes up from any sleep mode except Power-off. If a reset occurs during sleep mode, the MCU wakes up and executes from the Reset Vector.

Figure 10-1. Sleep mode state diagram.

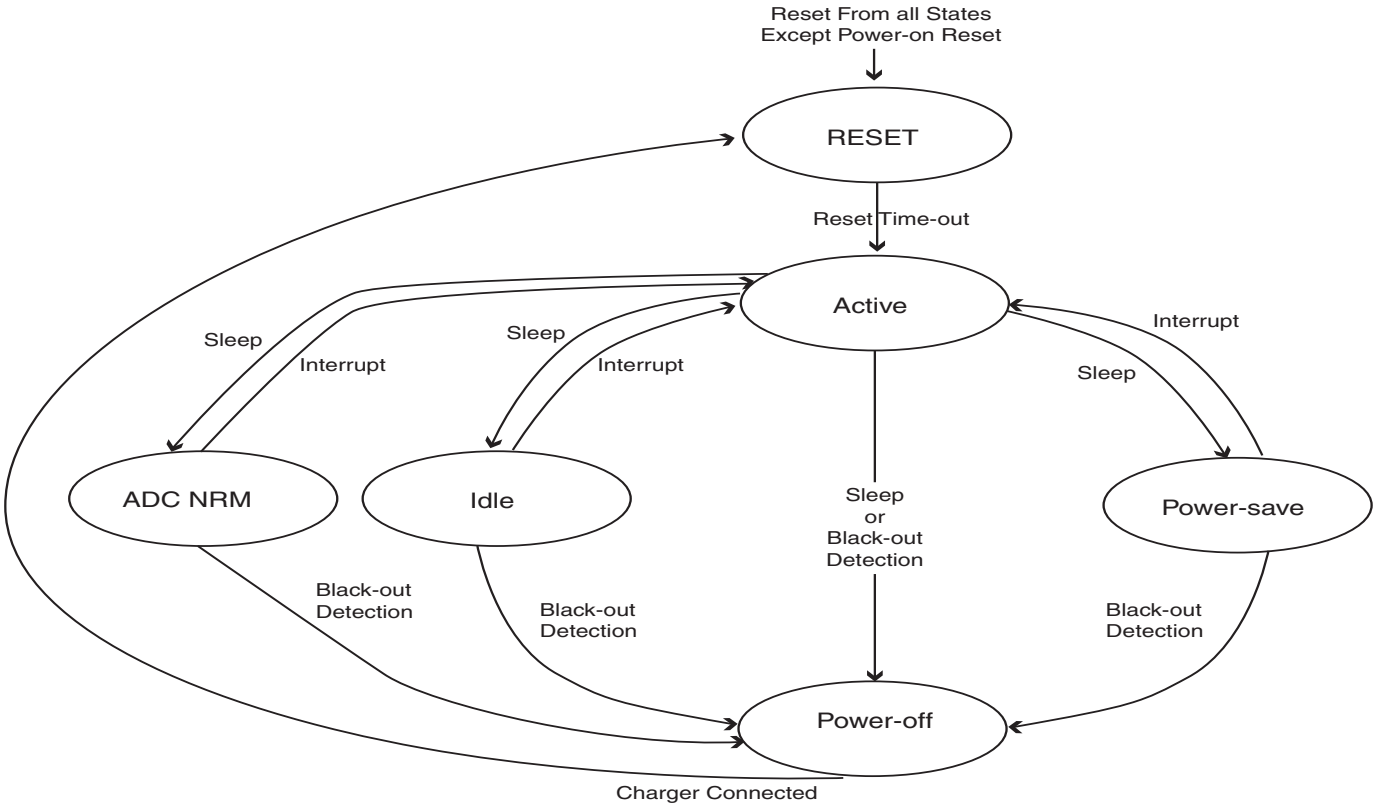


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Table 10-2. Active modules in different sleep modes.

	Mode				
Module	**Active**	**Idle**	**ADC noise reduction**	**Power-save**	**Power-off**
RCOSC_FAST	X	X	X	X	
RCOSC_ULP	X	X	X	X	
RCOSC_SLOW	X (1)	X (1)	X (2)	X (2)	
OSI	X	X			
CPU	X				
Flash	X				
8-bit Timer/16-bit Timer	X	X			
TWI/SMBus	X	X	X (3)	X (3)	
SPI	X	X			
V-ADC	X	X	X		
CC-ADC	X	X	X	X	

Table 10-2. Active modules in different sleep modes. (Continued)

Module	Mode				
	Active	Idle	ADC noise reduction	Power-save	Power-off
External Interrupts	X	X	X	X	
Battery Protection	X	X	X	X	
Watchdog Timer	X	X	X	X	
Voltage Regulator	X	X	X	X [5]	
Bandgap Reference	X	X	X	X	
FET Driver	X	X	X	X	
CHARGER_DETECT[4]	X	X	X	X	X

Notes:
1. Runs only when CC-ADC is enabled, or OSI is enabled and RCOSC_SLOW is selected as source for OSI.
2. Runs only when CC-ADC is enabled.
3. Address Match and Bus Connect/Disconnect Wake-up only.
4. Discharge FET must be switched off for Charger Detect to be enabled.
5. VREGMON interrupt (Regulator Operation Condition Warning) not available.

10.2 Idle mode

When the SM2:0 bits are written to 000, the SLEEP instruction makes the MCU enter Idle mode, stopping the CPU but allowing all peripheral functions to continue operating. This sleep mode basically halts clk_{CPU} and clk_{FLASH}, while allowing the other clocks to run. Idle mode enables the MCU to wake up from external triggered interrupts as well as internal ones like the Timer Overflow interrupt.

10.3 ADC noise reduction

When the SM2:0 bits are written to 001, the SLEEP instruction makes the MCU enter ADC Noise Reduction mode, stopping the CPU but allowing the Voltage ADC (V-ADC), Voltage Regulator Monitor (VREGMON), Watchdog Timer (WDT), Coulomb Counter (CC), Current Battery Protection (CBP), Slow RC Oscillator (RCOSC_SLOW) (if CC is enabled), and the Ultra Low Power RC Oscillator (RCOSC_ULP) to continue operating. This sleep mode basically halts $clk_{I/O}$, clk_{CPU}, and clk_{FLASH}, while allowing the other clocks to run.

This improves the noise environment for the Voltage ADC, enabling higher accuracy on measurements.

10.4 Power-save mode

When the SM2:0 bits are written to 011, the SLEEP instruction makes the MCU enter Power-save mode. In this mode, the internal Fast RC Oscillator (RCOSC_FAST) is stopped, while Watchdog Timer (WDT), Coulomb Counter (CC), Current Battery Protection (CBP) , Slow RC Oscillator (RCOSC_SLOW) (if CC is enabled), and the Ultra Low Power RC Oscillator (RCOSC_ULP) continue operating.

This mode will be the default mode when application software does not require operation of CPU, Flash or any of the peripheral units running at the Fast internal Oscillator (RCOSC_FAST).

If the current through the sense resistor is so small that the Coulomb Counter cannot measure it accurately, Regular Current detection should be enabled to reduce power consumption. The WDT keeps accurately track of the time so that battery self discharge can be calculated.

Note that if a level triggered interrupt is used for wake-up from Power-save mode, the changed level must be held for some time to wake up the MCU. Refer to ”External interrupts” on page 58 for details.

When waking up from Power-save mode, there is a delay from the wake-up condition occurs until the wake-up becomes effective. This allows the clock to restart and become stable after having been stopped. The wake-up period is defined in ”Clock sources” on page 26.

10.5 Power-off mode

When the SM2..0 bits are written to 100 and the SE bit is set, the SLEEP instruction makes the CPU shut down the Voltage Regulator, leaving only the Charger Detect Circuitry operational. To ensure that the MCU enters Power-off mode only when intended, the SLEEP instruction must be executed within 4 clock cycles after the SM2..0 bits are written. The MCU will reset when returning from Power-off mode.

Note: 1. Before entering Power-off sleep mode, interrupts should be disabled by software. Otherwise interrupts may prevent the SLEEP instruction from being executed within the time limit.

10.6 Power Reduction Register

The Power Reduction Register (PRR), see ”PRR0 – Power Reduction Register 0” on page 40, provides a method to stop the clock to individual peripherals to reduce power consumption. The current state of the peripheral is frozen and the I/O registers can not be read or written. Resources used by the peripheral when stopping the clock will remain occupied, hence the peripheral should in most cases be disabled before stopping the clock. Waking up a module, which is done by clearing the bit in PRR, puts the module in the same state as before shutdown.

Module shutdown can be used in Idle mode and Active mode to significantly reduce the overall power consumption. In all other sleep modes, the clock is already stopped.

10.7 Minimizing power consumption

There are several issues to consider when trying to minimize the power consumption in an AVR controlled system. In general, sleep modes should be used as much as possible, and the sleep mode should be selected so that as few as possible of the device’s functions are operating. All functions not needed should be disabled. In particular, the following modules may need special consideration when trying to achieve the lowest possible power consumption.

10.7.1 Watchdog Timer

If the Watchdog Timer is not needed in the application, the module should be turned off. If the Watchdog Timer is enabled, it will be enabled in all sleep modes except Power-off. The Watchdog Timer current consumption is significant only in Power-save mode. Refer to ”Watchdog timer” on page 46 for details on how to configure the Watchdog Timer.

10.7.2 Port pins

When entering a sleep mode, all port pins should be configured to use minimum power. The most important is then to ensure that no pins drive resistive loads. In sleep modes where both the I/O clock ($clk_{I/O}$) and the ADC clock (clk_{ADC}) are stopped, the input buffers of the device will be disabled. This ensures that no power is consumed by the input logic when not needed. In

some cases, the input logic is needed for detecting wake-up conditions, and it will then be enabled. Refer to the section ”Digital input enable and sleep modes” on page 71 for details on which pins are enabled. If the input buffer is enabled and the input signal is left floating or have an analog signal level close to $V_{REG}/2$, the input buffer will use excessive power.

For analog input pins, the digital input buffer should be disabled at all times. An analog signal level close to $V_{REG}/2$ on an input pin can cause significant current even in active mode. Digital input buffers can be disabled by writing to the Digital Input Disable Register. Refer to ”DIDR0 – Digital Input Disable Register 0” on page 121 for details.

10.7.3 On-chip debug system

A programmed DWEN Fuse enables some parts of the clock system to be running in all sleep modes. This will increase the power consumption while in sleep. Thus, the DWEN Fuse should be disabled when debugWire is not used.

10.7.4 Battery protection

If one of the Battery Protection features is not needed by the application, this feature should be disabled, see ”BPCR – Battery Protection Control Register” on page 138. The current consumption in the Battery Protection circuitry is only significant in Power-save mode. Disabling both FETs will automatically disable the Battery Protection module in order to save power. The bandgap reference should always be enabled whenever Battery Protection is enabled.

10.7.5 Voltage ADC

If enabled, the V-ADC will consume power independent of sleep mode. To save power, the V-ADC should be disabled when not used, and before entering Power-save sleep mode. See ”Voltage ADC – 7-channel general purpose 12-bit Sigma-Delta ADC” on page 116 for details on V-ADC operation.

10.7.6 Coulomb counter

If enabled, the CC-ADC will consume power independent of sleep mode. To save power, the CC-ADC should be disabled when not used, or set in Regular Current detection mode. See ”Coulomb counter – Dedicated fuel gauging Sigma-Delta ADC” on page 108 for details on CC-ADC operation.

10.7.7 Bandgap voltage reference

If enabled, the Bandgap reference will consume power independent of sleep mode. To save power, the Bandgap reference should be disabled when not used as reference for the Voltage ADC, the Coloumb Counter or Battery Protection. See ”Voltage reference and temperature sensor” on page 122 for details.

10.8 Register description

10.8.1 SMCR – Sleep Mode Control Register

The Sleep Mode Control Register contains control bits for power management.

Bit	7	6	5	4	3	2	1	0	
0x33 (0x53)	–	–	–	–	SM2	SM1	SM0	SE	SMCR
Read/Write	R	R	R	R	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:4 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB, and will always read as zero.

- **Bits 3:1 – SM2:0: Sleep Mode Select Bits 2, 1 and 0**

These bits select between the four available sleep modes as shown in Table 10-3.

Table 10-3. Sleep Mode Select.

SM2	SM1	SM0	Sleep Mode
0	0	0	Idle
0	0	1	ADC Noise Reduction
0	1	0	Reserved
0	1	1	Power-save
1	0	0	Power-off
1	0	1	Reserved
1	1	0	Reserved
1	1	1	Reserved

- **Bit 0 – SE: Sleep Enable**

The SE bit must be written to logic one to make the MCU enter the sleep mode when the SLEEP instruction is executed. To avoid the MCU entering the sleep mode unless it is the programmer's purpose, it is recommended to write the Sleep Enable (SE) bit to one just before the execution of the SLEEP instruction and to clear it immediately after waking up.

10.8.2 PRR0 – Power Reduction Register 0

Bit	7	6	5	4	3	2	1	0	
(0x64)	–	PRTWI	PRVRM	–	PRSPI	PRTIM1	PRTIM0	PRVADC	PRR0
Read/Write	R	R/W	R/W	R	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7, 4 – Reserved**

These bits are reserved for future use. For compatibility with future devices, these bits must be written to zero when PRR0 is written.

- **Bit 6 – PRTWI: Power Reduction TWI**

Writing a logic one to this bit shuts down the TWI by stopping the clock to the module. When waking up the TWI again, the TWI should be re initialized to ensure proper operation.

- **Bit 5 – PRVRM: Power Reduction Voltage Regulator Monitor**

Writing a logic one to this bit shuts down the Voltage Regulator Monitor interface by stopping the clock of the module.

- **Bit 3 – PRSPI: Power Reduction Serial Peripheral Interface**

Writing logic one to this bit shuts down the Serial Peripheral Interface by stopping the clock to the module. When waking up the SPI again, the SPI should be reinitialized to ensure proper operation.

- **Bit 2 – PRTIM1: Power Reduction Timer/Counter1**

Writing a logic one to this bit shuts down the Timer/Counter1 module. When the Timer/Counter1 is enabled, operation will continue like before the shutdown.

- **Bit 1 – PRTIM0: Power Reduction Timer/Counter0**

Writing a logic one to this bit shuts down the Timer/Counter0 module. When the Timer/Counter0 is enabled, operation will continue like before the shutdown.

- **Bit 0 – PRVADC: Power Reduction V-ADC**

Writing a logic one to this bit shuts down the V-ADC. Before writing the PRVADC bit, make sure that the VADEN bit is cleared to minimize the power consumption.

Note: V-ADC control registers can be updated even if the PRVADC bit is set.

11. System control and reset

11.1 Resetting the AVR

During reset, all I/O Registers are set to their initial values, and the program starts execution from the Reset Vector. The instruction placed at the Reset Vector must be a JMP – Absolute Jump – instruction to the reset handling routine. If the program never enables an interrupt source, the Interrupt Vectors are not used, and regular program code can be placed at these locations. The circuit diagram in ”Reset logic.” on page 43 shows the reset logic. Table 12-1 on page 52 defines the electrical parameters of the reset circuitry.

The I/O ports of the AVR are immediately reset to their initial state when a reset source goes active. This does not require any clock source to be running.

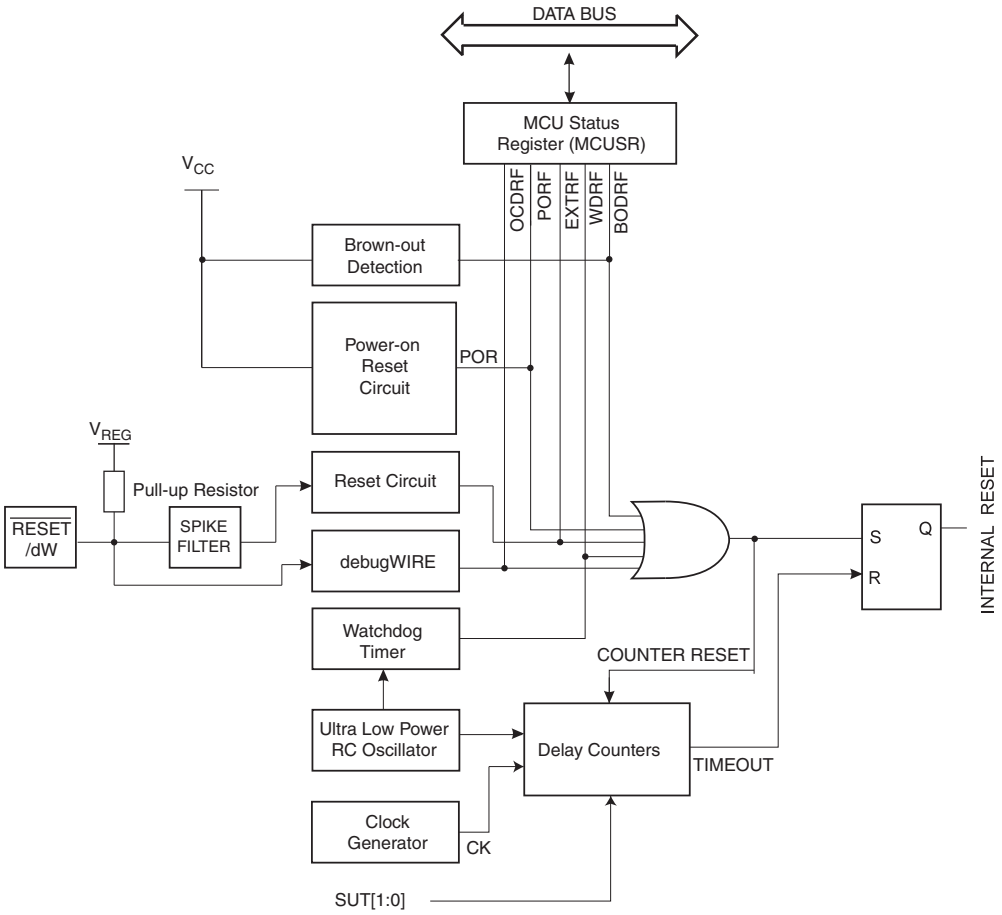
After all reset sources have gone inactive, a delay counter is invoked, stretching the internal reset. This allows the voltage regulator to reach a stable level before normal operation starts. The time-out period of the delay counter is defined by the user through the SUT Fuses. The different selections for the delay period are presented in ”Clock sources” on page 26.

11.2 Reset sources

The Atmel ATmega16HVB/32HVB has five sources of reset:

- The Power-on Reset module generates a Power-on Reset when the Voltage Regulator starts up
- External Reset. The MCU is reset when a low level is present on the RESET pin for longer than the minimum pulse length
- Watchdog Reset. The MCU is reset when the Watchdog Timer period expires and the Watchdog is enabled
- Brown-out Reset. The MCU is reset when V_{REG} is below the Brown-out Reset Threshold, V_{BOT}. see ”Brown-out detection” on page 45
- debugWIRE Reset. In On-chip Debug mode, the debugWIRE resets the MCU when giving the Reset command

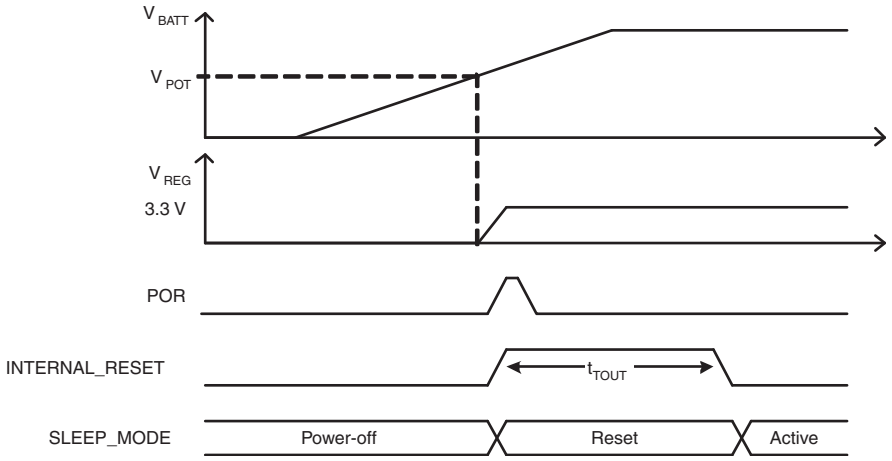
Figure 11-1. Reset logic.



11.2.1 Power-on reset and charger connect

The Voltage Regulator will not start up until the Charger Detect module has enabled it. Before this happens the chip will be in Power-off mode and only the Charger Detect module is enabled. In order for the Charger Detect module to enable the Voltage Regulator, the voltage at the BATT pin must exceed the Power-On Threshold Voltage, V_{POT}. When the voltage at the BATT pin exceeds V_{POT}, the Voltage Regulator starts up and the chip enters RESET mode. When the Delay Counter times out, the chip will enter Active mode. See Figure 10-1 on page 36. For details on Charger Detect, see ”Charger detect” on page 126.

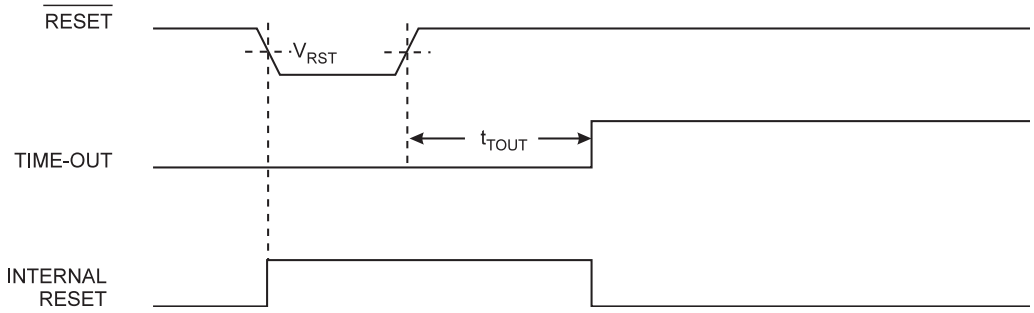
Figure 11-2. Powering up Atmel ATmega16HVB/32HVB.



11.2.2 External Reset

An External Reset is generated by a low level on the $\overline{\text{RESET}}$ pin. Reset pulses longer than the minimum pulse width (see Table 32-3 on page 227) will generate a reset, even if the clock is not running. Shorter pulses are not guaranteed to generate a reset. When the applied signal reaches the Reset Threshold Voltage – V_{RST} – on its positive edge, the delay counter starts the MCU after the Time-out period – t_{TOUT} – has expired.

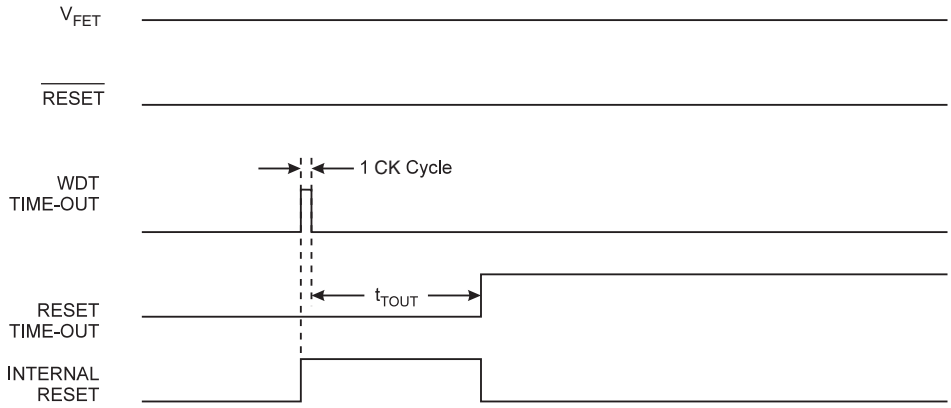
Figure 11-3. External Reset During Operation.



11.2.3 Watchdog Reset

When the Watchdog times out, it will generate a short reset pulse of one CK cycle duration. On the falling edge of this pulse, the delay timer starts counting the Time-out period t_{TOUT}. Refer to page 46 for details on operation of the Watchdog Timer.

Figure 11-4. Watchdog reset during operation.



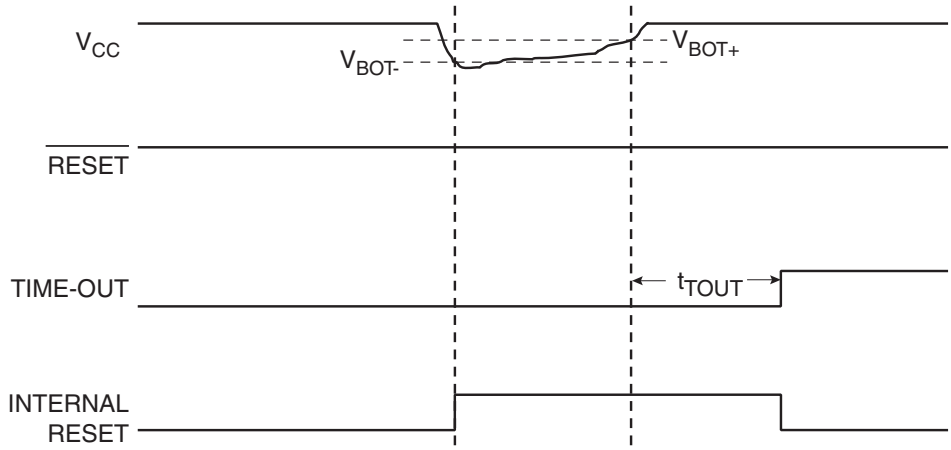
11.2.4 Brown-out detection

Atmel ATmega16HVB/32HVB has an On-chip Brown-out Detection (BOD) circuit for monitoring the V_{CC} level during operation by comparing it to a fixed trigger level V_{BOT}. The trigger level has a hysteresis to ensure spike free Brown-out Detection. The hysteresis on the detection level should be interpreted as $V_{BOT+} = V_{BOT} + V_{HYST}/2$ and $V_{BOT-} = V_{BOT} - V_{HYST}/2$.

The BOD is automatically enabled in all modes of operation, except in Power-off mode.

When the BOD is enabled, and V_{CC} decreases to a value below the trigger level (V_{BOT-} in Figure 11-5), the Brown-out Reset is immediately activated. When V_{CC} increases above the trigger level (V_{BOT+} in Figure 11-5), the delay counter starts the MCU after the Time-out period t_{TOUT} has expired.

Figure 11-5. Brown-out reset during operation.



11.3 Reset and the voltage reference

The Voltage Reference is important for the performance of the system as the V_{REF} voltage will be used as reference voltage for several modules. It is therefore important to notice that after a reset condition the Voltage Reference needs calibration and settling before the V_{REF} voltage is accurate. For details on Voltage Reference calibration and settling time, see "Voltage reference and temperature sensor" on page 122.

11.4 Watchdog timer

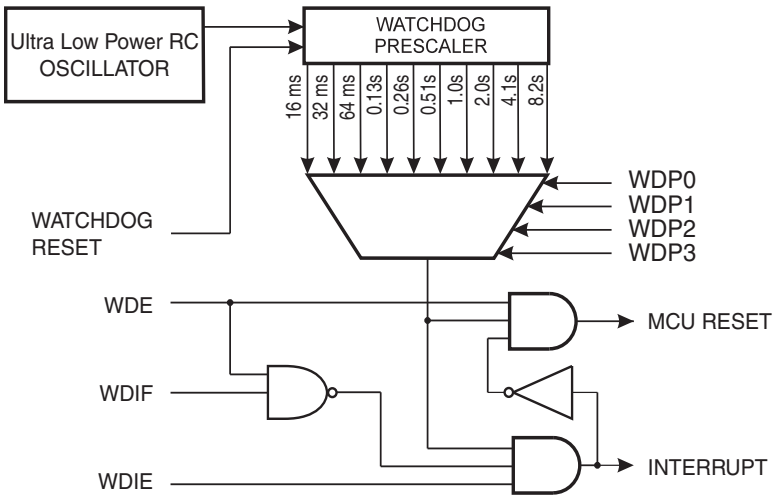
11.4.1 Features

- **Clocked from separate nn-chip oscillator**
- **Three operating modes**
  - **Interrupt**
  - **System reset**
  - **Interrupt and system reset**
- **Selectable time-out period from 16ms to 8s**
- **Possible hardware fuse watchdog always on (WDTON) for fail-safe mode**

11.4.2 Overview

Atmel ATmega16HVB/32HVB has an Enhanced Watchdog Timer (WDT). The WDT counts cycles of the Ultra Low Power RC Oscillator. The WDT gives an interrupt or a system reset when the counter reaches a given time-out value. In normal operation mode, it is required that the system uses the WDR - Watchdog Timer Reset - instruction to restart the counter before the time-out value is reached. If the system doesn't restart the counter, an interrupt or system reset will be issued.

Figure 11-6. Watchdog timer.



In Interrupt mode, the WDT gives an interrupt when the timer expires. This interrupt can be used to wake the device from sleep-modes, and also as a general system timer. One example is to limit the maximum time allowed for certain operations, giving an interrupt when the operation has run longer than expected. In System Reset mode, the WDT gives a reset when the timer expires. This is typically used to prevent system hang-up in case of runaway code. The third mode, Interrupt and System Reset mode, combines the other two modes by first giving an interrupt and then switch to System Reset mode. This mode will for instance allow a safe shutdown by saving critical parameters before a system reset.

The Watchdog always on (WDTON) fuse, if programmed, will force the Watchdog Timer to System Reset mode. With the fuse programmed the System Reset mode bit (WDE) and Interrupt mode bit (WDIE) are locked to one and null respectively. To further ensure program security, alterations to the Watchdog set-up must follow timed sequences. The sequence for clearing WDE and changing time-out configuration is as follows:

1. In the same operation, write a logic one to the Watchdog change enable bit (WDCE) and WDE. A logic one must be written to WDE regardless of the previous value of the WDE bit.
2. Within the next four clock cycles, write the WDE and Watchdog prescaler bits (WDP) as desired, but with the WDCE bit cleared. This must be done in one operation.

The following code example shows one assembly and one C function for turning off the Watchdog Timer. The example assumes that interrupts are controlled (for example by disabling interrupts globally) so that no interrupts will occur during the execution of these functions.

Assembly code example [1]

```
WDT_off:
  ; Turn off global interrupt
  cli
  ; Reset Watchdog Timer
  wdr
  ; Clear WDRF in MCUSR
  in    r16, MCUSR
  andi  r16, (0xff & (0<<WDRF))
  out   MCUSR, r16
  ; Write logical one to WDCE and WDE
  ; Keep old prescaler setting to prevent unintentional time-out
  in    r16, WDTCSR
  ori   r16, (1<<WDCE) | (1<<WDE)
  out   WDTCSR, r16
  ; Turn off WDT
  ldi   r16, (0<<WDE)
  out   WDTCSR, r16
  ; Turn on global interrupt
  sei
  ret
```

C code example [1]

```
void WDT_off(void)
{
  __disable_interrupt();
  __watchdog_reset();
  /* Clear WDRF in MCUSR */
  MCUSR &= ~(1<<WDRF);
  /* Write logical one to WDCE and WDE */
  /* Keep old prescaler setting to prevent unintentional time-out */
  WDTCSR |= (1<<WDCE) | (1<<WDE);
  /* Turn off WDT */
  WDTCSR = 0x00;
  __enable_interrupt();
}
```

Note: 1. See "About code examples" on page 8.

Note: If the Watchdog is accidentally enabled, for example by a runaway pointer or brown-out condition, the device will be reset and the Watchdog Timer will stay enabled. If the code is not set up to handle the Watchdog, this might lead to an eternal loop of time-out resets. To avoid this situation, the application software should always clear the Watchdog System Reset Flag (WDRF) and the WDE control bit in the initialization routine, even if the Watchdog is not in use.

The following code example shows one assembly and one C function for changing the time-out value of the Watchdog Timer.

Assembly code example (1)

```
WDT_Prescaler_Change:
  ; Turn off global interrupt
  cli
  ; Reset Watchdog Timer
  wdr
  ; Start timed sequence
  in    r16, WDTCSR
  ori   r16, (1<<WDCE) | (1<<WDE)
  out   WDTCSR, r16
  ; --  Got four cycles to set the new values from here -
  ; Set new prescaler(time-out) value = 64K cycles (~0.5 s)
  ldi   r16, (1<<WDE) | (1<<WDP2) | (1<<WDP0)
  out   WDTCSR, r16
  ; --  Finished setting new values, used 2 cycles -
  ; Turn on global interrupt
  sei
  ret
```

C code example (1)

```
void WDT_Prescaler_Change(void)
{
  __disable_interrupt();
  __watchdog_reset();
  /* Start timed  equence */
  WDTCSR |= (1<<WDCE) | (1<<WDE);
  /* Set new prescaler(time-out) value = 64K cycles (~0.5 s) */
  WDTCSR  = (1<<WDE) | (1<<WDP2) | (1<<WDP0);
  __enable_interrupt();
}
```

Note: 1. See "About code examples" on page 8.

Note: The Watchdog Timer should be reset before any change of the WDP bits, since a change in the WDP bits can result in a time-out when switching to a shorter time-out period.

11.5 Register description

11.5.1 MCUSR – MCU Status Register

The MCU Status Register provides information on which reset source caused an MCU reset.

Bit	7	6	5	4	3	2	1	0	
0x34 (0x54)	–	–	–	OCDRF	WDRF	BODRF	EXTRF	PORF	MCUSR
Read/Write	R	R	R	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	See Bit Description					

- **Bits 7:5 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB, and will always read as zero.

- **Bit 4 – OCDRF: OCD Reset Flag**

This bit is set if a debugWIRE Reset occurs. The bit is reset by a Power-on Reset, or by writing a logic zero to the flag.

- **Bit 3 – WDRF: Watchdog Reset Flag**

This bit is set if a Watchdog Reset occurs. The bit is reset by a Power-on Reset, or by writing a logic zero to the flag.

- **Bit 2 – BODRF: Brown-out Reset Flag**

This bit is set if a Brown-out Reset occurs. In the case of a Power-on Reset, both the BODRF and the PORF will be set. The BODRF is reset by writing a logic zero to the flag.

- **Bit 1 – EXTRF: External Reset Flag**

This bit is set if an External Reset occurs. The bit is reset by a Power-on Reset, or by writing a logic zero to the flag.

- **Bit 0 – PORF: Power-on Reset Flag**

This bit is set if a Power-on Reset occurs. The bit is reset only by writing a logic zero to the flag.

To make use of the Reset flags to identify a reset condition, the user should read and then reset the MCUSR as early as possible in the program. If the register is cleared before another reset occurs, the source of the reset can be found by examining the reset flags.

11.5.2 WDTCSR – Watchdog Timer Control Register

Bit	7	6	5	4	3	2	1	0	
(0x60)	WDIF	WDIE	WDP3	WDCE	WDE	WDP2	WDP1	WDP0	WDTCSR
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	X	0	0	0	

- **Bit 7 – WDIF: Watchdog Interrupt Flag**

This bit is set when a time-out occurs in the Watchdog Timer and the Watchdog Timer is configured for interrupt. WDIF is cleared by hardware when executing the corresponding interrupt handling vector. Alternatively, WDIF is cleared by writing a logic one to the flag. When the I-bit in SREG and WDIE are set, the Watchdog Time-out Interrupt is executed.

- **Bit 6 – WDIE: Watchdog Interrupt Enable**

When this bit is written to one and the I-bit in the Status Register is set, the Watchdog Interrupt is enabled. If WDE is cleared in combination with this setting, the Watchdog Timer is in Interrupt Mode, and the corresponding interrupt is executed if time-out in the Watchdog Timer occurs.

If WDE is set, the Watchdog Timer is in Interrupt and System Reset Mode. The first time-out in the Watchdog Timer will set WDIF. Executing the corresponding interrupt vector will clear WDIE and WDIF automatically by hardware (the Watchdog goes to System Reset Mode). This is useful for keeping the Watchdog Timer security while using the interrupt. To stay in Interrupt and System Reset Mode, WDIE must be set after each interrupt. This should however not be done within the interrupt service routine itself, as this might compromise the safety-function of the Watchdog System Reset mode. If the interrupt is not executed before the next time-out, a System Reset will be applied.

Table 11-1. Watchdog timer configuration.

WDTON [1]	WDE	WDIE	Mode	Action on timeout
1	0	0	Stopped	None
1	0	1	Interrupt mode	Interrupt
1	1	0	System Reset mode	Reset
1	1	1	Interrupt and System Reset mode	Interrupt, then go to System Reset mode
0	x	x	System Reset mode	Reset

Note: 1. WDTON fuse set to “0” means programmed, “1” means unprogrammed.

- **Bit 5, 2:0 – WDP3:0 : Watchdog Timer Prescaler three, two, one, and null**

The WDP3..0 bits determine the Watchdog Timer prescaling when the Watchdog Timer is enabled. The different prescaling values and their corresponding Timeout Periods are shown in Table 11-2 on page 51.

- **Bit 4 – WDCE: Watchdog Change Enable**

This bit is used in timed sequences for changing WDE and prescaler bits. To clear the WDE bit, and/or change the prescaler bits, WDCE must be set.

Once written to one, hardware will clear WDCE after four clock cycles.

- **Bit 3 – WDE: Watchdog System Reset Enable**

WDE is overridden by WDRF in MCUSR. This means that WDE is always set when WDRF is set. To clear WDE, WDRF must be cleared first. This feature ensures multiple resets during conditions causing failure, and a safe start-up after the failure.

- **Bits 5, 2:0 – WDP3:0: Watchdog Timer Prescaler three, two, one, and null**

The WDP3..0 bits determine the Watchdog Timer prescaling when the Watchdog Timer is enabled. The different prescaling values and their corresponding Timeout Periods are shown in Table 11-2 on page 51.

.

Table 11-2. Watchdog timer prescale select.

WDP3	WDP2	WDP1	WDP0	Number of WDT oscillator cycles	Typical timeout (1)
0	0	0	0	2K cycles	16ms
0	0	0	1	4K cycles	32ms
0	0	1	0	8K cycles	64ms
0	0	1	1	16K cycles	0.13s
0	1	0	0	32K cycles	0.26s
0	1	0	1	64K cycles	0.51s
0	1	1	0	128K cycles	1.0s
0	1	1	1	256K cycles	2.0s
1	0	0	0	512K cycles	4.1s
1	0	0	1	1024K cycles	8.2s
1	0	1	0	Reserved	
1	0	1	1		
1	1	0	0		
1	1	0	1		
1	1	1	0		
1	1	1	1		

Note: 1. The actual timeout value depends on the actual clock period of the Ultra Low Power RC Oscillator, refer to ”Ultra Low Power RC oscillator” on page 27 for details.

2. Due to synchronization logic in the Watchdog timer, the time between two consecutive WDT time-outs will be three cycles longer than the numbers listed.

12. Interrupts

12.1 Overview

This section describes the specifics of the interrupt handling as performed in Atmel ATmega16HVB/32HVB. For a general explanation of the AVR interrupt handling, refer to ”Reset and interrupt handling” on page 14.

12.2 Interrupt vectors in Atmel ATmega16HVB/32HVB

Table 12-1. Reset and interrupt vectors.

Vector No.	Program address (1)	Source	Interrupt definition
1	0x0000	RESET	External pin, power-on reset, brown-out reset, watchdog reset, and debugWIRE reset
2	0x0002	BPINT	Battery protection interrupt
3	0x0004	VREGMON	Voltage regulator monitor interrupt
4	0x0006	INT0	External Interrupt Request 0
5	0x0008	INT1	External Interrupt Request 1
6	0x000A	INT2	External Interrupt Request 2
7	0x000C	INT3	External Interrupt Request 3
8	0x000E	PCINT0	Pin Change Interrupt 0
9	0x0010	PCINT1	Pin Change Interrupt 1
10	0x0012	WDT	Watchdog timeout interrupt
11	0x0014	BGSCD	Bandgap buffer short circuit detected
12	0x0016	CHDET	Charger detect
13	0x0018	TIMER1 IC	Timer/Counter 1 input capture
14	0x001A	TIMER1 COMPA	Timer/Counter 1 compare Match A
15	0x001C	TIMER1 COMPB	Timer/Counter 1 compare Match B
16	0x001E	TIMER1 OVF	Timer/Counter 1 overflow
17	0x0020	TIMER0 IC	Timer/Counter 0 input capture
18	0x0022	TIMER0 COMPA	Timer/Counter 0 compare Match A
19	0x0024	TIMER0 COMPB	Timer /Counter0 compare Match B
20	0x0026	TIMER0 OVF	Timer/Counter 0 overflow
21	0x0028	TWI BUS C/D	Two-wire bus connect/disconnect
22	0x002A	TWI	Two-wire serial interface
23	0x002C	SPI, STC	SPI, Serial Transfer Complete
24	0x002E	VADC	Voltage ADC conversion complete
25	0x0030	CCADC CONV	CC-ADC instantaneous current conversion complete
26	0x0032	CCADC REG CUR	CC-ADC regular current

Table 12-1. Reset and interrupt vectors. (Continued)

Vector No.	Program address (1)	Source	Interrupt definition
27	0x0034	CCADC ACC	CC-ADC accumulate current conversion complete
28	0x0036	EE READY	EEPROM ready
29	0x0038	SPM	SPM ready

Notes: 1. When the IVSEL bit in MCUCR is set, Interrupt Vectors will be moved to the start of the Boot Flash Section. The address of each Interrupt Vector will then be the address in this table added to the start address of the Boot Flash Section.
2. When the BOOTRST Fuses are programmed, the device will jump to the Boot Loader address at reset, see "Boot loader support – Read-while-write self-programming" on page 188.

If the program never enables an interrupt source, the Interrupt Vectors are not used, and regular program code can be placed at these locations.

Table 12-2 shows reset and Interrupt Vectors placement for the various combinations of BOOTRST and IVSEL settings. If the program never enables an interrupt source, the Interrupt Vectors are not used, and regular program code can be placed at these locations. This is also the case if the Reset Vector is in the Application section while the Interrupt Vectors are in the Boot section or vice versa.

Table 12-2. Reset and interrupt vectors placement (1).

BOOTRST	IVSEL	Reset address	Interrupt vectors start address
1	0	0x0000	0x0002
1	1	0x0000	Boot reset address + 0x0002
0	0	Boot reset address	0x0002
0	1	Boot reset address	Boot reset address + 0x0002

Note: 1. The Boot Reset Address is shown in Table 29-5 on page 200. For the BOOTRST Fuse "1" means unprogrammed while "0" means programmed.

The most typical and general program setup for the Reset and Interrupt Vector Addresses in Atmel ATmega16HVB/32HVB is:

```
Address   Labels   Code                 Comments
0x0000             jmp      RESET       ; Reset Handler
0x0002             jmp      BPINT       ; Battery Protection Interrupt Handler
0x0004             jmp      VREGMON_INT ; Voltage Regulator Monitor Interrupt Handler
0x0006             jmp      EXT_INT0    ; External Interrupt Request 0 Handler
0x0008             jmp      EXT_INT1    ; External Interrupt Request 1 Handler
0x000A             jmp      EXT_INT2    ; External Interrupt Request 2 Handler
0x000C             jmp      EXT_INT3    ; External Interrupt Request 3 Handler
0x000E             jmp      PCINT0      ; Pin Change Interrupt 0 Handler
0x0010             jmp      PCINT1      ; Pin Change Interrupt 1 Handler
0x0012             jmp      WDT         ; Watchdog Time-out Interrupt
0x0014             jmp      BGSCD       ; Bandgap Buffer Short Circuit Detected
0x0016             jmp      CHDET       ; Charger Detect
0x0018             jmp      TIM1_IC     ; Timer1 Input Capture Handler
0x001A             jmp      TIM1_COMPA  ; Timer1 Compare A Handler
```

```
0x001C          jmp     TIM1_COMPB          ; Timer1 Compare B Handler
0x001E          jmp     TIM1_OVF            ; Timer1 Overflow Handler
0X0020          jmp     TIM0_IC             ; Timer0 Input Capture Handler
0x0022          jmp     TIM0_COMPA          ; Timer0 CompareA Handler
0x0024          jmp     TIM0_COMPB          ; Timer0 CompareB Handler
0x0026          jmp     TIM0_OVF            ; Timer0 Overflow Handler
0x0028          jmp     TWI_BUS_CD          ; Two-wire Bus Connect/Disconnect Handler
0x002A          jmp     TWI                 ; Two-wire Serial Interface Handler
0x002C          jmp     SPI, STC            ; SPI, Serial Transfer Complete
0x002E          jmp     VADC                ; Voltage ADC Conversion Complete Handler
0x0030          jmp     CCADC_CONV          ; CC-ADC Instantaneous Current Conversion Complete Handler
0x0032          jmp     CCADC_REC_CUR       ; CC-ADC Regular Current Handler
0x0034          jmp     CCADC_ACC           ; CC-ADC Accumulate Current Conversion Complete Handler
0x0036          jmp     EE_RDY              ; EEPROM Ready Handler
0x0038          jmp     SPM                 ; Store Program Memory Ready Handler
;
0x003A   RESET: ldi     r16, high(RAMEND)   ; Main program start
0x003B          out     SPH,r16             ; Set Stack Pointer to top of RAM
0x003C          ldi     r16, low(RAMEND)
0x003D          out     SPL,r16
0x003E          sei                         ; Enable interrupts
0x003F          <instr>  xxx
0x0040   ...    ...     ...
;
```

When the BOOTRST Fuse is unprogrammed, the Boot section size set to 4Kbytes and the IVSEL bit in the MCUCR Register is set before any interrupts are enabled, the most typical and general program setup for the Reset and Interrupt Vector Addresses is:

```
Address  Labels  Code                  Comments
0x0000   RESET:  ldi     r16,high(RAMEND); Main program start
0x0001           out     SPH,r16         ; Set Stack Pointer to top of RAM
0x0002           ldi     r16,low(RAMEND)
0x0003           out     SPL,r16
0x0004           sei                     ; Enable interrupts
0x0005           <instr>  xxx
;
.org 0x4C02
0x4C02           jmp     BPINT           ; Battery Protection Interrupt Handler
0x4C04           jmp     EXT_INT0        ; External Interrupt Request 0 Handler
...              ...     ...             ;
0x4C2C           jmp     SPM_RDY         ; Store Program Memory Ready Handler
```

When the BOOTRST Fuse is programmed and the Boot section size set to 4Kbytes, the most typical and general program setup for the Reset and Interrupt Vector Addresses is:

```
Address  Labels  Code                  Comments
.org 0x0002
0x0002           jmp     BPINT           ; Battery Protection Interrupt Handler
0x0004           jmp     EXT_INT0        ; External Interrupt Request 0 Handler
```

```
...             ...     ...             ;
0x002C      jmp     SPM_RDY         ; Store Program Memory Ready Handler
;
.org 0x4C00
0x4C00  RESET:  ldi     r16,high(RAMEND); Main program start
0x4C01          out     SPH,r16         ; Set Stack Pointer to top of RAM
0x4C02          ldi     r16,low(RAMEND)
0x4C03          out     SPL,r16
0x4C04          sei                     ; Enable interrupts
0x4C05          <instr>  xxx
```

When the BOOTRST Fuse is programmed, the Boot section size set to 4Kbytes and the IVSEL bit in the MCUCR Register is set before any interrupts are enabled, the most typical and general program setup for the Reset and Interrupt Vector Addresses is:

```
Address  Labels Code                    Comments
;
.org 0x4C00
0x4C00          jmp     RESET           ; Reset handler
0x4C02          jmp     BPINT           ; Battery Protection Interrupt Handler
0x4C04          jmp     EXT_INT0        ; External Interrupt Request 0 Handler
...             ...     ...             ;
0x4C2C          jmp     SPM_RDY         ; Store Program Memory Ready Handler
;
0x4C2E  RESET:  ldi     r16,high(RAMEND); Main program start
0x4C2F          out     SPH,r16         ; Set Stack Pointer to top of RAM
0x4C30          ldi     r16,low(RAMEND)
0x4C31          out     SPL,r16
0x4C32          sei                     ; Enable interrupts
0x4C33          <instr>  xxx
```

12.3 Moving interrupts between application and boot space

The General Interrupt Control Register controls the placement of the Interrupt Vector table.

Assembly code example

```
Move_interrupts:
  ; Enable change of Interrupt Vectors
  ldi  r16, (1<<IVCE)
  out  MCUCR, r16
  ; Move interrupts to Boot Flash section
  ldi  r16, (1<<IVSEL)
  out  MCUCR, r16
  ret
```

C code example

```
void Move_interrupts(void)
{
  /* Enable change of Interrupt Vectors */
  MCUCR = (1<<IVCE);
  /* Move interrupts to Boot Flash section */
  MCUCR = (1<<IVSEL);
}
```

12.4 Register description

12.4.1 MCUCR – MCU Control Register

Bit	7	6	5	4	3	2	1	0	
0x35 (0x55)	JTD	–	–	PUD	–	–	IVSEL	IVCE	MCUCR
Read/Write	R/W	R	R	R/W	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 1 – IVSEL: Interrupt Vector Select**

When the IVSEL bit is cleared (zero), the Interrupt Vectors are placed at the start of the Flash memory. When this bit is set (one), the Interrupt Vectors are moved to the beginning of the Boot Loader section of the Flash. The actual address of the start of the Boot Flash Section is determined by the BOOTSZ Fuses. Refer to the section ”Boot loader support – Read-while-write self-programming” on page 188 for details. To avoid unintentional changes of Interrupt Vector tables, a special write procedure must be followed to change the IVSEL bit:

a. Write the Interrupt Vector Change Enable (IVCE) bit to one.
b. Within four cycles, write the desired value to IVSEL while writing a zero to IVCE.

Interrupts will automatically be disabled while this sequence is executed. Interrupts are disabled in the cycle IVCE is set, and they remain disabled until after the instruction following the write to IVSEL. If IVSEL is not written, interrupts remain disabled for four cycles. The I-bit in the Status Register is unaffected by the automatic disabling.

Note: If Interrupt Vectors are placed in the Boot Loader section and Boot Lock bit BLB02 is programmed, interrupts are disabled while executing from the Application section. If Interrupt Vectors are placed in the Application section and Boot Lock bit BLB12 is programed, interrupts are disabled while

executing from the Boot Loader section. Refer to the section ”Boot loader support – Read-while-write self-programming” on page 188 for details on Boot Lock bits.

- **Bit 0 – IVCE: Interrupt Vector Change Enable**

The IVCE bit must be written to logic one to enable change of the IVSEL bit. IVCE is cleared by hardware four cycles after it is written or when IVSEL is written. Setting the IVCE bit will disable interrupts, as explained in the IVSEL description above. See Code Example in ”Moving interrupts between application and boot space” on page 56.

13. External interrupts

13.1 Overview

The External Interrupts are triggered by the INT3:0 pin or any of the PCINT11:0 pins. Observe that, if enabled, the interrupts will trigger even if the INT3:0 or PCINT11:0 pins are configured as outputs. This feature provides a way of generating a software interrupt.

The External Interrupts can be triggered by a falling or rising edge or a low level. This is set up as indicated in the specification for the "EICRA – External Interrupt Control Register A" . When the external interrupt is enabled and is configured as level triggered, the interrupt will trigger as long as the pin is held low. Interrupts are detected asynchronously. This implies that these interrupts can be used for waking the part also from sleep modes other than Idle mode. The I/O clock is halted in all sleep modes except Idle mode.

The Pin change interrupt PCI1 will trigger if any enabled PCINT11:4 pin toggles and Pin change interrupts PCI0 will trigger if any enabled PCINT3:0 pin toggles. PCMSK1 and PCMSK0 Registers control which pins contribute to the pin change interrupts. Pin change interrupts on PCINT11:0 are detected asynchronously. This implies that these interrupts can be used for waking the part also from sleep modes other than Idle mode.

Note that if a level triggered interrupt is used for wake-up from Power-save, the required level must be held long enough for the MCU to complete the wake-up to trigger the level interrupt. If the level disappears before the end of the Start-up Time, the MCU will still wake up, but no interrupt will be generated. The start-up time is defined by the SUT fuses as described in "Clock systems and their distribution" on page 25.

13.2 Register description

13.2.1 EICRA – External Interrupt Control Register A

Bit	7	6	5	4	3	2	1	0	
(0x69)	ISC31	ISC30	ISC21	ISC20	ISC11	ISC10	ISC01	ISC00	EICRA
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:0 – ISCn: External Interrupt Sense Control Bits**

The External Interrupts 3:0 are activated by the external pins INT3:0 if the SREG I-flag and the corresponding interrupt mask in the EIMSK is set. The level and edges on the external pins that activate the interrupts are defined in Table 13-1 on page 59. Edges on INT3..INT0 are registered asynchronously. Pulses on INT3:0 pins wider than the minimum pulse width given in Table 32-11 on page 230 will generate an interrupt. Shorter pulses are not guaranteed to generate an interrupt. If low level interrupt is selected, the low level must be held until the completion of the currently executing instruction to generate an interrupt. If enabled, a level triggered interrupt will generate an interrupt request as long as the pin is held low. When changing the ISCn bit, an interrupt can occur. Therefore, it is recommended to first disable INTn by clearing its Interrupt Enable bit in the EIMSK Register. Then, the ISCn bit can be changed. Finally, the INTn interrupt flag should be cleared by writing a logical one to its Interrupt Flag bit (INTFn) in the EIFR Register before the interrupt is re-enabled.

Table 13-1. Interrupt sense control.

ISCn1	ISCn0	Description
0	0	The low level of INTn generates an interrupt request
0	1	Any logical change on INTn generates an interrupt request
1	0	The falling edge of INTn generates an interrupt request
1	1	The rising edge of INTn generates an interrupt request

Note: 1. n = 3, 2, 1, or 0.
When changing the ISCn1/ISCn0 bits, the interrupt must be disabled by clearing its Interrupt Enable bit in the EIMSK Register. Otherwise an interrupt can occur when the bits are changed.

13.2.2 EIMSK – External Interrupt Mask Register

Bit	7	6	5	4	3	2	1	0	
0x1D (0x3D)	–	–	–	–	INT3	INT2	INT1	INT0	EIMSK
Read/Write	R	R	R	R	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:4 – Reserved**

These bits are reserved ins the Atmel ATmega16HVB/32HVB, and will always read as zero.

- **Bits 3:0 – INT3 – INT0: External Interrupt Request 3:0 enable**

When an INT3 – INT0 bit is written to one and the I-bit in the Status Register (SREG) is set (one), the corresponding external pin interrupt is enabled. The Interrupt Sense Control bits in the External Interrupt Control Register – EICRA – defines whether the external interrupt is activated on rising or falling edge or level sensed. Activity on any of these pins will trigger an interrupt request even if the pin is enabled as an output. This provides a way of generating a software interrupt.

13.2.3 EIFR – External Interrupt Flag Register

Bit	7	6	5	4	3	2	1	0	
0x1C (0x3C)	–	–	–	–	INTF3	INTF2	INTF1	INTF0	EIFR
Read/Write	R	R	R	R	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:4 – Reserved**

These bits are reserved ins the ATmega16HVB/32HVB, and will always read as zero.

- **Bits 3:0 – INTF3 – INTF0: External Interrupt Flags 3:0**

When an edge or logic change on the INT3:0 pin triggers an interrupt request, INTF3:0 becomes set (one). If the I-bit in SREG and the corresponding interrupt enable bit, INT3:0 in EIMSK, are set (one), the MCU will jump to the interrupt vector. The flag is cleared when the interrupt routine is executed. Alternatively, the flag can be cleared by writing a logical one to it. These flags are always cleared when INT3:0 are configured as level interrupt. Note that when entering sleep mode with the INT3:0 interrupts disabled, the input buffers on these pins will be disabled. This may cause a logic change in internal signals which will set the INTF3:0 flags. See ”Digital input enable and sleep modes” on page 71 for more information.

13.2.4 PCICR – Pin Change Interrupt Control Register

Bit	7	6	5	4	3	2	1	0	
(0x68)	–	–	–	–	–	–	PCIE1	PCIE0	PCICR
Read/Write	R	R	R	R	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:2 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB, and will always read as zero.

- **Bit 1 – PCIE1: Pin Change Interrupt Enable 1**

When the PCIE1 bit is set (one) and the I-bit in the Status Register (SREG) is set (one), pin change interrupt 1 is enabled. Any change on any enabled PCINT11..4 pin will cause an interrupt. The corresponding interrupt of Pin Change Interrupt Request is executed from the PCI1 Interrupt Vector. PCINT11..4 pins are enabled individually by the PCMSK1 Register.

- **Bit 0 – PCIE0: Pin Change Interrupt Enable 0**

When the PCIE0 bit is set (one) and the I-bit in the Status Register (SREG) is set (one), pin change interrupt 0 is enabled. Any change on any enabled PCINT3..0 pin will cause an interrupt. The corresponding interrupt of Pin Change Interrupt Request is executed from the PCI0 Interrupt Vector. PCINT3..0 pins are enabled individually by the PCMSK0 Register.

13.2.5 PCIFR – Pin Change Interrupt Flag Register

Bit	7	6	5	4	3	2	1	0	
0x1B (0x3B)	–	–	–	–	–	–	PCIF1	PCIF0	PCIFR
Read/Write	R	R	R	R	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:2 – Reserved**

These bits are reserved in the ATmega16HVB/32HVB, and will always read as zero.

- **Bit 1 – PCIF1: Pin Change Interrupt Flag 1**

When a logic change on any PCINT11..4 pin triggers an interrupt request, PCIF1 becomes set (one). If the I-bit in SREG and the PCIE1 bit in EIMSK are set (one), the MCU will jump to the corresponding Interrupt Vector. The flag is cleared when the interrupt routine is executed. Alternatively, the flag can be cleared by writing a logical one to it.

- **Bit 0 – PCIF0: Pin Change Interrupt Flag 0**

When a logic change on any PCINT3:0 pin triggers an interrupt request, PCIF0 becomes set (one). If the I-bit in SREG and the PCIE0 bit in EIMSK are set (one), the MCU will jump to the corresponding Interrupt Vector. The flag is cleared when the interrupt routine is executed. Alternatively, the flag can be cleared by writing a logical one to it.

13.2.6 PCMSK1 – Pin Change Mask Register 1

Bit	7	6	5	4	3	2	1	0	
(0x6C)	PCINT11	PCINT10	PCINT9	PCINT8	PCINT7	PCINT6	PCINT5	PCINT4	PCMSK1
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7:0 – PCINT[11:4]: Pin Change Enable Mask 15:8**

These bits select whether pin change interrupt is enabled on the corresponding I/O pin. If PCINT[11:4] is set and the PCIE1 bit in EIMSK is set, pin change interrupt is enabled on the corresponding I/O pin. If PCINT[11:4] is cleared, pin change interrupt on the corresponding I/O pin is disabled.

13.2.7 PCMSK0 – Pin Change Mask Register 0

Bit	7	6	5	4	3	2	1	0	
(0x6B)	–	–	–	–	PCINT3	PCINT2	PCINT1	PCINT0	PCMSK0
Read/Write	R	R	R	R	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:4 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB, and will always read as zero.

- **Bit 3:0 – PCINT[3:0]: Pin Change Enable Mask 3:0**

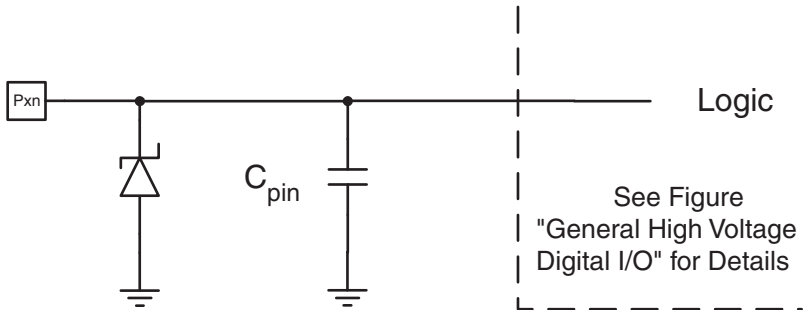
Each PCINT[3:0] bit selects whether pin change interrupt is enabled on the corresponding I/O pin. If PCINT[3:0] is set and the PCIE0 bit in PCICR is set, pin change interrupt is enabled on the corresponding I/O pin. If PCINT[3:0] is cleared, pin change interrupt on the corresponding I/O pin is disabled.

14. High voltage I/O ports

14.1 Overview

All high voltage AVR ports have true Read-Modify-Write functionality when used as general digital I/O ports. This means that the state of one port pin can be changed without unintentionally changing the state of any other pin with the SBI and CBI instructions. All high voltage I/O pins have protection Zener diodes to Ground as indicated in Figure 14-1. See ”Electrical characteristics” on page 225 for a complete list of parameters.

Figure 14-1. High voltage I/O pin equivalent schematic.



All registers and bit references in this section are written in general form. A lower case “x” represents the numbering letter for the port, and a lower case “n” represents the bit number. However, when using the register or bit defines in a program, the precise form must be used. For example, PORTC3 for bit number three in Port C, here documented generally as PORTxn. The physical I/O Registers and bit locations are listed in ”Register description” on page 66.

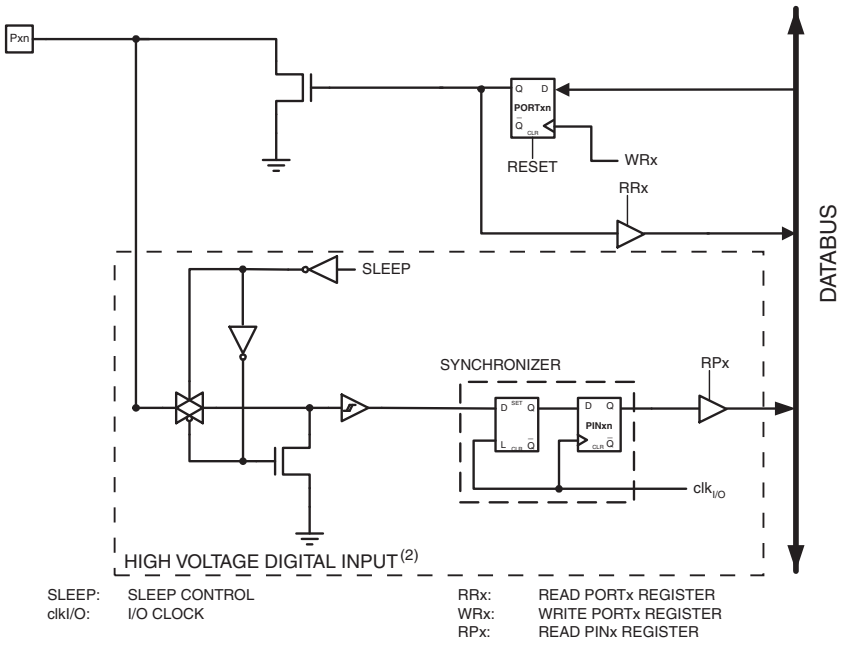
One I/O Memory address location is allocated for each high voltage port, the Data Register – PORTx. The Data Register is read/write.

Using the I/O port as General Digital Output is described in ”High voltage ports as general digital I/O” on page 63.

14.2 High voltage ports as general digital I/O

The high voltage ports are high voltage tolerant open collector output ports. In addition they can be used as general digital inputs. Figure 14-2 shows a functional description of one output port pin, here generically called Pxn.

Figure 14-2. General high voltage digital I/O [1].



Notes:
1. WRx, RRx and RPx are common to all pins within the same port. $clk_{I/O}$ and SLEEP are common to all ports.
2. The High Voltage Digital Input is not present on PC5.

14.2.1 Configuring the pin

Each port pin consist of two register bits: PORTxn and PINxn. As shown in ”Register description” on page 66, the PORTxn bits are accesed at the PORTx I/O address, and the PINxn bits at the PINx I/O address.

If PORTxn is written logic one, the port pin is driven low (zero). If PORTxn is written logic zero, the port pin is tri-stated. The port pins are tri-stated when a reset condition becomes active, even if no clocks are running.

14.2.2 Reading the pin

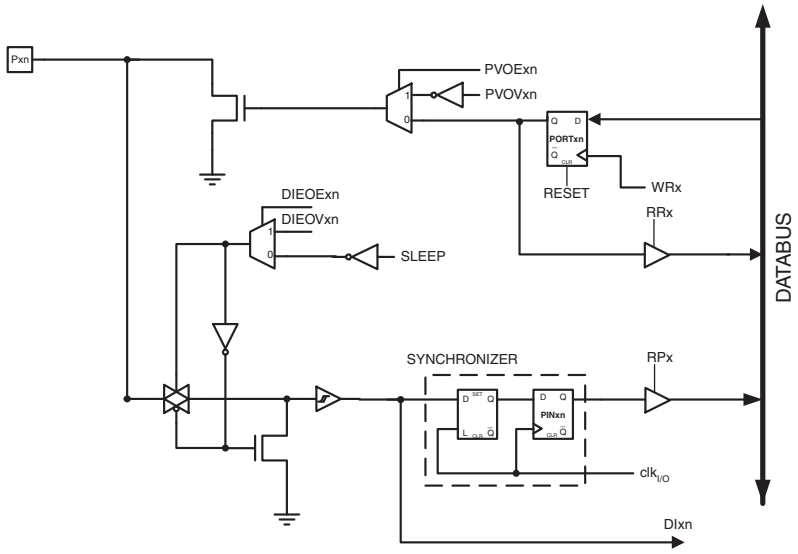
The port pin can be read through the PINxn Register bit. As shown in Figure 14-2, the PINxn Register bit and the preceding latch constitute a synchronizer. This is needed to avoid metastability if the physical pin changes value near the edge of the internal clock, but it also introduces a delay.

14.3 Overview

14.4 Alternate port functions

The High Voltage I/O has alternate port functions in addition to being general digital I/O. Figure 14-3 shows how the port pin control signals from the simplified Figure 14-2 on page 63 can be overridden by alternate functions.

Figure 14-3. High voltage digital I/O [(1)(2)].



PVOExn:	Pxn PORT VALUE OVERRIDE ENABLE	RRx:	READ PORTx REGISTER
PVOVxn:	Pxn PORT VALUE OVERRIDE VALUE	WRx:	WRITE PORTx REGISTER
DIEOExn:	Pxn DIGITAL INPUT-ENABLE OVERRIDE ENABLE	RPx:	READ PINx REGISTER
DIEOVxn:	Pxn DIGITAL INPUT-ENABLE OVERRIDE VALUE	$clk_{I/O}$:	I/O CLOCK
		DIxn:	DIGITAL INPUT PIN n ON PORTx
		SLEEP:	SLEEP CONTROL

Notes:
1. WRx, RRx and RPx are common to all pins within the same port. $clk_{I/O}$ and SLEEP are common to all ports. All other signals are unique for each pin.
2. The High Voltage Digital Input is not present on PC5.

Table 14-1 on page 65 summarizes the function of the overriding signals. The pin and port indexes from Figure 14-3 are not shown in the succeeding tables. The overriding signals are generated internally in the modules having the alternate function.

Table 14-1. Generic description of overriding signals for alternate functions.

Signal name	Full name	Description
PVOE	Port value override enable	If this signal is set and the Output Driver is enabled, the port value is controlled by the PVOV signal. If PVOE is cleared, and the Output Driver is enabled, the port Value is controlled by the PORTxn Register bit
PVOV	Port value override value	If PVOE is set, the port value is set to PVOV, regardless of the setting of the PORTxn Register bit
DIEOE	Digital input enable override enable	If this bit is set, the Digital Input Enable is controlled by the DIEOV signal. If this signal is cleared, the Digital Input Enable is determined by MCU state (Normal mode, sleep mode)
DIEOV	Digital input enable override value	If DIEOE is set, the Digital Input is enabled/disabled when DIEOV is set/cleared, regardless of the MCU state (Normal mode, sleep mode)
DI	Digital input	This is the Digital Input to alternate functions. In the figure, the signal is connected to the output of the schmitt trigger but before the synchronizer. Unless the Digital Input is used as a clock source, the module with the alternate function will use its own synchronizer

14.4.1 Alternate functions of Port C

The Port C pins with alternate functions are shown in Table 14-2.

Table 14-2. Port C pins alternate functions.

Port pin	Alternate function
PC0	INT0/ EXTPROT(External Interrupt 0 or External Battery Protection Input)
PC1	INT1 (External Interrupt 1)
PC2	INT1 (External Interrupt 2)
PC3	INT3/ SDA (External Interrupt 3 or SM bus data line)
PC4	SCL (SM Bus Clock line)

The alternate pin configuration is as follows:

- **INT0/ EXTPROT – Port C, Bit0**

INT0: External Interrupt Source 0. This pin can serve as external interrupt source. INT0 can be used as an interrupt pin regardless of whether another function is enabled or not.

EXTPROT: External Battery Protection Input. This pin can serve as external battery protection input to be able to override the FET controller externally.

- **INT1 – Port C, Bit1**

INT1: External Interrupt Source 1. This pin can serve as external interrupt source. INT1 can be used as an interrupt pin regardless of whether another function is enabled or not.

- **INT2 – Port C, Bit2**

INT2: External Interrupt Source 2. This pin can serve as external interrupt source. INT2 can be used as an interrupt pin regardless of whether another function is enabled or not.

- **INT3/ SDA – Port C, Bit3**

INT3: External Interrupt Source 3. This pin can serve as external interrupt source. INT3 can be used as an interrupt pin regardless of whether another function is enabled or not.

SDA: SM Bus Data. This pin can serve as bidirectional serial data line for the 2-wire Serial Interface.

- **SCL – Port C, Bit4**

SCL: SM Bus Clock. This pin can serve as bidirectional clock line for the 2-wire Serial Interface

Table 14-3 relates the alternate functions of Port C to the overriding signals shown in Figure 14-3 on page 64.

Table 14-3. Overriding signals for Alternate Functions in PC4:0.

Signal name	PC4/SCL	PC3/INT3/SDA	PC2/INT2	PC1/INT1	PC0/INT0/EXTPROT
PVOE	SM BUS ENABLED	SM BUS ENABLED			EXTPROT ENABLE
PVOV	SM BUS CLOCK	SM BUS DATA			1
DIEOE	SM BUS ENABLED	INT3 ENABLE SM BUS ENABLED	INT2 ENABLE	INT1ENABLE	INT0 ENABLE EXTPROT ENABLE
DIEOV	1	1	1	1	1
DI	SM BUS CLOCK	INT3 INPUT SM BUS DATA	INT2 INPUT	INT1 INPUT	INT0 INPUT EXTPROT INPUT
DIDR					

14.5 Register description

14.5.1 PORTC – Port C Data Register

Bit	7	6	5	4	3	2	1	0	
0x08 (0x28)	–	–	PORTC5	PORTC4	PORTC3	PORTC2	PORTC1	PORTC0	PORTC
Read/Write	R	R	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

14.5.2 PINC – Port C Input Pins Address

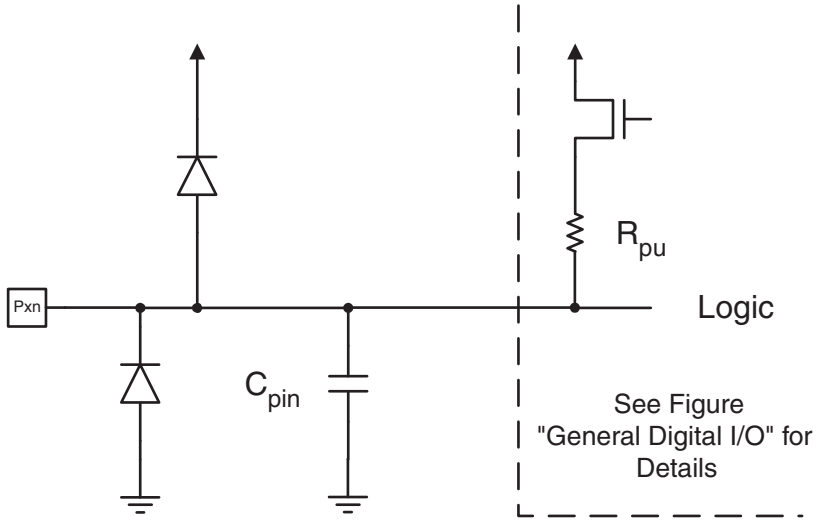
Bit	7	6	5	4	3	2	1	0	
0x06 (0x26)	–	–	–	PINC4	PINC3	PINC2	PINC1	PINC0	PINC
Read/Write	R	R	R	R	R	R	R	R	
Initial Value	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	

15. Low voltage I/O-Ports

15.1 Overview

All low voltage AVR ports have true Read-Modify-Write functionality when used as general digital I/O ports. This means that the direction of one port pin can be changed without unintentionally changing the direction of any other pin with the SBI and CBI instructions. The same applies when changing drive value (if configured as output) or enabling/disabling of pull-up resistors (if configured as input). All low voltage port pins have individually selectable pull-up resistors with a supply-voltage invariant resistance. All I/O pins have protection diodes to both V_{REG} and Ground as indicated in Figure 15-1. Refer to ”Electrical characteristics” on page 225 for a complete list of parameters.

Figure 15-1. Low voltage I/O pin equivalent schematic.



All registers and bit references in this section are written in general form. A lower case “x” represents the numbering letter for the port, and a lower case “n” represents the bit number. However, when using the register or bit defines in a program, the precise form must be used. For example, PORTB3 for bit no. 3 in Port B, here documented generally as PORTxn. The physical I/O Registers and bit locations are listed in ”Register description” on page 78.

Three I/O memory address locations are allocated for each low voltage port, one each for the Data Register – PORTx, Data Direction Register – DDRx, and the Port Input Pins – PINx. The Port Input Pins I/O location is read only, while the Data Register and the Data Direction Register are read/write. However, writing a logic one to a bit in the PINx Register, will result in a toggle in the corresponding bit in the Data Register. In addition, the Pull-up Disable – PUD bit in MCUCR disables the pull-up function for all low voltage pins in all ports when set.

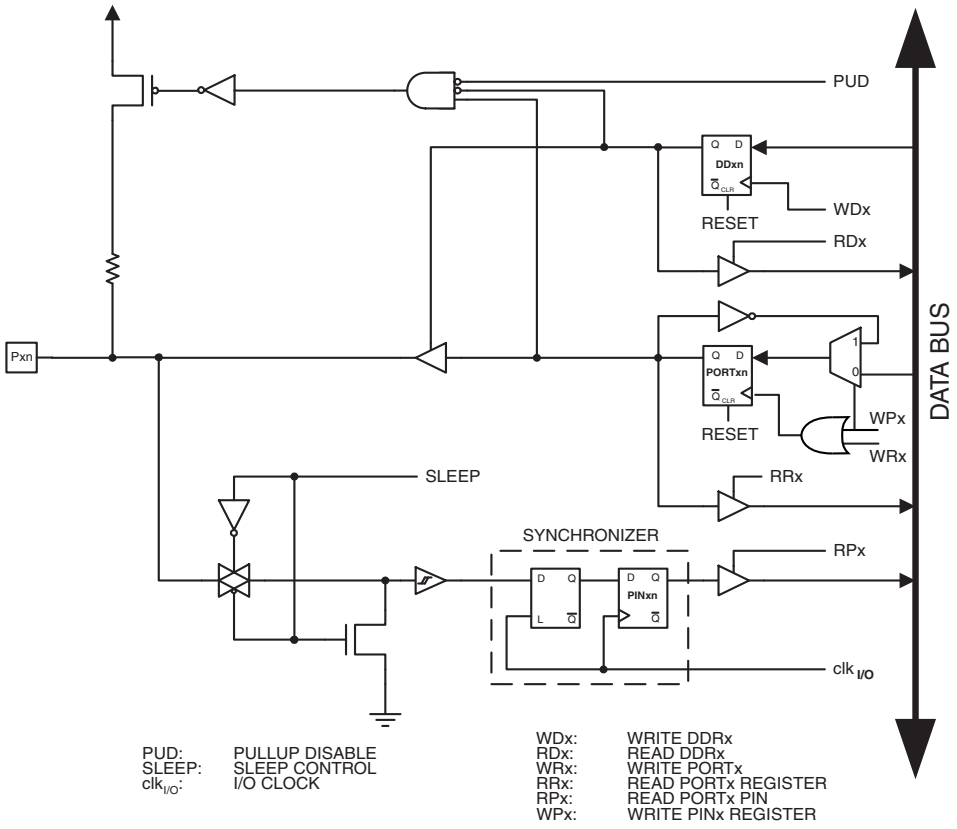
Using the I/O port as General Digital I/O is described in ”Low voltage ports as general digital I/O” on page 68. Many low voltage port pins are multiplexed with alternate functions for the peripheral features on the device. How each alternate function interferes with the port pin is described in ”Alternate port functions” on page 72. Refer to the individual module sections for a full description of the alternate functions.

Note that enabling the alternate function of some of the port pins does not affect the use of the other pins in the port as general digital I/O.

15.2 Low voltage ports as general digital I/O

The low voltage ports are bi-directional I/O ports with optional internal pull-ups. Figure 15-2 shows a functional description of one I/O-port pin, here generically called Pxn.

Figure 15-2. General low voltage digital I/O [(1)].



Note: 1. WRx, WPx, WDx, RRx, RPx, and RDx are common to all pins within the same port. $clk_{I/O}$, SLEEP, and PUD are common to all ports.

15.2.1 Configuring the pin

Each port pin consists of three register bits: DDxn, PORTxn, and PINxn. As shown in ”Register description” on page 78, the DDxn bits are accessed at the DDRx I/O address, the PORTxn bits at the PORTx I/O address, and the PINxn bits at the PINx I/O address.

The DDxn bit in the DDRx Register selects the direction of this pin. If DDxn is written logic one, Pxn is configured as an output pin. If DDxn is written logic zero, Pxn is configured as an input pin.

If PORTxn is written logic one when the pin is configured as an input pin, the pull-up resistor is activated. To switch the pull-up resistor off, PORTxn has to be written logic zero or the pin has to be configured as an output pin. The port pins are tri-stated when reset condition becomes active, even if no clocks are running.

If PORTxn is written logic one when the pin is configured as an output pin, the port pin is driven high (one). If PORTxn is written logic zero when the pin is configured as an output pin, the port pin is driven low (zero).

15.2.2 Toggling the pin

Writing a logic one to PINxn toggles the value of PORTxn, independent on the value of DDRxn. Note that the SBI instruction can be used to toggle one single bit in a port.

15.2.3 Switching between input and output

When switching between tri-state ({DDxn, PORTxn} = 0b00) and output high ({DDxn, PORTxn} = 0b11), an intermediate state with either pull-up enabled {DDxn, PORTxn} = 0b01) or output low ({DDxn, PORTxn} = 0b10) must occur. Normally, the pull-up enabled state is fully acceptable, as a high-impedant environment will not notice the difference between a strong high driver and a pull-up. If this is not the case, the PUD bit in the MCUCR Register can be set to disable all pull-ups in all ports.

Switching between input with pull-up and output low generates the same problem. The user must use either the tri-state ({DDxn, PORTxn} = 0b00) or the output high state ({DDxn, PORTxn} = 0b11) as an intermediate step.

Table 15-1 summarizes the control signals for the pin value.

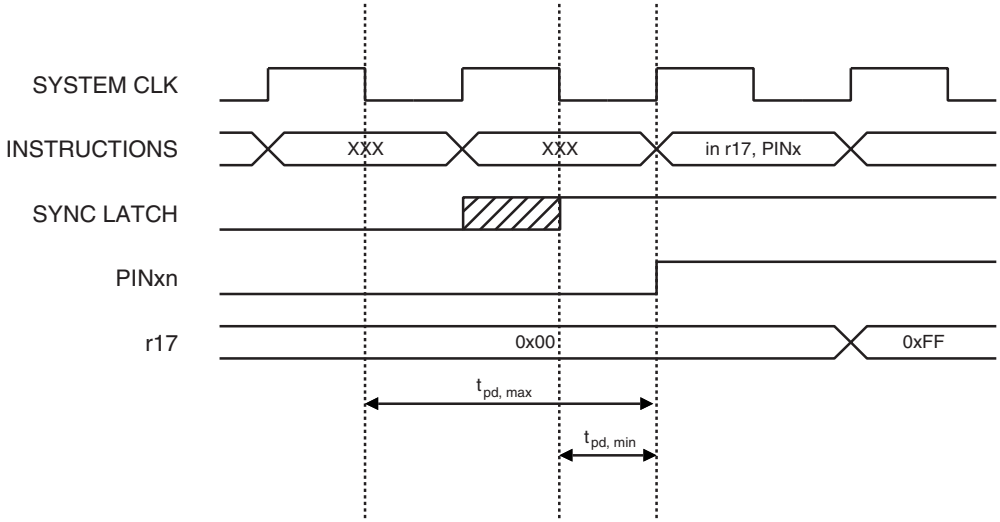
Table 15-1. Port pin configurations.

DDxn	PORTxn	PUD (in MCUCR)	I/O	Pull-up	Comment
0	0	X	Input	No	Tri-state (Hi-Z)
0	1	0	Input	Yes	Pxn will source current if ext. pulled low
0	1	1	Input	No	Tri-state (Hi-Z)
1	0	X	Output	No	Output Low (Sink)
1	1	X	Output	No	Output High (Source)

15.2.4 Reading the pin value

Independent of the setting of Data Direction bit DDxn, the port pin can be read through the PINxn Register bit. As shown in Figure 15-2 on page 68, the PINxn Register bit and the preceding latch constitute a synchronizer. This is needed to avoid metastability if the physical pin changes value near the edge of the internal clock, but it also introduces a delay. Figure 15-3 on page 70 shows a timing diagram of the synchronization when reading an externally applied pin value. The maximum and minimum propagation delays are denoted $t_{pd,max}$ and $t_{pd,min}$ respectively.

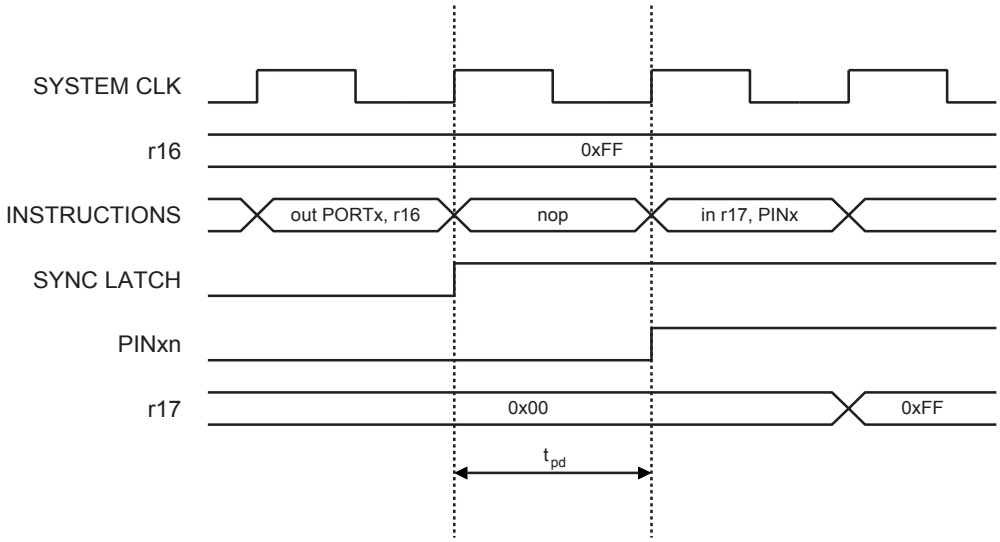
Figure 15-3. Synchronization when reading an externally applied pin value.



Consider the clock period starting shortly after the first falling edge of the system clock. The latch is closed when the clock is low, and goes transparent when the clock is high, as indicated by the shaded region of the “SYNC LATCH” signal. The signal value is latched when the system clock goes low. It is clocked into the PINxn Register at the succeeding positive clock edge. As indicated by the two arrows tpd,max and tpd,min, a single signal transition on the pin will be delayed between ½ and 1½ system clock period depending upon the time of assertion.

When reading back a software assigned pin value, a nop instruction must be inserted as indicated in Figure 15-4. The out instruction sets the “SYNC LATCH” signal at the positive edge of the clock. In this case, the delay t_{pd} through the synchronizer is one system clock period.

Figure 15-4. Synchronization when reading a software assigned pin value.



The following code example shows how to set port B pins 0 and 1 high, 2 and 3 low, and define the port pins from 4 to 7 as input with pull-ups assigned to port pins 6 and 7. The resulting pin values are read back again, but as previously discussed, a nop instruction is included to be able to read back the value recently assigned to some of the pins.

Assembly code example [1]

```
...
; Define pull-ups and set outputs high
; Define directions for port pins
ldi  r16,(1<<PB7)|(1<<PB6)|(1<<PB1)|(1<<PB0)
ldi  r17,(1<<DDB3)|(1<<DDB2)|(1<<DDB1)|(1<<DDB0)
out  PORTB,r16
out  DDRB,r17
; Insert nop for synchronization
nop
; Read port pins
in   r16,PINB
...
```

C code example

```
unsigned char i;
...
/* Define pull-ups and set outputs high */
/* Define directions for port pins */
PORTB = (1<<PB7)|(1<<PB6)|(1<<PB1)|(1<<PB0);
DDRB = (1<<DDB3)|(1<<DDB2)|(1<<DDB1)|(1<<DDB0);
/* Insert nop for synchronization*/
_NOP();
/* Read port pins */
i = PINB;
...
```

Note: 1. For the assembly program, two temporary registers are used to minimize the time from pull-ups are set on pins 0, 1, 6, and 7, until the direction bits are correctly set, defining bit 2 and 3 as low and redefining bits 0 and 1 as strong high drivers.

15.2.5 Digital input enable and sleep modes

As shown in Figure 15-2 on page 68, the digital input signal can be clamped to ground at the input of the schmiSchmidtt-trigger. The signal denoted SLEEP in the figure, is set by the MCU Sleep Controller in Power-save mode to avoid high power consumption if some input signals are left floating, or have an analog signal level close to $V_{REG}/2$.

SLEEP is overridden for port pins enabled as external interrupt pins. If the external interrupt request is not enabled, SLEEP is active also for these pins. SLEEP is also overridden by various other alternate functions as described in "Alternate port functions" on page 72.

If a logic high level ("one") is present on an asynchronous external interrupt pin configured as "Interrupt on Rising Edge, Falling Edge, or Any Logic Change on Pin" while the external interrupt is *not* enabled, the corresponding External Interrupt Flag will be set when resuming from the above mentioned Sleep mode, as the clamping in these sleep mode produces the requested logic change.

15.2.6 Unconnected pins

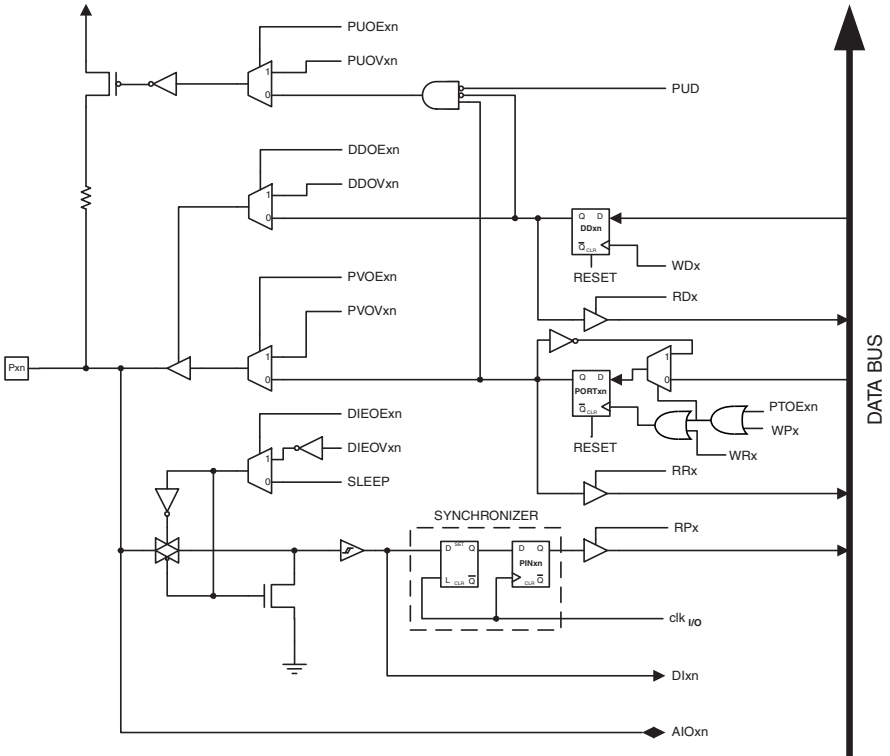
If some pins are unused, it is recommended to ensure that these pins have a defined level. Even though most of the digital inputs are disabled in the deep sleep modes as described above, floating inputs should be avoided to reduce current consumption in all other modes where the digital inputs are enabled (Reset, Active mode and Idle mode).

The simplest method to ensure a defined level of an unused pin, is to enable the internal pull-up. In this case, the pull-up will be disabled during reset. If low power consumption during reset is important, it is recommended to use an external pull-up or pull-down. Connecting unused pins directly to V_{CC} or GND is not recommended, since this may cause excessive currents if the pin is accidentally configured as an output.

15.3 Alternate port functions

Many low voltage port pins have alternate functions in addition to being general digital I/Os. Figure 15-5 shows how the port pin control signals from the simplified Figure 15-2 on page 68 can be overridden by alternate functions. The overriding signals may not be present in all port pins, but the figure serves as a generic description applicable to all port pins in the AVR microcontroller family.

Figure 15-5. Alternate port functions [1].



PUOExn:	Pxn PULL-UP OVERRIDE ENABLE	PUD:	PULLUP DISABLE
PUOVxn:	Pxn PULL-UP OVERRIDE VALUE	WDx:	WRITE DDRx
DDOExn:	Pxn DATA DIRECTION OVERRIDE ENABLE	RDx:	READ DDRx
DDOVxn:	Pxn DATA DIRECTION OVERRIDE VALUE	RRx:	READ PORTx REGISTER
PVOExn:	Pxn PORT VALUE OVERRIDE ENABLE	WRx:	WRITE PORTx
PVOVxn:	Pxn PORT VALUE OVERRIDE VALUE	RPx:	READ PORTx PIN
DIEOExn:	Pxn DIGITAL INPUT-ENABLE OVERRIDE ENABLE	WPx:	WRITE PINx
DIEOVxn:	Pxn DIGITAL INPUT-ENABLE OVERRIDE VALUE	$clk_{I/O}$:	I/O CLOCK
SLEEP:	SLEEP CONTROL	DIxn:	DIGITAL INPUT PIN n ON PORTx
PTOExn:	Pxn, PORT TOGGLE OVERRIDE ENABLE	AIOxn:	ANALOG INPUT/OUTPUT PIN n ON PORTx

Note: 1. WRx, WPx, WDx, RRx, RPx, and RDx are common to all pins within the same port. $clk_{I/O}$, SLEEP, and PUD are common to all ports. All other signals are unique for each pin.

Table 15-2 summarizes the function of the overriding signals. The pin and port indexes from Figure 15-5 on page 72 are not shown in the succeeding tables. The overriding signals are generated internally in the modules having the alternate function.

Table 15-2. Generic description of overriding signals for alternate functions.

Signal name	Full name	Description
PUOE	Pull-up override enable	If this signal is set, the pull-up enable is controlled by the PUOV signal. If this signal is cleared, the pull-up is enabled when {DDxn, PORTxn, PUD} = 0b010
PUOV	Pull-up override value	If PUOE is set, the pull-up is enabled/disabled when PUOV is set/cleared, regardless of the setting of the DDxn, PORTxn, and PUD Register bits
DDOE	Data direction override enable	If this signal is set, the Output Driver Enable is controlled by the DDOV signal. If this signal is cleared, the Output driver is enabled by the DDxn Register bit
DDOV	Data direction override value	If DDOE is set, the Output Driver is enabled/disabled when DDOV is set/cleared, regardless of the setting of the DDxn Register bit
PVOE	Port value override enable	If this signal is set and the Output Driver is enabled, the port value is controlled by the PVOV signal. If PVOE is cleared, and the Output Driver is enabled, the port Value is controlled by the PORTxn Register bit
PVOV	Port value override value	If PVOE is set, the port value is set to PVOV, regardless of the setting of the PORTxn Register bit
PTOE	Port toggle override enable	If PTOE is set, the PORTxn Register bit is inverted
DIEOE	Digital input enable override enable	If this bit is set, the Digital Input Enable is controlled by the DIEOV signal. If this signal is cleared, the Digital Input Enable is determined by MCU state (Normal mode, sleep mode)
DIEOV	Digital input enable override value	If DIEOE is set, the Digital Input is enabled/disabled when DIEOV is set/cleared, regardless of the MCU state (Normal mode, sleep mode)
DI	Digital input	This is the Digital Input to alternate functions. In the figure, the signal is connected to the output of the schmitt trigger but before the synchronizer. Unless the Digital Input is used as a clock source, the module with the alternate function will use its own synchronizer
AIO	Analog input/output	This is the Analog Input/output to/from alternate functions. The signal is connected directly to the pad, and can be used bi-directionally

The following subsections shortly describe the alternate functions for each port, and relate the overriding signals to the alternate function. Refer to the alternate function description for further details.

15.3.1 Alternate functions of Port A

The Port A pins with alternate functions are shown in Table 15-3.

Table 15-3. Port A pins alternate functions.

Port pin	Alternate function
PA3	T1/PCINT3 (Timer/Counter1 Clock Input or Pin Change Interrupt 3)
PA2	T0/PCINT2 (Timer/Counter0 Clock Input or Pin Change Interrupt 2)
PA1	ADC1/SGND/PCINT1 (ADC Input Channel 1, Signal Ground or Pin Change Interrupt 1)
PA0	ADC0/SGND/PCINT0 (ADC Input Channel 0, Signal Ground or Pin Change Interrupt 0)

The alternate pin configuration is as follows:

- **ADC0/SGND/PCINT0 – Port A, Bit0**

ADC0: Voltage ADC Channel0. This pin can serve as Channel 0 Input for the Voltage ADC.

SGND: Voltage ADC Signal Ground. This pin can serve as Channel 1 Signal Ground for the Voltage ADC.

PCINT0. Pin Change Interrupt 0. This pin can serve as external interrupt source.

- **ADC1/SGND/PCINT1 – Port A, Bit1**

ADC1: Voltage ADC Channel 1: This pin can serve as Channel 1 for the Voltage ADC.

SGND: Voltage ADC Signal Ground. This pin can serve as Channel 0 Signal Ground for the Voltage ADC.

PCINT1: Pin Change Interrupt 1. This pin can serve as external interrupt source.

- **T0/PCINT2 – Port A, Bit2**

T0: Timer/Counter0. This pin can serve as Timer/Counter0 clock source.

PCINT2: Pin Change Interrupt 2. This pin can serve as external interrupt source.

- **T1/PCINT3 – Port A, Bit3**

T1: Timer/Counter1. This pin can serve as Timer/Counter1 clock source.

PCINT3: Pin Change Interrupt 3.

These pins can serve as external interrupt source. Table 15-4 on page 75 relates the alternate functions of Port A to the overriding signals shown in Figure 15-5 on page 72.

Table 15-4. Overriding signals for alternate functions in PA3:PA0.

Signal name	PA3/T1/PCINT3	PA2/T0/PCINT2	PA1/ADC1/SGND/PCINT1	PA0/ADC0/SGND/PCINT0
PUOE	0	0	0	0
PUOV	0	0	0	0
DDOE	0	0	VADSC • VADMUX=ADC0	VADSC • VADMUX=ADC1
DDOV	0	0	1	1
PVOE	0	0	VADSC • VADMUX=ADC0	VADSC • VADMUX=ADC1
PVOV	0	0	0	0
PTOE	-	-	-	-
DIEOE	PCINT3 • PCIE0	PCINT2 • PCIE0	DIDR1| (PCINT1 • PCIE0)	DIDR0 | (PCINT0 • PCIE0)
DIEOV	1	1	$\overline{\text{DIDR1}}$	$\overline{\text{DIDR0}}$
DI	T1 INPUT PCINT3 INPUT	T0 INPUT PCINT2 INPUT	PCINT1 INPUT	PCINT0 INPUT
AIO	-	-	ADC1 INPUT/ SGND	ADC0 INPUT/ SGND

15.3.2 Alternate functions of Port B

The Port B pins with alternate functions are shown in Table 15-5.

Table 15-5. Port B pins alternate functions.

Port pin	Alternate functions
PB7	MISO/PCINT11 (SPI Bus Master Input/Slave Output or Pin Change Interrupt 11)
PB6	MOSI/PCINT10 (SPI Bus Master Output/Slave Input or Pin Change Interrupt 10)
PB5	SCK/PCINT9 (SPI Bus Serial Clock or Pin Change Interrupt 9)
PB4	$\overline{\text{SS}}$/PCINT8 (SPI Bus Slave Select input or Pin Change Interrupt 8)
PB3	PCINT7 (Pin Change Interrupt 7)
PB2	PCINT6 (Pin Change Interrupt 6)
PB1	CKOUT/PCINT5 (Clock output or Pin Change Interrupt 5)
PB0	PCINT4/ICP00 (Pin Change Interrupt 4 or Timer/Counter0 Input Capture Trigger)

The alternate pin configuration is as follows:

- **MISO/PCINT11 – Port B, Bit7**

MISO, Master Data input: Slave Data output pin for SPI channel. When the SPI is enabled as a Master, this pin is configured as an input regardless of the setting of DDB7. When the SPI is enabled as a Slave, the data direction of this pin is controlled by DDB7. When the pin is forced by the SPI to be an input, the pull-up can still be controlled by the PORTB7 bit. When not operating in SPI mode, this pin can serve as an external interrupt source.

PCINT11: Pin Change Interrupt 11. This pin can serve as external interrupt source.

- **MOSI/PCINT10 – Port B, Bit6**

MOSI, SPI Master Data output: Slave Data input for SPI channel. When the SPI is enabled as a Slave, this pin is configured as an input regardless of the setting of DDB6. When the SPI is

enabled as a Master, the data direction of this pin is controlled by DDB6. When the pin is forced by the SPI to be an input, the pull-up can still be controlled by the PORTB6 bit. When not operating in SPI mode, this pin can serve as an external interrupt source.

PCINT10: Pin Change Interrupt 10. This pin can serve as external interrupt source.

- **SCK/PCINT9 – Port B, Bit5**

SCK, Master Clock output: Slave Clock input pin for SPI channel. When the SPI is enabled as a Slave, this pin is configured as an input regardless of the setting of DDB5. When the SPI is enabled as a Master, the data direction of this pin is controlled by DDB5. When the pin is forced by the SPI to be an input, the pull-up can still be controlled by the PORTB5 bit.

PCINT9: Pin Change Interrupt 9. This pin can serve as external interrupt source.

- **$\overline{SS}$/PCINT8 – Port B, Bit4**

SS, Slave Select input: When the SPI is enabled as a Slave, this pin is configured as an input regardless of the setting of DDB4. As a Slave, the SPI is activated when this pin is driven low. When the SPI is enabled as a Master, the data direction of this pin is controlled by DDB4. When the pin is forced by the SPI to be an input, the pull-up can still be controlled by the PORTB4 bit. When not operating in SPI mode, this pin can serve as Clock Output, CPU Clock divided by 2. See ”Clock output” on page 28.

PCINT8: Pin Change Interrupt 8. This pin can serve as external interrupt source.

- **PCINT7 – Port B, Bit3**

PCINT7: Pin Change Interrupt 7. This pin can serve as external interrupt source.

- **PCINT6 – Port B, Bit2**

PCINT6: Pin Change Interrupt 6. This pin can serve as external interrupt source.

- **CKOUT/PCINT5 – Port B, Bit1**

CKOUT: Clock output. This pin can serve as clock output pin.

PCINT5: Pin Change Interrupt 5. This pin can serve as external interrupt source.

- **ICP00/PCINT4 – Port B, Bit0**

ICP00: Input Capture Timer/Counter0. This pin can serve as Input Capture Trigger for Timer/Counter0.

PCINT4: Pin Change Interrupt 4. This pin can serve as external interrupt source.

Table 15-6. Overriding signals for alternate functions in PB7:PB4.

Signal name	PB7/MISO/PCINT11	PB6/MOSI/PCINT10	PB5/SCK/PCINT9	PB4/$\overline{SS}$/PCINT8
PUOE	SPE • MSTR	SPE • $\overline{MSTR}$	SPE • $\overline{MSTR}$	SPE • $\overline{MSTR}$
PUOV	PORTB7 • $\overline{PUD}$	PORTB6 • $\overline{PUD}$	PORTB5 • $\overline{PUD}$	PORTB0 • $\overline{PUD}$
DDOE	SPE • MSTR	SPE • $\overline{MSTR}$	SPE • $\overline{MSTR}$	SPE • $\overline{MSTR}$
DDOV	0	0	0	0
PVOE	SPE • $\overline{MSTR}$	SPE • MSTR	SPE • MSTR	0
PVOV	SPI SLAVE OUTPUT	SPI MSTR OUTPUT	SCK OUTPUT	0
PTOE	–	–	–	–
DIEOE	PCINT11 • PCIE1	PCINT10 • PCIE1	PCINT9 • PCIE1	PCINT8 • PCIE1
DIEOV	1	1	–	1
DI	SPI MSTR INPUT PCINT11 INPUT	SPI SLAVE INPUT PCINT10 INPUT	SCK INPUT PCINT9 INPUT	$\overline{SS}$ INPUT PCINT8 INPUT
AIO	–	–	–	–

Table 15-7. Overriding signals for alternate functions in PB3:PB0.

Signal name	PB3/PCINT7	PB2/PCINT6	PB1/CKOE/PCINT5	PB0/PCINT4
PUOE	0	0	CKOE	0
PUOV	0	0	0	0
DDOE	0	0	CKOE	0
DDOV	0	0	CKOE	0
PVOE	0	0	CKOE	0
PVOV	0	0	CKOUT	0
PTOE	–	–	–	–
DIEOE	PCINT7 • PCIE1	PCINT6 • PCIE1	(PCINT6 • PCIE1)|CKOE	PCINT4 • PCIE1
DIEOV	1	1	(PCINT6 • PCIE1)|$\overline{CKOE}$	1
DI	PCINT7 INPUT	PCINT6 INPUT	PCINT5 INPUT	IPC0 INPUT PCINT4 INPUT
AIO	–	–	–	–

15.4 Register description

15.4.1 MCUCR – MCU Control Register

Bit	7	6	5	4	3	2	1	0	
0x35 (0x55)	–	–	CKOE	PUD	–	–	IVSEL	IVCE	MCUCR
Read/Write	R	R	R/W	R/W	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 4 – PUD: Pull-up disable**

When this bit is written to one, the pull-ups in the I/O ports are disabled even if the DDxn and PORTxn Registers are configured to enable the pull-ups ({DDxn, PORTxn} = 0b01). See ”Configuring the pin” on page 68 for more details about this feature.

15.4.2 PORTA – Port A Data Register

Bit	7	6	5	4	3	2	1	0	
0x02 (0x22)	–	–	–	–	PORTA3	PORTA2	PORTA1	PORTA0	PORTA
Read/Write	R	R	R	R	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

15.4.3 DDRA – Port A Data Direction Register

Bit	7	6	5	4	3	2	1	0	
0x01 (0x21)	–	–	–	–	DDA3	DDA2	DDA1	DDA0	DDRA
Read/Write	R	R	R	R	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

15.4.4 PINA – Port A Input Pins Address

Bit	7	6	5	4	3	2	1	0	
0x00 (0x20)	–	–	–	–	PINA3	PINA2	PINA1	PINA0	PINA
Read/Write	R	R	R	R	R/W	R/W	R/W	R/W	
Initial Value	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	

15.4.5 PORTB – Port B Data Register

Bit	7	6	5	4	3	2	1	0	
0x05 (0x25)	PORTB7	PORTB6	PORTB5	PORTB4	PORTB3	PORTB2	PORTB1	PORTB0	PORTB
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

15.4.6 DDRB – Port B Data Direction Register

Bit	7	6	5	4	3	2	1	0	
0x04 (0x24)	DDB7	DDB6	DDB5	DDB4	DDB3	DDB2	DDB1	DDB0	DDRB
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

15.4.7 PINB – Port B Input Pins Address

Bit	7	6	5	4	3	2	1	0	
0x03 (0x23)	PINB7	PINB6	PINB5	PINB4	PINB3	PINB2	PINB1	PINB0	PINB
Read/Write	R	R	R	R	R	R	R	R	
Initial Value	N/A	N/A	N/A	N/A	N/A	N/A	N/A	N/A	

16. Timer/Counter0 and Timer/Counter1 prescalers

16.1 Overview

Timer/Counter1 and Timer/Counter0 share the same prescaler module, but the Timer/Counters can have different prescaler settings. The description below applies to both Timer/Counter1 and Timer/Counter0.

16.1.1 Internal clock source

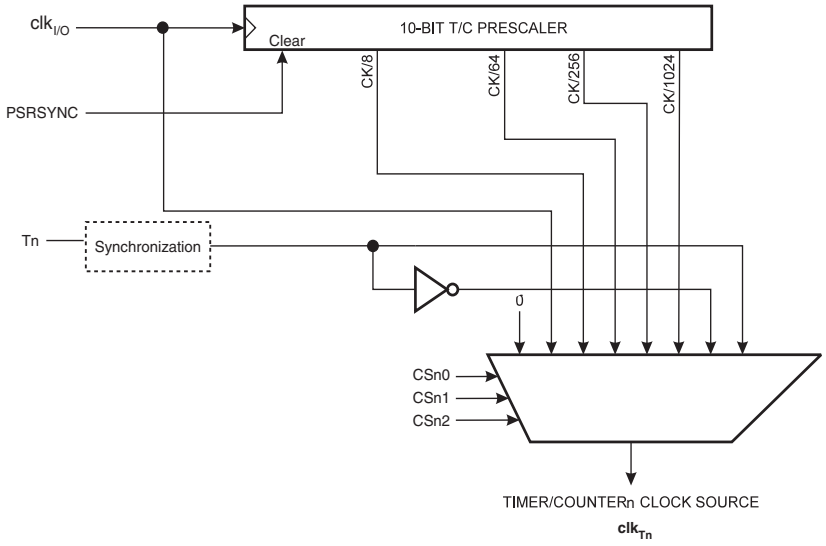
The Timer/Counter can be clocked directly by the system clock (by setting the CSn2:0 = 1). This provides the fastest operation, with a maximum Timer/Counter clock frequency equal to system clock frequency ($f_{CLK_I/O}$). Alternatively, one of four taps from the prescaler can be used as a clock source. The prescaled clock has a frequency of either $f_{CLK_I/O}/8$, $f_{CLK_I/O}/64$, $f_{CLK_I/O}/256$, or $f_{CLK_I/O}/1024$.

16.1.2 Prescaler reset

The prescaler is free running, that is, operates independently of the Clock Select logic of the Timer/Counter, and it is shared by Timer/Counter1 and Timer/Counter0. Since the prescaler is not affected by the Timer/Counter's clock select, the state of the prescaler will have implications for situations where a prescaled clock is used. One example of prescaling artifacts occurs when the timer is enabled and clocked by the prescaler (6 > CSn2:0 > 1). The number of system clock cycles from when the timer is enabled to the first count occurs can be from 1 to N+1 system clock cycles, where N equals the prescaler divisor (8, 64, 256, or 1024).

It is possible to use the prescaler reset for synchronizing the Timer/Counter to program execution. However, care must be taken if the other Timer/Counter that shares the same prescaler also uses prescaling. A prescaler reset will affect the prescaler period for all Timer/Counters it is connected to.

Figure 16-1. Prescaler for timer/counter.

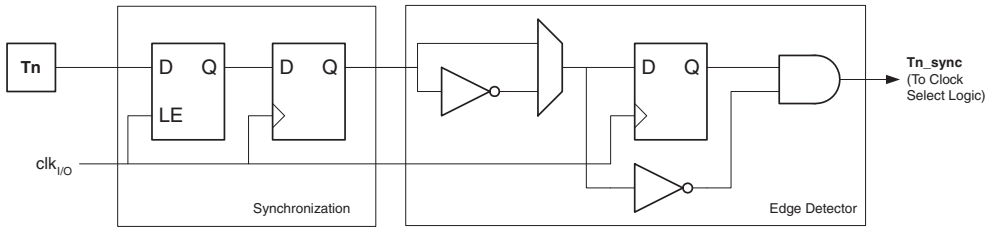


16.2 External clock source

An external clock source applied to the Tn pin can be used as Timer/Counter clock (clk_{Tn}). The Tn pin is sampled once every system clock cycle by the pin synchronization logic. The synchronized (sampled) signal is then passed through the edge detector. Figure 16-2 shows a functional equivalent block diagram of the Tn synchronization and edge detector logic. The registers are clocked at the positive edge of the internal system clock ($clk_{I/O}$). The latch is transparent in the high period of the internal system clock.

The edge detector generates one clk_{Tn} pulse for each positive (CSn2:0 = 7) or negative (CSn2:0 = 6) edge it detects. See Table 16-1 on page 81 for details.

Figure 16-2. Tn pin sampling.



The synchronization and edge detector logic introduces a delay of 2.5 to 3.5 system clock cycles from an edge has been applied to the Tn pin to the counter is updated.

Enabling and disabling of the clock input must be done when Tn has been stable for at least one system clock cycle, otherwise it is a risk that a false Timer/Counter clock pulse is generated.

Each half period of the external clock applied must be longer than one system clock cycle to ensure correct sampling. The external clock must be guaranteed to have less than half the system clock frequency ($f_{ExtClk} < f_{clk_I/O}/2$) given a 50/50% duty cycle. Since the edge detector uses sampling, the maximum frequency of an external clock it can detect is half the sampling frequency (Nyquist sampling theorem). However, due to variation of the system clock frequency and duty cycle caused by Oscillator source (crystal, resonator, and capacitors) tolerances, it is recommended that maximum frequency of an external clock source is less than $f_{clk_I/O}/2.5$.

An external clock source can not be prescaled.

Note: The synchronization logic on the input pins (Tn) is shown in Figure 16-2.

16.3 Register description

16.3.1 TCCRnB – Timer/Counter n Control Register B

Bit	7	6	5	4	3	2	1	0	
(0x80)(0x81)	–	–	–	–	–	CSn2	CSn1	CSn0	TCCRnB
Read/Write	R	R	R	R	R	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 2, 1, 0 – CSn2, CSn1, CSn0: Clock Select0, Bit 2, 1, and 0**

The Clock Select n bits 2, 1, and 0 define the prescaling source of Timer n.

Table 16-1. Clock Select Bit description.

CSn2	CSn1	CSn0	Description
0	0	0	No clock source (Timer/Counter stopped)
0	0	1	$clk_{I/O}$/(No prescaling)
0	1	0	$clk_{I/O}$/8 (From prescaler)
0	1	1	$clk_{I/O}$/64 (From prescaler)
1	0	0	$clk_{I/O}$/256 (From prescaler)
1	0	1	$clk_{I/O}$/1024 (From prescaler)
1	1	0	External clock source on Tn pin. Clock on falling edge
1	1	1	External clock source on Tn pin. Clock on rising edge

If external pin modes are used for the Timer/Counter n, transitions on the Tn pin will clock the counter even if the pin is configured as an output. This feature allows software control of the counting.

16.3.2 General Timer/Counter Control Register – GTCCR

Bit	7	6	5	4	3	2	1	0	
0x23 (0x43)	TSM	–	–	–	–	–	–	PSRSYNC	GTCCR
Read/Write	R/W	R	R	R	R	R	R	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7 – TSM: Timer/Counter Synchronization Mode**

Writing the TSM bit to one activates the Timer/Counter Synchronization mode. In this mode, the value that is written to the PSRSYNC bit is kept, hence keeping the corresponding prescaler reset signals asserted. This ensures that the corresponding Timer/Counters are halted and can be configured to the same value without the risk of one of them advancing during configuration. When the TSM bit is written to zero the PSRSYNC bit is cleared by hardware, and the Timer/Counters start counting simultaneously.

- **Bit 0 – PSRSYNC: Prescaler Reset**

When this bit is one, Timer/Counter1 and Timer/Counter0 prescaler will be Reset. This bit is normally cleared immediately by hardware, except if the TSM bit is set. Note that Timer/Counter1 and Timer/Counter0 share the same prescaler and a reset of this prescaler will affect both timers.

17. Timer/Counter (T/C0,T/C1)

17.1 Features

- **Clear timer on compare match (auto reload)**
- **Input capture unit**
- **Four independent interrupt sources (TOVn, OCFnA, OCFnB, ICFn)**
- **8-bit mode with two independent output compare units**
- **16-bit mode with one independent output compare unit**

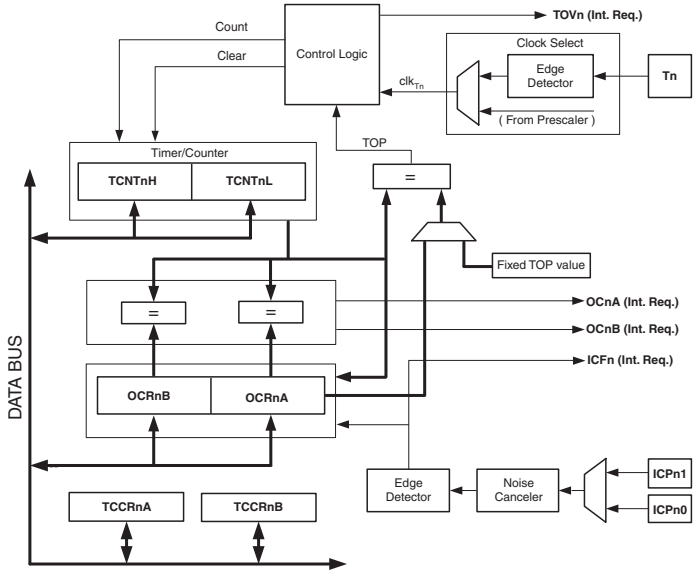
17.2 Overview

Timer/Counter n is a general purpose 8-bit/16-bit Timer/Counter module, with two/one Output Compare units and Input Capture feature.

The Atmel ATmega16HVB/32HVB has two Timer/Counters, Timer/Counter0 and Timer/Counter1. The functionality for both Timer/Counters is described below. Timer/Counter0 and Timer/Counter1 have different Timer/Counter registers, as shown in ”Register summary” on page 255.

The Timer/Counter general operation is described in 8-bit/16-bit mode. A simplified block diagram of the 8-bit/16-bit Timer/Counter is shown in Figure 17-1. CPU accessible I/O Registers, including I/O bits and I/O pins, are shown in bold. The device-specific I/O Register and bit locations are listed in the ”Register description” on page 94.

Figure 17-1. 8-bit/16-bit timer/counter block diagram.



17.2.1 Registers

The Timer/Counter Low Byte Register (TCNTnL) and Output Compare Registers (OCRnA and OCRnB) are 8-bit registers. Interrupt request (abbreviated to Int.Req. in Figure 17-1) signals are all visible in the Timer Interrupt Flag Register (TIFR). All interrupts are individually masked with the Timer Interrupt Mask Register (TIMSK). TIFR and TIMSK are not shown in the figure.

In 16-bit mode the Timer/Counter consists one more 8-bit register, the Timer/Counter High Byte Register (TCNTnH). Furthermore, there is only one Output Compare Unit in 16-bit mode as the two Output Compare Registers, OCRnA and OCRnB, are combined to one 16-bit Output Com-

pare Register. OCRnA contains the low byte of the word and OCRnB contains the higher byte of the word. When accessing 16-bit registers, special procedures described in section "Accessing registers in 16-bit mode" on page 90 must be followed.

The Timer/Counter can be clocked internally, via the prescaler, or by an external clock source on the Tn pin. The Clock Select logic block controls which clock source and edge the Timer/Counter uses to increment its value. The Timer/Counter is inactive when no clock source is selected. The output from the Clock Select logic is referred to as the timer clock (clk_{Tn}).

17.2.2 Definitions

Many register and bit references in this section are written in general form. A lower case "n" replaces the module number, for example Timer/Counter number. A lower case "x" replaces the unit, for example OCRnx and ICPnx describes OCRnA/B and ICP1/0x . However, when using the register or bit defines in a program, the precise form must be used, that is, TCNT0L for accessing Timer/Counter0 counter value and so on.

The definitions in Table 17-1 are also used extensively throughout the document.

Table 17-1. Definitions.

BOTTOM	The counter reaches the BOTTOM when it becomes 0
MAX	The counter reaches its MAXimum when it becomes 0xFF (decimal 255) in 8-bit mode or 0xFFFF (decimal 65535) in 16-bit mode
TOP	The counter reaches the TOP when it becomes equal to the highest value in the count sequence. The TOP value can be assigned to be the fixed value 0xFF/0xFFFF (MAX) or the value stored in the OCRnA Register

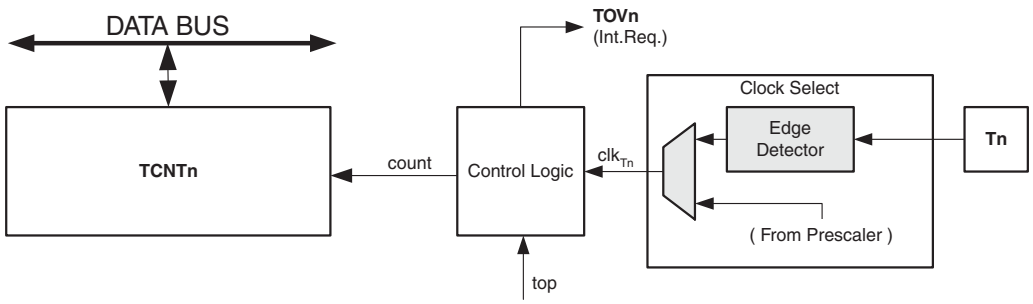
17.3 Timer/Counter clock sources

The Timer/Counter can be clocked internally, via the prescaler, or by an external clock source. The Clock Select logic is controlled by the Clock Select (CSn2:0) bits located in the Timer/Counter Control Register n B (TCCRnB), and controls which clock source and edge the Timer/Counter uses to increment its value. The Timer/Counter is inactive when no clock source is selected. The output from the Clock Select logic is referred to as the timer clock (clk_{Tn}). For details on clock sources and prescaler, see "Timer/Counter0 and Timer/Counter1 prescalers" on page 79.

17.4 Counter unit

The main part of the 8-bit Timer/Counter is the counter unit. Figure 17-2 shows a block diagram of the counter and its surroundings.

Figure 17-2. Counter unit block diagram.



Signal description (internal signals):

count	Increment or decrement TCNTn by one
clk_{Tn}	Timer/Counter clock, referred to as clk_{Tn} in the following
top	Signalize that TCNTn has reached maximum value

The counter is incremented at each timer clock (clk_{Tn}) until it passes its TOP value and then restarts from BOTTOM. The counting sequence is determined by the setting of the WGMn0 bits located in the Timer/Counter Control Register (TCCRnA). For more details about counting sequences, see "Timer/counter timing diagrams" on page 89. clk_{Tn} can be generated from an external or internal clock source, selected by the Clock Select bits (CSn2:0). When no clock source is selected (CSn2:0 = 0) the timer is stopped. However, the TCNTn value can be accessed by the CPU, regardless of whether clk_{Tn} is present or not. A CPU write overrides (has priority over) all counter clear or count operations. The Timer/Counter Overflow Flag (TOVn) is set when the counter reaches the maximum value and it can be used for generating a CPU interrupt.

17.5 Modes of operation

The mode of operation is defined by the Timer/Counter Width (TCWn), Input Capture Enable (ICENn) and the Waveform Generation Mode (WGMn0) bits in "TCCRnA – Timer/Counter n Control Register A" on page 94. Table 17-2 shows the different Modes of Operation.

Table 17-2. Modes of operation.

Mode	ICENn	TCWn	WGMn0	Timer/counter mode of operation	TOP	Update of OCRx at	TOV flag set on
0	0	0	0	Normal 8-bit Mode	0xFF	Immediate	MAX (0xFF)
1	0	0	1	8-bit CTC	OCRnA	Immediate	MAX (0xFF)
2	0	1	0	16-bit Mode	0xFFFF	Immediate	MAX (0xFFFF)
3	0	1	1	16-bit CTC	OCRnB, OCRnA	Immediate	MAX (0xFFFF)
4	1	0	0	8-bit Input Capture mode	0xFF	–	MAX (0xFF)
5	1	1	0	16-bit Input Capture mode	0xFFFF	–	MAX (0xFFFF)

17.5.1 Normal 8-bit mode

In the normal mode, the counter (TCNTnL) is incrementing until it overruns when it passes its maximum 8-bit value (MAX = 0xFF) and then restarts from the bottom (0x00), see Table 17-2 for bit settings. The Overflow Flag (TOVn) will be set in the same timer clock cycle as the TCNTnL becomes zero. The TOVn Flag in this case behaves like a ninth bit, except that it is only set, not cleared. However, combined with the timer overflow interrupt that automatically clears the TOVn Flag, the timer resolution can be increased by software. There are no special cases to consider in the Normal 8-bit mode, a new counter value can be written anytime. The Output Compare Unit can be used to generate interrupts at some given time.

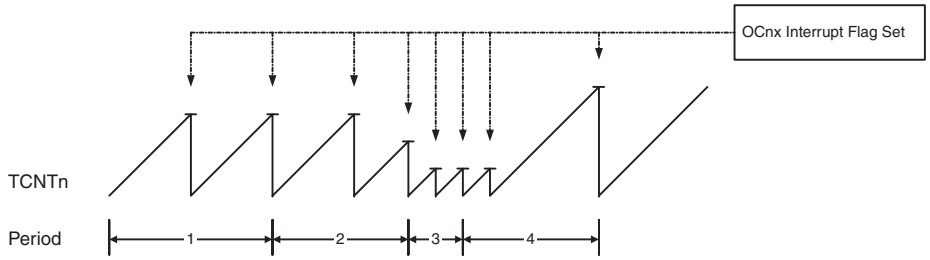
17.5.2 Clear timer on Compare Match (CTC) 8-bit mode

In Clear Timer on Compare or CTC mode, the OCRnA Register is used to manipulate the counter resolution, see Table 17-2 for bit settings. In CTC mode the counter is cleared to zero when

the counter value (TCNTn) matches the OCRnA. The OCRnA defines the top value for the counter, hence also its resolution. This mode allows greater control of the Compare Match output frequency. It also simplifies the operation of counting external events.

The timing diagram for the CTC mode is shown in Figure 17-3. The counter value (TCNTn) increases until a Compare Match occurs between TCNTn and OCRnA, and then counter (TCNTn) is cleared.

Figure 17-3. CTC Mode, timing diagram.



An interrupt can be generated each time the counter value reaches the TOP value by using the OCFnA Flag. If the interrupt is enabled, the interrupt handler routine can be used for updating the TOP value. However, changing TOP to a value close to BOTTOM when the counter is running with none or a low prescaler value must be done with care since the CTC mode does not have the double buffering feature. If the new value written to OCRnA is lower than the current value of TCNTn, the counter will miss the Compare Match. The counter will then have to count to its maximum value (0xFF) and wrap around starting at 0x00 before the Compare Match can occur. As for the Normal mode of operation, the TOVn Flag is set in the same timer clock cycle that the counter counts from MAX to 0x00.

17.5.3 16-bit mode

In 16-bit mode, the counter (TCNTnH/L) is a incrementing until it overruns when it passes its maximum 16-bit value (MAX = 0xFFFF) and then restarts from the bottom (0x0000), see Table 17-2 on page 84 for bit settings. The Overflow Flag (TOVn) will be set in the same timer clock cycle as the TCNTnH/L becomes zero. The TOVn Flag in this case behaves like a 17th bit, except that it is only set, not cleared. However, combined with the timer overflow interrupt that automatically clears the TOVn Flag, the timer resolution can be increased by software. There are no special cases to consider in the Normal mode, a new counter value can be written anytime. The Output Compare Unit can be used to generate interrupts at some given time.

17.5.4 Clear timer on Compare Match (CTC) 16-bit mode

In Clear Timer on Compare 16-bit mode, OCRAnA/B Registers are used to manipulate the counter resolution, see Table 17-2 on page 84 for bit settings. In CTC mode the counter is cleared to zero when the counter value (TCNTn) matches OCRnA/B, where OCRnB represents the eight most significant bits and OCRnA represents the eight least significant bits. OCRnA/B defines the top value of the counter, hence also its resolution. This mode allows greater control of the Compare Match output frequency. It also simplifies the operation of counting external events.

An interrupt can be generated each time the counter reaches the TOP value by using the OCFnA flag. If the interrupt is enabled, the interrupt handler routine can be used for updating the TOP value. However, changing the TOP to a value close the BOTTOM when the counter is running with none or a low prescaler value must be done with care since the CTC mode does not have the double buffering feature. If the new value written to OCRnA/B is lower than the current

value of TCNTn, the counter will miss the Compare Match. The counter will then have to count to its maximum value (0xFFFF) and wrap around starting at 0x0000 before Compare Match can occur. As for the 16-bit Mode, the TOVn Flag is set in the same timer clock cycle that the counter counts from MAX to 0x0000.

17.5.5 8-bit Input capture mode

The Timer/Counter can be used in a 8-bit Input Capture mode, see Table 17-2 on page 84 for bit settings. For full description, see “Input capture unit” .

17.5.6 16-bit input capture mode

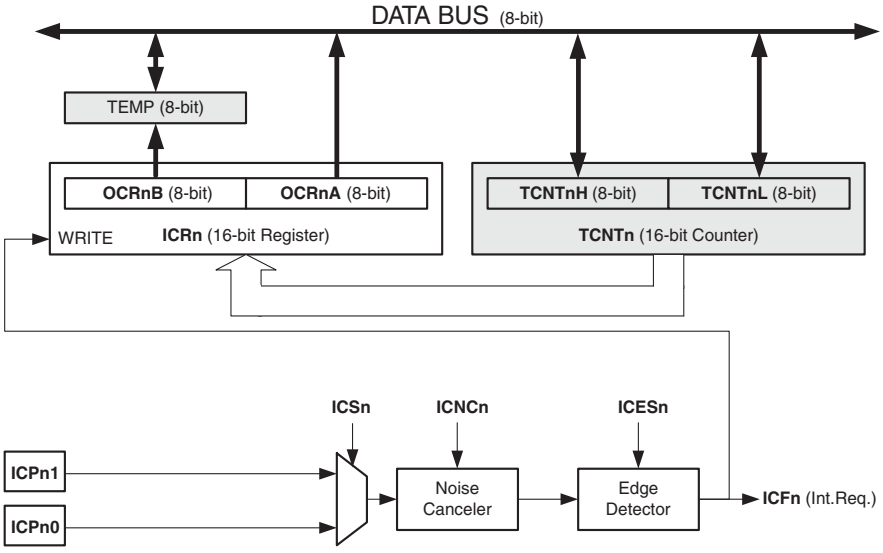
The Timer/Counter can also be used in a 16-bit Input Capture mode, see Table 17-2 on page 84 for bit settings. For full description, see “Input capture unit” .

17.6 Input capture unit

The Timer/Counter incorporates an Input Capture unit that can capture external events and give them a time-stamp indicating time of occurrence. The external signal indicates an event, or multiple events. For Timer/Counter0, the events can be applied via the PB0 pin (ICP00), or alternatively via the osi_posedge pin on the Oscillator Sampling Interface (ICP01). For Timer/Counter1, the events can be applied by the Battery Protection Interrupt (ICP10) or alternatively by the Voltage Regulator Interrupt (ICP11). The time-stamps can then be used to calculate frequency, duty-cycle, and other features of the signal applied. Alternatively the time-stamps can be used for creating a log of the events.

The Input Capture unit is illustrated by the block diagram shown in Figure 17-4. The elements of the block diagram that are not directly a part of the Input Capture unit are gray shaded.

Figure 17-4. Input Capture Unit block diagram.



The Output Compare Register OCRnA is a dual-purpose register that is also used as an 8-bit Input Capture Register ICRn. In 16-bit Input Capture mode the Output Compare Register OCRnB serves as the high byte of the Input Capture Register ICRn. In 8-bit Input Capture mode the Output Compare Register OCRnB is free to be used as a normal Output Compare Register, but in 16-bit Input Capture mode the Output Compare Unit cannot be used as there are no free Output Compare Register(s). Even though the Input Capture register is called ICRn in this sec-

tion, it is referring to the Output Compare Register(s). For more information on how to access the 16-bit registers refer to ”Accessing registers in 16-bit mode” on page 90.

When a change of the logic level (an event) occurs on the Input Capture pin (ICPx), and this change confirms to the setting of the edge detector, a capture will be triggered. When a capture is triggered, the value of the counter (TCNTn) is written to the Input Capture Register (ICRn). The Input Capture Flag (ICFn) is set at the same system clock as the TCNTn value is copied into Input Capture Register. If enabled (TICIEn=1), the Input Capture Flag generates an Input Capture interrupt. The ICFn flag is automatically cleared when the interrupt is executed. Alternatively the ICFn flag can be cleared by software by writing a logical one to its I/O bit location.

17.6.1 Input Capture trigger source

The default trigger source for the Input Capture unit is the I/O port PB0 in Timer/Counter0 and the Battery Protection Interrupt in Timer/Counter1. Alternatively can the osi_posedge pin on the Oscillator Sampling Interface in Timer/Counter0 and Voltage Regulator Interrupt in Timer/Counter1 be used as trigger sources. The osi_posedge pin in Timer/Counter0 Control Register A (TCCR0A) and the Voltage Regulator Interrupt bit in the Timer/Counter1 Control Register A (TCCR1A) is selected as trigger sources by setting the Input Capture Select (ICS0/1) bit. Be aware that changing trigger source can trigger a capture. The Input Capture Flag must therefore be cleared after the change.

Both Input Capture inputs are sampled using the same technique. The edge detector is also identical. However, when the noise canceler is enabled, additional logic is inserted before the edge detector, which increases the delay by four system clock cycles. An Input Capture on Timer/Counter0 can also be triggered by software by controlling the port of the PB0 pin.

17.6.2 Noise canceler

The noise canceler improves noise immunity by using a simple digital filtering scheme. The noise canceler input is monitored over four samples, and all four must be equal for changing the output that in turn is used by the edge detector.

The noise canceler is enabled by setting the Input Capture Noise Canceler (ICNCn) bit in Timer/Counter Control Register n B (TCCRnB). When enabled the noise canceler introduces additional four system clock cycles of delay from a change applied to the input, to the update of the ICRn Register. The noise canceler uses the system clock and is therefore not affected by the prescaler.

17.6.3 Using the Input Capture unit

The main challenge when using the Input Capture unit is to assign enough processor capacity for handling the incoming events. The time between two events is critical. If the processor has not read the captured value in the ICRn Register before the next event occurs, the ICRn will be overwritten with a new value. In this case the result of the capture will be incorrect.

When using the Input Capture interrupt, the ICRn Register should be read as early in the interrupt handler routine as possible. The maximum interrupt response time is dependent on the maximum number of clock cycles it takes to handle any of the other interrupt requests.

Measurement of an external signal duty cycle requires that the trigger edge is changed after each capture. Changing the edge sensing must be done as early as possible after the ICRn Register has been read. After a change of the edge, the Input Capture Flag (ICFn) must be cleared by software (writing a logical one to the I/O bit location). For measuring frequency only, the trigger edge change is not required.

Table 17-3. Timer/Counter0 Input Capture Source (ICS).

ICS0	Source
0	ICP00: Port PB0
1	ICP01: osi_posedge pin from OSI module (1)(2)

Note: 1. See "OSI – Oscillator sampling interface" on page 29 for details.
2. The noise canceler cannot be used with this source.

Table 17-4. Timer/Counter1 Input Capture Source (ICS).

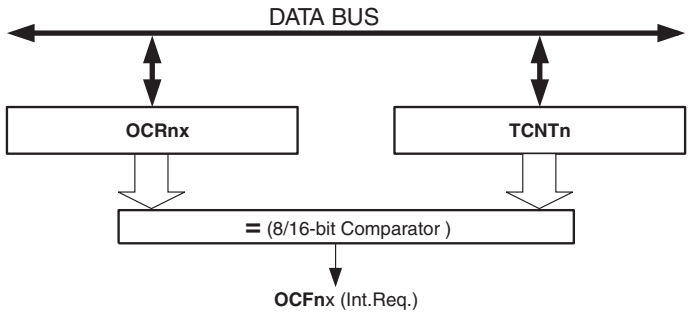
ICS1	Source
0	ICP10: Battery Protection Interrupt (1)
1	ICP11: Voltage Regulator Interrupt (1)

Note: 1. The noise canceller will filter out the input capture and it is therefore not recommended to use noise canceler with these sources.

17.7 Output compare unit

The comparator continuously compares the Timer/Counter (TCNTn) with the Output Compare Registers (OCRnA and OCRnB), and whenever the Timer/Counter equals to the Output Compare Registers, the comparator signals a match. A match will set the Output Compare Flag at the next timer clock cycle. In 8-bit mode the match can set either the Output Compare Flag OCFnA or OCFnB, but in 16-bit mode the match can set only the Output Compare Flag OCFnA as there is only one Output Compare Unit. If the corresponding interrupt is enabled, the Output Compare Flag generates an Output Compare interrupt. The Output Compare Flag is automatically cleared when the interrupt is executed. Alternatively, the flag can be cleared by software by writing a logical one to its I/O bit location. Figure 17-5 shows a block diagram of the Output Compare unit.

Figure 17-5. Output Compare Unit, block diagram.



17.7.1 Compare Match Blocking by TCNT0 write

All CPU write operations to the TCNTnH/L Register will block any Compare Match that occur in the next timer clock cycle, even when the timer is stopped. This feature allows OCRnA/B to be initialized to the same value as TCNTn without triggering an interrupt when the Timer/Counter clock is enabled.

17.7.2 Using the Output Compare Unit

Since writing TCNTnH/L will block all Compare Matches for one timer clock cycle, there are risks involved when changing TCNTnH/L when using the Output Compare Unit, independently of whether the Timer/Counter is running or not. If the value written to TCNTnH/L equals the OCRnA/B value, the Compare Match will be missed.

17.8 Timer/counter timing diagrams

The Timer/Counter is a synchronous design and the timer clock (clk_{Tn}) is therefore shown as a clock enable signal in the following figures. The figures include information on when Interrupt Flags are set. Figure 17-6 contains timing data for basic Timer/Counter operation. The figure shows the count sequence close to the MAX value.

Figure 17-6. Timer/counter timing diagram, no prescaling.

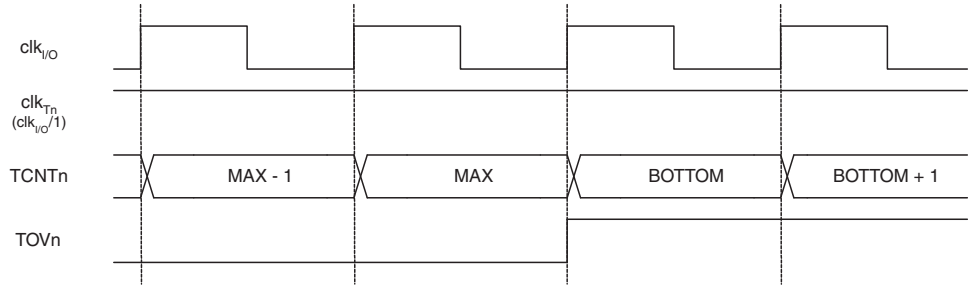


Figure 17-7 shows the same timing data, but with the prescaler enabled.

Figure 17-7. Timer/counter timing diagram, with prescaler ($f_{clk_I/O}/8$).

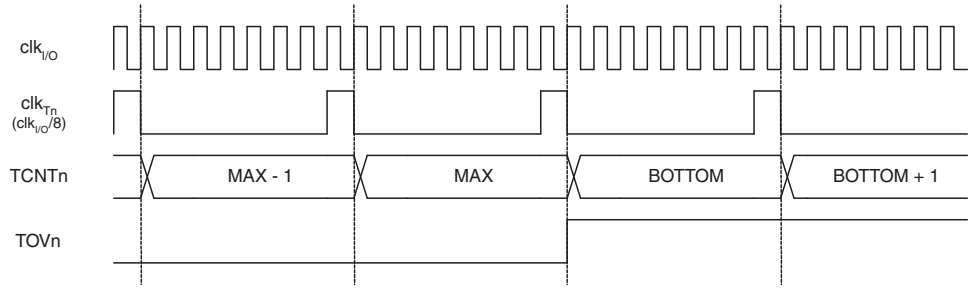


Figure 17-8 shows the setting of OCFnA and OCFnB in Normal mode.

Figure 17-8. Timer/counter timing diagram, setting of OCFnx, with prescaler ($f_{clk_I/O}/8$).

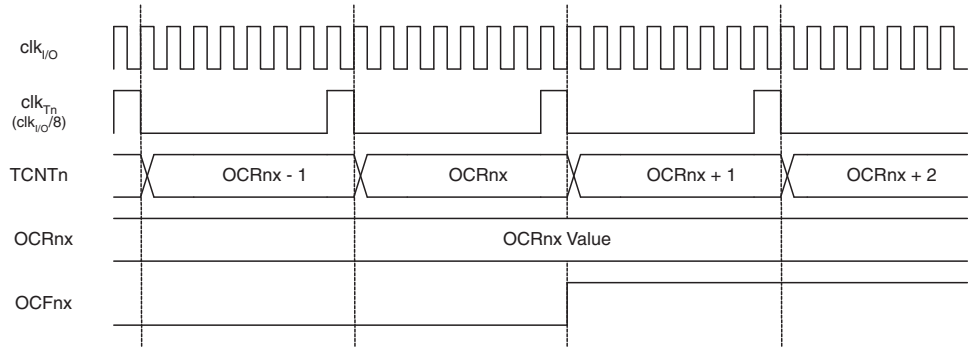
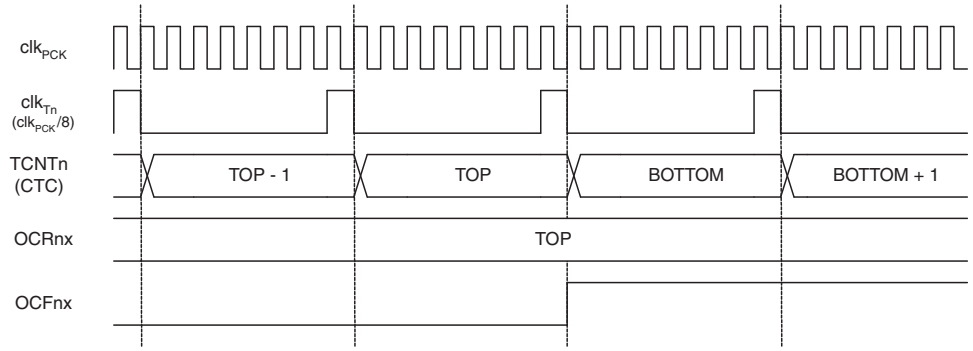


Figure 17-9 shows the setting of OCFnA and the clearing of TCNTn in CTC mode.

Figure 17-9. Timer/counter timing diagram, CTC mode, with prescaler ($f_{clk_I/O}/8$).



17.9 Accessing registers in 16-bit mode

In 16-bit mode (the TCWn bit is set to one) the TCNTnH/L and OCRnA/B or TCNTnL/H and OCRnB/A are 16-bit registers that can be accessed by the AVR CPU via the 8-bit data bus. The 16-bit register must be byte accessed using two read or write operations. The 16-bit Timer/Counter has a single 8-bit register for temporary storing of the high byte of the 16-bit access. The same temporary register is shared between all 16-bit registers. Accessing the low byte triggers the 16-bit read or write operation. When the low byte of a 16-bit register is written by the CPU, the high byte stored in the temporary register, and the low byte written are both copied into the 16-bit register in the same clock cycle. When the low byte of a 16-bit register is read by the CPU, the high byte of the 16-bit register is copied into the temporary register in the same clock cycle as the low byte is read.

There is one exception in the temporary register usage. In the Output Compare mode the 16-bit Output Compare Register OCRnA/B is read without the temporary register, because the Output Compare Register contains a fixed value that is only changed by CPU access. However, in 16-bit Input Capture mode the ICRn register formed by the OCRnA and OCRnB registers must be accessed with the temporary register.

To do a 16-bit write, the high byte must be written before the low byte. For a 16-bit read, the low byte must be read before the high byte.

The following code examples show how to access the 16-bit timer registers assuming that no interrupts updates the temporary register. The same principle can be used directly for accessing the OCRnA/B registers.

Assembly code example

```
...
; Set TCNTn to 0x01FF
ldi r17,0x01
ldi r16,0xFF
out TCNTnH,r17
out TCNTnL,r16
; Read TCNTn into r17:r16
in  r16,TCNTnL
in  r17,TCNTnH
...
```

C code example

```
unsigned int i;
...
/* Set TCNTn to 0x01FF */
TCNTn = 0x1FF;
/* Read TCNTn into i */
i = TCNTn;
...
```

Note: 1. See ”About code examples” on page 8.

The assembly code example returns the TCNTnH/L value in the r17:r16 register pair.

It is important to notice that accessing 16-bit registers are atomic operations. If an interrupt occurs between the two instructions accessing the 16-bit register, and the interrupt code updates the temporary register by accessing the same or any other of the 16-bit timer registers, then the result of the access outside the interrupt will be corrupted. Therefore, when both the main code and the interrupt code update the temporary register, the main code must disable the interrupts during the 16-bit access.

The following code examples show how to do an atomic read of the TCNTn register contents. Reading any of the OCRn register can be done by using the same principle.

Assembly code example

```
TIMn_ReadTCNTn:
  ; Save global interrupt flag
  in  r18,SREG
  ; Disable interrupts
  cli
  ; Read TCNTn into r17:r16
  in  r16,TCNTnL
  in  r17,TCNTnH
  ; Restore global interrupt flag
  out SREG,r18
  ret
```

C code example

```
unsigned int TIMn_ReadTCNTn( void )
{
  unsigned char sreg;
  unsigned int i;
  /* Save global interrupt flag */
  sreg = SREG;
  /* Disable interrupts */
  _CLI();
  /* Read TCNTn into i */
  i = TCNTn;
  /* Restore global interrupt flag */
  SREG = sreg;
  return i;
}
```

Note: 1. See ”About code examples” on page 8.

The assembly code example returns the TCNTnH/L value in the r17:r16 register pair.

The following code examples show how to do an atomic write of the TCNTnH/L register contents. Writing any of the OCRnA/B registers can be done by using the same principle.

Assembly code example

```
TIMn_WriteTCNTn:
  ; Save global interrupt flag
  in  r18,SREG
  ; Disable interrupts
  cli
  ; Set TCNTn to r17:r16
  out TCNTnH,r17
  out TCNTnL,r16
  ; Restore global interrupt flag
  out SREG,r18
  ret
```

C code example

```
void TIMn_WriteTCNTn( unsigned int i )
{
  unsigned char sreg;
  unsigned int i;
  /* Save global interrupt flag */
  sreg = SREG;
  /* Disable interrupts */
  _CLI();
  /* Set TCNTn to i */
  TCNTn = i;
  /* Restore global interrupt flag */
  SREG = sreg;
}
```

Note: 1. See ”About code examples” on page 8.

The assembly code example requires that the r17:r16 register pair contains the value to be written to TCNTnH/L.

17.9.1 Reusing the temporary high byte register

If writing to more than one 16-bit register where the high byte is the same for all registers written, then the high byte only needs to be written once. However, note that the same rule of atomic operation described previously also applies in this case.

17.10 Register description

17.10.1 TCCRnA – Timer/Counter n Control Register A

Bit	7	6	5	4	3	2	1	0	
0x24 (0x44)	TCWn	ICENn	ICNCn	ICESn	ICSn	–	–	WGMn0	TCCRnA
Read/Write	R/W	R/W	R/W	R/W	R/W	R	R	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7 – TCWn: Timer/Counter Width**

When this bit is written to one 16-bit mode is selected. Timer/Counter n width is set to 16-bits and the Output Compare Registers OCRnA and OCRnB are combined to form one 16-bit Output Compare Register. Because the 16-bit registers TCNTnH/L and OCRnB/A are accessed by the AVR CPU via the 8-bit data bus, special procedures must be followed. These procedures are described in section ”Accessing registers in 16-bit mode” on page 90.

- **Bit 6 – ICENn: Input Capture Mode Enable**

The Input Capture Mode is enabled when this bit is written to one.

- **Bit 5 – ICNCn: Input Capture Noise Canceler**

Setting this bit activates the Input Capture Noise Canceler. When the noise canceler is activated, the input from the Input Capture Source is filtered. The filter function requires four successive equal valued samples of the Input Capture Source for changing its output. The Input Capture is therefore delayed by four System Clock cycles when the noise canceler is enabled.

- **Bit 4 – ICESn: Input Capture Edge Select**

This bit selects which edge on the Input Capture Source that is used to trigger a capture event. When the ICESn bit is written to zero, a falling (negative) edge is used as trigger, and when the ICESn bit is written to one, a rising (positive) edge will trigger the capture. When a capture is triggered according to the ICESn setting, the counter value is copied into the Input Capture Register. The event will also set the Input Capture Flag (ICFn), and this can be used to cause an Input Capture Interrupt, if this interrupt is enabled.

- **Bit 3 – ICSn: Input Capture Select**

When written logic one, this bit enables the input capture function in Timer/Counter n to be triggered by the alternative Input Capture Source. To make the comparator trigger the Timer/Counter n Input Capture interrupt, the TICIEn bit in the Timer Interrupt Mask Register (TIMSK) must be set. See Table 17-3 on page 88 and Table 17-4 on page 88.

- **Bits 2:1 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB and will always read as zero.

- **Bit 0 – WGMn0: Waveform Generation Mode**

This bit controls the counting sequence of the counter, the source for maximum (TOP) counter value, see Figure 17-6 on page 89. Modes of operation supported by the Timer/Counter unit are: Normal mode (counter) and Clear Timer on Compare Match (CTC) mode (see ”Timer/counter timing diagrams” on page 89).

17.10.2 TCNTnL – Timer/Counter n Register Low Byte

Bit	7	6	5	4	3	2	1	0	
0x26 (0x46)	TCNTnL[7:0]								TCNTnL
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

The Timer/Counter Register TCNTnL gives direct access, both for read and write operations, to the Timer/Counter unit 8-bit counter. Writing to the TCNTnL Register blocks (disables) the Compare Match on the following timer clock. Modifying the counter (TCNTnL) while the counter is running, introduces a risk of missing a Compare Match between TCNTnL and the OCRnx Registers. In 16-bit mode the TCNTnL register contains the lower part of the 16-bit Timer/Counter n Register.

17.10.3 TCNTnH – Timer/Counter n Register High Byte

Bit	7	6	5	4	3	2	1	0	
0x27 (0x47)	TCNTnH[7:0]								TCNTnH
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

When 16-bit mode is selected (the TCWn bit is set to one) the Timer/Counter Register TCNTnH combined to the Timer/Counter Register TCNTnL gives direct access, both for read and write operations, to the Timer/Counter unit 16-bit counter. To ensure that both the high and low bytes are read and written simultaneously when the CPU accesses these registers, the access is performed using an 8-bit temporary high byte register (TEMP). This temporary register is shared by all the other 16-bit registers. See ”Accessing registers in 16-bit mode” on page 90.

17.10.4 OCRnA – Timer/Counter n Output Compare Register A

Bit	7	6	5	4	3	2	1	0	
0x28 (0x48)	OCRnA[7:0]								OCRnA
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

The Output Compare Register A contains an 8-bit value that is continuously compared with the counter value (TCNTnL). A match can be used to generate an Output Compare interrupt.

In 16-bit mode the OCRnA register contains the low byte of the 16-bit Output Compare Register. To ensure that both the high and the low bytes are written simultaneously when the CPU writes to these registers, the access is performed using an 8-bit temporary high byte register (TEMP). This temporary register is shared by all the other 16-bit registers. See ”Accessing registers in 16-bit mode” on page 90.

17.10.5 OCRnB – Timer/Counter n Output Compare Register B

Bit	7	6	5	4	3	2	1	0	
0x29 (0x49)	OCRnB[7:0]								OCRnB
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

The Output Compare Register B contains an 8-bit value that is continuously compared with the counter value (TCNTnL in 8-bit mode and TCNTnH in 16-bit mode). A match can be used to generate an Output Compare interrupt.

In 16-bit mode the OCRnB register contains the high byte of the 16-bit Output Compare Register. To ensure that both the high and the low bytes are written simultaneously when the CPU writes to these registers, the access is performed using an 8-bit temporary high byte register (TEMP). This temporary register is shared by all the other 16-bit registers. See ”Accessing registers in 16-bit mode” on page 90.

17.10.6 TIMSKn – Timer/Counter n Interrupt Mask Register

Bit	7	6	5	4	3	2	1	0	
(0x6E)(0x6F)	–	–	–	–	ICIEn	OCIEnB	OCIEnA	TOIEn	TIMSKn
Read/Write	R	R	R	R	R/W	R/W	R/W	R	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 3 – ICIEn: Timer/Counter n Input Capture Interrupt Enable**

When this bit is written to one, and the I-flag in the Status Register is set (interrupts globally enabled), the Timer/Counter n Input Capture interrupt is enabled. The corresponding Interrupt Vector (see ”Interrupts” on page 52) is executed when the ICFn flag, located in TIFRn, is set.

- **Bit 2 – OCIEnB: Timer/Counter n Output Compare Match B Interrupt Enable**

When the OCIEnB bit is written to one, and the I-bit in the Status Register is set, the Timer/Counter Compare Match B interrupt is enabled. The corresponding interrupt is executed if a Compare Match in Timer/Counter occurs, that is, when the OCFnB bit is set in the Timer/Counter Interrupt Flag Register – TIFRn.

- **Bit 1 – OCIEnA: Timer/Counter n Output Compare Match A Interrupt Enable**

When the OCIEnA bit is written to one, and the I-bit in the Status Register is set, the Timer/Counter n Compare Match A interrupt is enabled. The corresponding interrupt is executed if a Compare Match in Timer/Counter n occurs, that is, when the OCFnA bit is set in the Timer/Counter n Interrupt Flag Register – TIFRn.

- **Bit 0 – TOIEn: Timer/Counter n Overflow Interrupt Enable**

When the TOIEn bit is written to one, and the I-bit in the Status Register is set, the Timer/Counter n Overflow interrupt is enabled. The corresponding interrupt is executed if an overflow in Timer/Counter n occurs, that is, when the TOVn bit is set in the Timer/Counter n Interrupt Flag Register – TIFRn.

17.10.7 TIFRn – Timer/Counter n Interrupt Flag Register

Bit	7	6	5	4	3	2	1	0	
0x15 (0x35)	–	–	–	–	ICFn	OCFnB	OCFnA	TOVn	TIFRn
Read/Write	R	R	R	R	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 3 – ICFn: Timer/Counter n Input Capture Flag**

This flag is set when a capture event occurs, according to the setting of ICENn, ICESn and ICSn bits in the TCCRnA Register.

ICFn is automatically cleared when the Input Capture Interrupt Vector is executed. Alternatively, ICFn can be cleared by writing a logic one to its bit location.

- **Bit 2 – OCFnB: Output Compare Flag n B**

The OCFnB bit is set when a Compare Match occurs between the Timer/Counter and the data in OCRnB – Output Compare Register n B. OCFnB is cleared by hardware when executing the corresponding interrupt handling vector. Alternatively, OCFnB is cleared by writing a logic one to the flag. When the I-bit in SREG, OCIEnB (Timer/Counter Compare B Match Interrupt Enable), and OCFnB are set, the Timer/Counter Compare Match Interrupt is executed.

The OCFnB is not set in 16-bit Output Compare mode when the Output Compare Register OCRnB is used as the high byte of the 16-bit Output Compare Register or in 16-bit Input Capture mode when the Output Compare Register OCRnB is used as the high byte of the Input Capture Register.

- **Bit 1 – OCFnA: Output Compare Flag n A**

The OCFnA bit is set when a Compare Match occurs between the Timer/Counter n and the data in OCRnA – Output Compare Register n. OCFnA is cleared by hardware when executing the corresponding interrupt handling vector. Alternatively, OCFnA is cleared by writing a logic one to the flag. When the I-bit in SREG, OCIEnA (Timer/Counter n Compare Match Interrupt Enable), and OCFnA are set, the Timer/Counter n Compare Match Interrupt is executed.

The OCFnA is also set in 16-bit mode when a Compare Match occurs between the Timer/Counter n and 16-bit data in OCRnB/A. The OCFnA is not set in Input Capture mode when the Output Compare Register OCRnA is used as an Input Capture Register.

- **Bit 0 – TOVn: Timer/Counter n Overflow Flag**

The bit TOVn is set when an overflow occurs in Timer/Counter n. TOVn is cleared by hardware when executing the corresponding interrupt handling vector. Alternatively, TOVn is cleared by writing a logic one to the flag. When the SREG I-bit, TOIEn (Timer/Counter n Overflow Interrupt Enable), and TOVn are set, the Timer/Counter n Overflow interrupt is executed.

18. SPI – Serial Peripheral Interface

18.1 Features

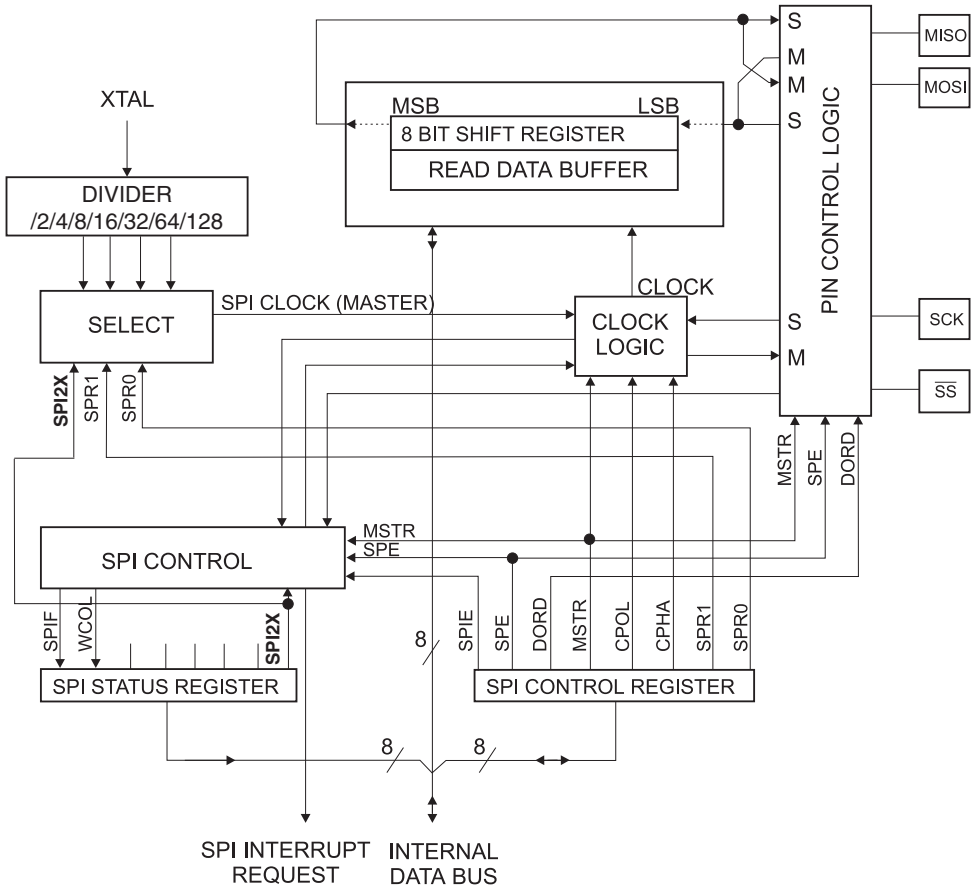
- **Full-duplex, three-wire synchronous data transfer**
- **Master or slave operation**
- **LSB first or MSB first data transfer**
- **Seven programmable bit rates**
- **End of transmission interrupt flag**
- **Write collision protection flag**
- **Wake-up from idle mode**
- **Double speed (CK/2) master SPI mode**

18.2 Overview

The Serial Peripheral Interface (SPI) allows high-speed synchronous data transfer between the Atmel ATmega16HVB/32HVB and peripheral devices or between several AVR devices.

When the SPI is not used, power consumption can be minimized by writing the PRSPI bit in PRR0 to one. See ”PRR0 – Power Reduction Register 0” on page 40 for details on how to use the PRSPI bit.

Figure 18-1. SPI block diagram [(1)].



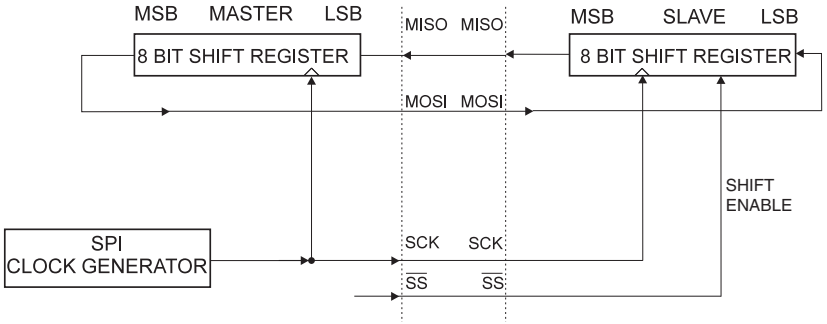
Note: 1. Refer to ”Alternate port functions” on page 72 for SPI pin placement.

The interconnection between Master and Slave CPUs with SPI is shown in Figure 18-2. The system consists of two shift Registers, and a Master clock generator. The SPI Master initiates the communication cycle when pulling low the Slave Select $\overline{SS}$ pin of the desired Slave. Master and Slave prepare the data to be sent in their respective shift Registers, and the Master generates the required clock pulses on the SCK line to interchange data. Data is always shifted from Master to Slave on the Master Out – Slave In, MOSI, line, and from Slave to Master on the Master In – Slave Out, MISO, line. After each data packet, the Master will synchronize the Slave by pulling high the Slave Select, $\overline{SS}$, line.

When configured as a Master, the SPI interface has no automatic control of the $\overline{SS}$ line. This must be handled by user software before communication can start. When this is done, writing a byte to the SPI Data Register starts the SPI clock generator, and the hardware shifts the eight bits into the Slave. After shifting one byte, the SPI clock generator stops, setting the end of Transmission Flag (SPIF). If the SPI Interrupt Enable bit (SPIE) in the SPCR Register is set, an interrupt is requested. The Master may continue to shift the next byte by writing it into SPDR, or signal the end of packet by pulling high the Slave Select, $\overline{SS}$ line. The last incoming byte will be kept in the Buffer Register for later use.

When configured as a Slave, the SPI interface will remain sleeping with MISO tri-stated as long as the $\overline{SS}$ pin is driven high. In this state, software may update the contents of the SPI Data Register, SPDR, but the data will not be shifted out by incoming clock pulses on the SCK pin until the $\overline{SS}$ pin is driven low. As one byte has been completely shifted, the end of Transmission Flag, SPIF is set. If the SPI Interrupt Enable bit, SPIE, in the SPCR Register is set, an interrupt is requested. The Slave may continue to place new data to be sent into SPDR before reading the incoming data. The last incoming byte will be kept in the Buffer Register for later use.

Figure 18-2. SPI Master-slave interconnection.



The system is single buffered in the transmit direction and double buffered in the receive direction. This means that bytes to be transmitted cannot be written to the SPI Data Register before the entire shift cycle is completed. When receiving data, however, a received character must be read from the SPI Data Register before the next character has been completely shifted in. Otherwise, the first byte is lost.

In SPI Slave mode, the control logic will sample the incoming signal of the SCK pin. To ensure correct sampling of the clock signal, the frequency of the SPI clock should never exceed $f_{osc}/4$.

When the SPI is enabled, the data direction of the MOSI, MISO, SCK, and $\overline{SS}$ pins is overridden according to Table 18-1 on page 100. For more details on automatic port overrides, refer to "Alternate port functions" on page 72.

Table 18-1. SPI pin overrides [1].

Pin	Direction, Master SPI	Direction, Slave SPI
MOSI	User Defined	Input
MISO	Input	User Defined
SCK	User Defined	Input
$\overline{SS}$	User Defined	Input

Note: 1. See "Alternate functions of Port B" on page 75 for a detailed description of how to define the direction of the user defined SPI pins.

The following code examples show how to initialize the SPI as a Master and how to perform a simple transmission. DDR_SPI in the examples must be replaced by the actual Data Direction Register controlling the SPI pins. DD_MOSI, DD_MISO and DD_SCK must be replaced by the actual data direction bits for these pins, for example, if MOSI is placed on pin PB5, replace DD_MOSI with DDB5 and DDR_SPI with DDRB.

Assembly code example [1]

```
SPI_MasterInit:
  ; Set MOSI and SCK output, all others input
  ldi  r17,(1<<DD_MOSI)|(1<<DD_SCK)
  out  DDR_SPI,r17
  ; Enable SPI, Master, set clock rate fck/16
  ldi  r17,(1<<SPE)|(1<<MSTR)|(1<<SPR0)
  out  SPCR,r17
  ret

SPI_MasterTransmit:
  ; Start transmission of data (r16)
  out  SPDR,r16
  Wait_Transmit:
  ; Wait for transmission complete
  in r16,SPSR
  sbrs r16,SPIF
  rjmp Wait_Transmit
  ret
```

C code example [1]

```
void SPI_MasterInit(void)
{
  /* Set MOSI and SCK output, all others input */
  DDR_SPI = (1<<DD_MOSI)|(1<<DD_SCK);
  /* Enable SPI, Master, set clock rate fck/16 */
  SPCR = (1<<SPE)|(1<<MSTR)|(1<<SPR0);
}

void SPI_MasterTransmit(char cData)
{
  /* Start transmission */
  SPDR = cData;
  /* Wait for transmission complete */
  while(!(SPSR & (1<<SPIF)))
    ;
}
```

Note: 1. See ”About code examples” on page 8.

The following code examples show how to initialize the SPI as a Slave and how to perform a simple reception.

Assembly code example [1]

```
SPI_SlaveInit:
; Set MISO output, all others input
ldi  r17,(1<<DD_MISO)
out  DDR_SPI,r17
; Enable SPI
ldi  r17,(1<<SPE)
out  SPCR,r17
ret

SPI_SlaveReceive:
; Wait for reception complete
in r16,SPSR
sbrs r16,SPIF
rjmp SPI_SlaveReceive
; Read received data and return
in   r16,SPDR
ret
```

C code example [1]

```
void SPI_SlaveInit(void)
{
  /* Set MISO output, all others input */
  DDR_SPI = (1<<DD_MISO);
  /* Enable SPI */
  SPCR = (1<<SPE);
}

char SPI_SlaveReceive(void)
{
  /* Wait for reception complete */
  while(!(SPSR & (1<<SPIF)))
    ;
  /* Return Data Register */
  return SPDR;
}
```

Note: 1. See "About code examples" on page 8.

18.3 $\overline{SS}$ pin functionality

18.3.1 Slave mode

When the SPI is configured as a Slave, the Slave Select ($\overline{SS}$) pin is always input. When $\overline{SS}$ is held low, the SPI is activated, and MISO becomes an output if configured so by the user. All other pins are inputs. When $\overline{SS}$ is driven high, all pins are inputs, and the SPI is passive, which means that it will not receive incoming data. Note that the SPI logic will be reset once the $\overline{SS}$ pin is driven high.

The $\overline{SS}$ pin is useful for packet/byte synchronization to keep the slave bit counter synchronous with the master clock generator. When the $\overline{SS}$ pin is driven high, the SPI slave will immediately reset the send and receive logic, and drop any partially received data in the Shift Register.

18.3.2 Master mode

When the SPI is configured as a Master (MSTR in SPCR is set), the user can determine the direction of the $\overline{SS}$ pin.

If $\overline{SS}$ is configured as an output, the pin is a general output pin which does not affect the SPI system. Typically, the pin will be driving the $\overline{SS}$ pin of the SPI Slave.

If $\overline{SS}$ is configured as an input, it must be held high to ensure Master SPI operation. If the $\overline{SS}$ pin is driven low by peripheral circuitry when the SPI is configured as a Master with the $\overline{SS}$ pin defined as an input, the SPI system interprets this as another master selecting the SPI as a slave and starting to send data to it. To avoid bus contention, the SPI system takes the following actions:

1. The MSTR bit in SPCR is cleared and the SPI system becomes a Slave. As a result of the SPI becoming a Slave, the MOSI and SCK pins become inputs.
2. The SPIF Flag in SPSR is set, and if the SPI interrupt is enabled, and the I-bit in SREG is set, the interrupt routine will be executed.

Thus, when interrupt-driven SPI transmission is used in Master mode, and there exists a possibility that $\overline{SS}$ is driven low, the interrupt should always check that the MSTR bit is still set. If the MSTR bit has been cleared by a slave select, it must be set by the user to re-enable SPI Master mode.

18.4 Data modes

There are four combinations of SCK phase and polarity with respect to serial data, which are determined by control bits CPHA and CPOL. The SPI data transfer formats are shown in Figure 18-3 on page 104 and Figure 18-4 on page 104. Data bits are shifted out and latched in on opposite edges of the SCK signal, ensuring sufficient time for data signals to stabilize. This is clearly seen by summarizing Table 18-3 on page 105 and Table 18-4 on page 105, as done in Table 18-2.

Table 18-2. SPI modes.

SPI mode	Conditions	Leading edge	Trailing edge
0	CPOL=0, CPHA=0	Sample (Rising)	Setup (Falling)
1	CPOL=0, CPHA=1	Setup (Rising)	Sample (Falling)
2	CPOL=1, CPHA=0	Sample (Falling)	Setup (Rising)
3	CPOL=1, CPHA=1	Setup (Falling)	Sample (Rising)

Figure 18-3. SPI transfer format with CPHA = 0.

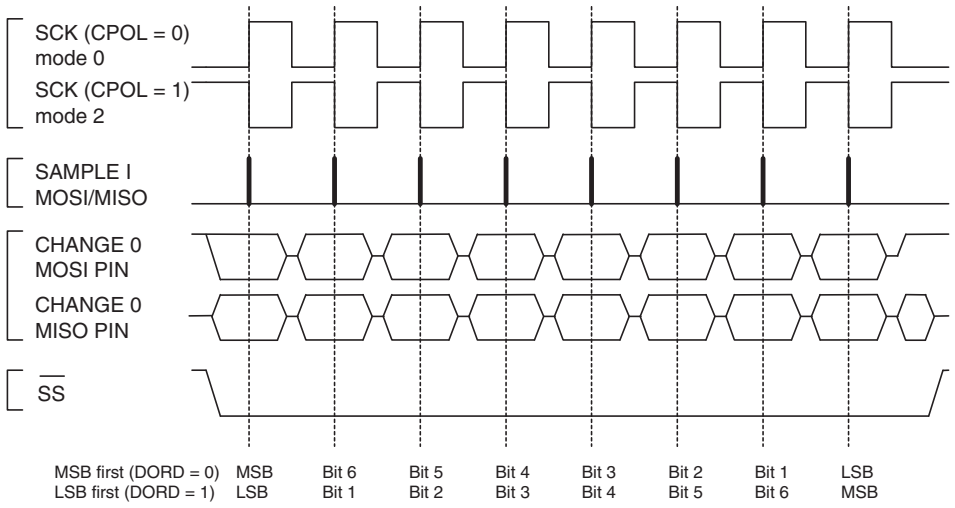
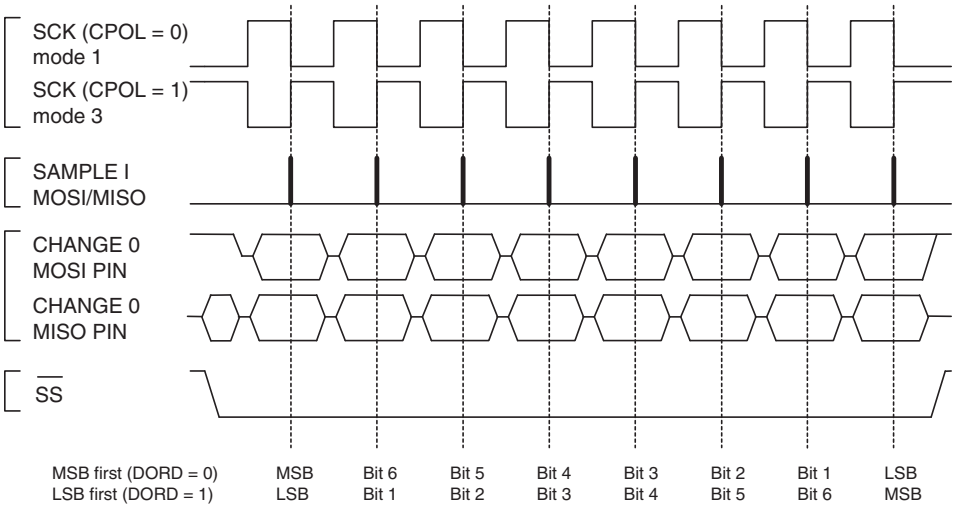


Figure 18-4. SPI transfer format with CPHA = 1.



18.5 Register description

18.5.1 SPCR – SPI Control Register

Bit	7	6	5	4	3	2	1	0	
0x2C (0x4C)	SPIE	SPE	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	SPCR
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7 – SPIE: SPI Interrupt Enable**

This bit causes the SPI interrupt to be executed if SPIF bit in the SPSR Register is set and the if the Global Interrupt Enable bit in SREG is set.

- **Bit 6 – SPE: SPI Enable**

When the SPE bit is written to one, the SPI is enabled. This bit must be set to enable any SPI operations.

- **Bit 5 – DORD: Data Order**

When the DORD bit is written to one, the LSB of the data word is transmitted first.

When the DORD bit is written to zero, the MSB of the data word is transmitted first.

- **Bit 4 – MSTR: Master/Slave Select**

This bit selects Master SPI mode when written to one, and Slave SPI mode when written logic zero. If $\overline{SS}$ is configured as an input and is driven low while MSTR is set, MSTR will be cleared, and SPIF in SPSR will become set. The user will then have to set MSTR to re-enable SPI Master mode.

- **Bit 3 – CPOL: Clock Polarity**

When this bit is written to one, SCK is high when idle. When CPOL is written to zero, SCK is low when idle. Refer to Figure 18-3 on page 104 and Figure 18-4 on page 104 for an example. The CPOL functionality is summarized below:

Table 18-3. CPOL functionality.

CPOL	Leading edge	Trailing edge
0	Rising	Falling
1	Falling	Rising

- **Bit 2 – CPHA: Clock Phase**

The settings of the Clock Phase bit (CPHA) determine if data is sampled on the leading (first) or trailing (last) edge of SCK. Refer to Figure 18-3 on page 104 and Figure 18-4 on page 104 for an example. The CPOL functionality is summarized below:

Table 18-4. CPHA functionality.

CPHA	Leading edge	Trailing edge
0	Sample	Setup
1	Setup	Sample

- **Bits 1, 0 – SPR1, SPR0: SPI Clock Rate Select 1 and 0**

These two bits control the SCK rate of the device configured as a Master. SPR1 and SPR0 have no effect on the Slave. The relationship between SCK and the Oscillator Clock frequency f_{osc} is shown in the following table:

Table 18-5. Relationship between SCK and the oscillator frequency.

SPI2X	SPR1	SPR0	SCK frequency
0	0	0	$f_{osc}/4$
0	0	1	$f_{osc}/16$
0	1	0	$f_{osc}/64$
0	1	1	$f_{osc}/128$
1	0	0	$f_{osc}/2$
1	0	1	$f_{osc}/8$
1	1	0	$f_{osc}/32$
1	1	1	$f_{osc}/64$

18.5.2 SPSR – SPI Status Register

Bit	7	6	5	4	3	2	1	0	
0x2D (0x4D)	SPIF	WCOL	–	–	–	–	–	SPI2X	SPSR
Read/Write	R	R	R	R	R	R	R	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7 – SPIF: SPI Interrupt Flag**

When a serial transfer is complete, the SPIF Flag is set. An interrupt is generated if SPIE in SPCR is set and global interrupts are enabled. If $\overline{SS}$ is an input and is driven low when the SPI is in Master mode, this will also set the SPIF Flag. SPIF is cleared by hardware when executing the corresponding interrupt handling vector. Alternatively, the SPIF bit is cleared by first reading the SPI Status Register with SPIF set, then accessing the SPI Data Register (SPDR).

- **Bit 6 – WCOL: Write Collision Flag**

The WCOL bit is set if the SPI Data Register (SPDR) is written during a data transfer. The WCOL bit (and the SPIF bit) are cleared by first reading the SPI Status Register with WCOL set, and then accessing the SPI Data Register.

- **Bit 5:1 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB and will always read as zero.

- **Bit 0 – SPI2X: Double SPI Speed Bit**

When this bit is written logic one the SPI speed (SCK Frequency) will be doubled when the SPI is in Master mode (see Table 18-5). This means that the minimum SCK period will be two CPU clock periods. When the SPI is configured as Slave, the SPI is only guaranteed to work at $f_{osc}/4$ or lower.

The SPI interface on the ATmega16HVB/32HVB is also used for program memory and EEPROM downloading or uploading. See ”Serial programming” on page 207 for serial programming and verification.

18.5.3 SPDR – SPI Data Register

Bit	7	6	5	4	3	2	1	0	
0x2E (0x4E)	MSB							LSB	SPDR
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	X	X	X	X	X	X	X	X	Undefined

The SPI Data Register is a read/write register used for data transfer between the Register File and the SPI Shift Register. Writing to the register initiates data transmission. Reading the register causes the Shift Register Receive buffer to be read.

19. Coulomb counter – Dedicated fuel gauging Sigma-Delta ADC

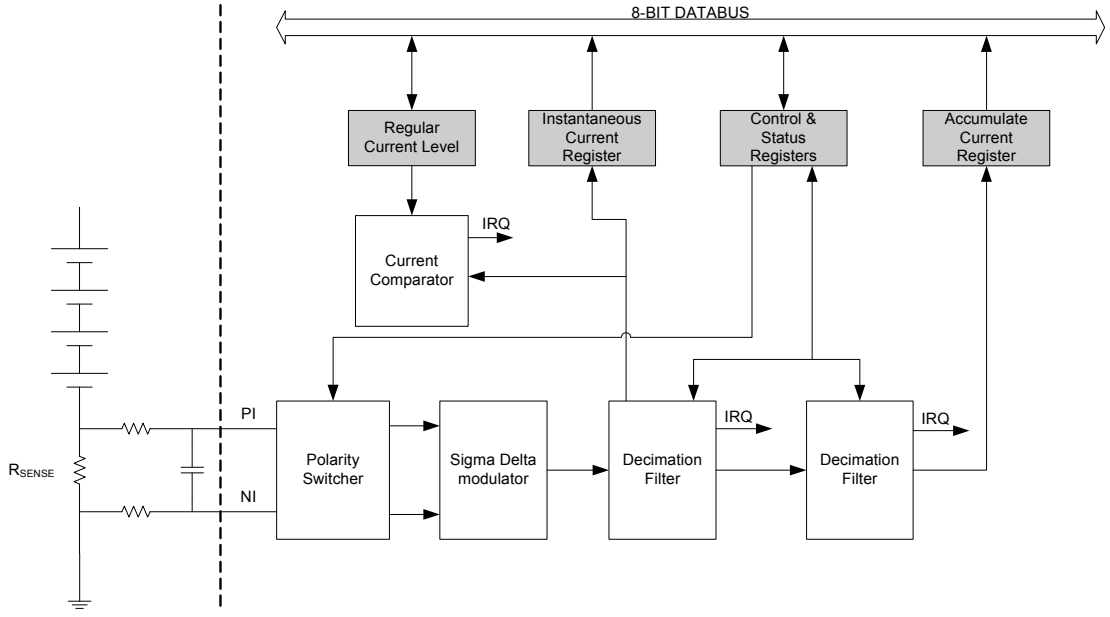
19.1 Features

- **Sampled system Coulomb counter**
- **Low power Sigma-Delta ADC optimized for Coulomb counting**
- **Instantaneous current output with 3.9ms conversion time**
  - **13-bit resolution (including sign bit)**
  - **Interrupt on instantaneous current conversion complete**
- **Accumulate current output**
  - **Programmable conversion time: 128/256/512/1024ms**
  - **18-bit resolution (including sign bit)**
  - **Interrupt on accumulation current conversion complete**
- **Regular current detection mode**
  - **Programmable sampling interval: 256/512/1024/2048ms**
- **Programmable input voltage range ±100/200mV**
  - **Allowing measurement of ±20/40A @ 5mΩ**
- **Offset canceling by input polarity switching**

19.2 Overview

The Atmel ATmega16/32HVB features a dedicated Sigma-Delta ADC (CC-ADC) optimized for Coulomb Counting. By sampling the charge or discharge current flowing through an external sense resistor RSENSE, the CC-ADC is used to track the flow of current going into and out of the battery cells.

Figure 19-1. Coulomb counter block diagram.



The CC-ADC has a programmable voltage range allowing trade-off to be made between resolution, dynamic range and external sense resistor RSENSE.

In normal conversion mode two different output values are provided, Instantaneous Current and Accumulate Current. The Instantaneous Current Output has a short conversion time at the cost

of lower resolution. The Accumulate Current Output provides a highly accurate current measurement for Coulomb Counting.

The CC-ADC also provides a special Regular Current detection mode. This allows ultra-low power operation in Power-save mode when small charge or discharge currents are flowing.

For offset cancellation the polarity of the input signal could be switched run time. Using this feature, the internal CC-ADC offset could be removed. See the Atmel AVR352 application note.

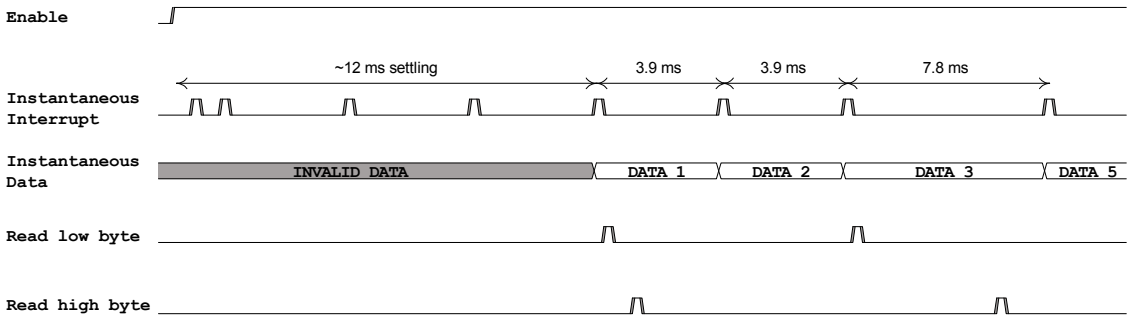
19.3 Normal operation

When enabled the CC-ADC continuously measures the voltage over the external sense resistor R_{SENSE}. Running in normal conversion mode, two data conversion outputs are provided.

- Instantaneous Conversion Result
- Accumulation Conversion Result

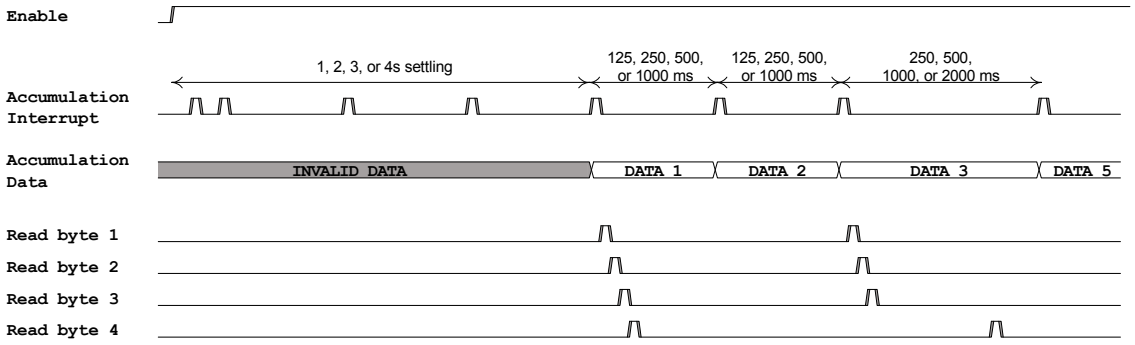
The Instantaneous Current conversion time is fixed to 3.9ms (typical value) allowing the output value to closely follow the input. After each Instantaneous Current conversion an interrupt is generated if the interrupt is enabled. Data from conversion will be updated in the Instantaneous Current registers CADICL and CADICH simultaneously as the interrupt is given. To avoid losing conversion data, both the low and high byte must be read within a 3.9ms timing window after the corresponding interrupt is given. When the low byte register is read, updating of the Instantaneous Current registers and interrupts will be stopped until the high byte is read. Figure 19-2 shows an Instantaneous Current conversion diagram, where DATA4 will be lost because DATA3 reading is not completed within the limited period.

Figure 19-2. Instantaneous current conversions.



The Accumulate Current output is a high-resolution, high accuracy output with programmable conversion time selected by the CADAS bits in CADCSRA. The converted value is an accurate measurement of the average current flow during one conversion period. The CC-ADC generates an interrupt each time a new Accumulate Current conversion has finished if the interrupt is enabled. Data from conversion will be updated in the Accumulation Current registers - CADAC0, CADAC1, CADAC2 and CADAC3 simultaneously as the interrupt is given. To avoid losing conversion data, all bytes must be read within the selected conversion period. When the lower byte registers are read, updating of the Accumulation Current registers and interrupts will be stopped until the highest byte is read. Figure 19-3 on page 110 shows an Accumulation Current conversion example, where DATA4 will be lost because DATA3 reading is not completed within the limited period.

Figure 19-3. Accumulation current conversions.



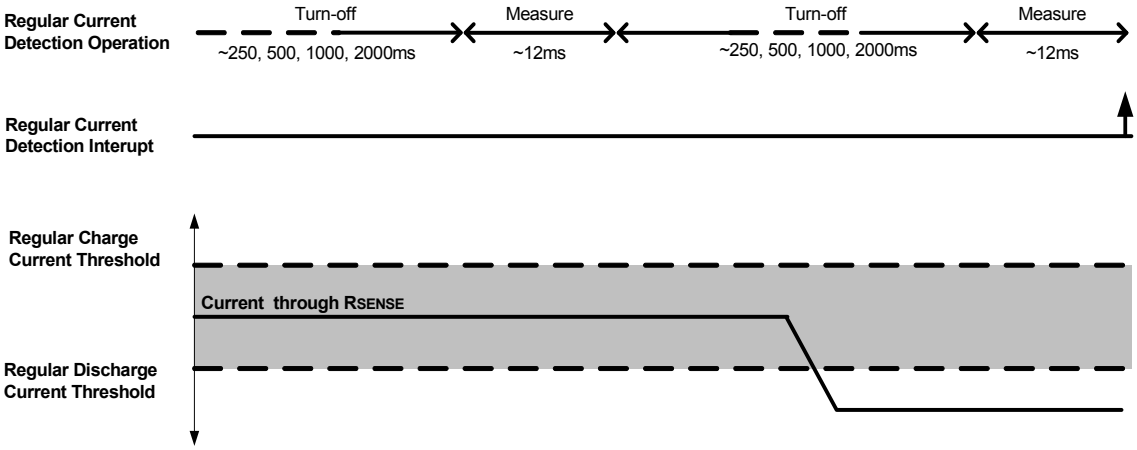
19.4 Regular current detection operation

By setting the CADSE bit in CADCSRA the CC-ADC will enter a special Regular Current Detection Sampling Mode.

In this mode the CC-ADC will do one Instantaneous Current Conversion on regular sampling intervals while updating of the Accumulation Current Register is automatically disabled. The sampling interval is controlled by writing to the CADSI bits in CADCSRA.

Each time a conversion is completed the result is compared with Regular Charge/Discharge Threshold levels specified in the CADRCC/CADRDC registers. If interrupt is enabled and the voltage is above/below the specified limit a Regular Current Detection Interrupt will be issued. Figure 19-4 illustrates the Regular Current Detection Mode.

Figure 19-4. Regular current detection mode (CADSE=1).



19.5 Offset canceling by polarity switching

The CC-ADC offers Polarity Switching for internal offset canceling. By switching the polarity of the sampled input signal at selected time intervals, the internal voltage offset of the CC-ADC will cancel at the output. This feature prevents the CC-ADC from accumulating an offset error over time.

19.6 Configuration and usage

While the CC-ADC is converting, the CPU can enter sleep mode and wait for an interrupt. After adding the conversion data for the Coulomb Counting, the CPU can go back to sleep again. This reduces the CPU workload, and allows more time spent in low power modes, reducing power consumption.

To use the CC-ADC the bandgap voltage reference must be enabled separately, see ”Voltage reference and temperature sensor” on page 122.

The CC-ADC will not consume power when CADEN is cleared. It is therefore recommended to switch off the CC-ADC whenever the Coulomb Counter or Regular Current Detection functions are not used. The CC-ADC is automatically disabled in Power-off mode.

After the CC-ADC is enabled by setting the CADEN bit, the first four conversions do not contain useful data and should be ignored. This also applies after clearing the CADSE bit, or after changing the CADPOL or CADVSE bits.

The conversion times and sampling intervals are controlled by the Ultra Low Power RC Oscillator (see ”Ultra Low Power RC oscillator” on page 27), and will depend on its actual frequency. To obtain accurate coulomb counting results, the actual conversion time should be calculated. Refer to ”System clock and clock options” on page 25 for details.

19.7 Register description

19.7.1 CADCSRA – CC-ADC Control and Status Register A

Bit	7	6	5	4	3	2	1	0	
(0xE6)	CADEN	CADPOL	CADUB	CADAS1	CADAS0	CADSI1	CADSI0	CADSE	CADCSRA
Read/Write	R/W	R/W	R	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7 – CADEN: CC-ADC Enable**

When the CADEN bit is cleared (zero), the CC-ADC is disabled, and any ongoing conversions will be terminated. When the CADEN bit is set (one), the CC-ADC will continuously measure the voltage drop over the external sense resistor R_{SENSE}. In Power-off, the CC-ADC is always disabled.

Note that the bandgap voltage reference must be enabled separately, see ”Voltage reference and temperature sensor” on page 122.

- **Bit 6 – CADPOL: CC-ADC Polarity**

The CADPOL bit is used to change input sampling polarity in the Sigma Delta Modulator. Writing this bit to one, the polaritiy will be negative. When the bit is zero, the polarity will be positive.

- **Bit 5 – CADUB: CC-ADC Update Busy**

The CC-ADC operates in a different clock domain than the CPU. Whenever a new value is written to CADCSRA, CADCSRC, CADRCC or CADRDC, this value must be synchronized to the CC-ADC clock domain. Subsequent writes to these registers will be blocked during this synchronization. Synchronization of one of the registers will block updating of all the others. The CADUB bit will be read as one while any of these registers is being synchronized, and will be read as zero when neither register is being synchronized.

- **Bits 4:3 – CADAS1:0: CC-ADC Accumulate Current Select**

The CADAS bits select the conversion time for the Accumulate Current output as shown in the Table 19-1.

Table 19-1. CC-ADC Accumulate Current Conversion Time.

CADAS1:0	CC-ADC Accumulate Current Conversion Time (1)	Number of CC-ADC clock cycles
00	128ms	4096
01	256ms	8192
10	512ms	16384
11	1s	32768

Note: 1. The actual value depends on the actual frequency of the "Ultra Low Power RC oscillator" on page 27. See "Electrical characteristics" on page 225.

- **Bits 2:1 – CADSI1:0: CC-ADC Current Sampling Interval**

The CADSI bits determine the current sampling interval for the Regular Current detection as shown in the Table 19-2.

Table 19-2. CC-ADC Regular Current Sampling Interval.

CADSI1:0	CC-ADC Regular Current Sampling Interval (1)(2)	Number of CC-ADC clock cycles
00	256ms (+ sampling time)	8192 (+ sampling time)
01	512ms (+ sampling time)	16384 (+ sampling time)
10	1s (+ sampling time)	32768 (+ sampling time)
11	2s (+ sampling time)	65536 (+ sampling time)

Notes: 1. The actual value depends on the actual frequency of the "Ultra Low Power RC oscillator" on page 27. See "Electrical characteristics" on page 225.
2. Sampling time ~12ms.

- **Bit 0 – CADSE: CC-ADC Sampling Enable**

When the CADSE bit is written to one, the ongoing CC-ADC conversion is aborted and the CC-ADC enters Regular Current detection mode.

19.7.2 CADCSRB – CC-ADC Control and Status Register B

Bit	7	6	5	4	3	2	1	0	
(0xE7)	–	CADACIE	CADRCIE	CADICIE	–	CADACIF	CADRCIF	CADICIF	CADCSRB
Read/Write	R	R/W	R	R/W	R	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7, 3 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB and will always read as zero.

- **Bit 6 – CADACIE: CC-ADC Accumulate Current Interrupt Enable**

When the CADACIE bit is set (one), and the I-bit in the Status Register is set (one), the CC-ADC Accumulate Current Interrupt is enabled.

- **Bit 5 – CADRCIE: CC-ADC Regular Current Interrupt Enable**

When the CADRCIE bit is set (one), and the I-bit in the Status Register is set (one), the CC-ADC Regular Current Interrupt is enabled.

- **Bit 4 – CADICIE: CC-ADC Instantaneous Current Interrupt Enable**

When the CADICIE bit is set (one), and the I-bit in the Status Register is set (one), the CC-ADC Instantaneous Current Interrupt is enabled.

- **Bit 2 – CADACIF: CC-ADC Accumulate Current Interrupt Flag**

The CADACIF bit is set (one) after the Accumulate Current conversion has completed. The CC-ADC Accumulate Current Interrupt is executed if the CADACIE bit and the I-bit in SREG are set (one). CADACIF is cleared by hardware when executing the corresponding Interrupt Handling Vector. Alternatively, CADACIF is cleared by writing a logic one to the flag.

- **Bit 1 – CADRCIF: CC-ADC Regular Current Interrupt Flag**

The CADRCIF bit is set (one) when the absolute value of the result of the last CC-ADC conversion is greater than, or equal to, the compare values set by the CC-ADC Regular Charge/Discharge Current Level Registers. A positive value is compared to the Regular Charge Current Level, and a negative value is compared to the Regular Discharge Current Level. The CC-ADC Regular Current Interrupt is executed if the CADRCIE bit and the I-bit in SREG are set (one). CADRCIF is cleared by hardware when executing the corresponding Interrupt Handling Vector. Alternatively, CADRCIF is cleared by writing a logic one to the flag.

- **Bit 0 – CADICIF: CC-ADC Instantaneous Current Interrupt Flag**

The CADICIF bit is set (one) when a CC-ADC Instantaneous Current conversion is completed. The CC-ADC Instantaneous Current Interrupt is executed if the CADICIE bit and the I-bit in SREG are set (one). CADICIF is cleared by hardware when executing the corresponding Interrupt Handling vector. Alternatively, CADICIF is cleared by writing a logic one to the flag.

19.7.3 CADCSRC – CC-ADC Control and Status Register C

Bit	7	6	5	4	3	2	1	0	
(0xE8)	–	–	–	–	–	–	–	CADVSE	CADCSRC
Read/Write	R	R	R	R	R	R	R	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7:1 – Reserved**

These bits are reserved and will always read as zero.

- **Bit 0 – CADVSE: CC-ADC Voltage Scaling Enable**

Setting this bit enables the internal Voltage Scaling. When enabling the internal Voltage Scaling the internal CC-ADC reference will be divided by 2, affecting the Input Voltage Range and the resulting step-size. Table 19-3 on page 113 shows the Input Voltage Range and the conversion value step-size for the CADVSE settings

Table 19-3. Input voltage range and the conversion value step-size for the CADVSE settings.

CADVSE	Voltage range	Step-size CADAC	Step-size CADIC
0	±200mV	1.67µV	53.7µV
1	±100mV	0.84µV	26.9µV

19.7.4 CADICH and CADICL – CC-ADC instantaneous current

Bit	15	14	13	12	11	10	9	8	
(0xE5)	CADIC[15:8]								CADICH
(0xE4)	CADIC[7:0]								CADICL
Bit	7	6	5	4	3	2	1	0	
Read/Write	R	R	R	R	R	R	R	R	
	R	R	R	R	R	R	R	R	
Initial Value	0	0	0	0	0	0	0	0	
	0	0	0	0	0	0	0	0	

When a CC-ADC Instantaneous Current conversion is complete, the result is found in these two registers. CADIC15:0 represents the converted result in 2's complement format. Bits 12:0 are the 13-bit ADC result (including sign), while bit 15:13 are the sign extension bits.

When CADICL is read, the CC-ADC Instantaneous Current register is not updated until CADCH is read. Reading the registers in the sequence CADICL, CADICH will ensure that consistent values are read. When a conversion is completed, both registers must be read before the next conversion is completed, otherwise data will be lost.

19.7.5 CADAC3, CADAC2, CADAC1 and CADAC0 – CC-ADC accumulate current

Bit	31	30	29	28	27	26	25	24	
	23	22	21	20	19	18	17	16	
	15	14	13	12	11	10	9	8	
	7	6	5	4	3	2	1	0	
(0xE3)	CADAC[31:24]								CADAC3
(0xE2)	CADAC[23:16]								CADAC2
(0xE1)	CADAC[15:8]								CADAC1
(0xE0)	CADAC[7:0]								CADAC0
Read/Write	R	R	R	R	R	R	R	R	
	R	R	R	R	R	R	R	R	
	R	R	R	R	R	R	R	R	
Initial Value	0	0	0	0	0	0	0	0	
	0	0	0	0	0	0	0	0	
	0	0	0	0	0	0	0	0	

The CADAC3, CADAC2, CADAC1 and CADAC0 Registers contain the Accumulate Current measurements in 2’s complement format. Bits 17:0 are the 18-bit ADC result (including sign), while bit 31:18 are the sign extension bits.

When CADAC0 is read, the CC-ADC Accumulate Current register is not updated until CADAC3 is read. Reading the registers in the sequence CADAC0, CADAC1, CADAC2, CADAC3 will ensure that consistent values are read. When a conversion is completed, all four registers must be read before the next conversion is completed, otherwise data will be lost.

19.7.6 CADRCC – CC-ADC regular charge current

Bit	7	6	5	4	3	2	1	0	
(0xE9)	CADRCC[7:0]								CADRCC
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

The CC-ADC Regular Charge Current Register determines the threshold level for the Regular Charge Current detection. When the result of a CC-ADC Instantaneous Current conversion is positive with a value greater than, or equal to, the Regular Charge Current level, the CC-ADC Regular Current Interrupt Flag is set.

The value in this register defines the eight least significant bits of the Regular Charge Current level in 2's complement format, where the most significant bits of the Regular Charge Current level are always zero. The programmable range for the Regular Charge Current level is given in the Table 19-4.

Table 19-4. Programmable range for the regular charge current level [(1)].

		Minimum	Maximum	Step Size
Voltage (µV)		0	13696/6848	53.7/26.9
Current (mA)	R_{SENSE} = 1mΩ	0	13696/6848	53.7/26.9
	R_{SENSE} = 5mΩ	0	2740/1370	10.7/5.4
	R_{SENSE} = 10mΩ	0	1370/685	5.3/2.7

Note: 1. Values in the table are shown with the CADVSE set to both 0 and 1.

The CC-ADC Regular Charge Current Register does not affect the setting of the CC-ADC Conversion Complete Interrupt Flag.

19.7.7 CADRDC – CC-ADC regular discharge current

Bit	7	6	5	4	3	2	1	0	
(0xEA)	CADRDC[7:0]								CADRDC
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

The CC-ADC Regular Discharge Current Register determines the threshold level for the Regular Discharge Current detection. When the result of a CC-ADC Instantaneous Current conversion is negative with an absolute value greater than, or equal to, the Regular Discharge Current level, the CC-ADC Regular Current Interrupt Flag is set.

The value in this register defines the eight least significant bits of the Regular Discharge Current level in 2's complement format, where the most significant bits of the Regular Discharge Current level are always one. The programmable range for the Regular Discharge Current level is given in the Table 19-5 on page 115.

Table 19-5. Programmable range for the regular discharge current level.

		Minimum	Maximum	Step size
Voltage (µV)		0	13696/6848	53.7/26.9
Current (mA)	R_{SENSE} = 1mΩ	0	13696/6848	53.7/26.9
	R_{SENSE} = 5mΩ	0	2740/1370	10.7/5.4
	R_{SENSE} = 10mΩ	0	1370/685	5.3/2.7

Note: Values in the table are shown with the CADVSE set to both 0 and 1.

The CC-ADC Regular Discharge Current Register does not affect the setting of the CC-ADC Conversion Complete Interrupt Flag.

20. Voltage ADC – 7-channel general purpose 12-bit Sigma-Delta ADC

20.1 Features

- **12-bit resolution**
- **519µs conversion time @ 1MHz clk_{VADC}**
- **Four differential input channels for cell voltage measurements**
- **Three single ended input channels**
- **0.2× pre-scaling of cell voltages**
- **Interrupt on V-ADC conversion complete**

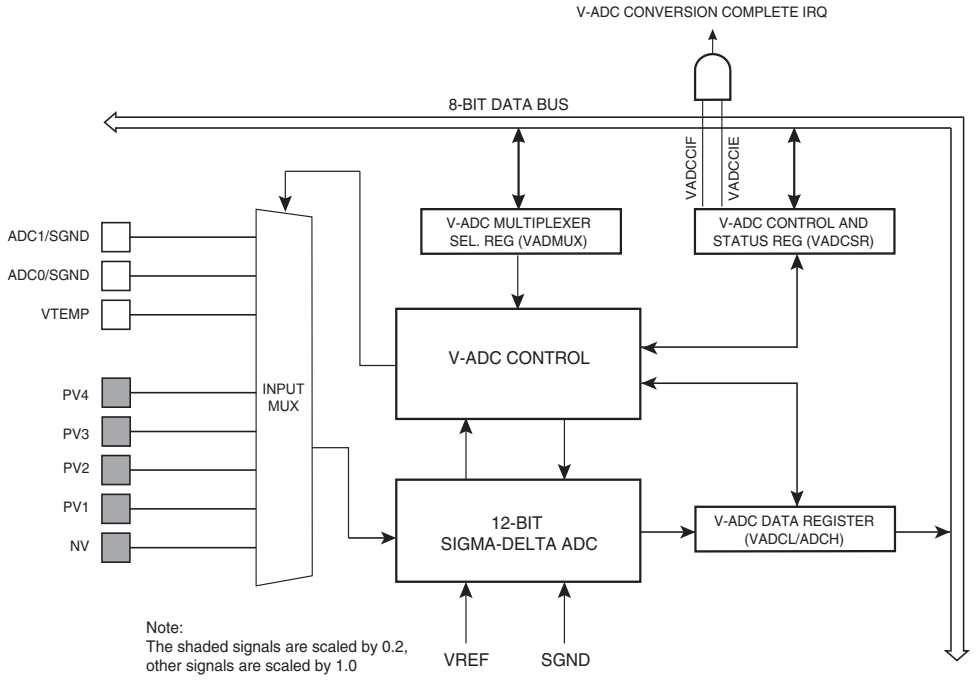
20.2 Overview

The Atmel ATmega16HVB/32HVB features a 12-bit Sigma-Delta ADC.

The Voltage ADC (V-ADC) is connected to seven different sources through the Input Multiplexer. There are four differential channels for Cell Voltage measurements. These channels are scaled 0.2× to comply with the Full Scale range of the V-ADC. In addition there are three single ended channels referenced to SGND. One channel is for measuring the internal temperature sensor VPTAT and two channels for measuring the voltage at ADC0 and ADC1.

When the V-ADC is not used, power consumption can be minimized by writing the PRVADC bit in PRR0 to one. See "PRR0 – Power Reduction Register 0" on page 40 for details on how to use the PRVADC bit.

Figure 20-1. Voltage ADC block schematic.

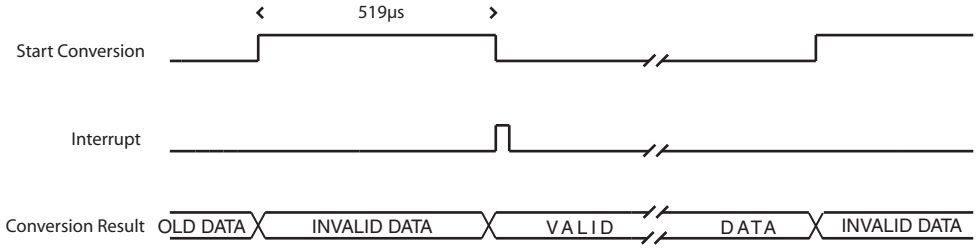


20.3 Operation

To enable V-ADC conversions, the V-ADC Enable bit, VADEN, in V-ADC Control and Status Register – VADCSR must be set. If this bit is cleared, the V-ADC will be switched off, and any ongoing conversions will be terminated. The V-ADC is automatically disabled in Power-save and

Power-off mode. Note that the bandgap voltage reference must be enabled and disabled separately, see ”Bandgap calibration” on page 123.

Figure 20-2. Voltage ADC conversion diagram.



To perform a V-ADC conversion, the analog input channel must first be selected by writing to the VADMUX register. When a logical one is written to the V-ADC Start Conversion bit VADSC, a conversion of the selected channel will start. The VADSC bit stays high as long as the conversion is in progress and will be cleared by hardware when the conversion is completed. When a conversion is in progress, the V-ADC Data Register - VADCL and VADCH will be invalid. If the System Clock Prescaler setting is changed during a V-ADC conversion, the conversion will be aborted. If a different data channel is selected while a conversion is in progress, the ADC will finish the current conversion before performing the channel change. When a conversion is finished the V-ADC Conversion Complete Interrupt Flag – VADCCIF is set. One 12-bit conversion takes 519µs to complete from the start bit is set to the interrupt flag is set. The V-ADC Data Register - VADCL and VADCH will be valid until a new conversion is started. To ensure that correct data is read, both high and low byte data registers should be read before starting a new conversion.

20.3.1 Configuring PA1 and PA0 for V-ADC operation

When one of the single ended channels ADC0 or ADC1 is used as analog input to the VADC, either PA0 or PA1 are used as signal ground (SGND). When ADC0/1 is selected as input channel, PA1/0 is automatically switched to SGND.

The use of PA1 and PA0 as SGND is efficient for the thermistor configuration shown in ”Operating circuit” on page 220. Both thermistors, RT32 and RT33 are connected through a common divider resistor, R31, to PA0 and PA1 respectively.

Both PA0 and PA1 have very high input impedance when used as ADC inputs, which makes it possible to connect two thermistors in the configuration, shown in ”Operating circuit” on page 220. However, input impedance is limited and if high accuracy is required, only one thermistor should be connected between PA0 and PA1. If two thermistors are connected, the configuration is as follows:

- When measuring RT33, PA1 should be used as input channel and PA0 is automatically switched to SGND
- When measuring RT32, PA0 should be used as input channel and PA1 is automatically switched to SGND

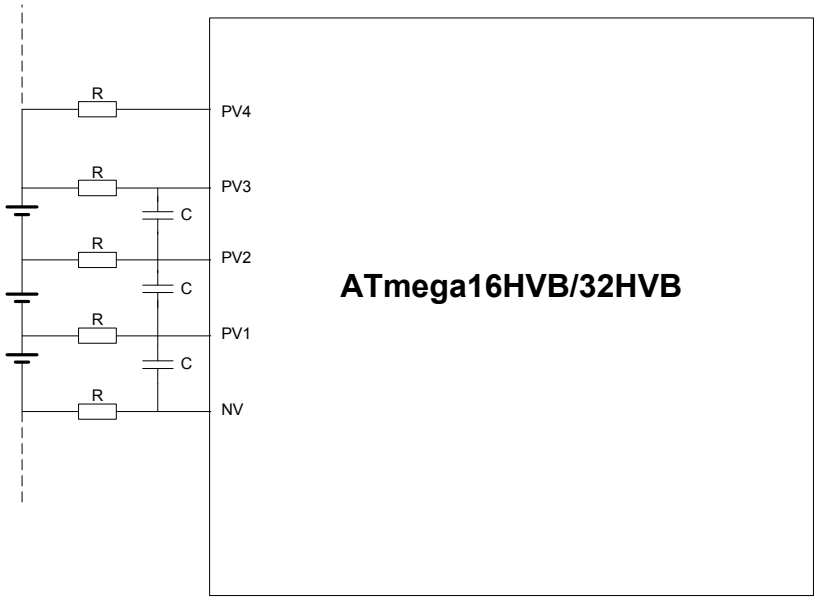
20.3.2 Cell inputs

The V-ADC features one input channel for each battery cell to be able to measure each cell individually and to measure the total battery voltage through the input pins NV, PV1, PV2, PV3 and PV4. Note that the internal Cell Balancing uses the same pins to bypass balancing current (see ”Cell balancing” on page 151) for details for balancing the battery cells. When balancing a cell the V-ADC should not do conversion on the selected channel, as the internal Cell balancing will affect the conversion result.

The V-ADC is designed to operate on PV1 pin voltages above 2V. If the battery cell voltage on PV1 input falls below 2V the upper cell voltage appears to be lower than the its actual value. To avoid that cells get potentially overcharged software should keep the cells in balance using the internal Cell Balancing. See ”Cell balancing” on page 151 for details.

When not using all the cell inputs, the unused cells should be connected to the cell below. An example external coupling in 3-cell mode is shown in Figure 20-3. Note that even if the input is not used, it is recommended to connect the input through an external resistance to limit inverse coupling current. This is to be able to protect the battery if cells are reversed coupled during production.

Figure 20-3. A 3-cell mode connection.



20.4 Register description

20.4.1 VADMUX – V-ADC Multiplexer Selection Register

Bit	7	6	5	4	3	2	1	0	
(0x7C)	–	–	–	–	VADMUX3	VADMUX2	VADMUX1	VADMUX0	VADMUX
Read/Write	R	R	R	R	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7:4 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB and will always read as zero.

- **Bit 3:0 – VADMUX[3:0]: V-ADC Channel Selection Bits**

The VADMUX bits determine the V-ADC channel selection. See Table 20-1.

Table 20-1. VADMUX channel selection.

VADMUX[3:0]	Channel selected	Scale
0000	RESERVED	–
0001	CELL1	0.2
0010	CELL2	0.2
0011	CELL3	0.2
0100	CELL4	0.2
0101	VTEMP	1.0
0110	ADC0	1.0
0111	ADC1	1.0
1000...1111	RESERVED	–

20.4.2 VADCSR – V-ADC Control and Status Register

Bit	7	6	5	4	3	2	1	0	
(0x7A)	–	–	–	–	VADEN	VADSC	VADCCIF	VADCCIE	VADCSR
Read/Write	R	R	R	R	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7:4 – Reserved**

These bits are reserved in the ATmega16HVB/32HVB and will always read as zero.

- **Bit 3 – VADEN: V-ADC Enable**

Writing this bit to one enables V-ADC conversion. By writing it to zero, the V-ADC is turned off. Turning the V-ADC off while a conversion is in progress will terminate this conversion. Note that the bandgap voltage reference must be enabled separately, see ”Bandgap calibration” on page 123.

- **Bit 2 – VADSC: Voltage ADC Start Conversion**

Write this bit to one to start a new conversion of the selected channel.

VADSC will read as one as long as the conversion is not finished. When the conversion is complete, it returns to zero. Writing zero to this bit has no effect. VADSC will automatically be cleared when the VADEN bit is written to zero.

- **Bit 1 – VADCCIF: V-ADC Conversion Complete Interrupt Flag**

This bit is set when a V-ADC conversion completes and the data registers are updated. The V-ADC Conversion Complete Interrupt is executed if the VADCCIE bit and the I-bit in SREG are set. VADCCIF is cleared by hardware when executing the corresponding interrupt handling vector. Alternatively, VADCCIF is cleared by writing a logical one to the flag. Beware that if doing a Read-Modify-Write on VADCSR, a pending interrupt can be lost.

- **Bit 0 – VADCCIE: V-ADC Conversion Complete Interrupt Enable**

When this bit is written to one and the I-bit in SREG is set, the V-ADC Conversion Complete Interrupt is activated.

20.4.3 VADCL and VADCH – V-ADC Data Register

Bit	15	14	13	12	11	10	9	8	
(0x79)	–	–	–	–	VADC[11:8]				VADCH
(0x78)	VADC[7:0]								VADCL
	7	6	5	4	3	2	1	0	
Read/Write	R	R	R	R	R	R	R	R	
	R	R	R	R	R	R	R	R	
Initial Value	0	0	0	0	0	0	0	0	
	0	0	0	0	0	0	0	0	

When a V-ADC conversion is complete, the result is found in these two registers. To ensure that correct data is read, both high and low byte data registers should be read before starting a new conversion.

- **VADC11:0: V-ADC Conversion Result**

These bits represent the result from the conversion.

To obtain the best absolute accuracy for the cell voltage measurements, gain and offset compensation is required. Factory calibration values are stored in the device signature row, refer to section "Reading the signature row from software" on page 195 for details. The cell voltage in mV is given by:

$$Cell_n[\text{mV}] = \frac{(\text{VADCH/L} - \text{VADC Cell}_n\text{Offset}) \cdot \text{VADC Cell}_n\text{ Gain Calibration Word}}{16384}$$

The voltage on the ADCn is given by:

$$\text{ADCn[mV]} = \frac{1}{10} \cdot \frac{(\text{VADCH/L} - \text{VADC ADCn Offset}) \cdot \text{VADC ADCn Gain Calibration Word}}{16384}$$

When performing a Vtemp conversion, the result must be adjusted by the factory calibration value stored in the signature row, refer to section ”Reading the signature row from software” on page 195 for details. The absolute temperature in Kelvin is given by:

$$T(K) = \frac{VADCH/L \cdot VPTAT\ CAL}{16384}$$

20.4.4 DIDR0 – Digital Input Disable Register 0

Bit	7	6	5	4	3	2	1	0	
(0x7E)	–	–	–	–	–	–	PA1DID	PA0DID	DIDR0
Read/Write	R	R	R	R	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:2 – Reserved**

These bits are reserved for future use. To ensure compatibility with future devices, these bits must be written to zero when DIDR0 is written.

- **Bit 1:0 – PA1DID:PA0DID: Digital Input Disable**

When this bit is written logic one, the digital input buffer on the corresponding Port A pin is disabled. The corresponding PIN Register bit will always read as zero when this bit is set. When an analog signal is applied to the PA1:0 pin and the digital input from this pin is not needed, this bit should be written logic one to reduce power consumption in the digital input buffer.

21. Voltage reference and temperature sensor

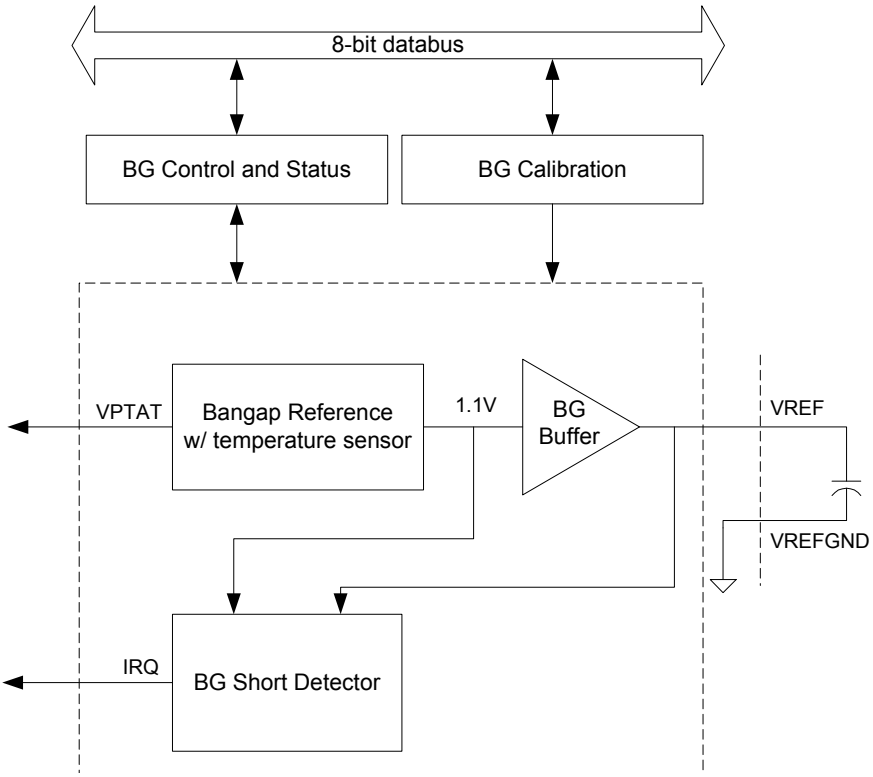
21.1 Features

- **Accurate voltage reference of 1.100V**
- **Voltage reference calibration interface**
- **Internal temperature sensor**
- **External decoupling for optimum noise performance**
- **Short circuit detection on the external decoupling pin**
- **Low power consumption**

21.2 Overview

The Atmel ATmega16HVB/32HVB features a highly accurate low power On-chip Bandgap Reference Voltage, VREF of 1.100V. This reference voltage is used as reference for the On-chip Voltage Regulator, the Brown-out Detector, the internal Cell Balancing, the Battery Protection, the V-ADC and the CC-ADC. Figure 21-1 shows an overview of the On-chip voltage reference.

Figure 21-1. Bandgap reference voltage.



In addition to the Bandgap Reference Voltage, the Voltage Reference includes a Calibration Unit that enables run time calibration of the Reference Voltage, an On-chip temperature sensor for monitoring the die temperature, and a Bandgap Short Detector to detect short circuit conditions on the external VREF pin for highest safety.

21.3 Operation

When the device is in power-off state, the Voltage Reference will be switched off. After a Power-on reset condition the Voltage Reference will automatically be enabled.

By default the Bandgap Buffer will be enabled as the buffered reference voltage is used as reference for the Battery Protection, the internal Cell Balancing, the V-ADC and the CC-ADC. If any of these modules are enabled the Bandgap Buffer must be enabled, otherwise it is recommended to disable the buffer by writing to the BGD bit in BGCSR to save power. Note that the Bandgap Buffer needs settling time before the voltage is stable. For details on settling time, see “Bandgap buffer settling time” .

To ensure that the battery protection has safe operation condition, the Voltage Reference includes a Short-circuit Detector. The Bandgap Short Detector continuously monitors the internal 1.100V reference voltage against the VREF pin voltage to detect potentially external short conditions to VCC or GND. If an external short condition is detected, the Bandgap Short Circuit Detection is capable of interrupting and waking up the CPU from any sleep mode. If a Bandgap Short-circuit condition occurs software should immediately disable the C-FET and D-FET. If no external protection is provided to detect such a condition it is recommended to always enable this feature, by setting the BGSCDE bit in the Bandgap Control and Status Register.

The Temperature Sensor generates a voltage Proportional-To-Absolute-Temperature, VPTAT. This voltage is connected to the multiplexer at the V-ADC input and it can be used for runtime compensation of temperature drift in both the voltage reference and the On-chip Oscillator. To get the absolute temperature in degrees Kelvin, the measured VPTAT voltage must be scaled with the VPTAT factory calibration value stored in the signature row. See ”Reading the signature row from software” on page 195 for details. See ”Electrical characteristics” on page 225 for details on temperature accuracy.

21.4 Bandgap calibration

To guarantee ultra low temperature drift the Voltage Reference includes two calibration registers that should be initialized by software after reset. See ”Register description” on page 124 for details. Changing values to the BGCCR IO register will change the nominal value of the Bandgap Reference Voltage, while changing values to the BGCRR IO register trims the temperature gradient of the bandgap reference.

When the calibration registers are changed it will affect both the Voltage Regulator output and BOD-level. The BOD will react quickly to new detection levels, while the regulator will adjust the voltage more slowly, depending on the size of the external decoupling capacitor. To avoid that a BOD-reset is issued when calibration is done, it is recommended to change the values of the BGCC and BGCR bits stepwise, with a step size of one, and with a hold-off time between each step. See ”Electrical characteristics” on page 225 for details on hold-off time.

Changing VREF will influence the conversion results for the V-ADC and CC-ADC. It is therefore not recommended to do V-ADC and CC-ADC conversions while calibrating the bandgap.

21.5 Bandgap buffer settling time

After the Voltage Reference have been enabled it needs a settling time before the voltage is stable. The settling time depends on the size of the external decoupling capacitor. With 1µF external capacitor a minimum settling time of 2ms should be used. Until settling is done it is not recommended to enable the NFET driver (OC/OD or enter DUVR operation), Battery Protection, V-ADC or CC-ADC.

Settling time is needed when the Buffer is enabled by software, or after a reset condition.

21.6 Register description

21.6.1 BGCCR – Bandgap Calibration C Register

Bit	7	6	5	4	3	2	1	0	
(0xD0)	–	–	BGCC5	BGCC4	BGCC3	BGCC2	BGCC1	BGCC0	BGCCR
Read/Write	R	R	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:6 – Reserved**

These bits are reserved and will always read as zero.

- **Bit 5:0 – BGCC[5:0]: BG Calibration of PTAT Current**

These bits are used for trimming of the nominal value of the bandgap reference voltage. These bits are binary coded. Minimum VREF: 000000, maximum VREF: 111111. Step size is approximately 2mV. The application software should read the Atmel factory calibration value and store it to the BGCCR register. See ”Reading the signature row from software” on page 195 for details.

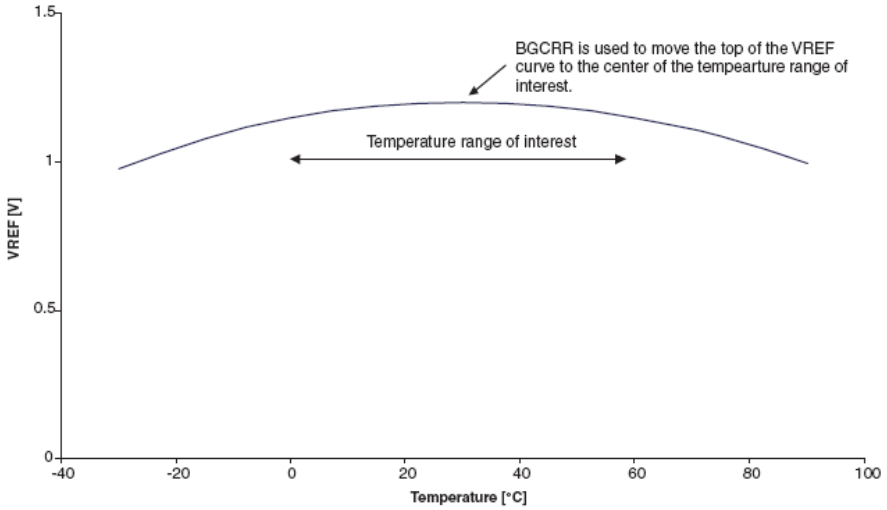
21.6.2 BGCRR – Bandgap Calibration R Register

Bit	7	6	5	4	3	2	1	0	
(0xD1)	BGCR7	BGCR6	BGCR5	BGCR4	BGCR3	BGCR2	BGCR1	BGCR0	BGCRR
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	1	1	1	1	

- **Bit 7:0 – BGCR[7:0]: BG Calibration of Resistor ladder**

These bits are used for temperature gradient adjustment of the bandgap reference. Figure 21-2 on page 125 illustrates VREF as a function of temperature. VREF has a positive temperature coefficient at low temperatures and negative temperature coefficient at high temperatures. Depending on the process variations, the top of the VREF curve may be located at higher or lower temperatures. To minimize the temperature drift in the temperature range of interest, BGCRR is used to adjust the top of the curve towards the centre of the temperature range of interest. The BGCRR bits are thermometer coded, resulting in 9 possible settings: 00000000, 00000001, 00000011, 00000111, … , 11111111. The value 00000000 shifts the top of the VREF curve to the highest possible temperature, and the value 11111111 shifts the top of the VREF curve to the lowest possible temperature. The application software should read the Atmel factory calibration value and store it to the BGCRR register. See ”Reading the signature row from software” on page 195 for details.

Figure 21-2. Illustration of VREF as a function of temperature.



21.6.3 BGCSR – Bandgap control and Status Register

Bit	7	6	5	4	3	2	1	0	
(0xD2)	–	–	BGD	BGSCDE	–	–	BGSCDIF	BGSCDIE	BGCSR
Read/Write	R	R	R/W	R/W	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:6 – Reserved**

These bits are reserved and will always read as zero.

- **Bit 5 – BGD: Bandgap Disable**

Setting this bit to one will disable the bandgap voltage reference. This bit must be cleared (zero) before enabling Cell Balancing, CC-ADC, V-ADC or Battery Protection, and must remain unset (zero) while either of these modules are enabled. Note that after clearing this bit, a settling time is required before the voltage is stable, see ”Bandgap buffer settling time” on page 123.

- **Bit 4 – BGSCDE: Bandgap Short Circuit Detection Enabled**

Setting this bit to one will enable the bandgap Short Circuit Detector. This bit should be cleared if the BGD bit in the BGCSR is set to one to avoid false setting of the BGSCDIF bit.

- **Bits 3:2 – Reserved**

These bits are reserved and will always read as zero.

- **Bit 1 – BGSCDIF: Bandgap Short Circuit Detection Interrupt Flag**

The bit is set when the Bandgap Short Circuit Detector is enabled and buffered bandgap reference is different from the unbuffered Bandgap reference. The BGSCDIF is cleared by hardware when executing the corresponding interrupt handling vector. Alternatively, BGSCDIF is cleared by writing a logic one to its bit position.

- **Bit 0 – BGSCDIE: Bandgap Short Circuit Detection Interrupt Enable**

When this bit is set, the Bandgap Short Circuit Detection Interrupt is enabled. The corresponding interrupt is executed if a short-circuit is detected on the External Decoupling Pin for the Voltage Reference.

22. Charger detect

22.1 Features

- **Operates directly from VFET supply**
- **Detects when a charger is connected or disconnected by monitoring the BATT pin**
- **Controls the operation state of the device by automatically enable/disable the internal voltage regulator**
- **Automatically disabled when discharge FET is ON**
- **Interrupt wake-up from all sleep modes**

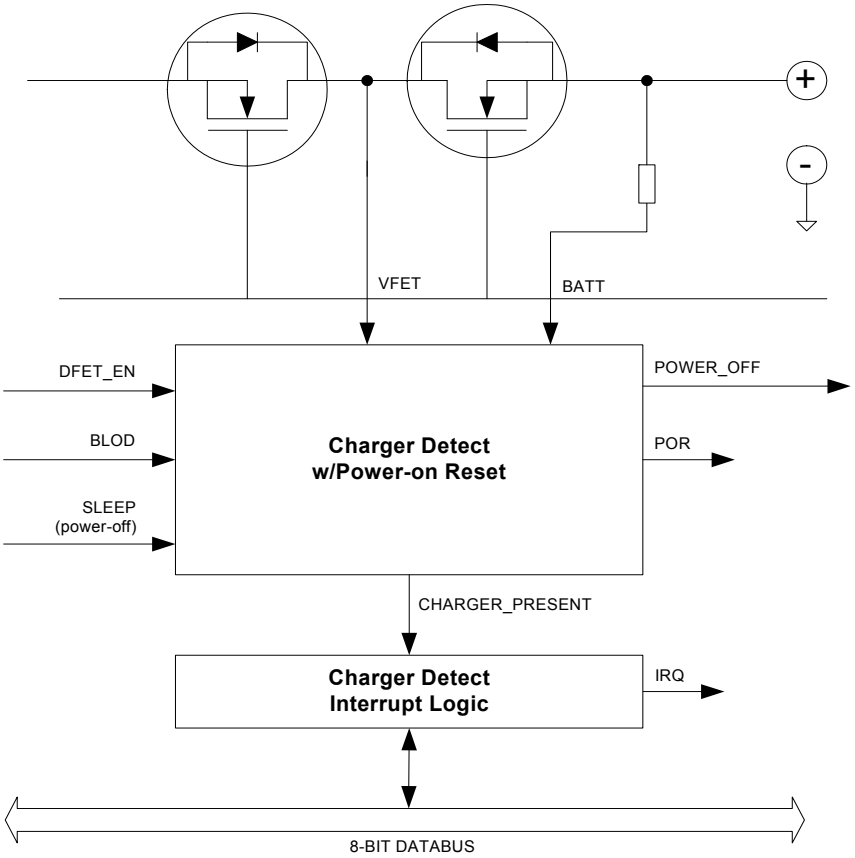
22.2 Overview

The Charger Detect module has two main functions:

- Control the device operating state (power-off or normal operation)
- Detect when a charger is connected/disconnected

Figure 22-1 shows a block diagram of the Charger Detect module.

Figure 22-1. Charger Detect block diagram.



22.3 Operation

The Charger Detect module is supplied directly from the VFET pin. When operating, the Charger Detect will monitor the voltage of the BATT pin and detect whether a charger is present or not. When the voltage on the BATT pin is above the Charger Detect Threshold level V_{POT} (see "Electrical characteristics" on page 225) the CHARGER_PRESENT signal will be high. This signal is edge detected to generate interrupt when a charger is connected or disconnected.

The Charger Detect module will operate as long as the Discharge FET is disabled and is able to detect a charger in all sleep modes including Power-off.

22.3.1 Device operating state

The Charger Detect module controls the operating state of the Atmel ATmega16HVB/32HVB by enabling/disabling the Voltage Regulator, which supplies the rest of the internal logic on the chip.

If the chip is in Power-off state the Charger Detect will keep the Voltage Regulator disabled allowing only the Charger Detect module itself to operate. To be able to start from a Power-off state a charge voltage above V_{POT} has to be applied at the BATT pin. When a charger is connected the Charger Detect module will automatically start the Voltage Regulator. When the VREG voltage rises, a Power-on Reset (POR) is given and the chip enters normal operating mode after a reset delay corresponding to T_{TOUT}. For details on POR, see "Power-on reset and charger connect" on page 43.

When the ATmega16HVB/32HVB is running in normal operation mode software or hardware could take the chip into Power-off state. For details on entering power-off by software, see "Power-off mode" on page 38. To protect the device against software malfunctions the ATmega16HVB/32HVB has a Black-out Detector (BLOD). When a Black-out condition occurs the Charger Detect will take the chip automatically into Power-off. For details on Black-out Detection, see "Voltage regulator" on page 129.

Note that after a software power-off the BATT pin voltage has to fall below the Charger Detect threshold limit, VPOT, before the chip is able to re-enable the Voltage Regulator and start-up the device.

22.3.2 Interrupt logic

When the ATmega16HVB/32HVB is running in normal operation mode, the Charger Detect is capable of giving an interrupt to the CPU if a charger is connected/disconnected or both. Interrupt is enabled/disabled by writing to the CHGDIE bit in the "CHGDCSR – Charger Detect Control and Status Register" on page 128.

Interrupt is given when a charger is connected, disconnected or both depending on interrupt sense control settings. Selecting the correct interrupt sensing is done by writing to the CHGDISC bits in the "CHGDCSR – Charger Detect Control and Status Register" on page 128.

Charger Detect interrupt works asynchronous and will wake the CPU from any sleep mode.

The Charger Detect is automatically disabled/enabled when changing the state of the Discharge FET, and any interrupt that occurs when enabling or disabling the Discharge FET has to be carefully interpreted.

- When enabling the Discharge-FET the Charger Detect module is automatically disabled. When disabling the charger detect module a charger appear to be disconnected even if a charger is present

- When disabling the Charge-FET the Charger Detect module is automatically enabled and a charger appear to be connected

22.4 Register description

22.4.1 CHGDCSR – Charger Detect Control and Status Register

Bit	7	6	5	4	3	2	1	0	
(0xD4)	–	–	–	BATTPVL	CHGDISC1	CHGDISC0	CHGDIF	CHGDIE	CHGDCSR
Read/Write	R	R	R	R	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7:5 – Reserved**

These bits are reserved and will always read as zero.

- **Bit 4 – BATTPVL: BATT pin Voltage Level**

BATTPVL will read one as long when the Charger Detect module is enabled and the BATT pin voltage is above the VPOT level. Otherwise the BATTPVL will read zero.

- **Bit 3:2 – CHGDISC[1:0]: Charger Detect Interrupt Sense Control**

Edges in the CHARGER_PRESENT signal shown in Figure 22-1 on page 126 are used to activate a Charger Detect Interrupt if the SREG I-flag and the interrupt enable bit in CHGDCSR are set. By writing the CHGDISC bits to the values shown in Table 22-1 the condition generating interrupt is configured. When changing the CHGDISC bits, an interrupt can occur. Therefore, it is recommended to first disable the Interrupt by clearing its CHGDIE bit in the CHGDICSR Register. Finally, the Charger Detect interrupt flag should be cleared by writing a logical one to CHGDIF bit before the interrupt is re-enabled.

Table 22-1. Charger Detect Interrupt Sense Control.

CHGISC[1:0]	Detection
00	Charger Connect
01	Charger Disconnect
10	Charger Connect/Disconnect
11	None

- **Bit 1 – CHGDIF: Charger Detect Interrupt Flag**

Depending on the configuration of the CHGDISC bits in the CHGDCSR, this bit is set when a charger is either connected or disconnected. The Charger Detect Interrupt is executed if the CHGDIE bit and the I-bit in SREG are set. This bit is cleared by hardware when executing the corresponding interrupt handling vector or alternatively by writing a logical one to the CHGDIF. It is recommended to write this bit to one when setting CHGDIE.

- **Bit 0 – CHGDIE: Charger Detect Interrupt Enable**

When the CHGDIE bit is set (one), and the I-bit in the Status Register is set (one), the Charger Detect Interrupt is enabled.

23. Voltage regulator

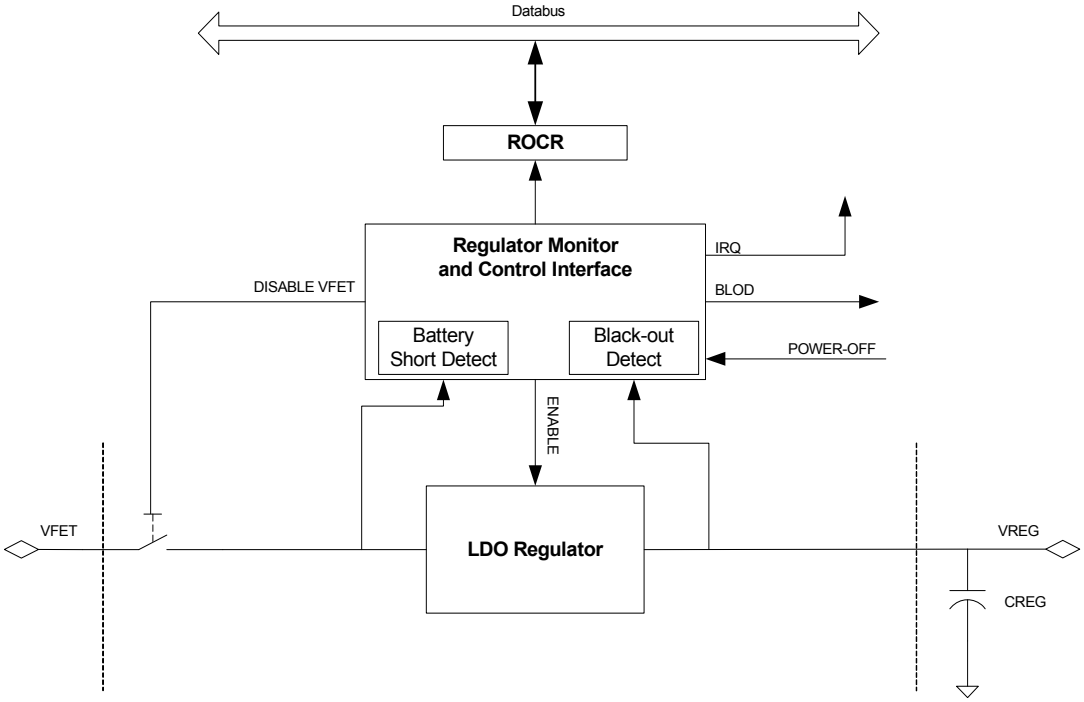
23.1 Features

- **Input voltage from 4V - 18V**
- **Fixed output voltage of 3.3V**
- **Battery pack short detection**
- **Black-out detection (BLOD)**

23.2 Overview

The Atmel ATmega16HVB/32HVB get its voltage supply through the VFET terminal. Operating range at the VFET terminal is 4V - 18V. The on-chip LDO regulator regulates the VFET terminal down to 3.3V, which is a suitable supply voltage for the internal logic, I/O lines and analog circuitry. Figure 23-1 illustrates the Voltage Regulator.

Figure 23-1. Voltage regulator.



To ensure safe operating condition the Voltage Regulator has built in protection mechanisms to protect the internal circuitry if the voltage drops on either the input or output terminal. The Regulator Monitoring includes.

- Battery Pack Short Detector
- Black-out Detector

An external decoupling capacitor (CREG) of minimum 1µF is needed to ensure stable regulator operation. The same capacitor also serves as a reservoir capacitor to ensure that the chip is able to operate for some time without voltage at the VFET terminal.

23.3 Regulator start-up

When the chip is in power-off mode the Voltage Regulator will be off and there will be no connection between VFET and VREG.

The regulator is started when the Charger Detect module detects that a charger is connected (for details on Charger Detect, see ”Charger detect” on page 126). When starting the regulator the Voltage Regulator will stay in a force mode where the VREG output is raised against the VFET input voltage. As VREG increases to the target voltage level the regulator will automatically enter regulation mode, with a stable output voltage of nominally 3.3V. Figure 11-2 on page 44, in System Control and Reset illustrates the start-up sequence from power-off.

23.4 Battery pack short detection

The Voltage Regulator will continuously monitor the operating condition at the VFET terminal. If the voltage at VFET drops below the Regulator Short-circuit Level (RSCL), see ”Electrical characteristics” on page 225, the Voltage Regulator enters the Battery Pack Short mode. In this mode, VFET is disconnected from VREG to avoid a quick drop in the voltage regulator output. When the voltage regulator enters this mode, the chip will be completely powered by the external reservoir capacitor (CREG). This allows the chip to operate a certain time without entering BOD reset, even if the VFET voltage is too low for the voltage regulator to operate.

An interrupt is issued when the regulator enters Battery Pack Short mode, if the ROCWIE bit in ROCR Register is set. This allows actions to be taken to reduce power consumption and hence prolonging the time that CREG can be used to power the chip.

In a typical short-circuit situation, VFET will drop as a consequence of high current consumption, and recover as soon as the Battery Protection module has disabled the FETs. Hence CREG should be dimensioned so that the chip can sustain operation without entering BOD reset, until the FETs are disabled either by HW or SW.

To minimize power consumption when the Voltage Regulator enters the Battery Pack Short mode, the chip should enter Power-save sleep mode as soon as possible after the ROCWIF interrupt is detected. The Watchdog Timer should be configured to wake up the CPU after a time that is considered safe, see application note AVR132 for use of enhanced Watchdog Timer. Software should then check the status of the ROC flag. If the ROCS flag is cleared, normal operation may be resumed.

23.5 Black-out detection

To ensure that the internal logic has safe operating condition, the Voltage Regulator has built-in Black-Out Detector (BLOD). If the voltage at the VREG pin drops below the Black-out Detection Level, V_{BLOT}, the chip will automatically enter Power-off mode.

23.6 Register description

23.6.1 ROCR – Regulator Operating Condition Register

Bit	7	6	5	4	3	2	1	0	
(0xC8)	ROCS	–	–	ROCD	–	–	ROCWIF	ROCWIE	ROCR
Read/Write	R	R	R	R/W	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7 – ROCS: ROC Status**

This bit is set when the Voltage Regulator operates in the Battery Pack Short mode, and cleared otherwise.

- **Bit 6:5 – Reserved**

These bits are reserved and will always read as zero.

- **Bit 4 – ROCD: ROC Disable**

Setting this bit will disable the Battery Pack Short Detector and VFET will never be disconnected from the LDO Regulator.

Note that it is NOT recommended to disable the Battery Pack Short Detector by setting the ROCD bit unless VFET protection is implemented externally.

- **Bit 3:2 – Reserved**

These bits are reserved and will always read as zero.

- **Bit 1 – ROCWIF: ROC Warning Interrupt Flag**

The ROCWIF Flag is set when the Voltage Regulator enters the Battery Pack Short mode. The flag is cleared by writing logic one to it or by hardware, by executing the corresponding interrupt handling vector.

- **Bit 0 – ROCWIE: ROC Warning Interrupt Enable**

The ROCWIE bit enables interrupt caused by the Regulator Operating Condition Warning interrupt flag.

24. Battery protection

24.1 Features

- **Short-circuit protection**
- **Discharge over-current protection**
- **Charge over-current protection**
- **Discharge high-current protection**
- **Charge high-current protection**
- **External protection input**
- **Programmable and lockable detection levels and reaction times**
- **Autonomous operation independent of CPU**

24.2 Overview

The Current Battery Protection circuitry (CBP) monitors the charge and discharge current and disables C-FET and D-FET if a Short-circuit, Over-current or High-current condition is detected. There are five different programmable detection levels: Short-circuit Detection Level, Discharge Over-current Detection Level, Charge Over-current Detection Level, Discharge High-current Detection Level, Charge High-current Detection Level. There are three different programmable delays for activating Current Battery Protection: Short-circuit Reaction Time, Over-current Reaction Time and High-current Reaction Time. After Current Battery Protection has been activated, the application software must re-enable the FETs. The Battery Protection hardware provides a hold-off time of one second before software can re-enable the FETs. This provides safety in case the application software should unintentionally try to re-enable the FETs too early.

The activation of a protection also issues an interrupt to the CPU. The battery protection interrupts can be individually enabled and disabled by the CPU.

In addition, the module offers an External Protection Input. The activation of the External Protection Input operates independently of the rest of the battery protection mechanisms. The activation/deactivation of this protection is instantaneously controlled from the External Protection Input port, and will not deactivate or affect the other battery protection mechanisms.

The effect of the various battery protection types are given in Table 24-1.

Table 24-1. Effect of battery protection types.

Battery protection type	Interrupt requests	PC-FET	C-FET	D-FET	Cell balancing FETs	MCU
Short-circuit Protection	Entry	Operational	Disabled	Disabled	Operational	Operational
Discharge Over-current Protection	Entry	Operational	Disabled	Disabled	Operational	Operational
Charge Over-current Protection	Entry	Operational	Disabled	Disabled	Operational	Operational
Discharge High-current Protection	Entry	Operational	Disabled	Disabled	Operational	Operational
Charge High-current Protection	Entry	Operational	Disabled	Disabled	Operational	Operational
External Protection Input	Entry and/or Exit	Operational	Disabled	Disabled	Operational	Operational

24.3 Operation

The Current Battery Protections (CBP) monitors the cell current by sampling the shunt resistor voltage at the PPI/NNI input pins. A differential operational amplifier amplifies the voltage with a suitable gain. The output from the operational amplifier is compared to an accurate, programmable On-chip voltage reference by an Analog Comparator. If the shunt resistor voltage is above the Detection level for a time longer than the corresponding Protection Reaction Time, the chip activates Current Protection. A sampled system clocked by the internal ULP Oscillator is used for Short-circuit, Over-current, and High-current Protection. This ensures a reliable clock source, offset cancellation and low power consumption.

24.3.1 Short-circuit protection

The Short-circuit detection is provided to enable a fast response time to very large discharge currents. If the voltage at the PPI/NNI pins is above the Short-circuit Detection Level for a period longer than Short-circuit Reaction Time, the Short-circuit Protection is activated.

When the Short-circuit Protection is activated, the external D-FET and C-FET are disabled and a Current Protection Timer is started. This timer ensures that the D-FET and C-FET are disabled for at least one second. The application software must then set the DFE and CFE bits in the FET Control and Status Register to re-enable normal operation. If the D-FET is re-enabled before the cause of the short-circuit condition is removed, the Short-circuit Protection will be activated again.

24.3.2 Discharge over-current protection

If the voltage at the PPI/NNI pins is above the Discharge Over-current Detection level for a time longer than Over-current Protection Reaction Time, the chip activates Discharge Over-current Protection.

When the Discharge Over-current Protection is activated, the external D-FET and C-FET are disabled and a Current Protection Timer is started. This timer ensures that the FETs are disabled for at least one second. The application software must then set the DFE and CFE bits in the FET Control and Status Register to re-enable normal operation. If the D-FET is re-enabled while the loading of the battery still is too large, the Discharge Over-current Protection will be activated again.

24.3.3 Charge over-current protection

If the voltage at the PPI/NNI pins is above the Charge Over-current Detection level for a time longer than Over-current Protection Reaction Time, the chip activates Charge Over-current Protection.

When the Charge Over-current Protection is activated, the external D-FET and C-FET are disabled and a Current Protection Timer is started. This timer ensures that the FETs are disabled for at least one second. The application software must then set the DFE and CFE bits in the FET Control and Status Register to re-enable normal operation. If the C-FET is re-enabled and the charger continues to supply too high currents, the Charge Over-current Protection will be activated again.

24.3.4 Discharge high-current protection

If the voltage at the PPI/NNI pins is above the Discharge High-current Detection level for a time longer than High-current Protection Reaction Time, the chip activates Discharge High-current Protection.

When the Discharge High-current Protection is activated, the external D-FET and C-FET are disabled and a Current Protection Timer is started. This timer ensures that the FETs are disabled for at least one second. The application software must then set the DFE and CFE bits in the FET Control and Status Register to re-enable normal operation. If the D-FET is re-enabled while the loading of the battery still is too large, the Discharge High-current Protection will be activated again.

24.3.5 Charge high-current protection

If the voltage at the PPI/NNI pins is above the Charge High-current Detection level for a time longer than High-current Protection Reaction Time, the chip activates Charge High-current Protection.

When the Charge High-current Protection is activated, the external D-FET and C-FET are disabled and a Current Protection Timer is started. This timer ensures that the FETs are disabled for at least one second. The application software must then set the DFE and CFE bits in the FET Control and Status Register to re-enable normal operation. If the C-FET is re-enabled and the charger continues to supply too high currents, the Charge High-current Protection will be activated again.

The Short-circuit, Over-current and High-current Protection parameters are programmable to adapt to different types of batteries. The parameters are set by writing to I/O Registers. The Parameter Registers can be locked after the initial configuration, prohibiting any further updates until the next Hardware Reset.

Refer to ”Register description” on page 137 for register descriptions of battery protection.

24.4 External protection input

The External Protection Input uses the alternate port function of the General Purpose High Voltage I/O to automatically disabling the external Charge and Discharge-FET. For details, see ”High voltage I/O ports” on page 62.

Using this together with the External Interrupt (see ”External interrupt characteristics” on page 230) features a highly flexible solution for the customer and it allows the user to customize an external protection scheme suitable for battery applications.

The External Protection Input disables both the C-FET and D-FET immediately when the voltage on EXTPROT pin is pulled high (logic ‘1’). It is also used to disable DUVR mode if DUVR mode is enabled. Note that, unlike a Battery Protection event, the External Protection input does not affect the status of the FCSR (CFE, DFE, DUVRD, and CPS) bits. When the ‘high’ condition disappears, the FET disabling is released immediately. DUVR mode is automatically re-entered if previously enabled.

The feature is automatically enabled when the chip starts up, and can be disabled before locking the BPCR register. When locking the BPCR register, the External Protection feature is also locked.

When External Protection Input is enabled, an override enable signal is set to EXTPROT pin configuring the pin as digital input. The port may be set up to give an interrupt when the pin value changes, and the protection status can be read from the port register.

Note that the External Protection Input is default enabled. This means that after reset (and during reset) the port is default overridden to digital input, independent of the port register setting.

The user must disable the External Protection Input in the BPCR register before the port can be used as a normal port.

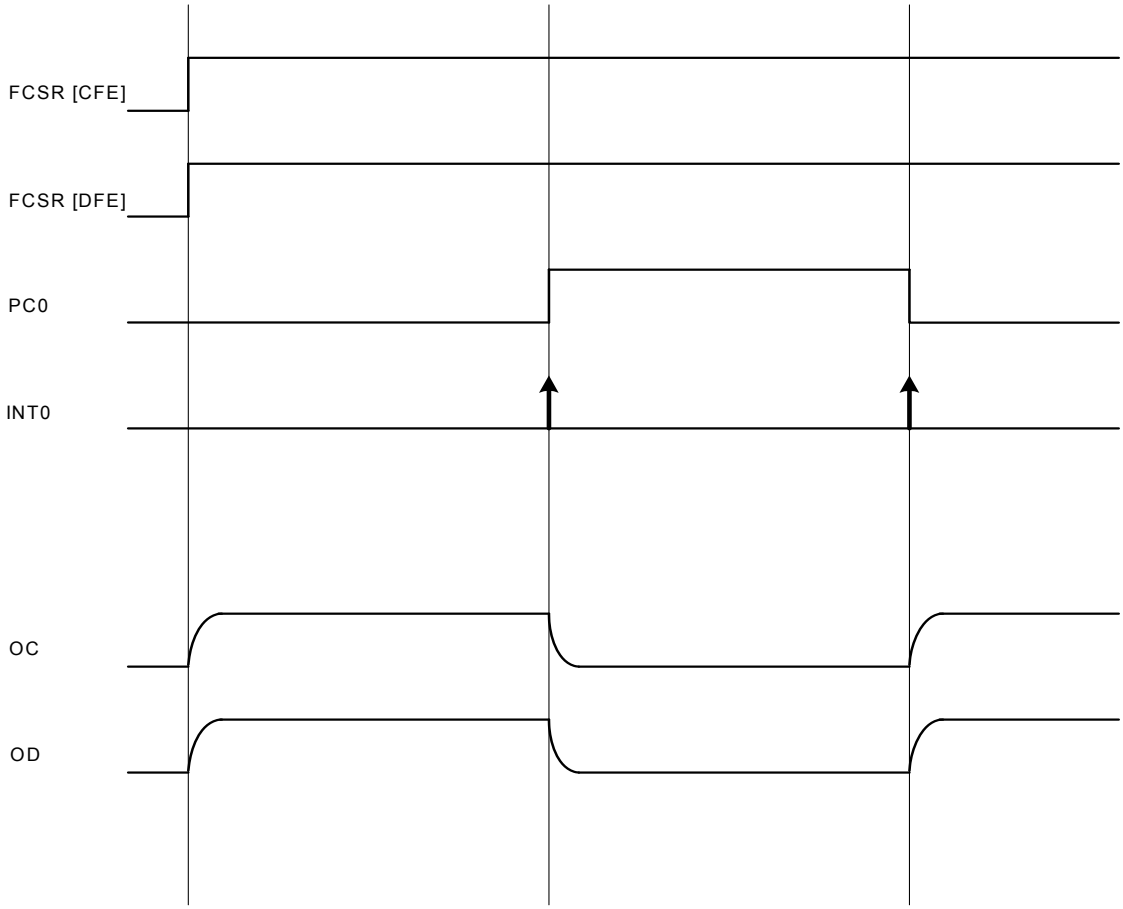
Also during the reset sequence, the External Protection Input may disable the FETs. Consequently, if the External Protection feature is not used and DUVR mode is enabled in reset, the External Protection input must be held low until disabled by SW.

It is recommended that the external interrupt on the External Protection Input port is configured to ‘any edge’ to generate an interrupt to the microcontroller when using this feature, indicating that the FET protection status has changed. By reading the pin register, the External Protection status can be determined. If the pin register is set, it means that External Protection is trigged and the FET control signals in FCSR (CFE, DFE and DUVRD) are overridden and the FETs are disabled. In the opposite case, External Protection violation is not present.

To ensure a safe exit from the External Protection Input condition, the FETs and DUVR mode should be disabled by SW when an External Protection condition is detected. This enables software to completely control when the FETs are switched ON again.

Short pulses on the EXTPROT pin, for instance caused by temporary high voltages on the BATT pin when connecting a charger, may trigger the External Protection Input (refer to ”Operating circuit” on page 220). However if the SW does not take any action, the C-FET and D-FET will be re-enabled automatically once the External Protection condition disappears.

Figure 24-1. External protection input example.



24.5 Optimizing usage for low power consumption

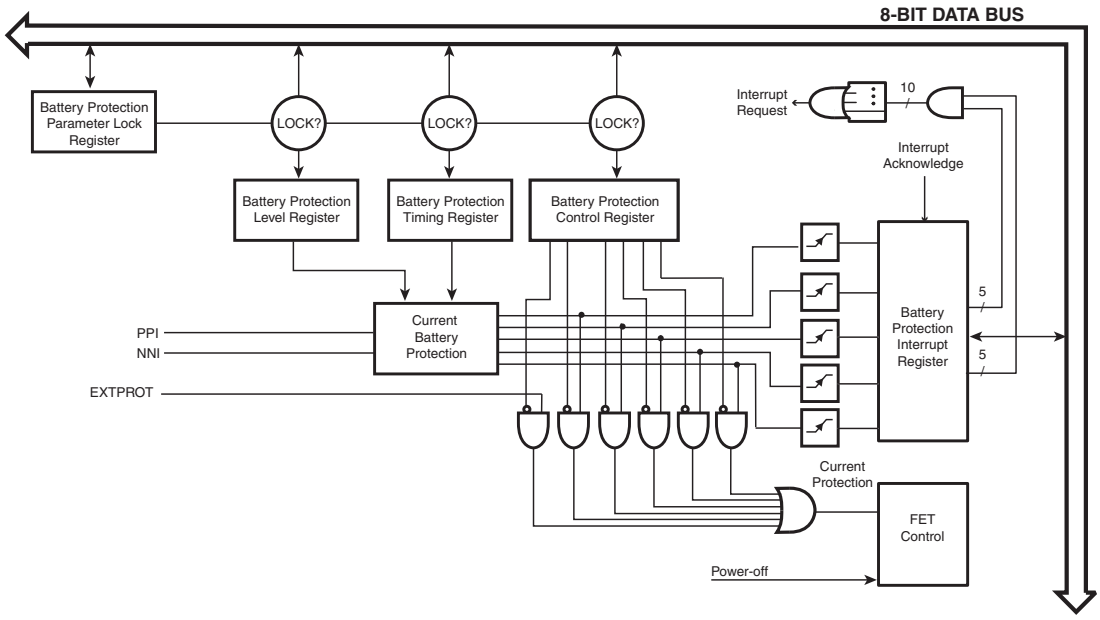
In order to reduce power consumption, Short-circuit, Discharge High-current and Discharge Over-current Protection are automatically deactivated when the D-FET is disabled. The Charge Over-current and Charge High-current Protection are disabled when the C-FET is disabled. Note however that Charge Over-current Protection and Charge High-current Protection are never automatically disabled when the chip is operated in DUVR mode.

Also note that none of the current protections are deactivated by the External Protection Input. To save power during an External Protection event, DFE and CFE in the FCSR register should be cleared and make sure that the chip is not operating in DUVR mode.

24.6 Battery protection CPU interface

The Battery Protection CPU Interface is illustrated in Figure 24-2.

Figure 24-2. Battery protection CPU interface.



Each protection originating from the Current Battery Protection module has an Interrupt Flag. Each Flag can be read and cleared by the CPU, and each flag has an individual interrupt enable. All enabled flags are combined into a single battery protection interrupt request to the CPU. This interrupt can wake up the CPU from any operation mode, except Power-off. The interrupt flags are cleared by writing a logic ‘1’ to their bit locations from the CPU. An interrupt event for the External Protection Input can be generated by enabling the external interrupt for the input port.

24.7 Register description

24.7.1 BPPLR – Battery Protection Parameter Lock Register

Bit	7	6	5	4	3	2	1	0	
(0xFE)	–	–	–	–	–	–	**BPPLE**	**BPPL**	**BPPLR**
Read/Write	R	R	R	R	R	R	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7:2 – Reserved**

These bits are reserved and will always read as zero.

- **Bit 1 – BPPLE: Battery Protection Parameter Lock Enable**

- **Bit 0 – BPPL: Battery Protection Parameter Lock**

The BPCR, BPHCTR, BPOCTR, BPSCTR, BPDHCD, BPCHCD, BPDOCD, BPCOCD and BPSCD Battery Protection registers can be locked from any further software updates. Once

locked, these registers cannot be accessed until the next hardware reset. This provides a safe method for protecting the registers from unintentional modification by software runaway. It is recommended that software sets these registers shortly after reset, and then protect the registers from further updates.

To lock these registers, the following algorithm must be followed:

1. In the same operation, write a logic one to BPPLE and BPPL.
2. Within the next four clock cycles, in the same operation, write a logic zero to BPPLE and a logic one to BPPL.

24.7.2 BPCR – Battery Protection Control Register

Bit	7	6	5	4	3	2	1	0	
(0xFD)	–	–	EPID	SCD	DOCD	COCD	DHCD	CHCD	BPCR
Read/Write	R	R	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:6 – Reserved**

These bits are reserved and will always read as zero.

- **Bit 5 – EPID: External Protection Input Disable**

When this bit is set, the External Protection Input is disabled and any External Protection Input will be ignored. Note that this bit overrides the GPIO functionality in the External Protection Input port. If not using the External Protection Input feature, it is recommended that this bit is always set.

- **Bit 4 – SCD: Short Circuit Protection Disabled**

When the SCD bit is set, the Short-circuit Protection is disabled. The Short-circuit Detection will be disabled, and any Short-circuit condition will be ignored.

- **Bit 3 – DOCD: Discharge Over-current Protection Disabled**

When the DOCD bit is set, the Discharge Over-current Protection is disabled. The Discharge Over-current Detection will be disabled, and any Discharge Over-current condition will be ignored.

- **Bit 2 – COCD: Charge Over-current Protection Disable**

When the COCD bit is set, the Charge Over-current Protection is disabled. The Charge Over-current Detection will be disabled, and any Charge Over-current condition will be ignored.

- **Bit 1 – DHCD: Discharge High-current Protection Disabled**

When the DHCD bit is set, the Discharge High-current Protection is disabled. The Discharge High-current Detection will be disabled, and any Discharge High-current condition will be ignored.

- **Bit 0 – CHCD: Charge High-current Protection Disable**

When the CHCD bit is set, the Charge High-current Protection is disabled. The Charge High-current Detection will be disabled, and any Charge High-current condition will be ignored.

Note: Due to synchronization of parameters between clock domains, a guard time of three ULP oscillator cycles plus three CPU clock cycles is required between each time the BPCR register is written. Any writing to the BPCR register during this period will be ignored.

24.7.3 BPSCTR – Battery Protection Short-current Timing Register

Bit	7	6	5	4	3	2	1	0	
(0xFA)	–	SCPT[6:0]							BPSCTR
Read/Write	R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	1	0	0	0	0	

- **Bit 7 – Reserved**

This bit is reserved in the Atmel ATmega16HVB/32HVB and will always read as zero.

- **Bit 6:0 – SCPT[6:0]: Short-current Protection Timing**

These bits control the delay of the Short-circuit Protection. The Short-circuit Timing can be set with a step size of 62.5µs as shown in Table 24-2.

Table 24-2. Short-circuit Protection Reaction Time. SCPT[6:0] with corresponding Short-circuit Delay Time.

Short-circuit Protection Reaction Time (1)	
SCPT[6:0] (2)	**Typ**
0x00	(15.5µs - 70.5µs) + T_d (3)
0x01	(15.5µs - 70.5µs) + T_d (3)
0x02	(78.0µs - 133.0µs) + T_d (3)
0x03	(140.5µs - 195.5µs) + T_d (3)
...	...
0x7E	(7.83ms - 7.88ms) + T_d (3)
0x7F	(7.89ms - 7.95ms) + T_d (3)

Notes:
1. The actual value depends on the actual frequency of the "Ultra Low Power RC oscillator" on page 27. See "Electrical characteristics" on page 225.
2. Initial value: SCPT[0x10](1ms).
3. An additional delay T_d can be expected after enabling the Discharge FET due to initialization of the protection circuit. With nomial ULP frequency this delay is maximum 86µs.

Note: Due to synchronization of parameters between clock domains, a guard time of 3 ULP oscillator cycles + 3 CPU clock cycles is required between each time the BPSCTR register is written. Any writing to the BPSCTR register during this period will be ignored.

24.7.4 BPOCTR – Battery Protection Over-current Timing Register

Bit	7	6	5	4	3	2	1	0	
(0xFB)	–	–	OCPT[5:0]						BPOCTR
Read/Write	R	R	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	1	0	

- **Bit 7:6 – Reserved**

These bits are reserved in the ATmega16HVB/32HVB and will always read as zero.

- **Bit 5:0 – OCPT[5:0]: Over-current Protection Timing**

These bits control the delay of the Over-circuit Protection. The Over-current Timing can be set with a step size of 0.5 ms as shown in Table 24-3 on page 140.

Table 24-3. Over-current protection reaction time. OCPT[5:0] with corresponding Over-current delay time.

Over-current protection reaction time [1]	
OCPT[5:0]	**Typ**
0x00	(0.0ms - 0.5ms) + T_d [3]
0x01	(0.0ms - 0.5ms) + T_d [3]
0x02 [2]	(0.5ms - 1.0ms) + T_d [3]
0x03	(1.0ms - 1.5ms) + T_d [3]
...	...
0x3E	(30.5ms - 31.0ms) + T_d [3]
0x3F	(31.0ms - 31.5ms) + T_d [3]

Notes:
1. The actual value depends on the actual frequency of the "Ultra Low Power RC oscillator" on page 27. See "Electrical characteristics" on page 225.
2. Initial value.
3. An additional delay T_d can be expected after enabling the corresponding FET. This is related to the initialization of the protection circuitry. For the Discharge Over-Current protection, this applies when enabling the Discharge FET. For Charge Over-Current protection, this applies when enabling the Charge FET. With nominal ULP frequency this delay is maximum 0.1ms.

Note: Due to synchronization of parameters between clock domains, a guard time of three ULP oscillator cycles plus three CPU clock cycles is required between each time the BPOCTR register is written. Any writing to the BPOCTR register during this period will be ignored.

24.7.5 BPHCTR – Battery protection high-current timing register

Bit	7	6	5	4	3	2	1	0	
(0xFC)	–	–	HCPT[5:0]						BPHCTR
Read/Write	R	R	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	1	

- **Bit 7:6 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB and will always read as zero.

- **Bit 5:0 – HCPT[5:0]: High-current protection timing**

These bits control the delay of the High-circuit Protection. The High-current Timing can be set with a step size of 2 ms as shown in Table 24-4.

Table 24-4. High-current protection reaction time. HCPT[5:0] with corresponding high-current delay time.

High-current protection reaction time [1]	
HCPT[5:0]	**Typ**
0x00	(0ms - 2ms) + T_d [3]
0x01 [2]	(0ms - 2ms) + T_d [3]
0x02	(2ms - 4ms) + T_d [3]
0x03	(4ms - 6ms) + T_d [3]

Table 24-4. High-current protection reaction time. HCPT[5:0] with corresponding high-current delay time. (Continued)

High-current protection reaction time [1]	
...	...
0x3E	(122ms - 124ms) + T_d [3]
0x3F	(124ms - 126ms) + T_d [3]

Notes:
1. The actual value depends on the actual frequency of the "Ultra Low Power RC oscillator" on page 27. See "Electrical characteristics" on page 225.
2. Initial value.
3. An additional delay T_d can be expected after enabling the corresponding FET. This is related to the initialization of the protection circuitry. For the Discharge High-Current protection, this applies when enabling the Discharge FET. For Charge High-Current protection, this applies when enabling the Charge FET. With nominal ULP frequency this delay is maximum 0.2ms.

Note: Due to synchronization of parameters between clock domains, a guard time of three ULP oscillator cycles plus three CPU clock cycles is required between each time the BPHCTR register is written. Any writing to the BPHCTR register during this period will be ignored.

24.7.6 BPSCD – Battery Protection Short-circuit Detection Level Register

Bit	7	6	5	4	3	2	1	0	
(0xF5)	SCDL[7:0]								BPSCD
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	1	1	1	1	0	0	1	1	

- **Bits 7:0 – SCDL[7:0]: Short-circuit Detection Level**

These bits sets the R_{SENSE} voltage level for detection of Short-circuit in the Discharge Direction, as defined in Table 24-5 on page 142.

Note: Due to synchronization of parameters between clock domains, a guard time of three ULP oscillator cycles plus three CPU clock cycles is required between each time the BPSCD register is written. Any writing to the BPSCD register during this period will be ignored.

24.7.7 BPDOCD – Battery Protection Discharge-Over-current Detection Level Register

Bit	7	6	5	4	3	2	1	0	
(0xF6)	DOCDL[7:0]								BPDOCD
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	1	1	1	1	0	0	1	1	

- **Bits 7:0 – DOCDL[7:0]: Discharge Over-current Detection Level**

These bits sets the R_{SENSE} voltage level for detection of Discharge Over-current, as defined in Table 24-5 on page 142.

Note: Due to synchronization of parameters between clock domains, a guard time of three ULP oscillator cycles plus three CPU clock cycles is required between each time the BPDOCD register is written. Any writing to the BPDOCD register during this period will be ignored.

24.7.8 BPCOCD – Battery Protection Charge-Over-current Detection Level Register

Bit	7	6	5	4	3	2	1	0	
(0xF7)	COCDL[7:0]								BPCOCD
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	1	1	1	1	0	0	1	1	

- **Bits 7:0 –COCDL[7:0]: Charge Over-current Detection Level**

These bits sets the R_{SENSE} voltage level for detection of Charge Over-current, as defined in Table 24-5.

Note: Due to synchronization of parameters between clock domains, a guard time of three ULP oscillator cycles plus three CPU clock cycles is required between each time the BPCOCD register is written. Any writing to the BPCOCD register during this period will be ignored.

24.7.9 BPDHCD – Battery Protection Discharge-High-current Detection Level Register

Bit	7	6	5	4	3	2	1	0	
(0xF8)	DHCDL[7:0]								BPDHCD
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	1	1	1	1	0	0	1	1	

- **Bits 7:0 – DHCDL[7:0]: Discharge High-current Detection Level**

These bits sets the R_{SENSE} voltage level for detection of DischargeHigh-current, as defined in Table 24-5.

Note: Due to synchronization of parameters between clock domains, a guard time of three ULP oscillator cycles plus three CPU clock cycles is required between each time the BPDHCD register is written. Any writing to the BPDHCD register during this period will be ignored.

24.7.10 BPCHCD – Battery Protection Charge-High-current Detection Level Register

Bit	7	6	5	4	3	2	1	0	
(0xF9)	CHCDL[7:0]								BPCHCD
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	1	1	1	1	0	0	1	1	

- **Bits 7:0 –CHCDL[7:0]: Charge High-current Detection Level**

These bits sets the R_{SENSE} voltage level for detection of Charge High-current, as defined in Table 24-5.

Note: Due to synchronization of parameters between clock domains, a guard time of three ULP oscillator cycles plus three CPU clock cycles is required between each time the BPCHCD register is written. Any writing to the BPCHCD register during this period will be ignored.

Table 24-5. DL[7:0] with corresponding R_{SENSE} voltage levels for all current detection level registers (BPSCD, BPDOCD, BPCOCD, BPDHCD, BPCHCD).

Current protection detection levels	
DL[7:0]	**Typical (mV)**
0xF3	20
0xF4	25
0xF5	30

Table 24-5. DL[7:0] with corresponding R_{SENSE} voltage levels for all current detection level registers (BPSCD, BPDOCD, BPCOCD, BPDHCD, BPCHCD). (Continued)

Current protection detection levels	
0xF6	35
0xF7	40
0xF8	45
0xF9	50
0xFA	55
0xFB	60
0xFC	65
0xFD	70
0x77	80
0x78	90
0x79	100
0x7A	110
0x7B	120
0x7C	130
0x7D	140
0x37	150
0x38	170
0x39	190
0x3A	210
0x3B	230
0x3C	250
0x3D	270
0x17	310
All other values	Reserved

24.7.11 BPIMSK – Battery Protection Interrupt Mask Register

Bit	7	6	5	4	3	2	1	0	
(0xF2)	–	–	–	SCIE	DOCIE	COCIE	DHCIE	CHCIE	BPIMSK
Read/Write	R	R	R	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7:5 – Reserved**

These bits are reserved and will always read as zero.

- **Bit 4 – SCIE: Short-circuit Protection Activated Interrupt**

The SCIE bit enables interrupt caused by the Short-circuit Protection Activated Interrupt.

- **Bit 3 – DOCIE: Discharge Over-current Protection Activated Interrupt**

The DOCIE bit enables interrupt caused by the Discharge Over-current Protection Activated Interrupt.

- **Bit 2 – COCIE: Charge Over-current Protection Activated Interrupt**

The COCIE bit enables interrupt caused by the Charge Over-current Protection Activated Interrupt.

- **Bit 1 – DHCIE : Discharger High-current Protection Activated Interrupt**

The DHCIE bit enables interrupt caused by the Discharge High-current Protection Activated Interrupt.

- **Bit 0 – CHCIE : Charger High-current Protection Activated Interrupt**

The CHCIE bit enables interrupt caused by the Charge High-current Protection Activated Interrupt.

24.7.12 BPIFR – Battery Protection Interrupt Flag Register

Bit	7	6	5	4	3	2	1	0	
(0xF3)	–	–	–	SCIF	DOCIF	COCIF	DHCIF	CHCIF	BPIFR
Read/Write	R	R	R	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7:5 – Res: Reserved**

These bits are reserved and will always read as zero.

- **Bit 4 – SCIF: Short-circuit Protection Activated Interrupt**

Once Short-circuit violation is detected, SCIF becomes set. The flag is cleared by writing a logic one to it.

- **Bit 3 – DOCIF: Discharge Over-current Protection Activated Interrupt**

Once Discharge Over-current violation is detected, DOCIF becomes set. The flag is cleared by writing a logic one to it.

- **Bit 2 – COCIF: Charge Over-current Protection Activated Interrupt**

Once Charge Over-current violation is detected, COCIF becomes set. The flag is cleared by writing a logic one to it.

- **Bit 1 – DHCIF: Discharge High-current Protection Activated Interrupt**

Once Discharge High-current violation is detected, DHCIF becomes set. The flag is cleared by writing a logic one to it.

- **Bit 0 – CHCIF: Charge High-current Protection Activated Interrupt**

Once Charge High-current violation is detected, CHCIF becomes set. The flag is cleared by writing a logic one to it.

25. FET driver

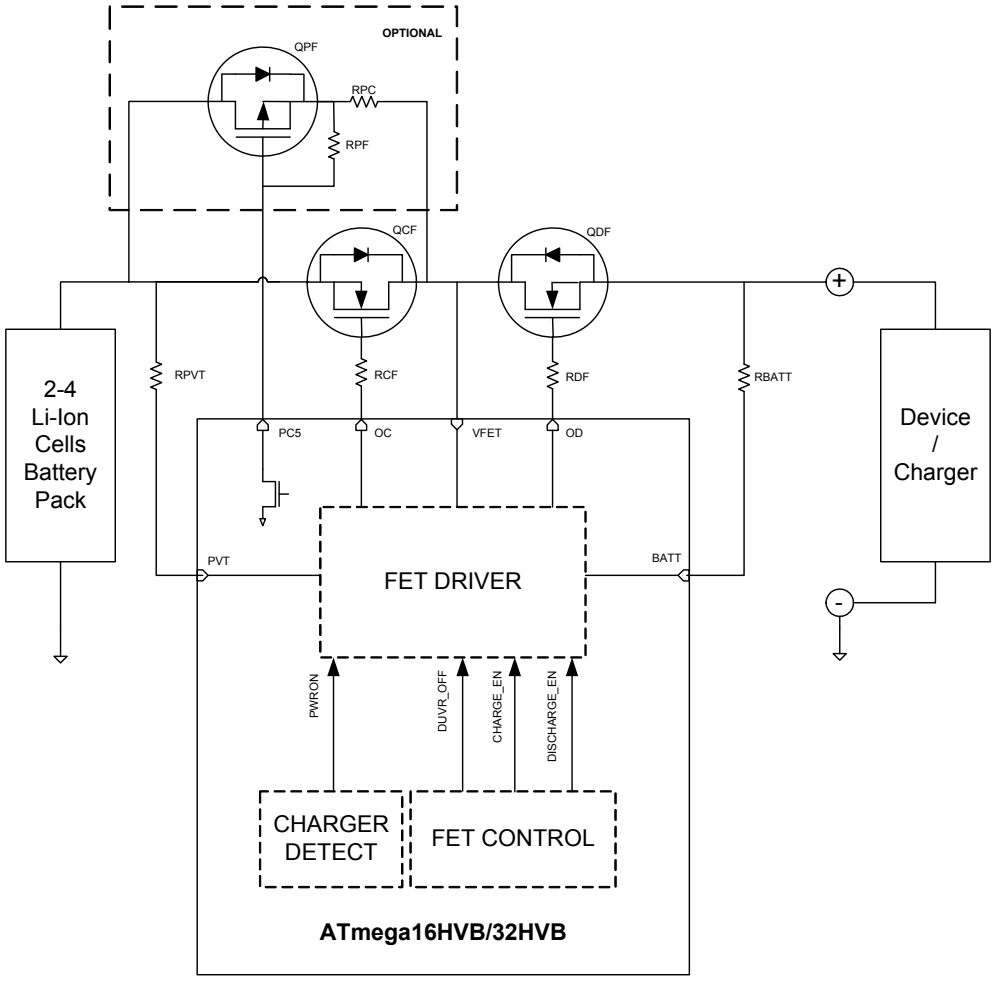
25.1 Features

- **High side N-channel FET driver for controlling charge and discharge FETs in Li-ion battery application**
- **Optional deep under-voltage recovery mode allowing normal operation while charging deeply discharged battery cells from 0-volt without an external pre-charge FET**
- **Optional pre-charge FET mode that allows chargers without pre-charge functionality to charge a deeply discharged battery from 0-volt**

25.2 Overview

The Atmel ATmega16HVB/32HVB integrates an N-channel FET driver for turning on and off external high-side Charge and Discharge FETs in Li-ion battery packs. The FET driver is designed for outputting a high voltage gate overdrive of typically 13V during normal operation.

Figure 25-1. Simplified block diagram.



In normal operation FET is controlled by software. SW can enable and disable the Charge FET and the Discharge FET by writing to the FET Control and Status Register (FCSR).

For safe operation the FET driver automatically turns off both the Charge and Discharge FET if the autonomous Battery Protection circuitry (see ”Battery protection” on page 132) detects an illegal current condition. If such conditions occur, software is not allowed to turn on the FETs until the current condition has normalized.

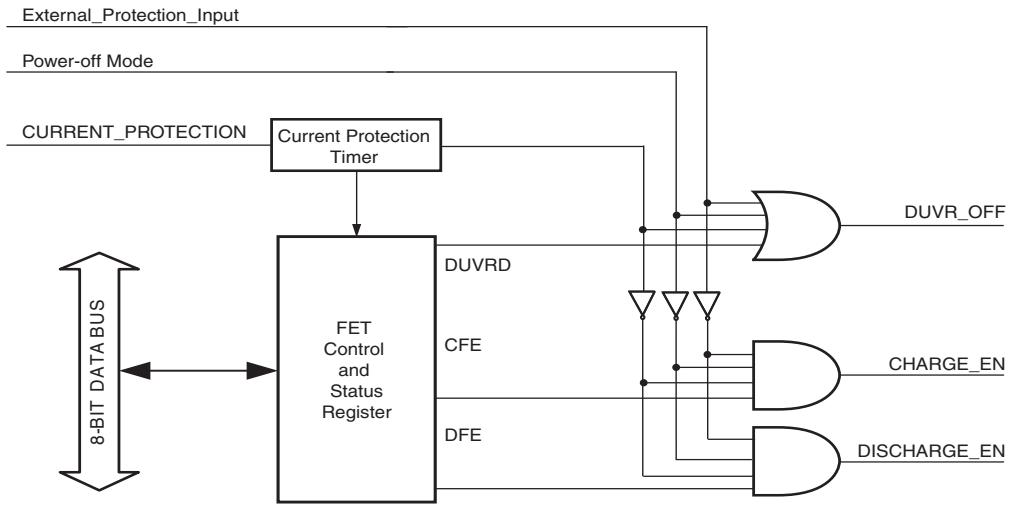
To charge deeply discharged cells the ATmega16HVB/32HVB can be configured to run in Deep Under Voltage Recovery (DUVR) mode. Using chargers with pre-charge current functionality, this allows charging of deeply discharge cells without an additional pre-charge FET. For chargers without a pre-charge limitation current, an optional pre-charge FET in parallel with a charge FET is supported to be able to charge deeply discharge cells.

25.3 Operation and usage

25.3.1 Normal operation

In normal operation (DUVRD=1), the FET control is used to enable and disable the Charge FET and Discharge FET. Normally, the FETs are enabled and disabled by SW writing to the FET Control and Status Register (FCSR). However, the autonomous Battery Protection circuitry will if necessary override SW settings to protect the battery cells from too high Charge- or Discharge currents. Note that the CPU is never allowed to enable a FET that is disabled by the battery protection circuitry. The FET control is shown in Figure 25-1 on page 145.

Figure 25-2. FET control module.



If Current Protection is activated by the Battery Protection circuitry both the Charge-FET and Discharge FET will be disabled by hardware. When the protection condition disappears the Current Protection Timer will ensure a hold-off time of 1 second before software can re-enable the external FETs.

To turn on the Charge and Discharge FET a minimum VFET supply voltage is required. When the C-FET/D-FET is off with a total cell voltage lower than 6V, SW should not turn on the C-FET/D-FET unless a charger is connected. If the total cell voltage is higher than 6V, it is safe for SW to turn on C-FET or D-FET. Note however, if the FETs are already turned-on, the FET driver can operate in the entire supply operating range of the device.

The C-FET/D-FETs is switched on by pumping the gate OC/OD above the source voltage (PVT/BATT) of the external FET. When the gate-source voltage has reached a level higher than

typically 13V the pumping frequency is reduced and is regulated to maintain the high gate-source voltage. For low VFET voltages this level is never reached, thus the pumping frequency is not reduced. Thus, increased power consumption from the FET driver is expected in this condition. The gate-source voltage for low VFET voltages is close to 2VFET-2V.

If the C-FET is disabled and D-FET enabled, discharge current will run through the body-drain diode of the C-FET and vice versa. To avoid the potential heat problem from this situation, software should ensure that the D-FET is not disabled when a large charge current is flowing, and that the C-FET is not disabled when a large discharge current is flowing.

25.3.2 DUVR – Deep under voltage recovery mode without pre-charge FET

To allow charging of deeply discharged cells using chargers with pre-charge functionality, the FET Driver can be configured to operate in Deep Under-Voltage Recovery (DUVR) mode. DUVR mode allows charging of deeply discharged cells without using an additional pre-charge FET. To enter Deep Under Voltage Recovery Mode, software should clear the DUVRD bit (DUVRD=0) in the FET Control and Status Register (FCSR). DUVR mode cannot be used in 2-cell applications, refer to ”Deep under voltage operation with pre-charge FET” on page 149.

In DUVR mode the FET Driver regulates the voltage at VFET quickly to typically 4.5V by partly opening the C-FET. At this voltage the chip is fully operational. With the C-FET partly open the charger is allowed to charge the battery with a pre-charge current. As the cell voltage starts to increase above 4.5V the VFET voltage follows the cell voltage. When the total cell voltage has been charged to a voltage higher than 5V, it is safe to exit DUVR mode and to turn-on the C-FET completely. Software should then set the DUVRD bit to exit DUVR and fully open the C-FET by setting the CFET bit. Note that it is recommended that this is done in two steps.

1. Exit DUVR mode by setting the DUVRD bit.
2. Wait until register synchronization is complete (see guard time notice in ”Register description” on page 149), and enable the C-FET by setting the CFE bit.

To avoid potential heating of the C-FET and D-FET in DUVR mode, the charger should not be allowed to enter quick-charge until the FET has been completely enabled and the FET driver has exit DUVR mode. It is therefore recommended to use the CC-ADC to continuously monitor the current flowing during DUVR mode charging, and to turn-off the FETs if an illegal charge current is measured. For fast tracking, it is recommended to use the CC-ADC Instantaneous Current Output. For details on CC-ADC usage, see ”Coulomb counter – Dedicated fuel gauging Sigma-Delta ADC” on page 108.

Before entering DUVR-mode it is recommended to enable the D-FET. After enabling the D-FET it is recommended that SW add a hold-off time of 10ms before DUVR mode is entered. This is to make sure that the D-FET is completely enabled.

To avoid that the charger enters quick-charge before the battery has exit DUVR mode, it is recommended that either:

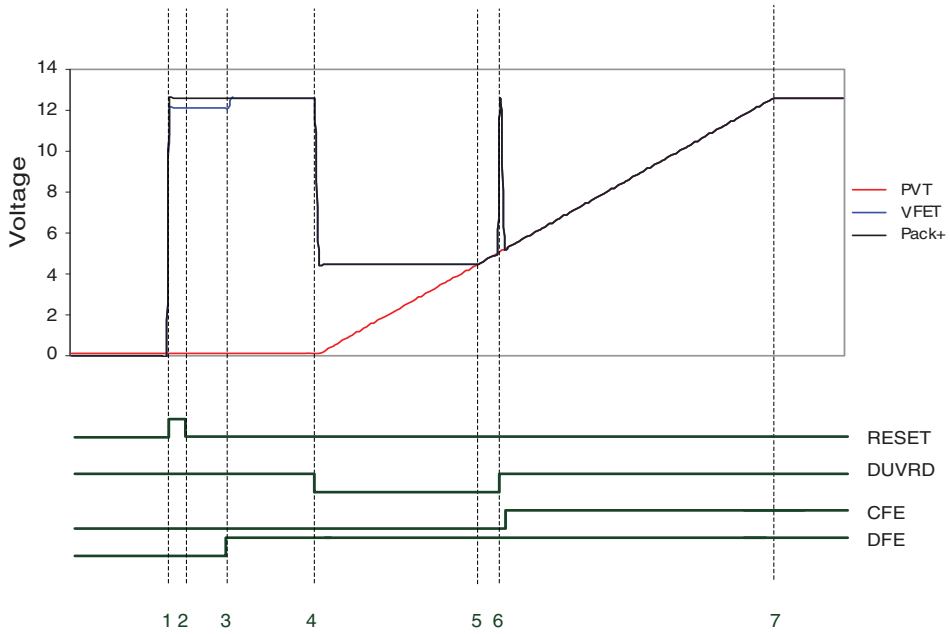
1. The battery controls when the charger is allowed to enter quick-charge. This is done by communicating to the charger over the SMBus line when the charger is allowed to enter increase the charge current.
2. The charger itself controls when to enter quick-charge by sensing the voltage at the Pack+ terminal. It is not recommended that the charger allows quick-charge until the charger senses a Pack+ voltage higher than 7V. To avoid potential heating problem SW need to ensure to exit DUVR mode and enable the C-FET before the charger sees this limit.

When the battery is started from a power-off condition by connecting a legal charger, SW should determine whether to allow charging or not before enabling the C-FET. Before allowing charging it is recommended to use the V-ADC to measure the cell temperature and cell voltages. Depending on the total cell voltage, the device should either start up in DUVR mode or in normal charging mode with the C-FET and D-FET enabled.

- If the total cell voltage is below 4.5V, the battery should enter DUVR charging mode. This ensures safe operation voltage while allowing charging
- If the total cell voltage is above 4.5V, the battery should enter normal charging mode with both C-FET and D-FET enabled

The Figure 25-3 shows an example of charging three deeply discharged Li-ion cells in series using DUVR mode.

Figure 25-3. DUVR mode charging in 3-cell mode configuration.



1. A charger with 12.6V charge voltage is plugged to the Pack+ pin and the Atmel ATmega16HVB/32HVB enters reset mode. Charger should be configured with a charge current limit (pre-charge current).
2. The ATmega16HVB/32HVB exit reset and initializes modules. To determine if charging should be allowed and if DUVR mode should be entered, cell temperature and cell voltages are measured by the V-ADC.
3. D-FET is enabled and the VFET voltage increase to the Pack+ level.
4. DUVR mode is entered by clearing the DUVRD bit in FCSR. The VFET voltage and the Pack+ voltage will now be regulated to approximately 4.5V.
5. The total cell voltage has reached the regulated VFET limit and VFET follows the cell voltage as the battery is charged.
6. The total cell voltage has reached 5V. DUVR mode is disabled and the C-FET can be fully enabled. DUVR mode should be disabled before the C-CFET is enabled. VFET and Pack+ will therefore rise to the charger voltage for a short period before the C-FET is enabled.
7. Battery voltage reached charger voltage.

25.3.3 Deep under voltage operation with pre-charge FET

If a charger without pre-charge functionality is used, the Pre-charge FET will provide the current path and the pre-charge resistor will limit the charge current during charging of deeply over-discharged cells. After reaching sufficient battery voltage it is safe to turn on the Charge FET to increase the charge current. Deep Under Voltage Operation with Pre-charge FET is supported through PC5, which is a high voltage open drain pin. For configuration and usage of this pin, see ”High voltage I/O ports” on page 62.

25.3.4 Operation in reset and power off

In reset and power-off the C-FET and D-FET will be automatically turned off. Safety is remained by active pulling OC/OD hard to ground.

25.4 Register description

25.4.1 FCSR – FET Control and Status Register

Bit	7	6	5	4	3	2	1	0	
(0xF0)	–	–	–	–	DUVRD	CPS	DFE	CFE	FCSR
Read/Write	R	R	R	R	R/W	R	R/W	R/W	
Initial Value	0	0	0	0	1	0	0	0	

- **Bits 7:4 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB, and will always read as zero.

- **Bit 3 – DUVRD: Deep Under-voltage Recovery Disabled**

When the DUVRD is cleared (zero), the FET Driver will be forced to operate in Deep Under-voltage Recovery DUVR mode. See ”DUVR – Deep under voltage recovery mode without pre-charge FET” on page 147 for details. To avoid that the FET driver tries to switch on the C-FET during current protection or during internal reset, the DUVRD bit is overridden to one by hardware in these cases. When this bit is set (one), Deep Under-voltage Recovery mode of the FET Driver will be disabled. DUVR mode should not be used in 2-cell applications.

- **Bit 2 – CPS: Current Protection Status**

The CPS bit shows the status of the Current Protection. This bit is set (one) when a Current Protection is active, and cleared (zero) otherwise.

- **Bit 1 – DFE: Discharge FET Enable**

When the DFE bit is cleared (zero), the Discharge FET will be disabled regardless of the state of the Battery Protection circuitry. When this bit is set (one), the Discharge FET is enabled. This bit will automatically be cleared by the CBP circuitry when Current Protection is activated. When this bit is cleared, Short-circuit, Discharge High-current and Discharge Over-current are disabled regardless of the settings in the BPCR Register.

- **Bit 0 – CFE: Charge FET Enable**

When the CFE bit is cleared (zero), the Charge FET will be disabled regardless of the state of the Battery Protection circuitry. When this bit is set (one), the Charge FET is enabled. This bit will automatically be cleared by the CBP circuitry when Current Protection is activated. When this bit is cleared and the DUVRD bit is set, Charge High-current Protection and Charge Over-current Protection are disabled regardless of the settings in the BPCR Register. When the

DUVRD bit is cleared, the charge FET will be enabled by DUVR mode regardless of the CFE status.

Notes:
1. Due to synchronization of parameters between clock domains, a guard time of three ULP oscillator cycles plus three CPU clock cycles is required between each time the FCSR register is written. Any writing to the FCSR register during this period will be ignored.
2. The NFET drivers require a minimum total cell voltage of 6V or higher or a charger connected to turn-on the FETs. Note that this limit only applies if the FET is disabled in advanced. If the FET is already enabled, the FET will be fully operational in the entire voltage range of the device (4V - 18V).

26. Cell balancing

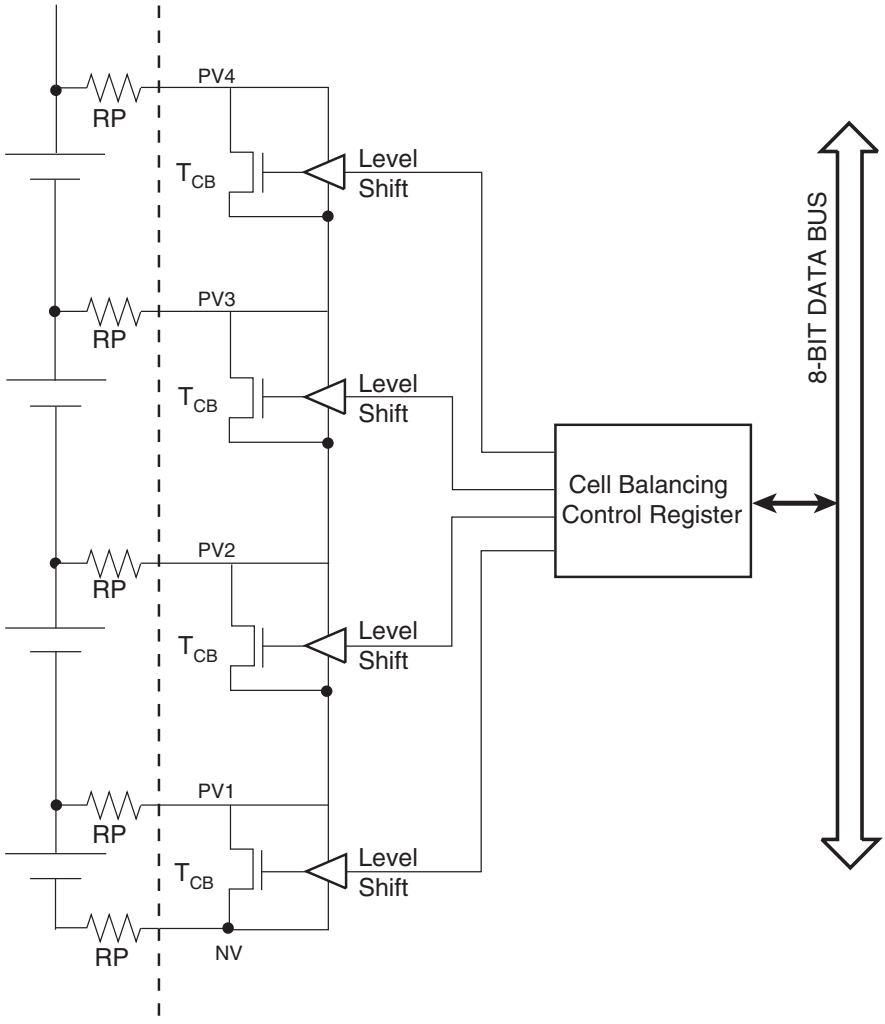
26.1 Overview

The Atmel ATmega16HVB/32HVB incorporates cell balancing FETs. The chip provides one cell balancing FET for each battery cell in series. The FETs are directly controlled by the application software, allowing the cell balancing algorithms to be implemented in software. The FETs are connected in parallel with the individual battery cells. The cell balancing is illustrated in Figure 26-1. The figure shows a four-cell configuration. The cell balancing FETs are disabled in the Power-off mode.

For typical current through the Cell Balancing FETs, see ”Electrical characteristics” on page 225.

The Cell Balancing FETs are controlled by the CBCR. Neighbouring FETs cannot be simultaneously enabled. If trying to enable two neighbouring FETs, both will be disabled.

Figure 26-1. Cell balancing.



26.2 Register description

26.2.1 CBCR – Cell Balancing Control Register

Bit	7	6	5	4	3	2	1	0	
(0xF1)	–	–	–	–	CBE4	CBE3	CBE2	CBE1	CBCR
Read/Write	R	R	R	R	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7:4 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB and will always read as zero.

- **Bit 3 – CBE4: Cell Balancing Enable 4**

When this bit is set, the integrated Cell Balancing FET between terminals PV4 and PV3 will be enabled. When the bit is cleared, the Cell Balancing FET will be disabled. The Cell Balancing FETs are always disabled in Power-off mode. CBE4 cannot be set if CBE3 is set.

- **Bit 2 – CBE3: Cell Balancing Enable 3**

When this bit is set, the integrated Cell Balancing FET between terminals PV3 and PV2 will be enabled. When the bit is cleared, the Cell Balancing FET will be disabled. The Cell Balancing FETs are always disabled in Power-off mode. CBE3 cannot be set if CBE2 or CBE4 is set.

- **Bit 1 – CBE2: Cell Balancing Enable 2**

When this bit is set, the integrated Cell Balancing FET between terminals PV2 and PV1 will be enabled. When the bit is cleared, the Cell Balancing FET will be disabled. The Cell Balancing FETs are always disabled in Power-off mode. CBE2 cannot be set if CBE1 or CBE3 is set.

- **Bit 0 – CBE1: Cell Balancing Enable 1**

When this bit is set (one), the integrated Cell Balancing FET between terminals PV1 and NV will be enabled. When the bit is cleared (zero), the Cell Balancing FET will be disabled. The Cell Balancing FETs are always disabled in Power-off mode. CBE1 cannot be set if CBE2 is set.

27. 2-wire serial interface

27.1 Features

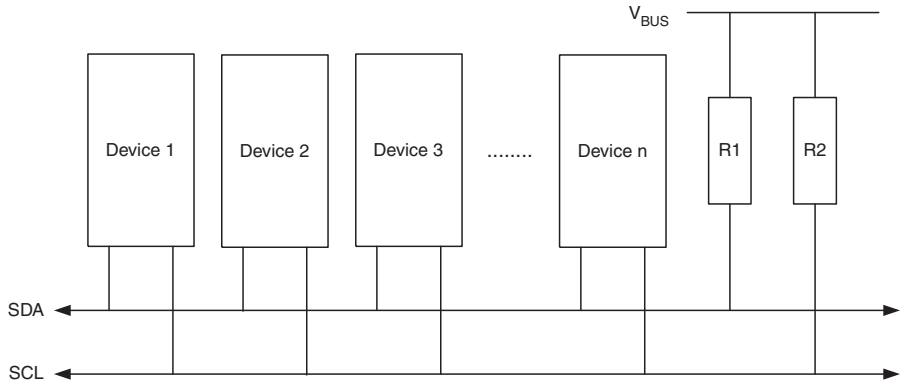
- **Simple yet powerful and flexible communication interface, only two bus lines needed**
- **Both master and slave operation supported**
- **Device can operate as transmitter or receiver**
- **7-bit address space allows up to 128 different slave addresses**
- **Multi-master arbitration support**
- **Supports SM bus transfer speeds from 10kHz to 100kHz**
- **Slew-rate limited output drivers**
- **Noise suppression circuitry rejects spikes on bus lines**
- **Fully programmable slave address with general call support**
- **Address recognition causes wake-up when AVR is in sleep mode**

27.2 Two-wire serial interface bus definition

The Two-wire Serial Interface (TWI) is ideally suited for typical microcontroller applications. The TWI protocol allows the systems designer to interconnect up to 128 different devices using only two bi-directional bus lines, one for clock (SCL) and one for data (SDA). The only external hardware needed to implement the bus is a single pull-up resistor for each of the TWI bus lines. All devices connected to the bus have individual addresses, and mechanisms for resolving bus contention are inherent in the TWI protocol.

When the TWI is not used, power consumption can be minimized by writing the PRTWI bit in PRR0 to one. See ”PRR0 – Power Reduction Register 0” on page 40 for details on how to use the PRTWI bit.

Figure 27-1. TWI bus interconnection.



27.2.1 TWI terminology

The following definitions are frequently encountered in this section.

Table 27-1. TWI terminology.

Term	Description
Master	The device that initiates and terminates a transmission. The Master also generates the SCL clock
Slave	The device addressed by a Master
Transmitter	The device placing data on the bus
Receiver	The device reading data from the bus

27.2.2 Electrical interconnection

As depicted in Figure 27-1 on page 153, both bus lines are connected to the positive supply voltage through pull-up resistors. The bus drivers of all TWI-compliant devices are open-drain or open-collector. This implements a wired-AND function which is essential to the operation of the interface. A low level on a TWI bus line is generated when one or more TWI devices output a zero. A high level is output when all TWI devices tri-state their outputs, allowing the pull-up resistors to pull the line high. Note that all AVR devices connected to the TWI bus must be powered in order to allow any bus operation.

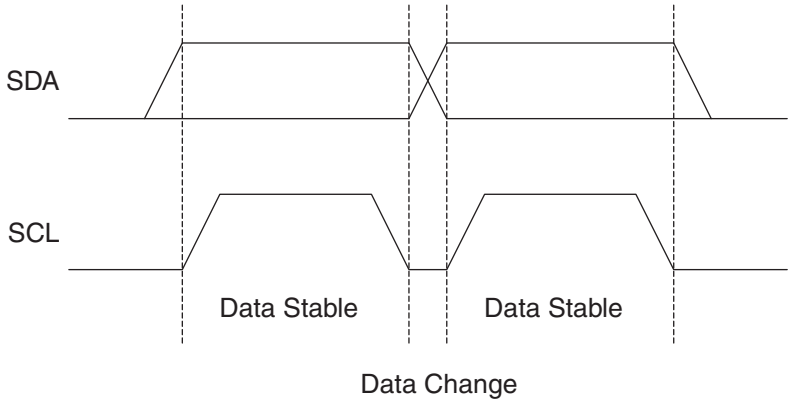
The number of devices that can be connected to the bus is only limited by the bus capacitance limit of 400pF and the 7-bit slave address space. A detailed specification of the electrical characteristics of the TWI is given in ”2-wire serial interface characteristics” on page 232.

27.3 Data transfer and frame format

27.3.1 Transferring bits

Each data bit transferred on the TWI bus is accompanied by a pulse on the clock line. The level of the data line must be stable when the clock line is high. The only exception to this rule is for generating start and stop conditions.

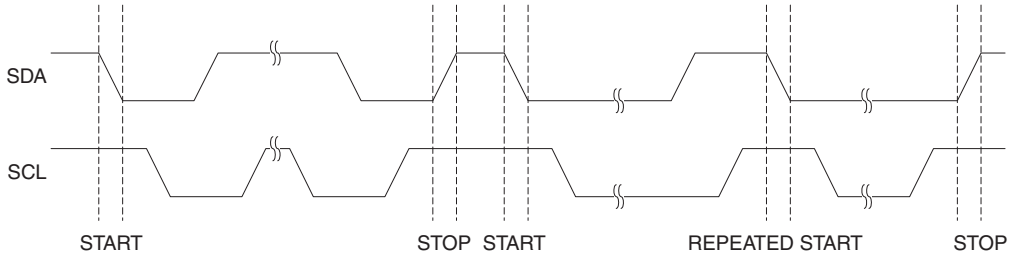
Figure 27-2. Data validity.



27.3.2 START and STOP conditions

The Master initiates and terminates a data transmission. The transmission is initiated when the Master issues a START condition on the bus, and it is terminated when the Master issues a STOP condition. Between a START and a STOP condition, the bus is considered busy, and no other Master should try to seize control of the bus. A special case occurs when a new START condition is issued between a START and STOP condition. This is referred to as a REPEATED START condition, and is used when the Master wishes to initiate a new transfer without relinquishing control of the bus. After a REPEATED START, the bus is considered busy until the next STOP. This is identical to the START behavior, and therefore START is used to describe both START and REPEATED START for the remainder of this datasheet, unless otherwise noted. As depicted below, START and STOP conditions are signalled by changing the level of the SDA line when the SCL line is high.

Figure 27-3. START, REPEATED START, and STOP conditions.



27.3.3 Address packet format

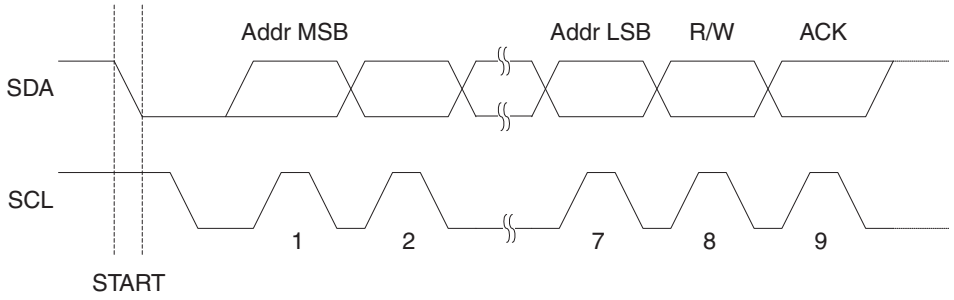
All address packets transmitted on the TWI bus are nine bits long, consisting of seven address bits, one READ/WRITE control bit and an acknowledge bit. If the READ/WRITE bit is set, a read operation is to be performed, otherwise a write operation should be performed. When a slave recognizes that it is being addressed, it should acknowledge by pulling SDA low in the ninth SCL (ACK) cycle. If the addressed Slave is busy, or for some other reason can not service the Master's request, the SDA line should be left high in the ACK clock cycle. The Master can then transmit a STOP condition, or a REPEATED START condition to initiate a new transmission. An address packet consisting of a slave address and a READ or a WRITE bit is called SLA+R or SLA+W, respectively.

The MSB of the address byte is transmitted first. Slave addresses can freely be allocated by the designer, but the address 0000 000 is reserved for a general call.

When a general call is issued, all slaves should respond by pulling the SDA line low in the ACK cycle. A general call is used when a Master wishes to transmit the same message to several slaves in the system. When the general call address followed by a write bit is transmitted on the bus, all slaves set up to acknowledge the general call will pull the SDA line low in the ack cycle. The following data packets will then be received by all the slaves that acknowledged the general call. Note that transmitting the general call address followed by a Read bit is meaningless, as this would cause contention if several slaves started transmitting different data.

All addresses of the format 1111 xxx should be reserved for future purposes.

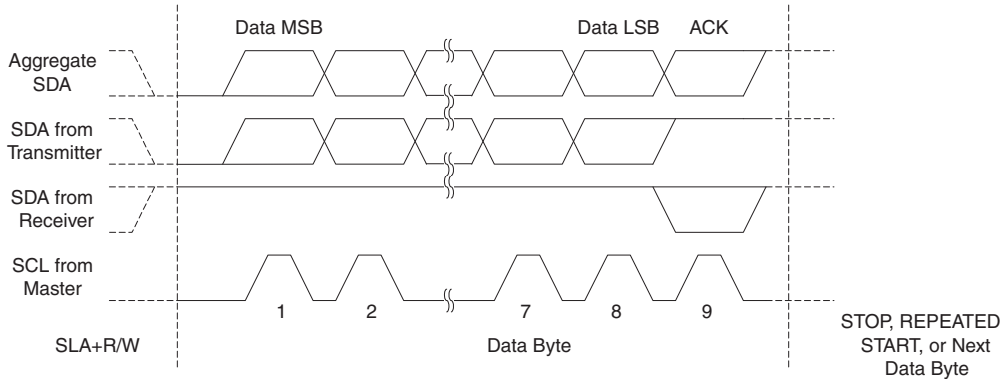
Figure 27-4. Address packet format.



27.3.4 Data packet format

All data packets transmitted on the TWI bus are nine bits long, consisting of one data byte and an acknowledge bit. During a data transfer, the Master generates the clock and the START and STOP conditions, while the Receiver is responsible for acknowledging the reception. An Acknowledge (ACK) is signalled by the Receiver pulling the SDA line low during the ninth SCL cycle. If the Receiver leaves the SDA line high, a NACK is signalled. When the Receiver has received the last byte, or for some reason cannot receive any more bytes, it should inform the Transmitter by sending a NACK after the final byte. The MSB of the data byte is transmitted first.

Figure 27-5. Data packet format.

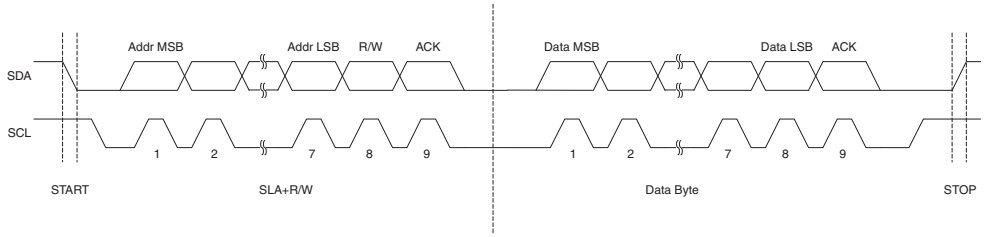


27.3.5 Combining address and data packets into a transmission

A transmission basically consists of a START condition, a SLA+R/W, one or more data packets and a STOP condition. An empty message, consisting of a START followed by a STOP condition, is illegal. Note that the wired-ANDing of the SCL line can be used to implement handshaking between the Master and the Slave. The Slave can extend the SCL low period by pulling the SCL line low. This is useful if the clock speed set up by the Master is too fast for the Slave, or the Slave needs extra time for processing between the data transmissions. The Slave extending the SCL low period will not affect the SCL high period, which is determined by the Master. As a consequence, the Slave can reduce the TWI data transfer speed by prolonging the SCL duty cycle.

Figure 27-6 on page 157 shows a typical data transmission. Note that several data bytes can be transmitted between the SLA+R/W and the STOP condition, depending on the software protocol implemented by the application software.

Figure 27-6. Typical data transmission.



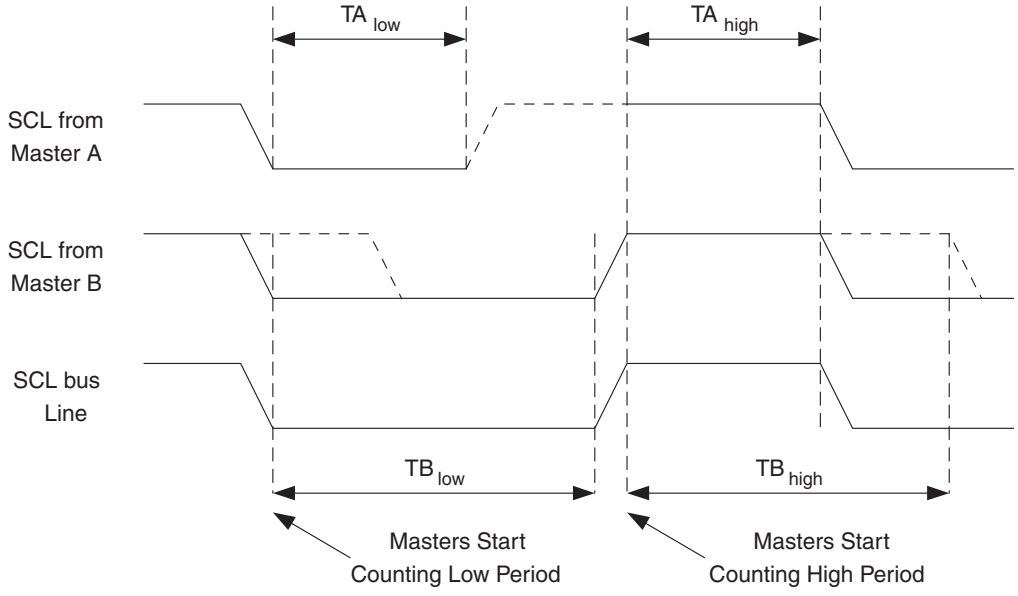
27.4 Multi-master bus systems, arbitration and synchronization

The TWI protocol allows bus systems with several masters. Special concerns have been taken in order to ensure that transmissions will proceed as normal, even if two or more masters initiate a transmission at the same time. Two problems arise in multi-master systems:

- An algorithm must be implemented allowing only one of the masters to complete the transmission. All other masters should cease transmission when they discover that they have lost the selection process. This selection process is called arbitration. When a contending master discovers that it has lost the arbitration process, it should immediately switch to Slave mode to check whether it is being addressed by the winning master. The fact that multiple masters have started transmission at the same time should not be detectable to the slaves (thet is, the data being transferred on the bus must not be corrupted)
- Different masters may use different SCL frequencies. A scheme must be devised to synchronize the serial clocks from all masters, in order to let the transmission proceed in a lockstep fashion. This will facilitate the arbitration process

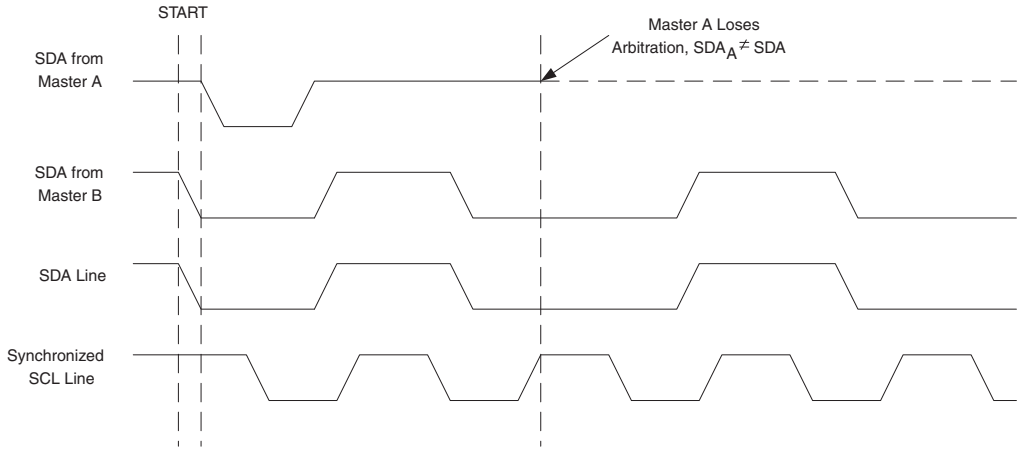
The wired-ANDing of the bus lines is used to solve both these problems. The serial clocks from all masters will be wired-ANDed, yielding a combined clock with a high period equal to the one from the master with the shortest high period. The low period of the combined clock is equal to the low period of the master with the longest low period. Note that all masters listen to the SCL line, effectively starting to count their SCL high and low Time-out periods when the combined SCL line goes high or low, respectively.

Figure 27-7. SCL synchronization between multiple masters.



Arbitration is carried out by all masters continuously monitoring the SDA line after outputting data. If the value read from the SDA line does not match the value the master had output, it has lost the arbitration. Note that a master can only lose arbitration when it outputs a high SDA value while another master outputs a low value. The losing master should immediately go to Slave mode, checking if it is being addressed by the winning master. The SDA line should be left high, but losing masters are allowed to generate a clock signal until the end of the current data or address packet. Arbitration will continue until only one master remains, and this may take many bits. If several masters are trying to address the same slave, arbitration will continue into the data packet.

Figure 27-8. Arbitration between two masters.



Note that arbitration is not allowed between:

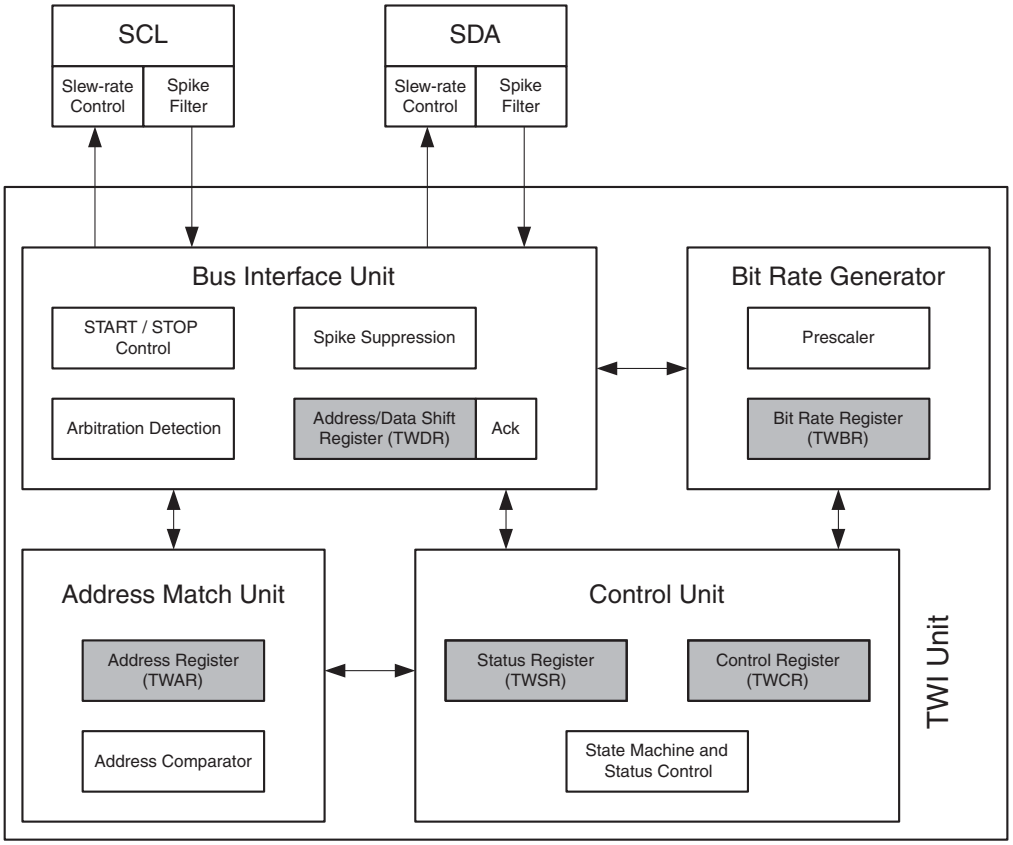
- A REPEATED START condition and a data bit
- A STOP condition and a data bit
- A REPEATED START and a STOP condition

It is the user software's responsibility to ensure that these illegal arbitration conditions never occur. This implies that in multi-master systems, all data transfers must use the same composition of SLA+R/W and data packets. In other words: All transmissions must contain the same number of data packets, otherwise the result of the arbitration is undefined.

27.5 Overview of the TWI module

The TWI module is comprised of several submodules, as shown in Figure 27-9. The shaded registers are accessible through the AVR data bus.

Figure 27-9. Overview of the TWI module.



27.5.1 SCL and SDA pins

These pins interface the AVR TWI with the rest of the MCU system. The output drivers contain a slew-rate limiter in order to conform to the TWI specification. The input stages contain a spike suppression unit removing spikes shorter than 50ns.

27.5.2 Bit rate generator unit

This unit controls the period of SCL when operating in a Master mode. The SCL period is controlled by settings in the TWI Bit Rate Register (TWBR) and the Prescaler bits in the TWI Status Register (TWSR). Slave operation does not depend on Bit Rate or Prescaler settings, but the CPU clock frequency in the slave must be at least 16 times higher than the SCL frequency. Note that slaves may prolong the SCL low period, thereby reducing the average TWI bus clock period. The SCL frequency is generated according to the following equation:

$$\text{SCL frequency} = \frac{\text{TWI clock frequency}}{16 + 2(\text{TWBR}) \cdot 4^{TWPS}}$$

- TWBR = Value of the TWI Bit Rate Register
- TWPS = Value of the prescaler bits in the TWI Status Register

Note: The TWI clock is synchronous to the CPU.

27.5.3 Bus interface unit

This unit contains the Data and Address Shift Register (TWDR), a START/STOP Controller and Arbitration detection hardware. The TWDR contains the address or data bytes to be transmitted, or the address or data bytes received. In addition to the 8-bit TWDR, the Bus Interface Unit also contains a register containing the (N)ACK bit to be transmitted or received. This (N)ACK Register is not directly accessible by the application software. However, when receiving, it can be set or cleared by manipulating the TWI Control Register (TWCR). When in Transmitter mode, the value of the received (N)ACK bit can be determined by the value in the TWSR.

The START/STOP Controller is responsible for generation and detection of START, REPEATED START, and STOP conditions. The START/STOP controller is able to detect START and STOP conditions even when the AVR MCU is in one of the sleep modes, enabling the MCU to wake up if addressed by a Master.

If the TWI has initiated a transmission as Master, the Arbitration Detection hardware continuously monitors the transmission trying to determine if arbitration is in process. If the TWI has lost an arbitration, the Control Unit is informed. Correct action can then be taken and appropriate status codes generated.

27.5.4 Address match unit

The Address Match unit checks if received address bytes match the 7-bit address in the TWI Address Register (TWAR). If the TWI General Call Recognition Enable (TWGCE) bit in the TWAR is written to one, all incoming address bits will also be compared against the General Call address. Upon an address match, the Control unit is informed, allowing correct action to be taken. The TWI may or may not acknowledge its address, depending on settings in the TWCR. The Address Match unit is able to compare addresses even when the AVR MCU is in sleep mode, enabling the MCU to wake-up if addressed by a Master.

27.5.5 Control unit

The Control unit monitors the TWI bus and generates responses corresponding to settings in the TWI Control Register (TWCR). When an event requiring the attention of the application occurs on the TWI bus, the TWI Interrupt Flag (TWINT) is asserted. In the next clock cycle, the TWI Status Register (TWSR) is updated with a status code identifying the event. The TWSR only contains relevant status information when the TWI interrupt flag is asserted. At all other times, the TWSR contains a special status code indicating that no relevant status information is available. As long as the TWINT flag is set, the SCL line is held low. This allows the application software to complete its tasks before allowing the TWI transmission to continue.

The TWINT flag is set in the following situations:

- After the TWI has transmitted a START/REPEATED START condition
- After the TWI has transmitted SLA+R/W
- After the TWI has transmitted an address byte
- After the TWI has lost arbitration
- After the TWI has been addressed by own slave address or general call
- After the TWI has received a data byte
- After a STOP or REPEATED START has been received while still addressed as a Slave
- When a bus error has occurred due to an illegal START or STOP condition

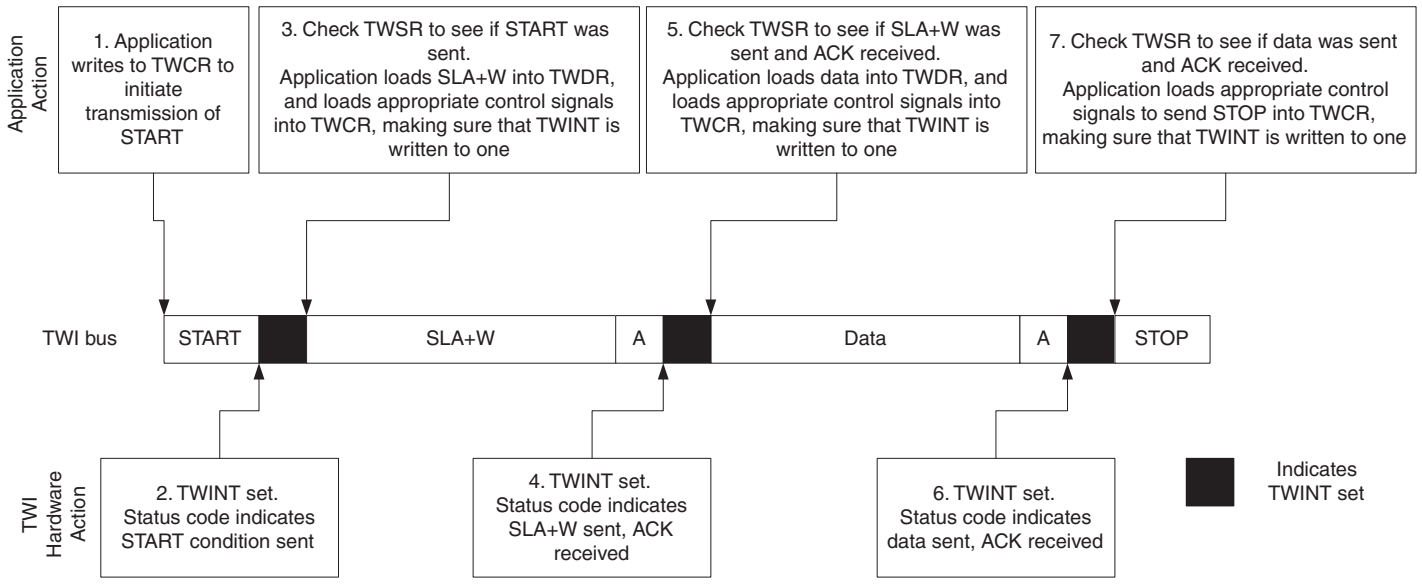
27.6 Using the TWI

The AVR TWI is byte-oriented and interrupt based. Interrupts are issued after all bus events, like reception of a byte or transmission of a START condition. Because the TWI is interrupt-based, the application software is free to carry on other operations during a TWI byte transfer. Note that the TWI Interrupt Enable (TWIE) bit in TWCR together with the Global Interrupt Enable bit in SREG allow the application to decide whether or not assertion of the TWINT flag should generate an interrupt request. If the TWIE bit is cleared, the application must poll the TWINT flag in order to detect actions on the TWI bus.

When the TWINT flag is asserted, the TWI has finished an operation and awaits application response. In this case, the TWI Status Register (TWSR) contains a value indicating the current state of the TWI bus. The application software can then decide how the TWI should behave in the next TWI bus cycle by manipulating the TWCR and TWDR registers.

Figure 27-10 is a simple example of how the application can interface to the TWI hardware. In this example, a Master wishes to transmit a single data byte to a Slave. This description is quite abstract, a more detailed explanation follows later in this section. A simple code example implementing the desired behavior is also presented.

Figure 27-10. Interfacing the application to the TWI in a typical transmission.



1. The first step in a TWI transmission is to transmit a START condition. This is done by writing a specific value into TWCR, instructing the TWI hardware to transmit a START condition. Which value to write is described later on. However, it is important that the TWINT bit is set in the value written. Writing a one to TWINT clears the flag. The TWI will not start any operation as long as the TWINT bit in TWCR is set. Immediately after the application has cleared TWINT, the TWI will initiate transmission of the START condition.
2. When the START condition has been transmitted, the TWINT flag in TWCR is set, and TWSR is updated with a status code indicating that the START condition has successfully been sent.
3. The application software should now examine the value of TWSR, to make sure that the START condition was successfully transmitted. If TWSR indicates otherwise, the application software might take some special action, like calling an error routine. Assuming that the status code is as expected, the application must load SLA+W into TWDR. Remember

that TWDR is used both for address and data. After TWDR has been loaded with the desired SLA+W, a specific value must be written to TWCR, instructing the TWI hardware to transmit the SLA+W present in TWDR. Which value to write is described later on. However, it is important that the TWINT bit is set in the value written. Writing a one to TWINT clears the flag. The TWI will not start any operation as long as the TWINT bit in TWCR is set. Immediately after the application has cleared TWINT, the TWI will initiate transmission of the address packet.

4. When the address packet has been transmitted, the TWINT flag in TWCR is set, and TWSR is updated with a status code indicating that the address packet has successfully been sent. The status code will also reflect whether a slave acknowledged the packet or not.
5. The application software should now examine the value of TWSR, to make sure that the address packet was successfully transmitted, and that the value of the ACK bit was as expected. If TWSR indicates otherwise, the application software might take some special action, like calling an error routine. Assuming that the status code is as expected, the application must load a data packet into TWDR. Subsequently, a specific value must be written to TWCR, instructing the TWI hardware to transmit the data packet present in TWDR. Which value to write is described later on. However, it is important that the TWINT bit is set in the value written. Writing a one to TWINT clears the flag. The TWI will not start any operation as long as the TWINT bit in TWCR is set. Immediately after the application has cleared TWINT, the TWI will initiate transmission of the data packet.
6. When the data packet has been transmitted, the TWINT flag in TWCR is set, and TWSR is updated with a status code indicating that the data packet has successfully been sent. The status code will also reflect whether a slave acknowledged the packet or not.
7. The application software should now examine the value of TWSR, to make sure that the data packet was successfully transmitted, and that the value of the ACK bit was as expected. If TWSR indicates otherwise, the application software might take some special action, like calling an error routine. Assuming that the status code is as expected, the application must write a specific value to TWCR, instructing the TWI hardware to transmit a STOP condition. Which value to write is described later on. However, it is important that the TWINT bit is set in the value written. Writing a one to TWINT clears the flag. The TWI will not start any operation as long as the TWINT bit in TWCR is set. Immediately after the application has cleared TWINT, the TWI will initiate transmission of the STOP condition. Note that TWINT is NOT set after a STOP condition has been sent.

Even though this example is simple, it shows the principles involved in all TWI transmissions. These can be summarized as follows:

- When the TWI has finished an operation and expects application response, the TWINT flag is set. The SCL line is pulled low until TWINT is cleared
- When the TWINT flag is set, the user must update all TWI registers with the value relevant for the next TWI bus cycle. As an example, TWDR must be loaded with the value to be transmitted in the next bus cycle
- After all TWI Register updates and other pending application software tasks have been completed, TWCR is written. When writing TWCR, the TWINT bit should be set. Writing a one to TWINT clears the flag. The TWI will then commence executing whatever operation was specified by the TWCR setting

In the following an assembly and C implementation of the example is given. Note that the code below assumes that several definitions have been made for example by using include-files.

	Assembly code example [1]	C example [1]	Comments
1	`ldi r16, (1<<TWINT)|(1<<TWSTA)| (1<<TWEN)` `out TWCR, r16`	`TWCR = (1<<TWINT)|(1<<TWSTA)| (1<<TWEN)`	Send START condition

2	`wait1:`
	`in r16,TWCR`
	`sbrs r16,TWINT`
	`rjmp wait1`
		`while (!(TWCR & (1<<TWINT)))`
		`;`
			Wait for TWINT flag set. This indicates that the START condition has been transmitted

3	`in r16,TWSR`
	`andi r16, 0xF8`
	`cpi r16, START`
	`brne ERROR`
		`if ((TWSR & 0xF8) != START)`
		`ERROR();`
			Check value of TWI Status Register. Mask prescaler bits. If status different from START go to ERROR

4	`ldi r16, SLA_W`
	`out TWDR, r16`
	`ldi r16, (1<<TWINT) | (1<<TWEN)`
	`out TWCR, r16`
		`TWDR = SLA_W;`
		`TWCR = (1<<TWINT) | (1<<TWEN);`
			Load SLA_W into TWDR Register. Clear TWINT bit in TWCR to start transmission of address

	`wait2:`
	`in r16,TWCR`
	`sbrs r16,TWINT`
	`rjmp wait2`
		`while (!(TWCR & (1<<TWINT)))`
		`;`
			Wait for TWINT flag set. This indicates that the SLA+W has been transmitted, and ACK/NACK has been received

5	`in r16,TWSR`
	`andi r16, 0xF8`
	`cpi r16, MT_SLA_ACK`
	`brne ERROR`
		`if ((TWSR & 0xF8) != MT_SLA_ACK)`
		`ERROR();`
			Check value of TWI Status Register. Mask prescaler bits. If status different from MT_SLA_ACK go to ERROR

	`ldi r16, DATA`
	`out TWDR, r16`
	`ldi r16, (1<<TWINT) | (1<<TWEN)`
	`out TWCR, r16`
		`TWDR = DATA;`
		`TWCR = (1<<TWINT) | (1<<TWEN);`
			Load DATA into TWDR Register. Clear TWINT bit in TWCR to start transmission of data

6	`wait3:`
	`in r16,TWCR`
	`sbrs r16,TWINT`
	`rjmp wait3`
		`while (!(TWCR & (1<<TWINT)))`
		`;`
			Wait for TWINT flag set. This indicates that the DATA has been transmitted, and ACK/NACK has been received

7	`in r16,TWSR`
	`andi r16, 0xF8`
	`cpi r16, MT_DATA_ACK`
	`brne ERROR`
		`if ((TWSR & 0xF8) != MT_DATA_ACK)`
		`ERROR();`
			Check value of TWI Status Register. Mask prescaler bits. If status different from MT_DATA_ACK go to ERROR

	`ldi r16, (1<<TWINT)|(1<<TWEN)| (1<<TWSTO)` `out TWCR, r16`	`TWCR = (1<<TWINT)|(1<<TWEN)| (1<<TWSTO);`	Transmit STOP condition

Note: 1. See "About code examples" on page 8.

27.7 Transmission modes

The TWI can operate in one of four major modes. These are named Master Transmitter (MT), Master Receiver (MR), Slave Transmitter (ST) and Slave Receiver (SR). Several of these modes can be used in the same application. As an example, the TWI can use MT mode to write data into a TWI EEPROM, MR mode to read the data back from the EEPROM. If other masters are present in the system, some of these might transmit data to the TWI, and then SR mode would be used. It is the application software that decides which modes are legal.

The following sections describe each of these modes. Possible status codes are described along with figures detailing data transmission in each of the modes. These figures contain the following abbreviations:

S:	START condition
Rs:	REPEATED START condition
R:	Read bit (high level at SDA)
W:	Write bit (low level at SDA)
A:	Acknowledge bit (low level at SDA)
$\overline{\mathbf{A}}$:	Not acknowledge bit (high level at SDA)
Data:	8-bit data byte
P:	STOP condition
SLA:	Slave Address

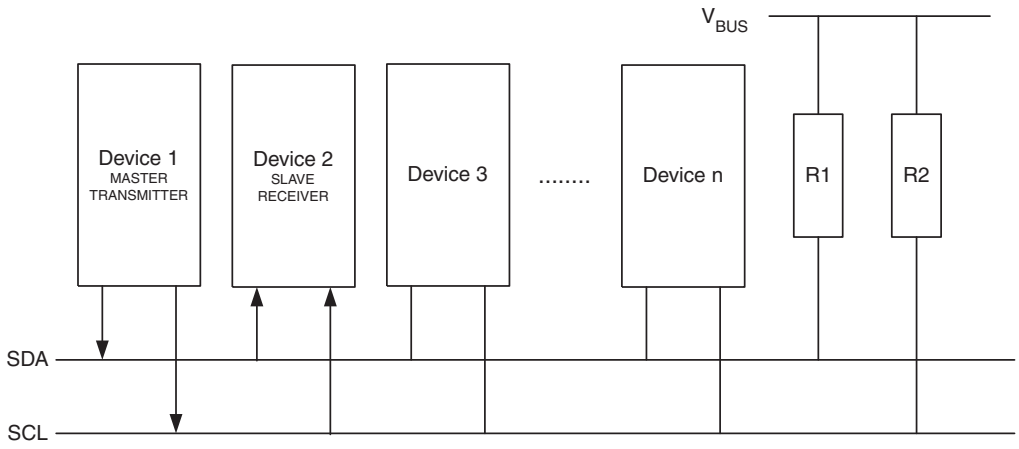
In Figure 27-12 on page 168 to Figure 27-18 on page 177, circles are used to indicate that the TWINT flag is set. The numbers in the circles show the status code held in TWSR, with the prescaler bits masked to zero. At these points, actions must be taken by the application to continue or complete the TWI transfer. The TWI transfer is suspended until the TWINT flag is cleared by software.

When the TWINT flag is set, the status code in TWSR is used to determine the appropriate software action. For each status code, the required software action and details of the following serial transfer are given in Table 27-2 on page 167 to Table 27-5 on page 176. Note that the prescaler bits are masked to zero in these tables.

27.7.1 Master Transmitter mode

In the Master Transmitter mode, a number of data bytes are transmitted to a slave receiver (see Figure 27-11 on page 166). In order to enter a Master mode, a START condition must be transmitted. The format of the following address packet determines whether Master Transmitter or Master Receiver mode is to be entered. If SLA+W is transmitted, MT mode is entered, if SLA+R is transmitted, MR mode is entered. All the status codes mentioned in this section assume that the prescaler bits are zero or are masked to zero.

Figure 27-11. Data transfer in the Master Transmitter mode.



A START condition is sent by writing the following value to TWCR:

TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE
Value	1	X	1	0	X	1	0	X

TWEN must be set to enable the Two-wire Serial Interface, TWSTA must be written to one to transmit a START condition and TWINT must be written to one to clear the TWINT flag. The TWI will then test the Two-wire Serial Bus and generate a START condition as soon as the bus becomes free. After a START condition has been transmitted, the TWINT flag is set by hardware, and the status code in TWSR will be 0x08 (see Table 27-2 on page 167). In order to enter MT mode, SLA+W must be transmitted. This is done by writing SLA+W to TWDR. Thereafter the TWINT bit should be cleared (by writing it to one) to continue the transfer. This is accomplished by writing the following value to TWCR:

TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE
Value	1	X	0	0	X	1	0	X

When SLA+W have been transmitted and an acknowledgment bit has been received, TWINT is set again and a number of status codes in TWSR are possible. Possible status codes in Master mode are 0x18, 0x20, or 0x38. The appropriate action to be taken for each of these status codes is detailed in Table 27-2 on page 167.

When SLA+W has been successfully transmitted, a data packet should be transmitted. This is done by writing the data byte to TWDR. TWDR must only be written when TWINT is high. If not, the access will be discarded, and the Write Collision bit (TWWC) will be set in the TWCR Register. After updating TWDR, the TWINT bit should be cleared (by writing it to one) to continue the transfer. This is accomplished by writing the following value to TWCR:

TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE
Value	1	X	0	0	X	1	0	X

This scheme is repeated until the last byte has been sent and the transfer is ended by generating a STOP condition or a repeated START condition. A STOP condition is generated by writing the following value to TWCR:

TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE
Value	1	X	0	1	X	1	0	X

A REPEATED START condition is generated by writing the following value to TWCR:

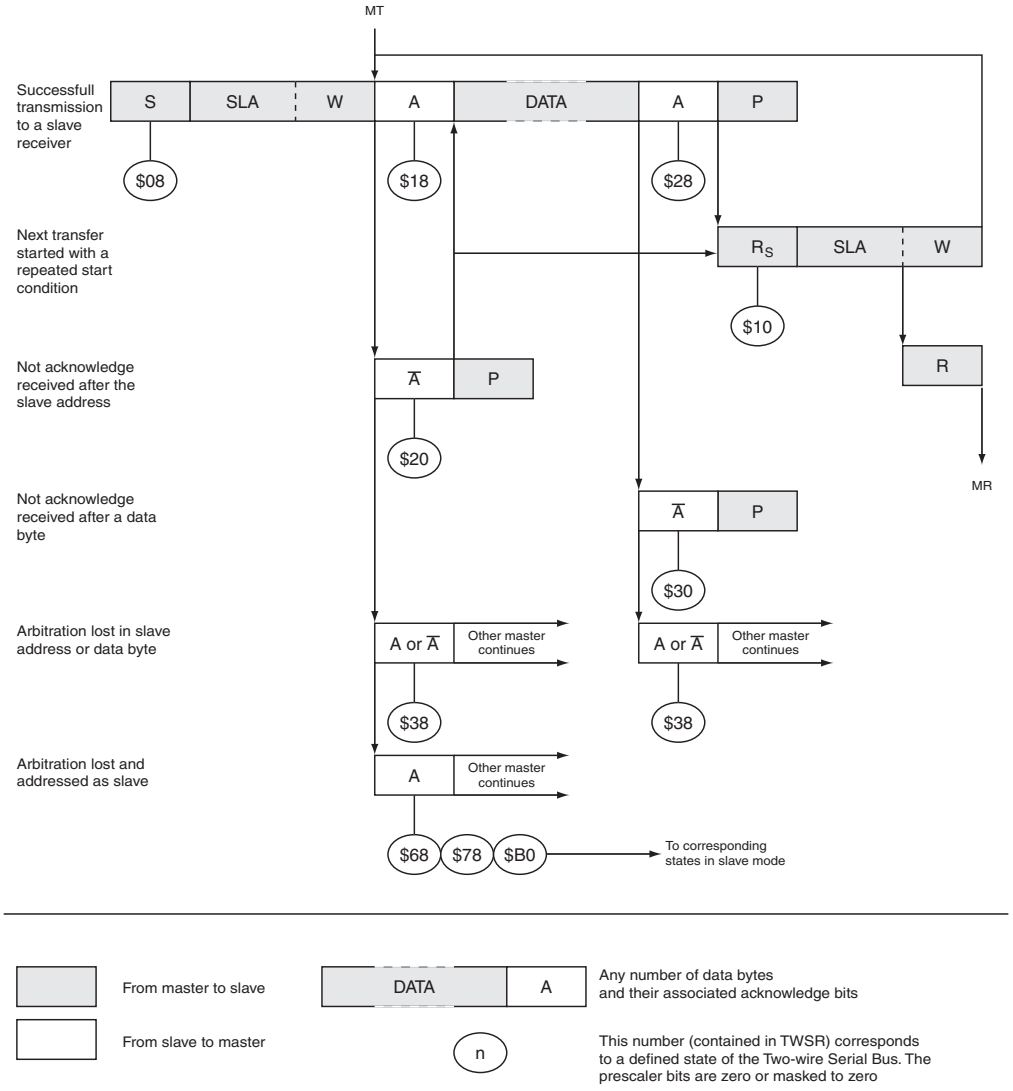
TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE
Value	1	X	1	0	X	1	0	X

After a repeated START condition (state 0x10) the Two-wire Serial Interface can access the same slave again, or a new slave without transmitting a STOP condition. Repeated START enables the master to switch between slaves, Master Transmitter mode and Master Receiver mode without losing control of the bus.

Table 27-2. Status codes for Master Transmitter mode.

Status code (TWSR) prescaler bits are 0	Status of the two-wire serial bus and two-wire serial interface hardware	Application software response					Next action taken by TWI hardware
		To/from TWDR	To TWCR STA	To TWCR STO	To TWCR TWINT	To TWCR TWEA	
0x08	A START condition has been transmitted	Load SLA+W	X	0	1	X	SLA+W will be transmitted; ACK or NOT ACK will be received
0x10	A repeated START condition has been transmitted	Load SLA+W or	X	0	1	X	SLA+W will be transmitted; ACK or NOT ACK will be received
		Load SLA+R	X	0	1	X	SLA+R will be transmitted; Logic will switch to Master Receiver mode
0x18	SLA+W has been transmitted; ACK has been received	Load data byte or	0	0	1	X	Data byte will be transmitted and ACK or NOT ACK will be received
		No TWDR action or	1	0	1	X	Repeated START will be transmitted
		No TWDR action or	0	1	1	X	STOP condition will be transmitted and TWSTO flag will be reset
		No TWDR action	1	1	1	X	STOP condition followed by a START condition will be transmitted and TWSTO flag will be reset
0x20	SLA+W has been transmitted; NOT ACK has been received	Load data byte or	0	0	1	X	Data byte will be transmitted and ACK or NOT ACK will be received
		No TWDR action or	1	0	1	X	Repeated START will be transmitted
		No TWDR action or	0	1	1	X	STOP condition will be transmitted and TWSTO flag will be reset
		No TWDR action	1	1	1	X	STOP condition followed by a START condition will be transmitted and TWSTO flag will be reset
0x28	Data byte has been transmitted; ACK has been received	Load data byte or	0	0	1	X	Data byte will be transmitted and ACK or NOT ACK will be received
		No TWDR action or	1	0	1	X	Repeated START will be transmitted
		No TWDR action or	0	1	1	X	STOP condition will be transmitted and TWSTO flag will be reset
		No TWDR action	1	1	1	X	STOP condition followed by a START condition will be transmitted and TWSTO flag will be reset
0x30	Data byte has been transmitted; NOT ACK has been received	Load data byte or	0	0	1	X	Data byte will be transmitted and ACK or NOT ACK will be received
		No TWDR action or	1	0	1	X	Repeated START will be transmitted
		No TWDR action or	0	1	1	X	STOP condition will be transmitted and TWSTO flag will be reset
		No TWDR action	1	1	1	X	STOP condition followed by a START condition will be transmitted and TWSTO flag will be reset
0x38	Arbitration lost in SLA+W or data bytes	No TWDR action or	0	0	1	X	Two-wire Serial Bus will be released and not addressed slave mode entered
		No TWDR action	1	0	1	X	A START condition will be transmitted when the bus becomes free

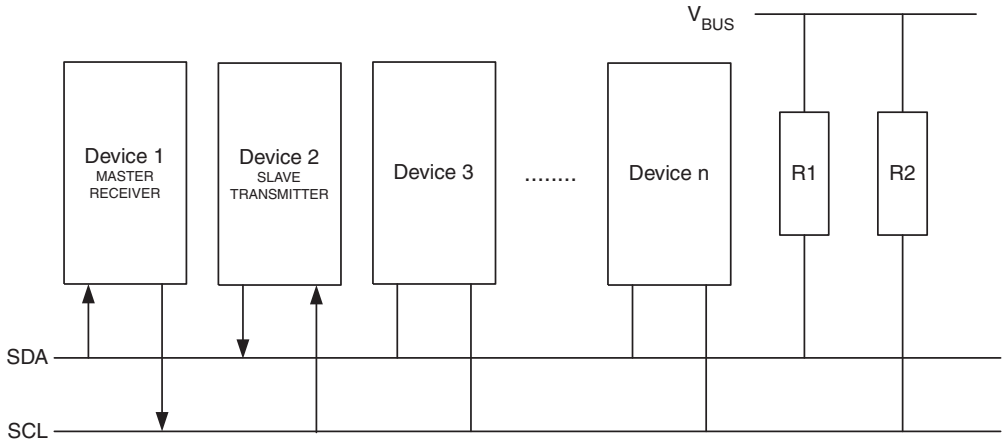
Figure 27-12. Formats and states in the Master Transmitter mode.



27.7.2 Master Receiver mode

In the Master Receiver mode, a number of data bytes are received from a slave transmitter (see Figure 27-13). In order to enter a Master mode, a START condition must be transmitted. The format of the following address packet determines whether Master Transmitter or Master Receiver mode is to be entered. If SLA+W is transmitted, MT mode is entered, if SLA+R is transmitted, MR mode is entered. All the status codes mentioned in this section assume that the prescaler bits are zero or are masked to zero.

Figure 27-13. Data transfer in Master Receiver mode.



A START condition is sent by writing the following value to TWCR:

TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE
Value	1	X	1	0	X	1	0	X

TWEN must be written to one to enable the Two-wire Serial Interface, TWSTA must be written to one to transmit a START condition and TWINT must be set to clear the TWINT flag. The TWI will then test the Two-wire Serial Bus and generate a START condition as soon as the bus becomes free. After a START condition has been transmitted, the TWINT flag is set by hardware, and the status code in TWSR will be 0x08 (see Table 27-2 on page 167). In order to enter MR mode, SLA+R must be transmitted. This is done by writing SLA+R to TWDR. Thereafter the TWINT bit should be cleared (by writing it to one) to continue the transfer. This is accomplished by writing the following value to TWCR:

TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE
Value	1	X	0	0	X	1	0	X

When SLA+R have been transmitted and an acknowledgment bit has been received, TWINT is set again and a number of status codes in TWSR are possible. Possible status codes in Master mode are 0x38, 0x40, or 0x48. The appropriate action to be taken for each of these status codes is detailed in Table 27-12 on page 168. Received data can be read from the TWDR Register when the TWINT flag is set high by hardware. This scheme is repeated until the last byte has been received. After the last byte has been received, the MR should inform the ST by sending a NACK after the last received data byte. The transfer is ended by generating a STOP condition or a repeated START condition.

A STOP condition is generated by writing the following value to TWCR:

TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE
Value	1	X	0	1	X	1	0	X

A REPEATED START condition is generated by writing the following value to TWCR:

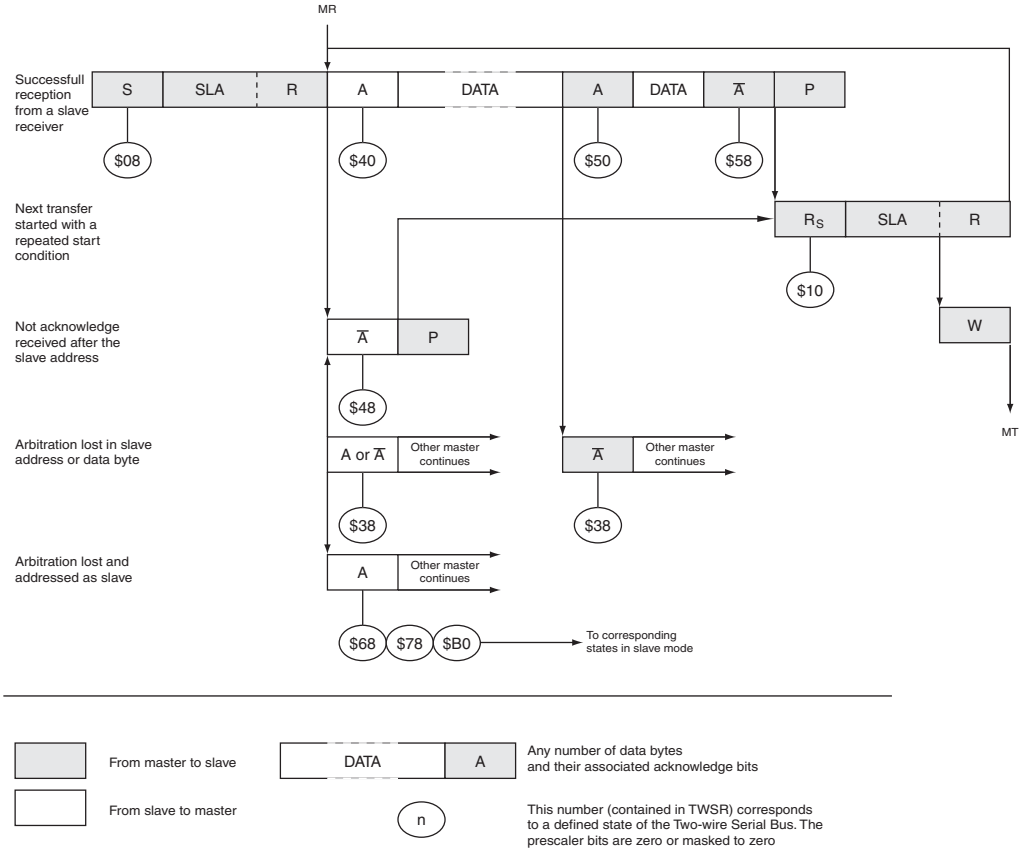
TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE
Value	1	X	1	0	X	1	0	X

After a repeated START condition (state 0x10) the Two-wire Serial Interface can access the same slave again, or a new slave without transmitting a STOP condition. Repeated START enables the master to switch between slaves, Master Transmitter mode and Master Receiver mode without losing control over the bus.

Table 27-3. Status codes for Master Receiver mode.

Status code (TWSR) prescaler bits are 0	Status of the two-wire serial bus and two-wire serial interface hardware	Application software response					Next action taken by TWI hardware
		To/from TWDR	To TWCR STA	STO	TWINT	TWEA	
0x08	A START condition has been transmitted	Load SLA+R	X	0	1	X	SLA+R will be transmitted ACK or NOT ACK will be received
0x10	A repeated START condition has been transmitted	Load SLA+R or	X	0	1	X	SLA+R will be transmitted ACK or NOT ACK will be received
		Load SLA+W	X	0	1	X	SLA+W will be transmitted Logic will switch to Master Transmitter mode
0x38	Arbitration lost in SLA+R or NOT ACK bit	No TWDR action or	0	0	1	X	Two-wire Serial Bus will be released and not addressed Slave mode will be entered
		No TWDR action	1	0	1	X	A START condition will be transmitted when the bus becomes free
0x40	SLA+R has been transmitted; ACK has been received	No TWDR action or	0	0	1	0	Data byte will be received and NOT ACK will be returned
		No TWDR action	0	0	1	1	Data byte will be received and ACK will be returned
0x48	SLA+R has been transmitted; NOT ACK has been received	No TWDR action or	1	0	1	X	Repeated START will be transmitted
		No TWDR action or	0	1	1	X	STOP condition will be transmitted and TWSTO flag will be reset
		No TWDR action	1	1	1	X	STOP condition followed by a START condition will be transmitted and TWSTO flag will be reset
0x50	Data byte has been received; ACK has been returned	Read data byte or	0	0	1	0	Data byte will be received and NOT ACK will be returned
		Read data byte	0	0	1	1	Data byte will be received and ACK will be returned
0x58	Data byte has been received; NOT ACK has been returned	Read data byte or	1	0	1	X	Repeated START will be transmitted
		Read data byte or	0	1	1	X	STOP condition will be transmitted and TWSTO flag will be reset
		Read data byte	1	1	1	X	STOP condition followed by a START condition will be transmitted and TWSTO flag will be reset

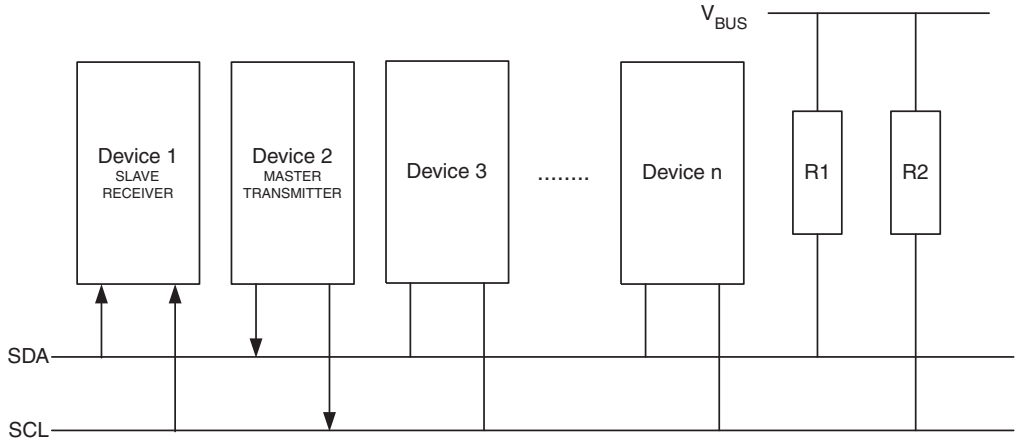
Figure 27-14. Formats and states in the Master Receiver mode.



27.7.3 Slave Receiver mode

In the Slave Receiver mode, a number of data bytes are received from a master transmitter (see Figure 27-15). All the status codes mentioned in this section assume that the prescaler bits are zero or are masked to zero.

Figure 27-15. Data transfer in Slave Receiver mode.



To initiate the Slave Receiver mode, TWAR and TWCR must be initialized as follows:

TWAR	TWA6	TWA5	TWA4	TWA3	TWA2	TWA1	TWA0	TWGCE
Value	Device's Own Slave Address							

The upper seven bits are the address to which the Two-wire Serial Interface will respond when addressed by a master. If the LSB is set, the TWI will respond to the general call address (0x00), otherwise it will ignore the general call address.

TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE
Value	0	1	0	0	0	1	0	X

TWEN must be written to one to enable the TWI. The TWEA bit must be written to one to enable the acknowledgment of the device's own slave address or the general call address. TWSTA and TWSTO must be written to zero.

When TWAR and TWCR have been initialized, the TWI waits until it is addressed by its own slave address (or the general call address if enabled) followed by the data direction bit. If the direction bit is "0" (write), the TWI will operate in SR mode, otherwise ST mode is entered. After its own slave address and the write bit have been received, the TWINT flag is set and a valid status code can be read from TWSR. The status code is used to determine the appropriate software action. The appropriate action to be taken for each status code is detailed in Table 27-4 on page 173. The Slave Receiver mode may also be entered if arbitration is lost while the TWI is in the Master mode (see states 0x68 and 0x78).

If the TWEA bit is reset during a transfer, the TWI will return a "Not Acknowledge" ("1") to SDA after the next received data byte. This can be used to indicate that the slave is not able to receive any more bytes. While TWEA is zero, the TWI does not acknowledge its own slave address. However, the Two-wire Serial Bus is still monitored and address recognition may resume at any time by setting TWEA. This implies that the TWEA bit may be used to temporarily isolate the TWI from the Two-wire Serial Bus.

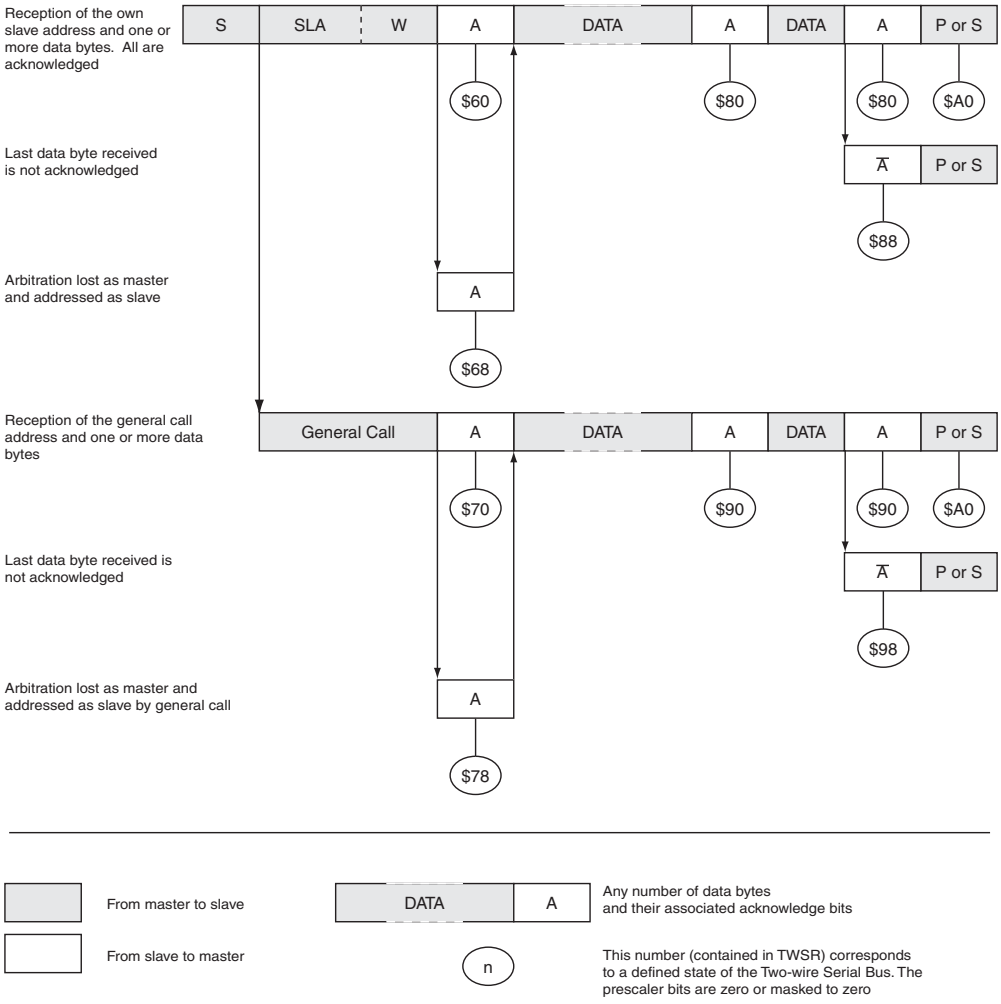
In all sleep modes other than Idle mode, the clock system to the TWI is turned off. If the TWEA bit is set, the interface can still acknowledge its own slave address or the general call address by using the Two-wire Serial Bus clock as a clock source. The part will then wake-up from sleep and the TWI will hold the SCL clock low during the wake up and until the TWINT flag is cleared (by writing it to one). Further data reception will be carried out as normal, with the AVR clocks running as normal. Observe that if the AVR is set up with a long start-up time, the SCL line may be held low for a long time, blocking other data transmissions.

Note that the Two-wire Serial Interface Data Register – TWDR does not reflect the last byte present on the bus when waking up from these Sleep modes.

Table 27-4. Status codes for Slave Receiver mode.

Status code (TWSR) prescaler bits are 0	Status of the two-wire serial bus and two-wire serial interface hardware	Application software response					Next action taken by TWI hardware
		To/from TWDR	To TWCR STA	STO	TWINT	TWEA	
0x60	Own SLA+W has been received; ACK has been returned	No TWDR action or	X	0	1	0	Data byte will be received and NOT ACK will be returned
		No TWDR action	X	0	1	1	Data byte will be received and ACK will be returned
0x68	Arbitration lost in SLA+R/W as master; own SLA+W has been received; ACK has been returned	No TWDR action or	X	0	1	0	Data byte will be received and NOT ACK will be returned
		No TWDR action	X	0	1	1	Data byte will be received and ACK will be returned
0x70	General call address has been received; ACK has been returned	No TWDR action or	X	0	1	0	Data byte will be received and NOT ACK will be returned
		No TWDR action	X	0	1	1	Data byte will be received and ACK will be returned
0x78	Arbitration lost in SLA+R/W as master; General call address has been received; ACK has been returned	No TWDR action or	X	0	1	0	Data byte will be received and NOT ACK will be returned
		No TWDR action	X	0	1	1	Data byte will be received and ACK will be returned
0x80	Previously addressed with own SLA+W; data has been received; ACK has been returned	Read data byte or	X	0	1	0	Data byte will be received and NOT ACK will be returned
		Read data byte	X	0	1	1	Data byte will be received and ACK will be returned
0x88	Previously addressed with own SLA+W; data has been received; NOT ACK has been returned	Read data byte or	0	0	1	0	Switched to the not addressed Slave mode; no recognition of own SLA or GCA
		Read data byte or	0	0	1	1	Switched to the not addressed Slave mode; own SLA will be recognized; GCA will be recognized if TWGCE = “1”
		Read data byte or	1	0	1	0	Switched to the not addressed Slave mode; no recognition of own SLA or GCA; a START condition will be transmitted when the bus becomes free
		Read data byte	1	0	1	1	Switched to the not addressed Slave mode; own SLA will be recognized; GCA will be recognized if TWGCE = “1”; a START condition will be transmitted when the bus becomes free
0x90	Previously addressed with general call; data has been received; ACK has been returned	Read data byte or	X	0	1	0	Data byte will be received and NOT ACK will be returned
		Read data byte	X	0	1	1	Data byte will be received and ACK will be returned
0x98	Previously addressed with general call; data has been received; NOT ACK has been returned	Read data byte or	0	0	1	0	Switched to the not addressed Slave mode; no recognition of own SLA or GCA
		Read data byte or	0	0	1	1	Switched to the not addressed Slave mode; own SLA will be recognized; GCA will be recognized if TWGCE = “1”
		Read data byte or	1	0	1	0	Switched to the not addressed Slave mode; no recognition of own SLA or GCA; a START condition will be transmitted when the bus becomes free
		Read data byte	1	0	1	1	Switched to the not addressed Slave mode; own SLA will be recognized; GCA will be recognized if TWGCE = “1”; a START condition will be transmitted when the bus becomes free
0xA0	A STOP condition or repeated START condition has been received while still addressed as slave	Read data byte or	0	0	1	0	Switched to the not addressed Slave mode; no recognition of own SLA or GCA
		Read data byte or	0	0	1	1	Switched to the not addressed Slave mode; own SLA will be recognized; GCA will be recognized if TWGCE = “1”
		Read data byte or	1	0	1	0	Switched to the not addressed Slave mode; no recognition of own SLA or GCA; a START condition will be transmitted when the bus becomes free
		Read data byte	1	0	1	1	Switched to the not addressed Slave mode; own SLA will be recognized; GCA will be recognized if TWGCE = “1”; a START condition will be transmitted when the bus becomes free

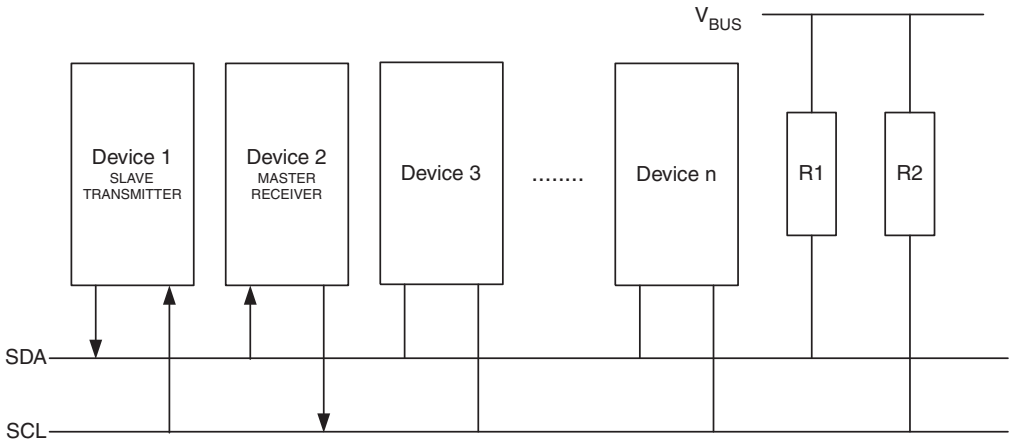
Figure 27-16. Formats and states in the Slave Receiver mode.



27.7.4 Slave Transmitter mode

In the Slave Transmitter mode, a number of data bytes are transmitted to a master receiver (see Figure 27-17). All the status codes mentioned in this section assume that the prescaler bits are zero or are masked to zero.

Figure 27-17. Data Transfer in Slave Transmitter Mode.



To initiate the Slave Transmitter mode, TWAR and TWCR must be initialized as follows:

TWAR	TWA6	TWA5	TWA4	TWA3	TWA2	TWA1	TWA0	TWGCE
Value	Device's Own Slave Address							

The upper seven bits are the address to which the Two-wire Serial Interface will respond when addressed by a master. If the LSB is set, the TWI will respond to the general call address (0x00), otherwise it will ignore the general call address.

TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE
Value	0	1	0	0	0	1	0	X

TWEN must be written to one to enable the TWI. The TWEA bit must be written to one to enable the acknowledgment of the device's own slave address or the general call address. TWSTA and TWSTO must be written to zero.

When TWAR and TWCR have been initialized, the TWI waits until it is addressed by its own slave address (or the general call address if enabled) followed by the data direction bit. If the direction bit is "1" (read), the TWI will operate in ST mode, otherwise SR mode is entered. After its own slave address and the write bit have been received, the TWINT flag is set and a valid status code can be read from TWSR. The status code is used to determine the appropriate software action. The appropriate action to be taken for each status code is detailed in Table 27-5 on page 176. The Slave Transmitter mode may also be entered if arbitration is lost while the TWI is in the Master mode (see state 0xB0).

If the TWEA bit is written to zero during a transfer, the TWI will transmit the last byte of the transfer. State 0xC0 or state 0xC8 will be entered, depending on whether the master receiver transmits a NACK or ACK after the final byte. The TWI is switched to the not addressed Slave mode, and will ignore the master if it continues the transfer. Thus the master receiver receives all "1" as serial data. State 0xC8 is entered if the master demands additional data bytes (by transmitting ACK), even though the slave has transmitted the last byte (TWEA zero and expecting NACK from the master).

While TWEA is zero, the TWI does not respond to its own slave address. However, the Two-wire Serial Bus is still monitored and address recognition may resume at any time by setting TWEA. This implies that the TWEA bit may be used to temporarily isolate the TWI from the Two-wire Serial Bus.

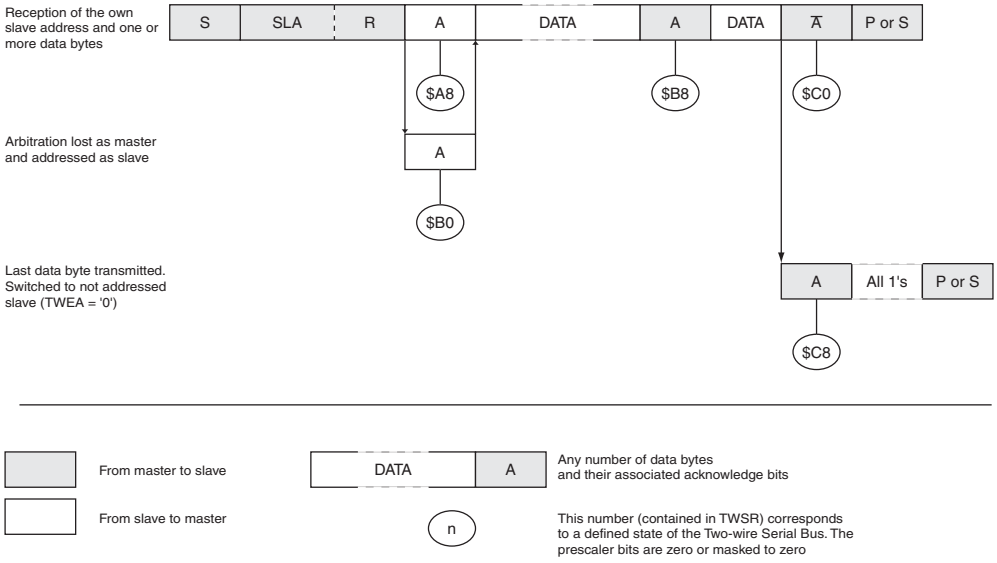
In all sleep modes other than Idle mode, the clock system to the TWI is turned off. If the TWEA bit is set, the interface can still acknowledge its own slave address or the general call address by using the Two-wire Serial Bus clock as a clock source. The part will then wake up from sleep and the TWI will hold the SCL clock will low during the wake up and until the TWINT flag is cleared (by writing it to one). Further data transmission will be carried out as normal, with the AVR clocks running as normal. Observe that if the AVR is set up with a long start-up time, the SCL line may be held low for a long time, blocking other data transmissions.

Note that the Two-wire Serial Interface Data Register – TWDR – does not reflect the last byte present on the bus when waking up from these sleep modes.

Table 27-5. Status codes for Slave Transmitter mode.

Status code (TWSR) prescaler bits are 0	Status of the two-wire serial bus and two-wire serial interface hardware	Application software response					Next action taken by TWI hardware
		To/from TWDR	To TWCR				
			STA	STO	TWINT	TWEA	
0xA8	Own SLA+R has been received; ACK has been returned	Load data byte or	X	0	1	0	Last data byte will be transmitted and NOT ACK should be received
		Load data byte	X	0	1	1	Data byte will be transmitted and ACK should be received
0xB0	Arbitration lost in SLA+R/W as master; own SLA+R has been received; ACK has been returned	Load data byte or	X	0	1	0	Last data byte will be transmitted and NOT ACK should be received
		Load data byte	X	0	1	1	Data byte will be transmitted and ACK should be received
0xB8	Data byte in TWDR has been transmitted; ACK has been received	Load data byte or	X	0	1	0	Last data byte will be transmitted and NOT ACK should be received
		Load data byte	X	0	1	1	Data byte will be transmitted and ACK should be received
0xC0	Data byte in TWDR has been transmitted; NOT ACK has been received	No TWDR action or	0	0	1	0	Switched to the not addressed Slave mode; no recognition of own SLA or GCA
		No TWDR action or	0	0	1	1	Switched to the not addressed Slave mode; own SLA will be recognized; GCA will be recognized if TWGCE = “1”
		No TWDR action or	1	0	1	0	Switched to the not addressed Slave mode; no recognition of own SLA or GCA; a START condition will be transmitted when the bus becomes free
		No TWDR action	1	0	1	1	Switched to the not addressed Slave mode; own SLA will be recognized; GCA will be recognized if TWGCE = “1”; a START condition will be transmitted when the bus becomes free
0xC8	Last data byte in TWDR has been transmitted (TWEA = “0”); ACK has been received	No TWDR action or	0	0	1	0	Switched to the not addressed Slave mode; no recognition of own SLA or GCA
		No TWDR action or	0	0	1	1	Switched to the not addressed Slave mode; own SLA will be recognized; GCA will be recognized if TWGCE = “1”
		No TWDR action or	1	0	1	0	Switched to the not addressed Slave mode; no recognition of own SLA or GCA; a START condition will be transmitted when the bus becomes free
		No TWDR action	1	0	1	1	Switched to the not addressed Slave mode; own SLA will be recognized; GCA will be recognized if TWGCE = “1”; a START condition will be transmitted when the bus becomes free

Figure 27-18. Formats and states in the Slave Transmitter mode.



27.7.5 Miscellaneous states

There are two status codes that do not correspond to a defined TWI state, see Table 27-6.

Status 0xF8 indicates that no relevant information is available because the TWINT flag is not set. This occurs between other states, and when the TWI is not involved in a serial transfer.

Status 0x00 indicates that a bus error has occurred during a Two-wire Serial Bus transfer. A bus error occurs when a START or STOP condition occurs at an illegal position in the format frame. Examples of such illegal positions are during the serial transfer of an address byte, a data byte, or an acknowledge bit. When a bus error occurs, TWINT is set. To recover from a bus error, the TWSTO flag must set and TWINT must be cleared by writing a logic one to it. This causes the TWI to enter the not addressed Slave mode and to clear the TWSTO flag (no other bits in TWCR are affected). The SDA and SCL lines are released, and no STOP condition is transmitted.

Table 27-6. Miscellaneous states.

Status code (TWSR) prescaler bits are 0	Status of the two-wire serial bus and two-wire serial interface hardware	Application software response					Next action taken by TWI hardware
		To/from TWDR	To TWCR				
			STA	STO	TWINT	TWEA	
0xF8	No relevant state information available; TWINT = “0”	No TWDR action	No TWCR action				Wait or proceed current transfer
0x00	Bus error due to an illegal START or STOP condition	No TWDR action	0	1	1	X	Only the internal hardware is affected, no STOP condition is sent on the bus. In all cases, the bus is released and TWSTO is cleared.

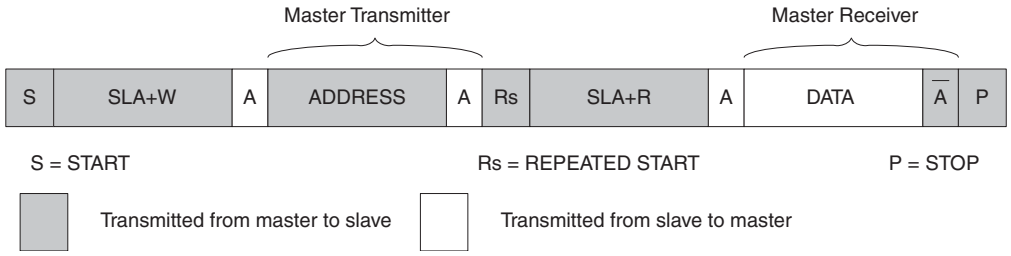
27.7.6 Combining several TWI modes

In some cases, several TWI modes must be combined in order to complete the desired action. Consider for example reading data from a serial EEPROM. Typically, such a transfer involves the following steps:

1. The transfer must be initiated.
2. The EEPROM must be instructed what location should be read.
3. The reading must be performed.
4. The transfer must be finished.

Note that data is transmitted both from Master to Slave and vice versa. The Master must instruct the slave what location it wants to read, requiring the use of the MT mode. Subsequently, data must be read from the slave, implying the use of the MR mode. Thus, the transfer direction must be changed. The Master must keep control of the bus during all these steps, and the steps should be carried out as an atomic operation. If this principle is violated in a multi-master system, another master can alter the data pointer in the EEPROM between steps 2 and 3, and the master will read the wrong data location. Such a change in transfer direction is accomplished by transmitting a REPEATED START between the transmission of the address byte and reception of the data. After a REPEATED START, the master keeps ownership of the bus. The following figure shows the flow in this transfer.

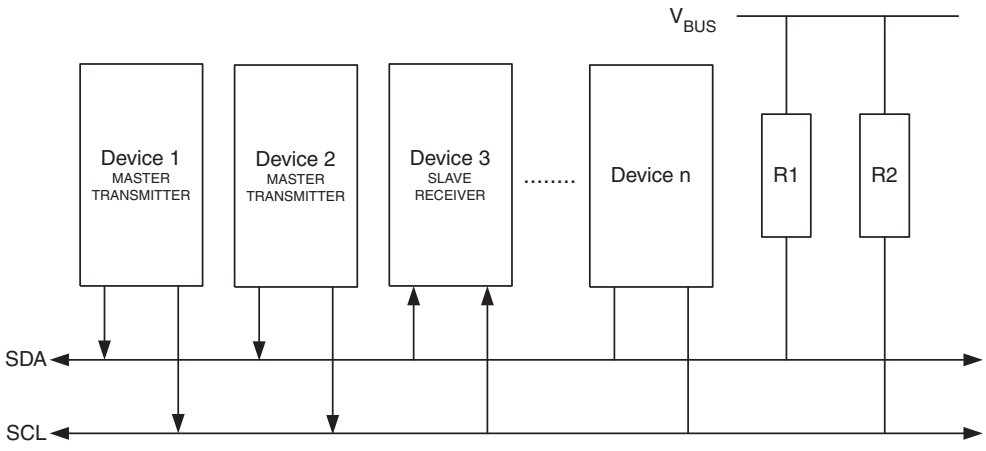
Figure 27-19. Combining Several TWI Modes to Access a Serial EEPROM.



27.8 Multi-master systems and arbitration

If multiple masters are connected to the same bus, transmissions may be initiated simultaneously by one or more of them. The TWI standard ensures that such situations are handled in such a way that one of the masters will be allowed to proceed with the transfer, and that no data will be lost in the process. An example of an arbitration situation is depicted below, where two masters are trying to transmit data to a slave receiver.

Figure 27-20. An arbitration example.



Several different scenarios may arise during arbitration, as described below:

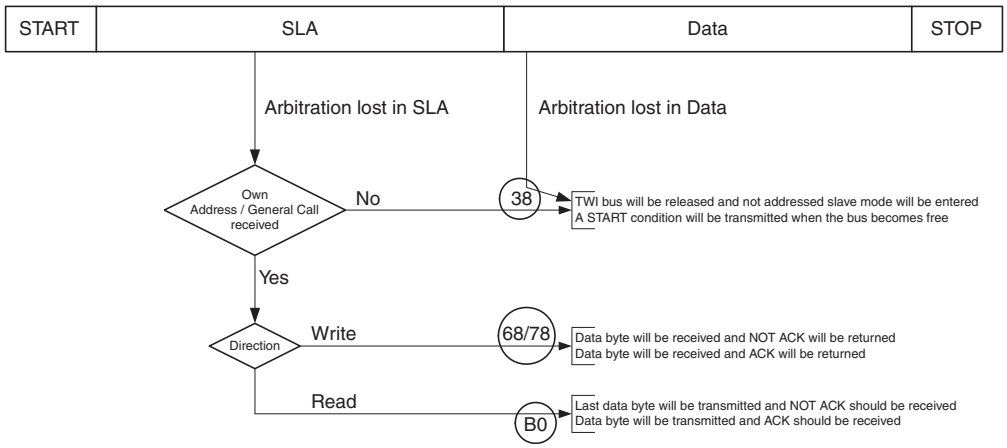
- Two or more masters are performing identical communication with the same slave. In this case, neither the slave nor any of the masters will know about the bus contention
- Two or more masters are accessing the same slave with different data or direction bit. In this case, arbitration will occur, either in the READ/WRITE bit or in the data bits. The masters trying

to output a one on SDA while another master outputs a zero will lose the arbitration. Losing masters will switch to not addressed Slave mode or wait until the bus is free and transmit a new START condition, depending on application software action

- Two or more masters are accessing different slaves. In this case, arbitration will occur in the SLA bits. Masters trying to output a one on SDA while another master outputs a zero will lose the arbitration. Masters losing arbitration in SLA will switch to Slave mode to check if they are being addressed by the winning master. If addressed, they will switch to SR or ST mode, depending on the value of the READ/WRITE bit. If they are not being addressed, they will switch to not addressed Slave mode or wait until the bus is free and transmit a new START condition, depending on application software action

This is summarized in Figure 27-21. Possible status values are given in circles.

Figure 27-21. Possible status codes caused by arbitration.



27.9 Bus connect/disconnect for two-wire serial interface

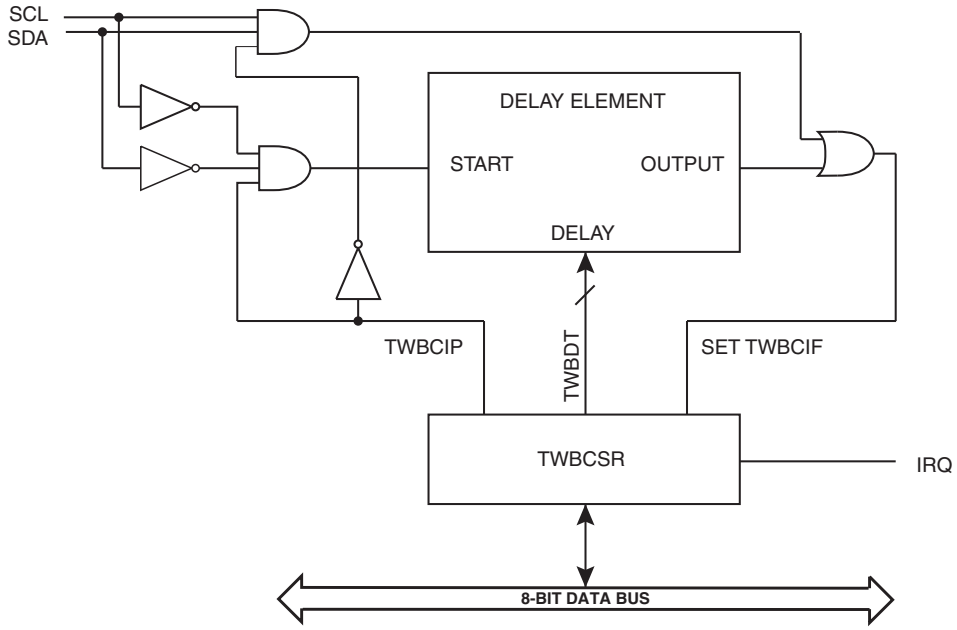
The Bus Connect/Disconnect module is an addition to the TWI Interface. Based on a configuration bit, an interrupt can be generated either when the TWI bus is connected or disconnected.

Figure 27-22 on page 180 illustrates the Bus Connect/Disconnect logic, where SDA and SCL are the TWI data and clock lines, respectively.

When the TWI bus is connected, both the SDA and the SCL lines will become high simultaneously. If the TWBCIP bit is cleared, the interrupt will be executed if enabled. Once the bus is connected, the TWBCIP bit should be set. This enables detection of when the bus is disconnected, and prevents repetitive interrupts every time both the SDA and SCL lines are high (for example bus IDLE state).

When the TWI bus is disconnected, both the SDA and the SCL lines will become low simultaneously. If the TWBCIP bit is set, the interrupt will be executed if enabled and if both lines remain low for a configurable time period. By adding this time constraint, unwanted interrupts caused by both lines going low during normal bus communication is prevented. Once the bus is disconnected, the TWBCIP bit should be cleared. This enables detection of when the bus is connected, and prevents repetitive interrupts if the SCL and SDA lines remain low.

Figure 27-22. Overview of bus connect/disconnect.



27.10 Register description

27.10.1 TWBR – TWI Bit Rate Register

Bit	7	6	5	4	3	2	1	0	
(0xB8)	TWBR7	TWBR6	TWBR5	TWBR4	TWBR3	TWBR2	TWBR1	TWBR0	TWBR
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:0 – TWI Bit Rate Register**

TWBR selects the division factor for the bit rate generator. The bit rate generator is a frequency divider which generates the SCL clock frequency in the Master modes. See ”Bit rate generator unit” on page 160 for calculating bit rates.

27.10.2 TWCR – TWI Control Register

Bit	7	6	5	4	3	2	1	0	
(0xBC)	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE	TWCR
Read/Write	R/W	R/W	R/W	R/W	R	R/W	R	R/W	
Initial Value	0	0	0	0	0	0	0	0	

The TWCR is used to control the operation of the TWI. It is used to enable the TWI, to initiate a Master access by applying a START condition to the bus, to generate a Receiver acknowledge, to generate a stop condition, and to control halting of the bus while the data to be written to the bus are written to the TWDR. It also indicates a write collision if data is attempted written to TWDR while the register is inaccessible.

- **Bit 7 – TWINT: TWI Interrupt Flag**

This bit is set by hardware when the TWI has finished its current job and expects application software response. If the I-bit in SREG and TWIE in TWCR are set, the MCU will jump to the TWI Interrupt Vector. While the TWINT flag is set, the SCL low period is stretched. The TWINT flag must be cleared by software by writing a logic one to it. Note that this flag is not automatically cleared by hardware when executing the interrupt routine. Also note that clearing this flag starts the operation of the TWI, so all accesses to the TWI Address Register (TWAR), TWI Status Register (TWSR), and TWI Data Register (TWDR) must be complete before clearing this flag.

- **Bit 6 – TWEA: TWI Enable Acknowledge Bit**

The TWEA bit controls the generation of the acknowledge pulse. If the TWEA bit is written to one, the ACK pulse is generated on the TWI bus if the following conditions are met:

1. The device’s own slave address has been received.
2. A general call has been received, while the TWGCE bit in the TWAR is set.
3. A data byte has been received in Master Receiver or Slave Receiver mode.

By writing the TWEA bit to zero, the device can be virtually disconnected from the Two-wire Serial Bus temporarily. Address recognition can then be resumed by writing the TWEA bit to one again.

- **Bit 5 – TWSTA: TWI START Condition Bit**

The application writes the TWSTA bit to one when it desires to become a Master on the Two-wire Serial Bus. The TWI hardware checks if the bus is available, and generates a START condition on the bus if it is free. However, if the bus is not free, the TWI waits until a STOP condition is detected, and then generates a new START condition to claim the Bus Master status. TWSTA is cleared by the TWI hardware when the START condition has been transmitted.

- **Bit 4 – TWSTO: TWI STOP Condition Bit**

Writing the TWSTO bit to one in Master mode will generate a STOP condition on the Two-wire Serial Bus. When the STOP condition is executed on the bus, the TWSTO bit is cleared automatically. In Slave mode, setting the TWSTO bit can be used to recover from an error condition. This will not generate a STOP condition, but the TWI returns to a well-defined unaddressed Slave mode and releases the SCL and SDA lines to a high impedance state.

- **Bit 3 – TWWC: TWI Write Collision Flag**

The TWWC bit is set when attempting to write to the TWI Data Register – TWDR when TWINT is low. This flag is cleared by writing the TWDR Register when TWINT is high.

- **Bit 2 – TWEN: TWI Enable Bit**

The TWEN bit enables TWI operation and activates the TWI interface. When TWEN is written to one, the TWI takes control over the I/O pins connected to the SCL and SDA pins, enabling the slew-rate limiters and spike filters. If this bit is written to zero, the TWI is switched off and all TWI transmissions are terminated, regardless of any ongoing operation.

- **Bit 1 – Reserved**

This bit is a reserved and will always read as zero.

- **Bit 0 – TWIE: TWI Interrupt Enable**

When this bit is written to one, and the I-bit in SREG is set, the TWI interrupt request will be activated for as long as the TWINT flag is high.

27.10.3 TWSR – TWI Status Register

Bit	7	6	5	4	3	2	1	0	
(0xB9)	TWS7	TWS6	TWS5	TWS4	TWS3	–	TWPS1	TWPS0	TWSR
Read/Write	R	R	R	R	R	R	R/W	R/W	
Initial Value	1	1	1	1	1	0	0	0	

- **Bits 7:3 – TWS: TWI Status**

These five bits reflect the status of the TWI logic and the Two-wire Serial Bus. The different status codes are described in Table 27-2 on page 167 through Table 27-5 on page 176. Note that the value read from TWSR contains both the 5-bit status value and the 2-bit prescaler value. The application designer should mask the prescaler bits to zero when checking the status bits. This makes status checking independent of prescaler setting. This approach is used in this datasheet, unless otherwise noted.

- **Bit 2 – Reserved**

This bit is reserved and will always read as zero.

- **Bits 1:0 – TWPS: TWI Prescaler Bits**

These bits can be read and written, and control the bit rate prescaler.

Table 27-7. TWI Bit rate prescaler.

TWPS1	TWPS0	Prescaler value
0	0	1
0	1	4
1	0	16
1	1	64

To calculate bit rates, see ”Bit rate generator unit” on page 160. The value of TWPS1:0 is used in the equation.

27.10.4 TWDR – TWI Data Register

Bit	7	6	5	4	3	2	1	0	
(0xBB)	TWD7	TWD6	TWD5	TWD4	TWD3	TWD2	TWD1	TWD0	TWDR
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	1	1	1	1	1	1	1	1	

In Transmit mode, TWDR contains the next byte to be transmitted. In Receive mode, the TWDR contains the last byte received. It is writable while the TWI is not in the process of shifting a byte. This occurs when the TWI Interrupt Flag (TWINT) is set by hardware. Note that the data register cannot be initialized by the user before the first interrupt occurs. The data in TWDR remains stable as long as TWINT is set. While data is shifted out, data on the bus is simultaneously shifted in. TWDR always contains the last byte present on the bus, except after a wake-up from a sleep mode by the TWI interrupt. In this case, the contents of TWDR is undefined. In the case of a lost bus arbitration, no data is lost in the transition from Master to Slave. Handling of the ACK bit is controlled automatically by the TWI logic, the CPU cannot access the ACK bit directly.

- **Bits 7:0 – TWD: TWI Data Register**

These eight bits constitute the next data byte to be transmitted, or the latest data byte received on the Two-wire Serial Bus.

27.10.5 TWAR – TWI (Slave) Address Register

Bit	7	6	5	4	3	2	1	0	
(0xBA)	TWA6	TWA5	TWA4	TWA3	TWA2	TWA1	TWA0	TWGCE	TWAR
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	1	1	1	1	1	1	1	0	

The TWAR should be loaded with the 7-bit slave address (in the seven most significant bits of TWAR) to which the TWI will respond when programmed as a slave transmitter or Receiver, and not needed in the Master modes. In multi-master systems, TWAR must be set in masters which can be addressed as slaves by other masters.

The LSB of TWAR is used to enable recognition of the general call address (0x00). There is an associated address comparator that looks for the slave address (or general call address if enabled) in the received serial address. If a match is found, an interrupt request is generated.

- **Bits 7:1 – TWA: TWI (Slave) Address Register**

These seven bits constitute the slave address of the TWI unit.

- **Bit 0 – TWGCE: TWI General Call Recognition Enable Bit**

If set, this bit enables the recognition of a General Call given over the Two-wire Serial Bus.

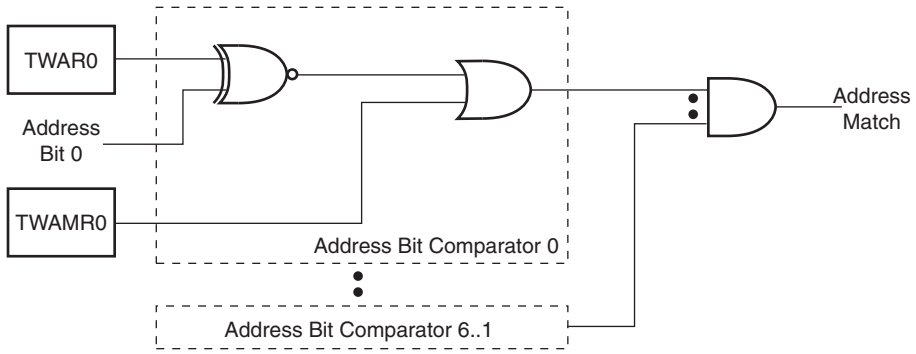
27.10.6 TWAMR – TWI (Slave) Address Mask Register

Bit	7	6	5	4	3	2	1	0	
(0xBD)	TWAM[6:0]							–	TWAMR
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R	
Initial Value	0	0	0	0	0	0	0	0	

- **Bits 7:1 – TWAM: TWI Address Mask**

The TWAMR can be loaded with a 7-bit Slave Address mask. Each of the bits in TWAMR can mask (disable) the corresponding address bits in the TWI Address Register (TWAR). If the mask bit is set to one then the address match logic ignores the compare between the incoming address bit and the corresponding bit in TWAR. Figure 27-23 shown the address match logic in detail.

Figure 27-23. TWI Address Match Logic, Block Diagram.



- **Bit 0 – Reserved**

This bit is an unused in the Atmel ATmega16HVB/32HVB, and will always read as zero.

27.10.7 TWBCSR – TWI Bus Control and Status Register

Bit	7	6	5	4	3	2	1	0	
(0xBE)	TWBCIF	TWBCIE	–	–	–	TWBDT1	TWBDT0	TWBCIP	TWBCSR
Read/Write	R/W	R/W	R	R	R	R/W	R/W	R/W	
Initial Value	X	0	0	0	0	0	0	0	

- **Bit 7 – TWBCIF: TWI Bus Connect/Disconnect Interrupt Flag**

Based on the TWBCIP bit, the TWBCIF bit is set when the TWI bus is connected or disconnected (1). TWBCIF is cleared by hardware when executing the corresponding interrupt handling vector. Alternatively, TWBCIF is cleared by writing a logic one to the flag. When the SREG I-bit, TWBCIE (TWI Bus Connect/Disconnect Interrupt Enable), and TWBCIF are set, the TWI Bus Connect/Disconnect Interrupt is executed. If both SDA and SCL are high during reset, TWBCIF will be set after reset. Otherwise TWBCIF will be cleared after reset.

Note: 1. The TWEN bit in the TWCR register must be set for the Bus Connect/Disconnect feature to be enabled.

- **Bit 6 – TWBCIE: TWI Bus Connect/Disconnect Interrupt Enable**

When the TWBCIE bit and the I-bit in the Status Register are set, the TWI Bus Connect/Disconnect Interrupt is enabled. The corresponding interrupt is executed if a TWI Bus Connect/Disconnect occurs, that is, when the TWBCIE bit is set.

- **Bit 5:3 – Reserved**

These bits are reserved in the Atmel ATmega16HVB/32HVB and will always read as zero.

- **Bit 2:1 – TWBDT1, TWBDT0: TWI Bus Disconnect Time-out Period**

The TWBDT bits decides how long both the TWI data (SDA) and clock (SCL) signals must be low before generating the TWI Bus Disconnect Interrupt. The different configuration values and their corresponding time-out periods are shown in Table 27-8.

Table 27-8. TW Bus disconnect time-out period.

TWBDT1	TWBDT0	TWI bus disconnect time-out period
0	0	250ms
0	1	500ms
1	0	1000ms
1	1	2000ms

- **Bit 0 – TWBCIP: TWI Bus Connect/Disconnect Interrupt Polarity**

The TWBCIP bit decide if the TWI Bus Connect/Disconnect Interrupt Flag (TWBCIF) should be set on a Bus Connect or a Bus Disconnect. If TWBCIP is cleared, the TWBCIF flag is set on a Bus Connect. If TWBCIP is set, the TWBCIF flag is set on a Bus Disconnect.

28. debugWIRE on-chip debug system

28.1 Features

- **Complete program flow control**
- **Emulates all øn-chip functions, both digital and analog, except RESET pin**
- **Real-time operation**
- **Symbolic debugging support (both at C and Assembler source level, or for other HLLs)**
- **Unlimited number of program break points (using software break points)**
- **Non-intrusive operation**
- **Electrical characteristics identical to real device**
- **Automatic configuration system**
- **High-speed operation**
- **Programming of non-volatile memories**

28.2 Overview

The debugWIRE On-chip debug system uses a One-wire, bi-directional interface to control the program flow, execute AVR instructions in the CPU and to program the different non-volatile memories.

28.3 Physical interface

When the debugWIRE Enable (DWEN) Fuse is programmed and Lock bits are unprogrammed, the debugWIRE system within the target device is activated. The RESET port pin is configured as a wire-AND (open-drain) bi-directional I/O pin with pull-up enabled and becomes the communication gateway between target and emulator.

Figure 28-1. The debugWIRE setup.

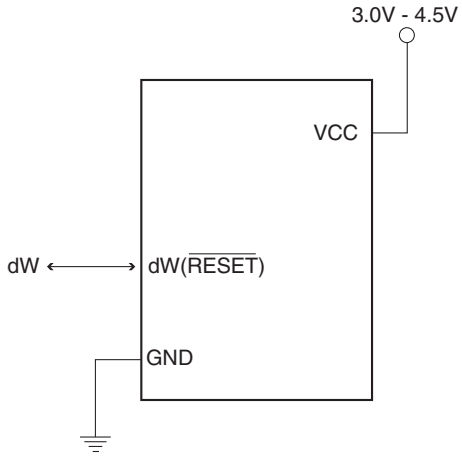


Figure 28-1 shows the schematic of a target MCU, with debugWIRE enabled, and the emulator connector. The system clock is not affected by debugWIRE and will always be the clock source selected by the OSCSEL Fuses.

When designing a system where debugWIRE will be used, the following observations must be made for correct operation:

- Pull-up resistors on the dW/(RESET) line must not be smaller than 10kΩ. The pull-up resistor is not required for debugWIRE functionality
- Connecting the RESET pin directly to V_{CC} will not work
- Capacitors connected to the RESET pin must be disconnected when using debugWire
- All external reset sources must be disconnected

28.4 Software break points

debugWIRE supports Program memory Break Points by the AVR Break instruction. Setting a Break Point in AVR Studio® will insert a BREAK instruction in the Program memory. The instruction replaced by the BREAK instruction will be stored. When program execution is continued, the stored instruction will be executed before continuing from the Program memory. A break can be inserted manually by putting the BREAK instruction in the program.

The Flash must be re-programmed each time a Break Point is changed. This is automatically handled by AVR Studio through the debugWIRE interface. The use of Break Points will therefore reduce the Flash Data retention. Devices used for debugging purposes should not be shipped to end customers.

28.5 Limitations of debugWIRE

The debugWIRE communication pin (dW) is physically located on the same pin as External Reset (RESET). An External Reset source is therefore not supported when the debugWIRE is enabled.

A programmed DWEN Fuse enables some parts of the clock system to be running in all sleep modes. This will increase the power consumption while in sleep. Thus, the DWEN Fuse should be disabled when debugWire is not used.

When using debugWIRE to access the flash (reading/writing), one must make sure the SPMCSR register is not locked from before. If SPMCSR is locked the result of the operation may not be as expected.

28.6 Register description

The following section describes the registers used with the debugWire.

28.6.1 DWDR – debugWire Data Register

Bit	7	6	5	4	3	2	1	0	
0x31 (0x51)	DWDR[7:0]								DWDR
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

The DWDR Register provides a communication channel from the running program in the MCU to the debugger. This register is only accessible by the debugWIRE and can therefore not be used as a general purpose register in the normal operations.

29. Boot loader support – Read-while-write self-programming

29.1 Features

- **Read-while-write self-programming**
- **Flexible boot memory size**
- **High security (separate boot lock bits for a flexible protection)**
- **Separate fuse to select reset vector**
- **Optimized page [1] size**
- **Code efficient algorithm**
- **Efficient read-modify-write support**

Note: 1. A page is a section in the Flash consisting of several bytes (see ”Page size” on page 207) used during programming. The page organization does not affect normal operation.

29.2 Overview

The Boot Loader Support provides a real Read-While-Write Self-Programming mechanism for downloading and uploading program code by the MCU itself. This feature allows flexible application software updates controlled by the MCU using a Flash-resident Boot Loader program. The Boot Loader program can use any available data interface and associated protocol to read code and write (program) that code into the Flash memory, or read the code from the program memory. The program code within the Boot Loader section has the capability to write into the entire Flash, including the Boot Loader memory. The Boot Loader can thus even modify itself, and it can also erase itself from the code if the feature is not needed anymore. The size of the Boot Loader memory is configurable with fuses and the Boot Loader has two separate sets of Boot Lock bits which can be set independently. This gives the user a unique flexibility to select different levels of protection.

29.3 Application and boot loader flash sections

The Flash memory is organized in two main sections, the Application section and the Boot Loader section. The size of the different sections is configured by the BOOTSZ Fuses as shown in Table 29-5 on page 200 and Figure 29-2 on page 191. These two sections can have different level of protection since they have different sets of Lock bits.

29.3.1 Application section

The Application section is the section of the Flash that is used for storing the application code. The protection level for the Application section can be selected by the application Boot Lock bits (Boot Lock bits 0), see Table 30-2 on page 204. The Application section can never store any Boot Loader code since the SPM instruction is disabled when executed from the Application section.

29.3.2 BLS – Boot loader section

While the Application section is used for storing the application code, the The Boot Loader software must be located in the BLS since the SPM instruction can initiate a programming when executing from the BLS only. The SPM instruction can access the entire Flash, including the BLS itself. The protection level for the Boot Loader section can be selected by the Boot Loader Lock bits (Boot Lock bits 1), see Table 30-2 on page 204.

29.4 Read-while-write and no read-while-write flash sections

Whether the CPU supports Read-While-Write or if the CPU is halted during a Boot Loader software update is dependent on which address that is being programmed. In addition to the two sections that are configurable by the BOOTSZ Fuses as described above, the Flash is also divided into two fixed sections, the Read-While-Write (RWW) section and the No Read-While-Write (NRWW) section. The limit between the RWW- and NRWW sections is given in Table 29-6 on page 200 and Figure 29-2 on page 191. The main difference between the two sections is:

- When erasing or writing a page located inside the RWW section, the NRWW section can be read during the operation
- When erasing or writing a page located inside the NRWW section, the CPU is halted during the entire operation

Note that the user software can never read any code that is located inside the RWW section during a Boot Loader software operation. The syntax “Read-While-Write section” refers to which section that is being programmed (erased or written), not which section that actually is being read during a Boot Loader software update.

29.4.1 RWW – Read-while-write section

If a Boot Loader software update is programming a page inside the RWW section, it is possible to read code from the Flash, but only code that is located in the NRWW section. During an ongoing programming, the software must ensure that the RWW section never is being read. If the user software is trying to read code that is located inside the RWW section (that is, by a call/jmp/lpm or an interrupt) during programming, the software might end up in an unknown state. To avoid this, the interrupts should either be disabled or moved to the Boot Loader section. The Boot Loader section is always located in the NRWW section. The RWW Section Busy bit (RWWSB) in the Store Program Memory Control and Status Register (SPMCSR) will be read as logical one as long as the RWW section is blocked for reading. After a programming is completed, the RWWSB must be cleared by software before reading code located in the RWW section. See ”SPMCSR – Store Program Memory Control and Status Register” on page 202 for details on how to clear RWWSB.

29.4.2 NRWW – No read-while-write section

The code located in the NRWW section can be read when the Boot Loader software is updating a page in the RWW section. When the Boot Loader code updates the NRWW section, the CPU is halted during the entire Page Erase or Page Write operation.

Table 29-1. Read-while-write features.

Which section does the Z-pointer address during the programming?	Which section can be read during programming?	CPU halted?	Read-while-write supported?
RWW section	NRWW section	No	Yes
NRWW section	None	Yes	No

Figure 29-1. Read-while-write vs. no read-while-write.

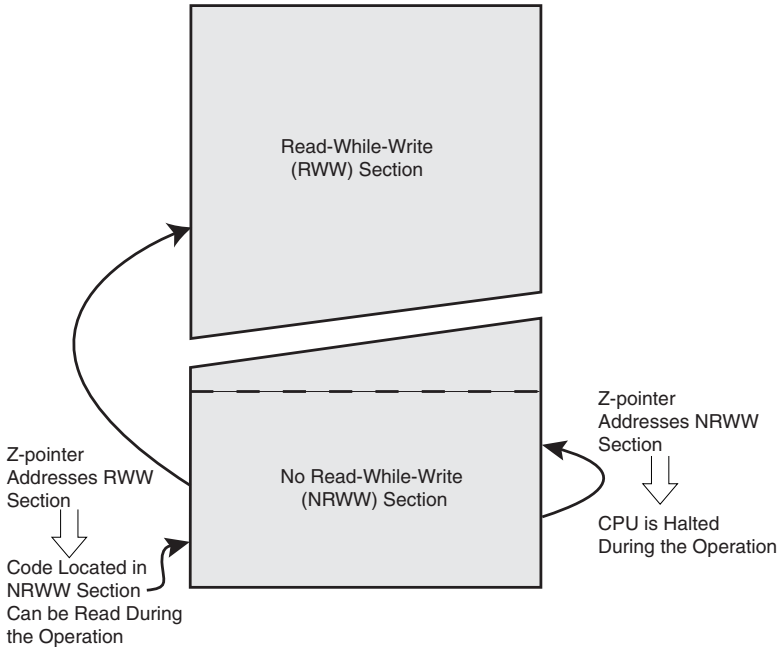
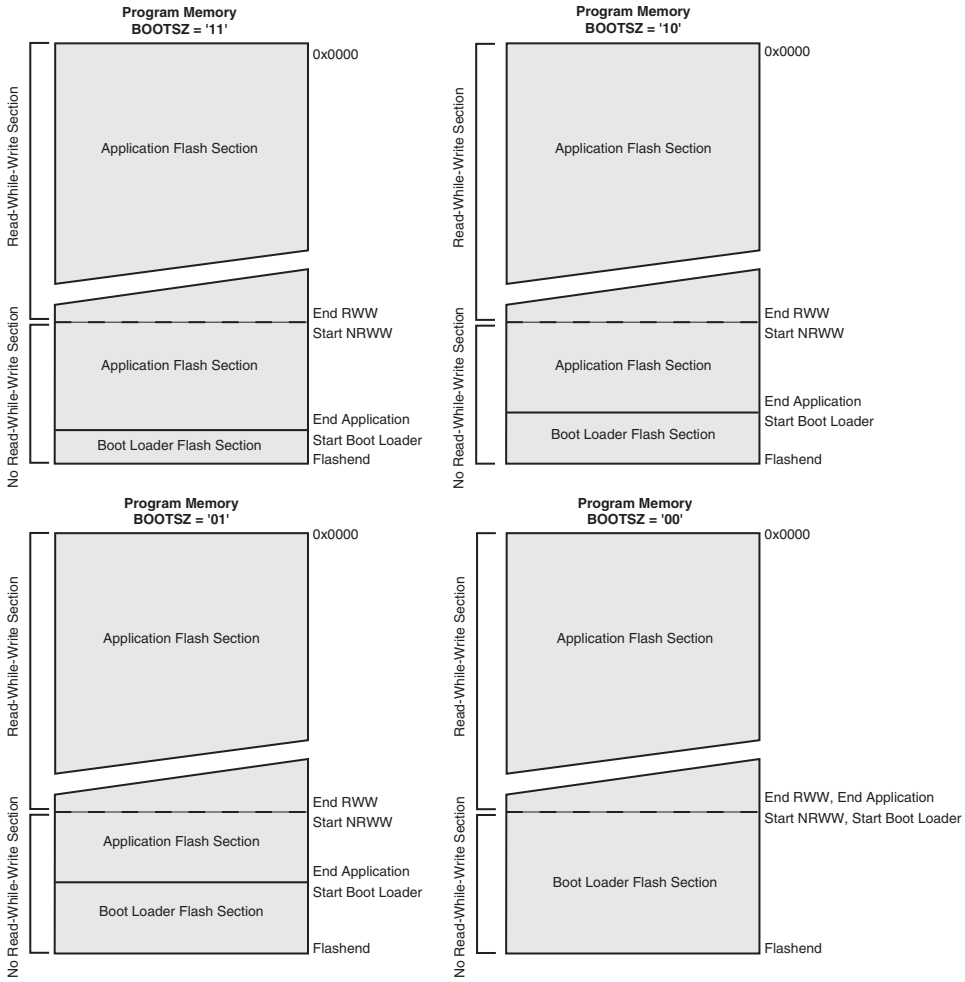


Figure 29-2. Memory sections.



Note: 1. The parameters in the figure above are given in Table 29-5 on page 200.

29.5 Boot loader lock bits

If no Boot Loader capability is needed, the entire Flash is available for application code. The Boot Loader has two separate sets of Boot Lock bits which can be set independently. This gives the user a unique flexibility to select different levels of protection.

The user can select:

- To protect the entire Flash from a software update by the MCU
- To protect only the Boot Loader Flash section from a software update by the MCU
- To protect only the Application Flash section from a software update by the MCU
- Allow software update in the entire Flash

See Table 30-2 on page 204 for further details. The Boot Lock bits can be set in software and in Serial or Parallel Programming mode, but they can be cleared by a Chip Erase command only. The general Write Lock (Lock Bit mode 2) does not control the programming of the Flash memory by SPM instruction. Similarly, the general Read/Write Lock (Lock Bit mode 1) does not control reading nor writing by LPM/SPM, if it is attempted.

29.6 Entering the boot loader program

Entering the Boot Loader takes place by a jump or call from the application program. This may be initiated by a trigger such as a command received via the TWI interface. Alternatively, the Boot Reset Fuse can be programmed so that the Reset Vector is pointing to the Boot Flash start address after a reset. In this case, the Boot Loader is started after a reset. After the application code is loaded, the program can start executing the application code. Note that the fuses cannot be changed by the MCU itself. This means that once the Boot Reset Fuse is programmed, the Reset Vector will always point to the Boot Loader Reset and the fuse can only be changed through the serial or parallel programming interface.

Table 29-2. Boot Reset Fuse [(1)].

BOOTRST	Reset address
1	Reset vector = Application reset (address 0x0000)
0	Reset vector = Boot loader reset (see Table 29-5 on page 200)

Note: 1. “1” means unprogrammed, “0” means programmed.

29.7 Addressing the flash during self-programming

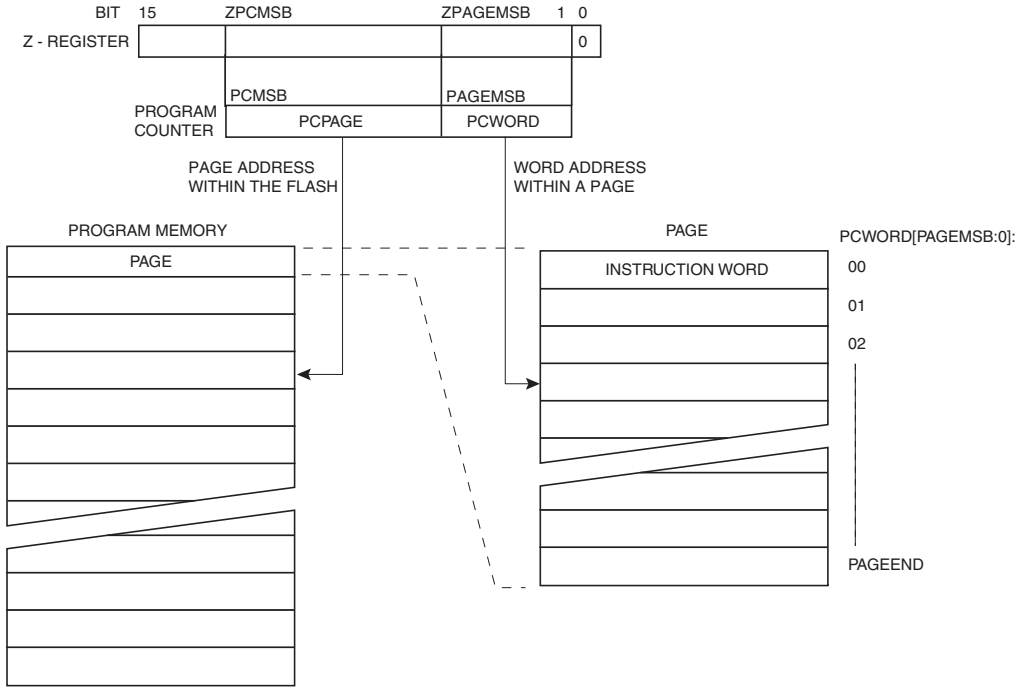
The Z-pointer is used to address the SPM commands.

Bit	15	14	13	12	11	10	9	8
ZH (R31)	**Z15**	**Z14**	**Z13**	**Z12**	**Z11**	**Z10**	**Z9**	**Z8**
ZL (R30)	**Z7**	**Z6**	**Z5**	**Z4**	**Z3**	**Z2**	**Z1**	**Z0**
	7	6	5	4	3	2	1	0

Since the Flash is organized in pages (see ”Fuse bits” on page 205), the Program Counter can be treated as having two different sections. One section, consisting of the least significant bits, is addressing the words within a page, while the most significant bits are addressing the pages. This is shown in Figure 29-3 on page 193. Note that the Page Erase and Page Write operations are addressed independently. Therefore it is of major importance that the Boot Loader software addresses the same page in both the Page Erase and Page Write operation. Once a programming operation is initiated, the address is latched and the Z-pointer can be used for other operations.

The only SPM operation that does not use the Z-pointer is Setting the Boot Loader Lock bits. The content of the Z-pointer is ignored and will have no effect on the operation. The LPM instruction does also use the Z-pointer to store the address. Since this instruction addresses the Flash byte-by-byte, also the LSB (bit Z0) of the Z-pointer is used.

Figure 29-3. Addressing the flash during SPM [1].



Note: 1. The different variables used in Figure 29-3 are listed in Table 29-7 on page 200 and Table 29-10 on page 201.

29.8 Self-programming the flash

The program memory is updated in a page by page fashion. Before programming a page with the data stored in the temporary page buffer, the page must be erased. The temporary page buffer is filled one word at a time using SPM and the buffer can be filled either before the Page Erase command or between a Page Erase and a Page Write operation:

Alternative one, fill the buffer before a Page Erase:

- Fill temporary page buffer
- Perform a Page Erase
- Perform a Page Write

Alternative two, fill the buffer after Page Erase:

- Perform a Page Erase
- Fill temporary page buffer
- Perform a Page Write

If only a part of the page needs to be changed, the rest of the page must be stored (for example in the temporary page buffer) before the erase, and then be rewritten. When using alternative 1, the Boot Loader provides an effective Read-Modify-Write feature which allows the user software to first read the page, do the necessary changes, and then write back the modified data. If alternative 2 is used, it is not possible to read the old data while loading since the page is already erased. The temporary page buffer can be accessed in a random sequence. It is essential that the page address used in both the Page Erase and Page Write operation is addressing the same page. See ”Simple assembly code example for a boot loader” on page 198 for an assembly code example.

29.8.1 Performing page erase by SPM

To execute Page Erase, set up the address in the Z-pointer, write “X0000011” to SPMCSR and execute SPM within four clock cycles after writing SPMCSR. The data in R1 and R0 is ignored. The page address must be written to PCPAGE in the Z-register. Other bits in the Z-pointer will be ignored during this operation.

- Page Erase to the RWW section: The NRWW section can be read during the Page Erase
- Page Erase to the NRWW section: The CPU is halted during the operation

29.8.2 Filling the temporary buffer (page loading)

To write an instruction word, set up the address in the Z-pointer and data in R1:R0, write “X0000001” to SPMCSR and execute SPM within four clock cycles after writing SPMCSR. The content of PCWORD in the Z-register is used to address the data in the temporary buffer. The temporary buffer will auto-erase after a Page Write operation or by writing the RWWSRE bit in SPMCSR. It is also erased after a system reset. Note that it is not possible to write more than one time to each address without erasing the temporary buffer.

29.8.3 Performing a page write

To execute Page Write, set up the address in the Z-pointer, write “X0000101” to SPMCSR and execute SPM within four clock cycles after writing SPMCSR. The data in R1 and R0 is ignored. The page address must be written to PCPAGE. Other bits in the Z-pointer will be ignored during this operation.

- Page Write to the RWW section: The NRWW section can be read during the Page Write
- Page Write to the NRWW section: The CPU is halted during the operation

29.8.4 Using the SPM interrupt

If the SPM interrupt is enabled, the SPM interrupt will generate a constant interrupt when the SPMEN bit in SPMCSR is cleared. This means that the interrupt can be used instead of polling the SPMCSR Register in software. When using the SPM interrupt, the Interrupt Vectors should be moved to the BLS section to avoid that an interrupt is accessing the RWW section when it is blocked for reading. How to move the interrupts is described in ”Interrupts” on page 52.

29.8.5 Consideration while updating BLS

Special care must be taken if the user allows the Boot Loader section to be updated by leaving Boot Lock bit11 unprogrammed. An accidental write to the Boot Loader itself can corrupt the entire Boot Loader, and further software updates might be impossible. If it is not necessary to change the Boot Loader software itself, it is recommended to program the Boot Lock bit11 to protect the Boot Loader software from any internal software changes.

29.8.6 Prevent reading the RWW section during self-programming

During Self-Programming (either Page Erase or Page Write), the RWW section is always blocked for reading. The user software itself must prevent that this section is addressed during the self programming operation. The RWWSB in the SPMCSR will be set as long as the RWW section is busy. During Self-Programming the Interrupt Vector table should be moved to the BLS as described in ”Interrupts” on page 52, or the interrupts must be disabled. Before addressing the RWW section after the programming is completed, the user software must clear the RWWSB by writing the RWWSRE. See ”Simple assembly code example for a boot loader” on page 198 for an example.

29.8.7 Setting the lock bits by SPM

To set the Lock bits, write the desired data to R0, write “X0001001” to SPMCSR and execute SPM within four clock cycles after writing SPMCSR.

Bit	7	6	5	4	3	2	1	0
R0	1	1	BLB12	BLB11	BLB02	BLB01	LB2	LB1

See Table 30-2 on page 204 for how the different settings of the Lock bits affect the Flash access.

If bits 5:0 in R0 are cleared (zero), the corresponding Lock bit will be programmed if an SPM instruction is executed within four cycles after LBSET and SPMEN are set in SPMCSR. The Z-pointer is don’t care during this operation, but for future compatibility it is recommended to load the Z-pointer with 0x0001 (same as used for reading the IO_{ck} bits). For future compatibility it is also recommended to set bits 7 and 6 in R0 to “1” when writing the Lock bits. When programming the Lock bits the entire Flash can be read during the operation.

29.8.8 Reading the fuse and lock bits from software

It is possible to read both the Fuse and Lock bits from software. To read the Lock bits, load the Z-pointer with 0x0001 and set the LBSET and SPMEN bits in SPMCSR. When an LPM instruction is executed within three CPU cycles after the LBSET and SPMEN bits are set in SPMCSR, the value of the Lock bits will be loaded in the destination register. The LBSET and SPMEN bits will auto-clear upon completion of reading the Lock bits. When LBSET and SPMEN are cleared, LPM will work as described in the ”AVR Instruction Set” description.

Bit	7	6	5	4	3	2	1	0
Rd	–	–	BLB12	BLB11	BLB02	BLB01	LB2	LB1

The algorithm for reading the Fuse Low byte is similar to the one described above for reading the Lock bits. To read the Fuse Low byte, load the Z-pointer with 0x0000 and set the LBSET and SPMEN bits in SPMCSR. When an LPM instruction is executed within three cycles after the LBSET and SPMEN bits are set in the SPMCSR, the value of the Fuse Low byte (FLB) will be loaded in the destination register as shown below. Refer to Table 30-4 on page 206 for a detailed description and mapping of the Fuse Low byte.

Bit	7	6	5	4	3	2	1	0
Rd	FLB7	FLB6	FLB5	FLB4	FLB3	FLB2	FLB1	FLB0

Similarly, when reading the Fuse High byte, load 0x0003 in the Z-pointer. When an LPM instruction is executed within three cycles after the LBSET and SPMEN bits are set in the SPMCSR, the value of the Fuse High byte (FHB) will be loaded in the destination register as shown below. Refer to Table 30-3 on page 205 for detailed description and mapping of the Fuse High byte.

Bit	7	6	5	4	3	2	1	0
Rd	FHB7	FHB6	FHB5	FHB4	FHB3	FHB2	FHB1	FHB0

Fuse and Lock bits that are programmed, will be read as zero. Fuse and Lock bits that are unprogrammed, will be read as one.

29.8.9 Reading the signature row from software

To read the Signature Row from software, load the Z-pointer with the signature byte address given in Table 29-3 on page 196 and set the SIGRD and SPMEN bits in SPMCSR. When an LPM instruction is executed within three CPU cycles after the SIGRD and SPMEN bits are set in SPMCSR, the signature byte value will be loaded in the destination register. The SIGRD and SPMEN bits will auto-clear 6 cycles after writing to SPMCSR, which is locked for further writing

during these cycles. When SIGRD and SPMEN are cleared, LPM will work as described in the Instruction set Manual.

Table 29-3. Signature row addressing.

Signature byte description	Z-pointer address
Device ID 0, manufacture ID	00H
Device ID 1, flash size	02H
Device ID 2, device	04H
FOSCCAL (1)	01H
FOSC SEGMENT (2)	03H
Reserved	05H
SLOW RC period L	06H
SLOW RC period H (3)	07H
SLOW RC temp prediction L	08H
SLOW RC temp prediction H (4)	09H
ULP RC FRQ (5)	0AH
SLOW RC FRQ (6)	0BH
ULP RC temp prediction coefficient L	OCH
ULP RC temp prediction coefficient H (7)	ODH
ULP RC period L	OEH
ULP RC period H (8)	OFH
BGCRR calibration byte	10H
BGCCR calibration byte	11H
Reserved	12H:17H
VPTAT CAL L	18H
VPTAT CAL H (9)	19H
V-ADC Cell1 gain calibration word L	1AH
V-ADC Cell1 gain calibration word H (10)	1BH
V-ADC Cell2 gain calibration word L	1CH
V-ADC Cell2 gain calibration word H (10)	1DH
V-ADC Cell3 gain calibration word L	1EH
V-ADC Cell3 gain calibration word H (10)	1FH
V-ADC Cell4 gain calibration word L	20H
V-ADC Cell4 gain calibration word H (10)	21H
V-ADC Cell1 offset (11)	22H
V-ADC Cell2 offset (11)	23H
V-ADC Cell3 offset (11)	24H
V-ADC Cell4 offset (11)	25H
V-ADC0 gain calibration word L	26H

Table 29-3. Signature row addressing. (Continued)

Signature byte description	Z-pointer address
V-ADC0 gain calibration word H (12)	27H
V-ADC1 gain calibration word L	28H
V-ADC1 gain calibration word H (13)	29H
V-ADC ADC0 offset (14)	2AH
V-ADC ADC1 offset (14)	2BH
Reserved	2CH:2FH
T_{HOT} (15)	30H
Device lot ID and position (16)	4AH:53H

Notes:
1. Default FOSCCAL value after reset.
2. FOSCCAL setting used to smooth the transition from one segment to the next when calibrating the Fast RC oscillator.
3. 8 prescaled Slow RC periods in µs using the Oscillator Sampling Interface (@T_{HOT}°C).
4. Slow RC oscillator frequency temperature drift prediction value.
5. ULP RC oscillator frequency in kHz (@ T_{HOT}°C).
6. Slow RC oscillator frequency in kHz (@T_{HOT}°C).
7. ULP RC oscillator frequency temperature drift prediction value.
8. 8 prescaled ULP RC periods in µs using the Oscillator Sampling Interface (@T_{HOT}°C).
9. Calibration word used to calculate the absolute temperature in Kelvin from a VTEMP conversion.
10. Calibration word used to compensate for gain error in V-ADC Cells.
11. Calibration byte used to compensate for offset in V-ADC Cells.
12. Calibration word used to compensate for gain error in ADC0.
13. Calibration word used to compensate for gain error in ADC1.
14. Calibration byte used to compensate for offset in ADC0 and ADC1.
15. Hot temperature used for factory calibration in °C.
16. Atmel does not test that the combination of lot ID and position is unique.

All other addresses are reserved for future use.

29.8.10 SPMCSR writing restrictions

Writing any other combination than “100001”, “010001”, “001001”, “000101”, “000011” or “000001” in the lower six bits will have no effect.

SPMCSR is locked for writing under the following conditions:

- One or more of the bits 5:0 in SPMCSR is set to 1
- During EEPROM write (status bit EEWE in EECR is set)

SPMCSR will be cleared at the following events:

- on completion of successful execution the following instructions:
  - LPM with LBSET and SPMEN set
  - SPM with LBSET and SPMEN set
  - SPM with PGERS and SPMEN set
  - SPM with PGWRT and SPMEN set
  - SPM with SPMEN set
- six cycles after writing SPMCSR if any other or no LPM/SPM is executed

29.8.11 Programming time for flash when using SPM

The Fast RC Oscillator is used to time Flash accesses. Table 29-4 shows the typical programming time for Flash accesses from the CPU.

Table 29-4. SPM Programming Time [1].

Symbol	Min programming time	Max programming time
Flash write (Page Erase, Page Write, and write Lock bits by SPM)	3.7ms	4.5ms

Note: 1. Minimum and maximum programming time is per individual operation.

29.8.12 Simple assembly code example for a boot loader

```
  ;-the routine writes one page of data from RAM to Flash
  ; the first data location in RAM is pointed to by the Y pointer
  ; the first data location in Flash is pointed to by the Z-pointer
  ;-error handling is not included
  ;-the routine must be placed inside the Boot space
  ; (at least the Do_spm sub routine). Only code inside NRWW section
  ; can be read during Self-Programming (Page Erase and Page Write).
  ;-registers used: r0, r1, temp1 (r16), temp2 (r17), looplo (r24),
  ; loophi (r25), spmcrval (r20)
  ; storing and restoring of registers is not included in the routine
  ; register usage can be optimized at the expense of code size
  ;-It is assumed that either the interrupt table is moved to the
  ; Boot loader section or that the interrupts are disabled.
.equ PAGESIZEB = PAGESIZE*2   ;PAGESIZEB is page size in BYTES, not words
.org SMALLBOOTSTART
Write_page:
  ; Page Erase
  ldi  spmcrval, (1<<PGERS) | (1<<SPMEN)
  call Do_spm

  ; re-enable the RWW section
  ldi  spmcrval, (1<<RWWSRE) | (1<<SPMEN)
  call Do_spm

  ; transfer data from RAM to Flash page buffer
  ldi  looplo, low(PAGESIZEB)   ;init loop variable
  ldi  loophi, high(PAGESIZEB)  ;not required for PAGESIZEB<=256
Wrloop:
  ld   r0, Y+
  ld   r1, Y+
  ldi  spmcrval, (1<<SPMEN)
  call Do_spm
  adiw ZH:ZL, 2
  sbiw loophi:looplo, 2         ;use subi for PAGESIZEB<=256
  brne Wrloop

  ; execute Page Write
  subi ZL, low(PAGESIZEB)       ;restore pointer
  sbci ZH, high(PAGESIZEB)      ;not required for PAGESIZEB<=256
  ldi  spmcrval, (1<<PGWRT) | (1<<SPMEN)
  call Do_spm

  ; re-enable the RWW section
  ldi  spmcrval, (1<<RWWSRE) | (1<<SPMEN)
```

```
  call Do_spm

  ; read back and check, optional
  ldi  looplo, low(PAGESIZEB)   ;init loop variable
  ldi  loophi, high(PAGESIZEB)  ;not required for PAGESIZEB<=256
  subi YL, low(PAGESIZEB)       ;restore pointer
  sbci YH, high(PAGESIZEB)
Rdloop:
  lpm  r0, Z+
  ld   r1, Y+
  cpse r0, r1
  jmp  Error
  sbiw loophi:looplo, 1         ;use subi for PAGESIZEB<=256
  brne Rdloop
  ; return to RWW section
  ; verify that RWW section is safe to read
Return:
  in   temp1, SPMCSR
  sbrs temp1, RWWSB     ; If RWWSB is set, the RWW section is not ready yet
  ret
  ; re-enable the RWW section
  ldi  spmcrval, (1<<RWWSRE) | (1<<SPMEN)
  call Do_spm
  rjmp Return

Do_spm:
  ; check for previous SPM complete
Wait_spm:
  in   temp1, SPMCSR
  sbrc temp1, SPMEN
  rjmp Wait_spm
  ; input: spmcrval determines SPM action
  ; disable interrupts if enabled, store status
  in   temp2, SREG
  cli
  ; check that no EEPROM write access is present
Wait_ee:
  sbic EECR, EEWE
  rjmp Wait_ee
  ; SPM timed sequence
  out  SPMCSR, spmcrval
  spm
  ; restore SREG (to enable interrupts if originally enabled)
  out  SREG, temp2
  ret
```

29.8.13 The Atmel ATmega16HVB boot loader parameters

In Table 29-5 through Table 29-7, the parameters used in the description of the Self-Programming are given

Table 29-5. Boot size configuration [1].

BOOTSZ1	BOOTSZ0	Boot size	Pages	Application flash section	Boot loader flash section	End application section	Boot reset address (start boot loader section)
1	1	256 words	4	0x0000 - 0x1EFF	0x1F00 - 0x1FFF	0x1EFF	0x1F00
1	0	512 words	8	0x0000 - 0x1DFF	0x1E00 - 0x1FFF	0x1DFF	0x1E00
0	1	1024 words	16	0x0000 - 0x1BFF	0x1C00 - 0x1FFF	0x1BFF	0x1C00
0	0	2048 words	32	0x0000 - 0x17FF	0x1800 - 0x1FFF	0x17FF	0x1800

Note: 1. The different BOOTSZ Fuse configurations are shown in Figure 29-2 on page 191.

Table 29-6. Read-while-write limit [1].

Section	Pages	Address
Read-while-write section (RWW)	96	0x0000 - 0x17FF
No read-while-write section (NRWW)	32	0x1800 - 0x1FFF

Note: 1. For details about these two section, see "NRWW – No read-while-write section" on page 189 and "RWW – Read-while-write section" on page 189.

Table 29-7. Explanation of different variables used in Figure 29-3 on page 193 and the mapping to the Z-pointer [1].

Variable		Corresponding Z-value	Description
PCMSB	12		Most significant bit in the Program Counter. (The Program Counter is 13 bits PC[12:0])
PAGEMSB	5		Most significant bit which is used to address the words within one page (64 words in a page requires six bits PC [5:0])
ZPCMSB		Z13	Bit in Z-register that is mapped to PCMSB. Because Z0 is not used, the ZPCMSB equals PCMSB + 1
ZPAGEMSB		Z6	Bit in Z-register that is mapped to PCMSB. Because Z0 is not used, the ZPAGEMSB equals PAGEMSB + 1
PCPAGE	PC[12:6]	Z12:Z7	Program Counter page address: Page select, for Page Erase and Page Write
PCWORD	PC[5:0]	Z6:Z1	Program Counter word address: Word select, for filling temporary buffer (must be zero during Page Write operation)

Note: 1. Z0: should be zero for all SPM commands, byte select for the LPM instruction. See "Addressing the flash during self-programming" on page 192 for details about the use of Z-pointer during Self-Programming.

29.8.14 The Atmel ATmega32HVB boot loader parameters

In Table 29-8 through Table 29-10, the parameters used in the description of the Self-Programming are given

Table 29-8. Boot size configuration [1].

BOOTSZ1	BOOTSZ0	Boot size	Pages	Application flash section	Boot loader flash section	End application section	Boot reset address (start boot loader section)
1	1	256 words	4	0x0000 - 0x3EFF	0x3F00 - 0x3FFF	0x3EFF	0x3F00
1	0	512 words	8	0x0000 - 0x3DFF	0x3E00 - 0x3FFF	0x3DFF	0x3E00
0	1	1024 words	16	0x0000 - 0x3BFF	0x3C00 - 0x3FFF	0x3BFF	0x3C00
0	0	2048 words	32	0x0000 - 0x37FF	0x3800 - 0x3FFF	0x37FF	0x3800

Note: 1. The different BOOTSZ Fuse configurations are shown in Figure 29-2 on page 191.

Table 29-9. Read-while-write limit [1].

Section	Pages	Address
Read-while-write section (RWW)	224	0x0000 - 0x37FF
No read-while-write section (NRWW)	32	0x3800 - 0x3FFF

For details about these two section, see "NRWW – No read-while-write section" on page 189 and "RWW – Read-while-write section" on page 189.

Table 29-10. Explanation of different variables used in Figure 29-3 on page 193 and the mapping to the Z-pointer [1].

Variable		Corresponding Z-value	Description
PCMSB	13		Most significant bit in the Program Counter. (The Program Counter is 14 bits PC[13:0])
PAGEMSB	5		Most significant bit which is used to address the words within one page (64 words in a page requires six bits PC [5:0])
ZPCMSB		Z14	Bit in Z-register that is mapped to PCMSB. Because Z0 is not used, the ZPCMSB equals PCMSB + 1
ZPAGEMSB		Z6	Bit in Z-register that is mapped to PCMSB. Because Z0 is not used, the ZPAGEMSB equals PAGEMSB + 1
PCPAGE	PC[13:6]	Z13:Z7	Program Counter page address: Page select, for Page Erase and Page Write
PCWORD	PC[5:0]	Z6:Z1	Program Counter word address: Word select, for filling temporary buffer (must be zero during Page Write operation)

Note: 1. Z0: should be zero for all SPM commands, byte select for the LPM instruction. See "Addressing the flash during self-programming" on page 192 for details about the use of Z-pointer during Self-Programming.

29.9 Register description

29.9.1 SPMCSR – Store Program Memory Control and Status Register

The Store Program Memory Control and Status Register contains the control bits needed to control the Boot Loader operations:

Bit	7	6	5	4	3	2	1	0	
0x37 (0x57)	SPMIE	RWWSB	SIGRD	RWWSRE	LBSET	PGWRT	PGERS	SPMEN	SPMCSR
Read/Write	R/W	R	R/W	R/W	R/W	R/W	R/W	R/W	
Initial Value	0	0	0	0	0	0	0	0	

- **Bit 7 – SPMIE: SPM Interrupt Enable**

When the SPMIE bit is written to one, and the I-bit in the Status Register is set (one), the SPM ready interrupt will be enabled. The SPM ready Interrupt will be executed as long as the SPMEN bit in the SPMCSR Register is cleared.

- **Bit 6 – RWWSB: Read-While-Write Section Busy**

When a Self-Programming (Page Erase or Page Write) operation to the RWW section is initiated, the RWWSB will be set (one) by hardware. When the RWWSB bit is set, the RWW section cannot be accessed. The RWWSB bit will be cleared if the RWWSRE bit is written to one after a Self-Programming operation is completed. Alternatively the RWWSB bit will automatically be cleared if a page load operation is initiated.

- **Bit 5 - SIGRD: Signature Row Read**

If this bit is written to one at the same time as SPMEN, the next LPM instruction within three clock cycles will read a byte from the signature row into the destination register. See ”Reading the signature row from software” on page 195 for details.

An SPM instruction within four cycles after SIGRD and SPMEN are set will have no effect. This operation is reserved for future use and should not be used.

- **Bit 4 – RWWSRE: Read-While-Write Section Read Enable**

When programming (Page Erase or Page Write) to the RWW section, the RWW section is blocked for reading (the RWWSB will be set by hardware). To re-enable the RWW section, the user software must wait until the programming is completed (SPMEN will be cleared). Then, if the RWWSRE bit is written to one at the same time as SPMEN, the next SPM instruction within four clock cycles re-enables the RWW section. The RWW section cannot be re-enabled while the Flash is busy with a Page Erase or a Page Write (SPMEN is set). If the RWWSRE bit is written while the Flash is being loaded, the Flash load operation will abort and the data loaded will be lost.

- **Bit 3 – LBSET: Lock Bit Set**

If this bit is written to one at the same time as SPMEN, the next SPM instruction within four clock cycles sets Lock bits, according to the data in R0. The data in R1 and the address in the Z-pointer are ignored. The LBSET bit will automatically be cleared upon completion of the Lock bit set, or after six cycles if no SPM instruction is executed within four clock cycles.

An LPM instruction within three cycles after LBSET and SPMEN are set in the SPMCSR Register, will read either the Lock bits or the Fuse bits (depending on Z0 in the Z-pointer) into the destination register. See ”Reading the fuse and lock bits” on page 218 for details.

- **Bit 2 – PGWRT: Page Write**

If this bit is written to one at the same time as SPMEN, the next SPM instruction within four clock cycles executes Page Write, with the data stored in the temporary buffer. The page address is taken from the high part of the Z-pointer. The data in R1 and R0 are ignored. The PGWRT bit will auto-clear upon completion of a Page Write, or after six cycles if no SPM instruction is executed within four clock cycles. The CPU is halted during the entire Page Write operation if the NRWW section is addressed.

- **Bit 1 – PGERS: Page Erase**

If this bit is written to one at the same time as SPMEN, the next SPM instruction within four clock cycles executes Page Erase. The page address is taken from the high part of the Z-pointer. The data in R1 and R0 are ignored. The PGERS bit will auto-clear upon completion of a Page Erase, or after six cycles if no SPM instruction is executed within four clock cycles. The CPU is halted during the entire Page Write operation if the NRWW section is addressed.

- **Bit 0 – SPMEN: Store Program Memory Enable**

This bit enables the SPM instruction for the next four clock cycles. If written to one together with either RWWSRE, LBSET, PGWRT' or PGERS, the following SPM instruction will have a special meaning, see description above. If only SPMEN is written, the following SPM instruction will store the value in R1:R0 in the temporary page buffer addressed by the Z-pointer. The LSB of the Z-pointer is ignored. The SPMEN bit will auto-clear upon completion of an SPM instruction, or after six cycles if no SPM instruction is executed within four clock cycles. During Page Erase and Page Write, the SPMEN bit remains high until the operation is completed.

30. Memory programming

30.1 Program and data memory lock bits

The Atmel ATmega16HVB/32HVB provides six Lock bits which can be left unprogrammed (“1”) or can be programmed (“0”) to obtain the additional features listed in Table 30-2. The Lock bits can only be erased to “1” with the Chip Erase command

Table 30-1. Lock bit byte [1].

Lock bit byte	Bit No	Description	Default value
	7	–	1 (unprogrammed)
	6	–	1 (unprogrammed)
BLB12	5	Boot lock bit	1 (unprogrammed)
BLB11	4	Boot lock bit	1 (unprogrammed)
BLB02	3	Boot lock bit	1 (unprogrammed)
BLB01	2	Boot lock bit	1 (unprogrammed)
LB2	1	Lock bit	1 (unprogrammed)
LB1	0	Lock bit	1 (unprogrammed)

Note: 1. “1” means unprogrammed, “0” means programmed.

Table 30-2. Lock bit protection modes [1][2].

Memory lock bits			Protection type
LB Mode	**LB2**	**LB1**	
1	1	1	No memory lock features enabled
2	1	0	Further programming of the Flash and EEPROM is disabled in Parallel and Serial Programming mode. The Fuse bits are locked in both Serial and Parallel Programming mode [1]
3	0	0	Further programming and verification of the Flash and EEPROM is disabled in Parallel and Serial Programming mode. The Boot Lock bits and Fuse bits are locked in both Serial and Parallel Programming mode [1]
BLB0 Mode	**BLB02**	**BLB01**	
1	1	1	No restrictions for SPM or LPM accessing the Application section
2	1	0	SPM is not allowed to write to the Application section
3	0	0	SPM is not allowed to write to the Application section, and LPM executing from the Boot Loader section is not allowed to read from the Application section. If Interrupt Vectors are placed in the Boot Loader section, interrupts are disabled while executing from the Application section
4	0	1	LPM executing from the Boot Loader section is not allowed to read from the Application section. If Interrupt Vectors are placed in the Boot Loader section, interrupts are disabled while executing from the Application section

Table 30-2. Lock bit protection modes [1][2]. (Continued)

Memory lock bits			Protection type
BLB1 Mode	BLB12	BLB11	
1	1	1	No restrictions for SPM or LPM accessing the Boot Loader section
2	1	0	SPM is not allowed to write to the Boot Loader section
3	0	0	SPM is not allowed to write to the Boot Loader section, and LPM executing from the Application section is not allowed to read from the Boot Loader section. If Interrupt Vectors are placed in the Application section, interrupts are disabled while executing from the Boot Loader section
4	0	1	LPM executing from the Application section is not allowed to read from the Boot Loader section. If Interrupt Vectors are placed in the Application section, interrupts are disabled while executing from the Boot Loader section

Notes: 1. Program the Fuse bits and Boot Lock bits before programming the LB1 and LB2.
2. "1" means unprogrammed, "0" means programmed.

30.2 Fuse bits

The Atmel ATmega16HVB/32HVB has two Fuse bytes. Table 30-4 on page 206 and Table 30-3 describe briefly the functionality of all the fuses and how they are mapped into the Fuse byte. Note that the fuses are read as logical zero, "0", if they are programmed.

30.2.1 High byte

Table 30-3. Fuse high byte.

Bit no	Fuse high byte	Description	Default value
7:5	–		
4	CKDIV8 [1]	Divide system clock by 8	0 (programmed)
3	DWEN	Enable debugWire	1 (unprogrammed)
2	BOOTSZ1	Select boot size	0 (programmed) [2]
1	BOOTSZ0	Select boot size	0 (programmed) [2]
0	BOOTRST	Select reset vector	1 (unprogrammed)

Notes: 1. The fuse controls the initial value of the System Clock prescaler, see "System clock prescaler" on page 28 for details.
2. The default value of BOOTSZ1:0 results in maximum Boot Size.

30.2.2 Low byte

Table 30-4. Fuse low byte.

Bit no	Fuse low byte	Description	Default value
7	WDTON	Watchdog Timer always on	1 (unprogrammed) (1)
6	EESAVE	EEPROM memory is preserved through the chip erase	1 (unprogrammed, EEPROM not preserved)
5	SPIEN	Enable serial programmable data downloading	0 (programmed, SPI programming enabled)
4	SUT2	Select start-up time	1 (unprogrammed) (2)
3	SUT1	Select start-up time	1 (unprogrammed) (2)
2	SUT0	Select start-up time	1 (unprogrammed) (2)
1	OSCSEL1	Oscillator select	0 (programmed) (3)
0	OSCSEL0	Oscillator select	1 (unprogrammed) (3)

Notes:
1. The Watchdog is enabled/disabling by writing to the Watchdog Timer Control and Status Register (WDTCSR). But as a fail-safe, the WDTON fuse can be used to force the Watchdog to run in System Reset mode.
2. The SUTx fuse bits are used to configure the startup time from sleep or reset. By default the longest startup time is selected.
3. The default OSCSEL1:0 setting should not be changed. OSCSEL1:0="00" is reserved for test purpose. Other values are reserved for future use.

The status of the Fuse bits is not affected by Chip Erase. Note that the Fuse bits are locked if Lock bit1 (LB1) is programmed. Program the Fuse bits before programming the Lock bits.

30.2.3 Latching of fuses

The fuse values are latched when the device enters programming mode and changes of the fuse values will have no effect until the part leaves Programming mode. This does not apply to the EESAVE Fuse which will take effect once it is programmed. The fuses are also latched on Power-up in Normal mode.

30.3 Signature bytes

All Atmel microcontrollers have a three-byte signature code which identifies the device. This code can be read in both Programming mode, also when the device is locked. The three bytes reside in a separate address space. The signature bytes of the Atmel ATmega16HVB/32HVB is given in Table 30-5.

Table 30-5. Device ID.

	Signature bytes address		
Part	**0x000**	**0x001**	**0x002**
The Atmel ATmega16HVB	0x1E	0x94	0x0D
The Atmel ATmega32HVB	0x1E	0x95	0x10

30.4 Calibration bytes

The Atmel ATmega16HVB/32HVB has calibration bytes for the RC Oscillators, internal voltage reference, internal temperature reference and each differential cell voltage input. These bytes reside in the signature address space. See ”Reading the signature row from software” on page 195 for details.

30.5 Page size

Table 30-6. No. of words in a page and no. of pages in the flash, Atmel ATmega16HVB.

Flash size	Page size	PCWORD	No. of pages	PCPAGE	PCMSB
8K words (16Kbytes)	64 words	PC[5:0]	128	PC[12:6]	12

Table 30-7. No. of words in a page and no. of pages in the flash, Atmel ATmega32HVB.

Flash size	Page size	PCWORD	No. of pages	PCPAGE	PCMSB
16K words (32Kbytes)	64 words	PC[5:0]	256	PC[13:6]	13

Table 30-8. No. of words in a page and no. of pages in the EEPROM, ATmega16HVB.

EEPROM size	Page size	PCWORD	No. of pages	PCPAGE	EEAMSB
512bytes	4bytes	EEA[1:0]	128	EEA[8:2]	8

Table 30-9. No. of words in a page and no. of pages in the EEPROM, ATmega32HVB.

EEPROM size	Page size	PCWORD	No. of pages	PCPAGE	EEAMSB
1Kbytes	4bytes	EEA[1:0]	256	EEA[9:2]	9

30.6 Serial programming

Both the Flash and EEPROM memory arrays can be programmed using the serial SPI bus while $\overline{\text{RESET}}$ is pulled to GND. The serial interface consists of pins SCK, MOSI (input) and MISO (output). After $\overline{\text{RESET}}$ is set low, the Programming Enable instruction needs to be executed first before program/erase operations can be executed.

Note: In Table 30-10 on page 208, the pin mapping for SPI programming is listed. Not all parts use the SPI pins dedicated for the internal SPI interface.

Figure 30-1. Serial programming and verify.

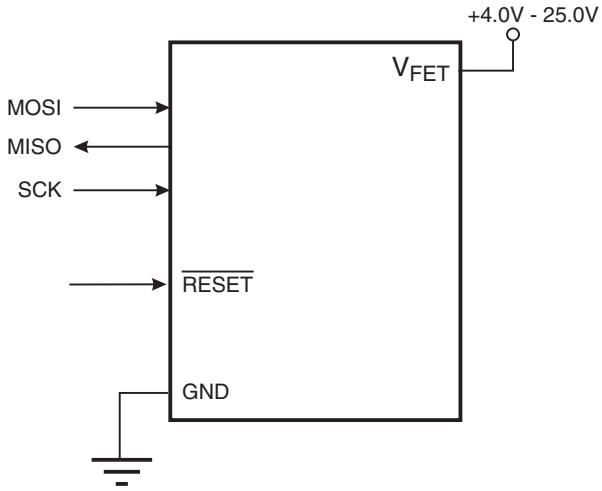


Table 30-10. Pin mapping serial programming.

Symbol	Pins	I/O	Description
SCK	PB5	I	Serial Clock
MOSI	PB6	I	Serial Data in
MISO	PB7	O	Serial Data out

When programming the EEPROM, an auto-erase cycle is built into the self-timed programming operation (in the Serial mode ONLY) and there is no need to first execute the Chip Erase instruction. The Chip Erase operation turns the content of every memory location in both the Program and EEPROM arrays into 0xFF.

Depending on OSCSEL Fuses, a valid clock must be present. The minimum low and high periods for the serial clock (SCK) input are defined as follows:

Low: > 2.2 CPU clock cycles for f_{ck} <12MHz, 3 CPU clock cycles for f_{ck} >=12MHz

High: > 2.2 CPU clock cycles for f_{ck} <12MHz, 3 CPU clock cycles for f_{ck} >=12MHz

30.6.1 Serial programming algorithm

When writing serial data to the Atmel ATmega16HVB/32HVB, data is clocked on the rising edge of SCK.

When reading data from the ATmega16HVB/32HVB, data is clocked on the falling edge of SCK. See ”Serial programming characteristics” on page 234 for timing details.

To program and verify the ATmega16HVB/32HVB in the Serial Programming mode, the following sequence is recommended (see four byte instruction formats in Table 30-12 on page 210):

1. Power-up sequence:
   Make sure the chip is started as explained in Section 11.2.1 ”Power-on reset and charger connect” on page 43 while $\overline{\text{RESET}}$ and SCK are set to “0”. In some systems, the programmer can not guarantee that SCK is held low during power-up. In this case, $\overline{\text{RESET}}$ must be given a positive pulse of at least two CPU clock cycles duration after SCK has been set to “0”.
2. Wait for at least 20ms and enable serial programming by sending the Programming Enable serial instruction to pin MOSI.

3. The serial programming instructions will not work if the communication is out of synchronization. When in sync. the second byte (0x53), will echo back when issuing the third byte of the Programming Enable instruction. Whether the echo is correct or not, all four bytes of the instruction must be transmitted. If the 0x53 did not echo back, give $\overline{\text{RESET}}$ a positive pulse and issue a new Programming Enable command.
4. The Flash is programmed one page at a time. The memory page is loaded one byte at a time by supplying the 5 LSB of the address and data together with the Load Program memory Page instruction. To ensure correct loading of the page, the data low byte must be loaded before data high byte is applied for a given address. The Program memory Page is stored by loading the Write Program memory Page instruction with the 7/8 MSB of the address (Atmel ATmega16HVB/ATmega32HVB). If polling (RDY/$\overline{\text{BSY}}$) is not used, the user must wait at least t_{WD_FLASH} before issuing the next page (see Table 30-11). Accessing the serial programming interface before the Flash write operation completes can result in incorrect programming.
5. **A:** The EEPROM array is programmed one byte at a time by supplying the address and data together with the appropriate Write instruction. An EEPROM memory location is first automatically erased before new data is written. If polling (RDY/$\overline{\text{BSY}}$) is not used, the user must wait at least t_{WD_EEPROM} before issuing the next byte (see Table 30-11). In a chip erased device, no 0xFFs in the data file(s) need to be programmed.
   B: The EEPROM array is programmed one page at a time. The Memory page is loaded one byte at a time by supplying the 2 LSB of the address and data together with the Load EEPROM Memory Page instruction. The EEPROM Memory Page is stored by loading the Write EEPROM Memory Page Instruction with the 7/8 MSB of the address (ATmega16HVB/ATmega32HVB). When using EEPROM page access only byte locations loaded with the Load EEPROM Memory Page instruction is altered. The remaining locations remain unchanged. If polling (RDY/$\overline{\text{BSY}}$) is not used, the used must wait at least t_{WD_EEPROM} before issuing the next page (see Table 30-8 on page 207). In a chip erased device, no 0xFF in the data file(s) need to be programmed.
6. Any memory location can be verified by using the Read instruction which returns the content at the selected address at serial output MISO.
7. At the end of the programming session, $\overline{\text{RESET}}$ can be set high to commence normal operation.
8. Power-off sequence (if needed):
   Set $\overline{\text{RESET}}$ to “1”.
   Turn V_{CC} power off.

Table 30-11. Minimum wait delay before writing the next flash or EEPROM location.

Symbol	Minimum wait delay
t_{WD_FLASH}	4.5ms
t_{WD_EEPROM}	4.0ms
t_{WD_ERASE}	4.0ms
t_{WD_FUSE}	4.5ms

30.6.2 Serial programming instruction set

Table 30-12 and Figure 30-2 on page 211 describes the instruction set.

Table 30-12. Serial programming instruction set.

Instruction/operation	Instruction format			
	Byte 1	**Byte 2**	**Byte 3**	**Byte 4**
Programming enable	$AC	$53	$00	$00
Chip erase (program memory/EEPROM)	$AC	$80	$00	$00
Poll RDY/$\overline{\text{BSY}}$	$F0	$00	$00	data byte out
Load instructions				
Load extended address byte (1)	$4D	$00	Extended adr	$00
Load program memory page, high byte	$48	adr MSB	adr LSB	high data byte in
Load program memory page, low byte	$40	adr MSB	adr LSB	low data byte in
Load EEPROM memory page (page access)	$C1	adr MSB	adr LSB	data byte in
Read instructions				
Read program memory, high byte	$28	adr MSB	adr LSB	high data byte out
Read program memory, low byte	$20	adr MSB	adr LSB	low data byte out
Read EEPROM memory	$A0	adr MSB	adr LSB	data byte out
Read lock bits	$58	$00	$00	data byte out
Read signature byte	$30	$00	adr LSB	data byte out
Read fuse bits	$50	$00	$00	data byte out
Read fuse high bits	$58	$08	$00	data byte out
Read extended fuse bits	$50	$08	$00	data byte out
Read calibration byte	$38	$00	$00	data byte out
Write instructions (6)				
Write program memory page	$4C	adr MSB	adr LSB	$00
Write EEPROM memory	$C0	adr MSB	adr LSB	data byte in
Write EEPROM memory page (page access)	$C2	adr MSB	adr LSB	$00
Write lock bits	$AC	$E0	$00	data byte in
Write fuse bits	$AC	$A0	$00	data byte in
Write fuse high bits	$AC	$A8	$00	data byte in
Write extended fuse bits	$AC	$A4	$00	data byte in

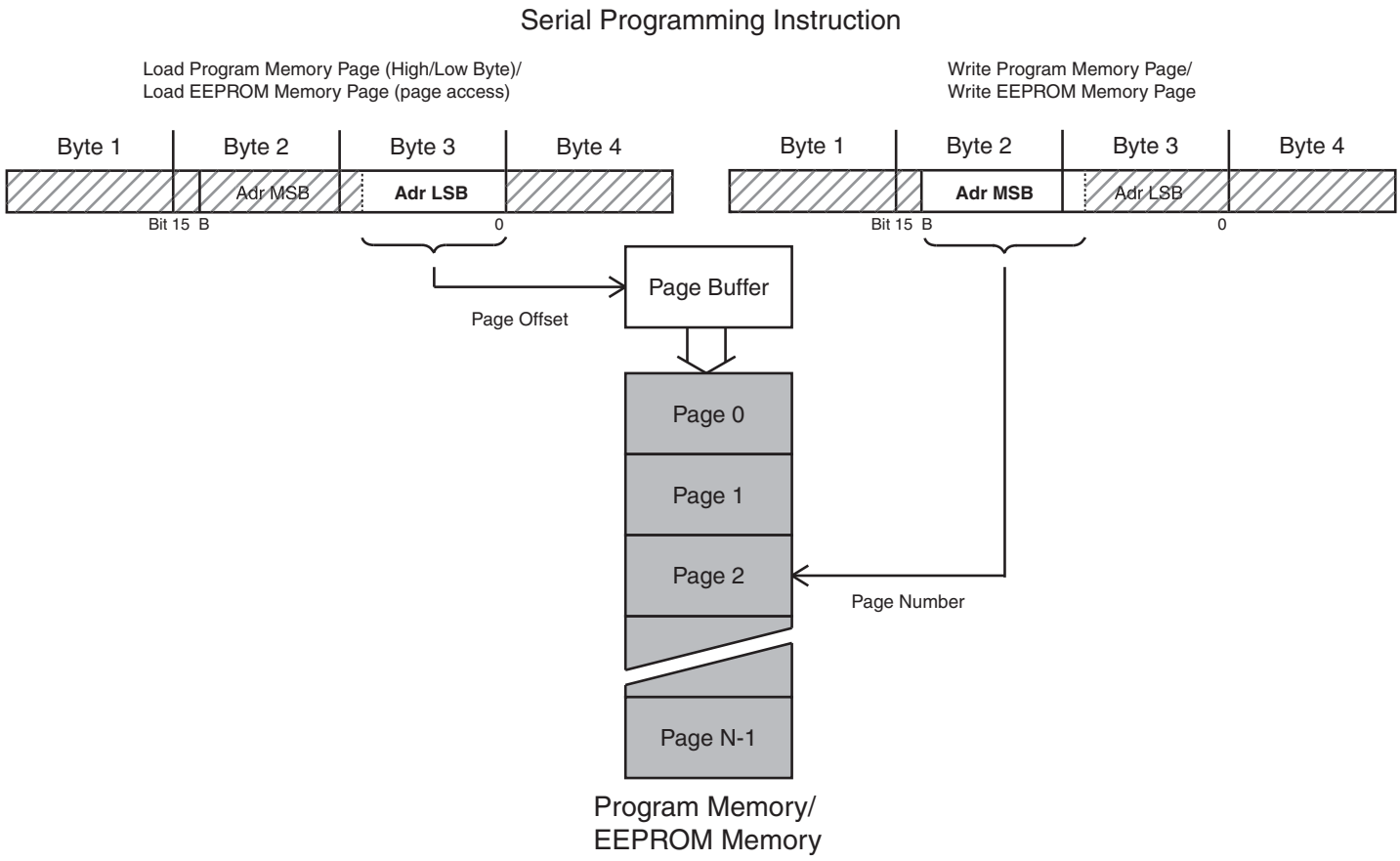
Notes:
1. Not all instructions are applicable for all parts.
2. adr = address.
3. Bits are programmed ‘0’, unprogrammed ‘1’.
4. To ensure future compatibility, unused Fuses and Lock bits should be unprogrammed (‘1’).
5. Refer to the corresponding section for Fuse and Lock bits, Calibration and Signature bytes and Page size.
6. Instructions accessing program memory use word address. This address may be random within the page range.
7. See http://www.atmel.com/avr for Application Notes regarding programming and programmers.

If the LSB in RDY/BSY data byte out is '1', a programming operation is still pending. Wait until this bit returns '0' before the next instruction is carried out.

Within the same page, the low data byte must be loaded prior to the high data byte.

After data is loaded to the page buffer, program the EEPROM page, see Figure 30-2.

Figure 30-2. Serial programming instruction example.



30.7 Parallel programming

This section describes parameters, pin mapping, and commands used to parallel program and verify Flash Program memory, EEPROM Data memory, Memory Lock bits, and Fuse bits in the Atmel ATmega16HVB/32HVB. Pulses are assumed to be at least 250 ns unless otherwise noted.

30.7.1 Considerations for efficient programming

The loaded command and address are retained in the device during programming. For efficient programming, the following should be considered.

- The command needs only be loaded once when writing or reading multiple memory locations
- Skip writing the data value 0xFF, that is the contents of the entire EEPROM (unless the EESAVE Fuse is programmed) and Flash after a Chip Erase

Address high byte needs only be loaded before programming or reading a new 256 word window in Flash or 256 byte EEPROM. This consideration also applies to Signature bytes reading.

30.7.2 Signal names

In this section, some pins of the Atmel ATmega16HVB/32HVB are referenced by signal names describing their functionality during parallel programming, see Figure 30-3 and Table 30-13. Pins not described in the following table are referenced by pin names.

The XA1/XA0 pins determine the action executed when the XTAL1 pin is given a positive pulse. The bit coding is shown in Table 30-15 on page 213.

When pulsing $\overline{WR}$ or $\overline{OE}$, the command loaded determines the action executed. The different Commands are shown in Table 30-16 on page 213. Table 32-18 on page 236 shows the Parallel programming characteristics.

Figure 30-3. Parallel programming.

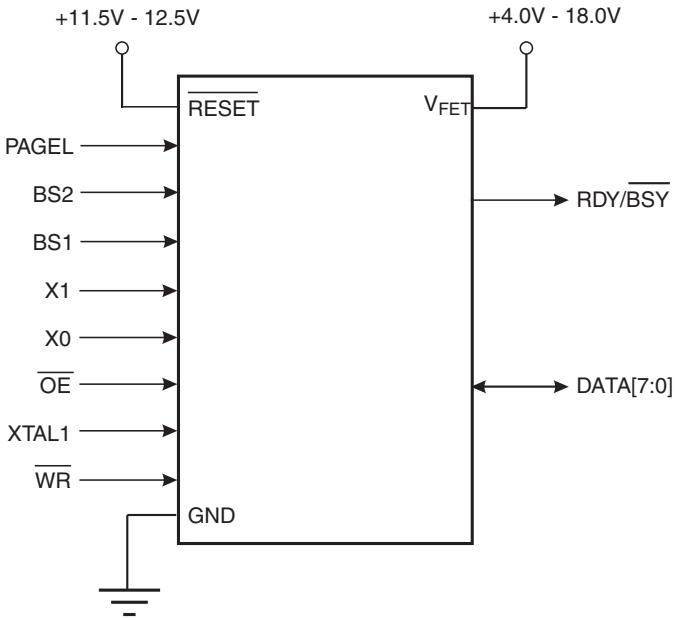


Table 30-13. Pin name mapping.

Signal name in programming mode	Pin name	I/O	Function
RDY/$\overline{BSY}$	PA0	O	0: Device is busy programming 1: Device is ready for new command
BS1	PA1	I	Byte select 1 (“0” selects low byte, “1” selects high byte)
BS2	PA2	I	Byte select 2 (“0” selects low byte, “1” selects 2’nd high byte)
PAGEL	PA3	I	Program memory and EEPROM data page load
$\overline{RESET}$	$\overline{RESET}$	I	
DATA	PB[7:0]	I/O	Bi-directional data bus (output when $\overline{OE}$ is low)
$\overline{WR}$	PC0	I	Write pulse (active low)
$\overline{OE}$	PC1	I	Output enable (active low)
XTAL	PC2	I	
XA0	PC3	I	XTAL action bit 0
XA1	PC4	I	XTAL action bit 1

Table 30-14. Pin values used to enter programming mode.

Pin	Symbol	Value
PB3	Prog_enable[3]	0
PB2	Prog_enable[2]	0
PB1	Prog_enable[1]	0
PB0	Prog_enable[0]	0

Table 30-15. XA1 and XA0 coding.

XA1	XA0	Action when XTAL1 is pulsed
0	0	Load flash or EEPROM address (High or low address byte determined by BS1)
0	1	Load data (High or Low data byte for Flash determined by BS1)
1	0	Load command
1	1	No action, idle

Table 30-16. Command byte bit coding.

Command byte	Command executed
1000 0000	Chip erase
0100 0000	Write fuse bits
0010 0000	Write lock bits
0001 0000	Write flash
0001 0001	Write EEPROM
0000 1000	Read signature bytes and calibration byte
0000 0100	Read fuse and lock bits
0000 0010	Read flash
0000 0011	Read EEPROM

30.7.3 Enter programming mode

The following algorithm puts the device in parallel programming mode:

1. Make sure the chip is started as explained in ”Power-on reset and charger connect” on page 43.
2. Set $\overline{\text{RESET}}$ to “0” and toggle XTAL1 at least six times.
3. Set the Prog_enable pins listed in Table 30-14 to “0000” and wait at least 100ns.
4. Apply 11.5V - 12.5V to $\overline{\text{RESET}}$. Any activity on Prog_enable pins within 100ns after +12V has been applied to $\overline{\text{RESET}}$, will cause the device to fail entering programming mode.
5. Wait at least 50µs before sending a new command.

30.7.4 Chip erase

The Chip Erase will erase the Flash and EEPROM [(1)] memories plus Lock bits. The Lock bits are not reset until the program memory has been completely erased. The Fuse bits are not changed. A Chip Erase must be performed before the Flash and/or EEPROM are reprogrammed.

Note: 1. The EEPRPOM memory is preserved during Chip Erase if the EESAVE Fuse is programmed.

Load command “Chip Erase”.

1. Set XA1, XA0 to “10”. This enables command loading.
2. Set BS1 to “0”.
3. Set DATA to “1000 0000”. This is the command for Chip Erase.
4. Give XTAL1 a positive pulse. This loads the command.
5. Give $\overline{WR}$ a negative pulse. This starts the Chip Erase. RDY/$\overline{BSY}$ goes low.
6. Wait until RDY/$\overline{BSY}$ goes high before loading a new command.

30.7.5 Programming the flash

The Flash is organized in pages, see Table 30-7 on page 207. When programming the Flash, the program data is latched into a page buffer. This allows one page of program data to be programmed simultaneously. The following procedure describes how to program the entire Flash memory:

A. Load Command “Write Flash”

1. Set XA1, XA0 to “10”. This enables command loading.
2. Set BS1 to “0”.
3. Set DATA to “0001 0000”. This is the command for Write Flash.
4. Give XTAL1 a positive pulse. This loads the command.

B. Load Address Low byte

1. Set XA1, XA0 to “00”. This enables address loading.
2. Set BS1 to “0”. This selects low address.
3. Set DATA = Address low byte (0x00 - 0xFF).
4. Give XTAL1 a positive pulse. This loads the address low byte.

C. Load Data Low Byte

1. Set XA1, XA0 to “01”. This enables data loading.
2. Set DATA = Data low byte (0x00 - 0xFF).
3. Give XTAL1 a positive pulse. This loads the data byte.

D. Load Data High Byte

1. Set BS1 to “1”. This selects high data byte.
2. Set XA1, XA0 to “01”. This enables data loading.
3. Set DATA = Data high byte (0x00 - 0xFF).
4. Give XTAL1 a positive pulse. This loads the data byte.

E. Latch Data

1. Set BS1 to “1”. This selects high data byte.
2. Give PAGEL a positive pulse. This latches the data bytes (see Figure 30-5 on page 216 for signal waveforms).

F. Repeat B through E until the entire buffer is filled or until all data within the page is loaded

While the lower bits in the address are mapped to words within the page, the higher bits address the pages within the FLASH. This is illustrated in Figure 30-4 on page 215. Note that if less than eight bits are required to address words in the page (pagesize <256), the most significant bit(s) in the address low byte are used to address the page when performing a Page Write.

G. Load Address High byte

1. Set XA1, XA0 to “00”. This enables address loading.
2. Set BS1 to “1”. This selects high address.
3. Set DATA = Address high byte (0x00 - 0xFF).
4. Give XTAL1 a positive pulse. This loads the address high byte.

H. Program Page

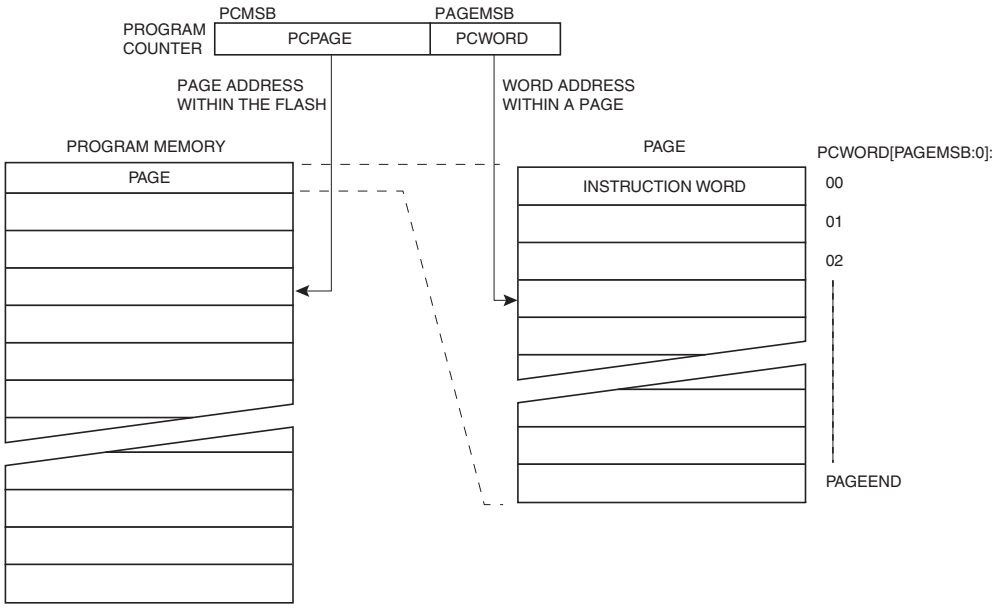
1. Give $\overline{WR}$ a negative pulse. This starts programming of the entire page of data. RDY/$\overline{BSY}$ goes low.
2. Wait until RDY/$\overline{BSY}$ goes high (see Figure 30-5 on page 216 for signal waveforms).

I. Repeat B through H until the entire Flash is programmed or until all data has been programmed.

J. End Page Programming

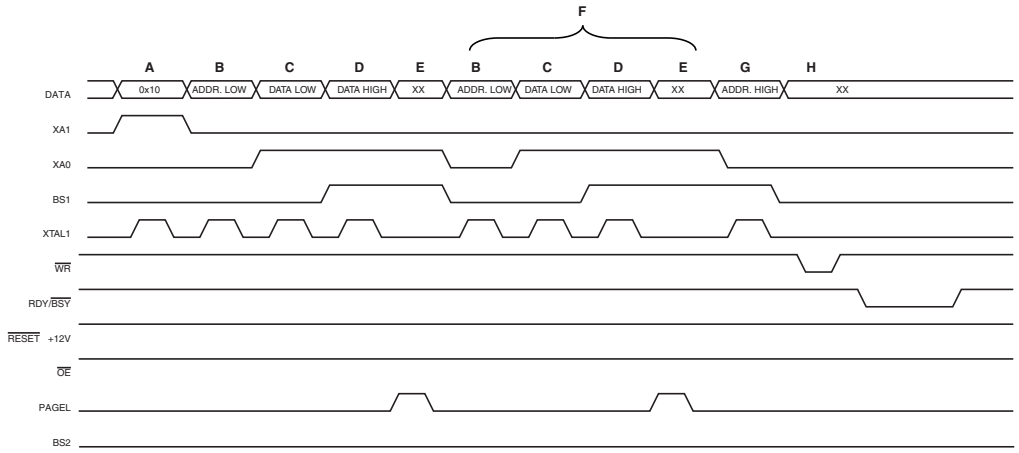
1. 1. Set XA1, XA0 to “10”. This enables command loading.
2. Set DATA to “0000 0000”. This is the command for No Operation.
3. Give XTAL1 a positive pulse. This loads the command, and the internal write signals are reset.

Figure 30-4. Addressing the flash which is organized in pages [1].



Note: 1. PCPAGE and PCWORD are listed in Table 30-7 on page 207.

Figure 30-5. Programming the flash waveforms [1].



Note: 1. “XX” is don’t care. The letters refer to the programming description above.

30.7.6 Programming the EEPROM

The EEPROM is organized in pages, see Table 30-8 on page 207. When programming the EEPROM, the program data is latched into a page buffer. This allows one page of data to be programmed simultaneously. The programming algorithm for the EEPROM data memory is as follows (refer to ”Programming the flash” on page 214 for details on Command, Address and Data loading):

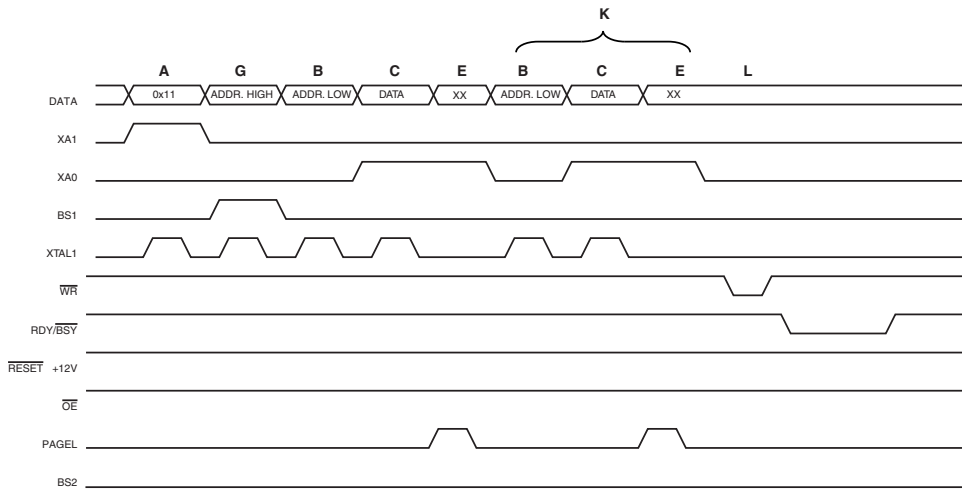
1. A: Load Command “0001 0001”.
2. G: Load Address High Byte (0x00 - 0xFF).
3. B: Load Address Low Byte (0x00 - 0xFF).
4. C: Load Data (0x00 - 0xFF).
5. E: Latch data (give PAGEL a positive pulse).

K: Repeat 3 through 5 until the entire buffer is filled

L: Program EEPROM page

1. Set BS to “0”.
2. Give $\overline{WR}$ a negative pulse. This starts programming of the EEPROM page. RDY/$\overline{BSY}$ goes low.
3. Wait until to RDY/$\overline{BSY}$ goes high before programming the next page (see Figure 30-6 on page 217 for signal waveforms).

Figure 30-6. Programming the EEPROM waveforms.



30.7.7 Reading the flash

The algorithm for reading the flash memory is as follows (refer to ”Programming the flash” on page 214 for details on Command and Address loading):

1. A: Load Command “0000 0010”.
2. G: Load Address High Byte (0x00 - 0xFF).
3. B: Load Address Low Byte (0x00 - 0xFF).
4. Set $\overline{OE}$ to “0”, and BS1 to “0”. The Flash word low byte can now be read at DATA.
5. Set BS to “1”. The Flash word high byte can now be read at DATA.
6. Set $\overline{OE}$ to “1”.

30.7.8 Reading the EEPROM

The algorithm for reading the EEPROM memory is as follows (refer to ”Programming the flash” on page 214 for details on Command and Address loading):

1. A: Load Command “0000 0011”.
2. G: Load Address High Byte (0x00 - 0xFF).
3. B: Load Address Low Byte (0x00 - 0xFF).
4. Set $\overline{OE}$ to “0”, and BS1 to “0”. The EEPROM Data byte can now be read at DATA.
5. Set $\overline{OE}$ to “1”.

30.7.9 Programming the fuse low bits

The algorithm for programming the Fuse Low bits is as follows (refer to ”Programming the flash” on page 214 for details on Command and Data loading):

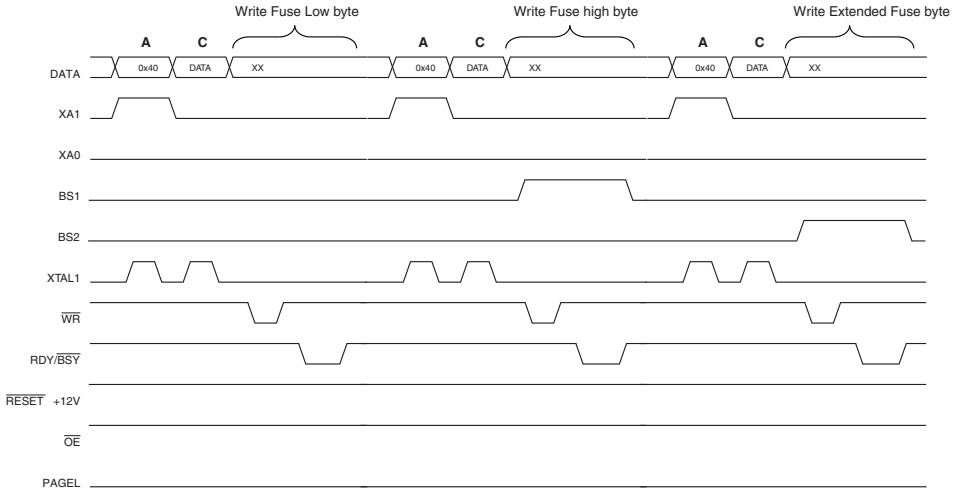
1. A: Load Command “0100 0000”.
2. C: Load Data Low Byte. Bit n = “0” programs and bit n = “1” erases the Fuse bit.
3. Give $\overline{WR}$ a negative pulse and wait for RDY/$\overline{BSY}$ to go high.

30.7.10 Programming the fuse high bits

The algorithm for programming the Fuse High bits is as follows (refer to ”Programming the flash” on page 214 for details on Command and Data loading):

1. A: Load Command “0100 0000”.
2. C: Load Data Low Byte. Bit n = “0” programs and bit n = “1” erases the Fuse bit.
3. Set BS1 to “1” and BS2 to “0”. This selects high data byte.
4. Give $\overline{WR}$ a negative pulse and wait for RDY/$\overline{BSY}$ to go high.
5. Set BS1 to “0”. This selects low data byte.

Figure 30-7. Programming the FUSES waveforms.



30.7.11 Programming the lock bits

The algorithm for programming the Lock bits is as follows (refer to ”Programming the flash” on page 214 for details on Command and Data loading):

1. A: Load Command “0010 0000”.
2. C: Load Data Low Byte. Bit n = “0” programs the Lock bit. If LB mode 3 is programmed (LB1 and LB2 is programmed), it is not possible to program the Boot Lock bits by any External Programming mode.
3. Give $\overline{WR}$ a negative pulse and wait for RDY/$\overline{BSY}$ to go high.

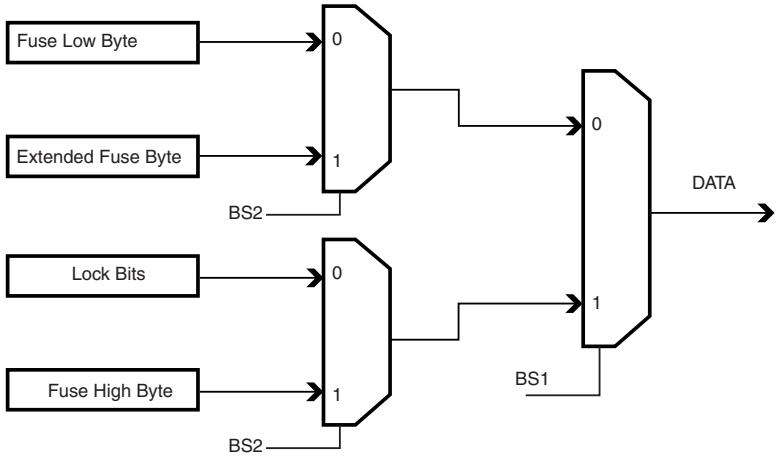
The Lock bits can only be cleared by executing Chip Erase.

30.7.12 Reading the fuse and lock bits

The algorithm for reading the Fuse and Lock bits is as follows (refer to ”Programming the flash” on page 214 for details on Command loading):

1. A: Load Command “0000 0100”.
2. Set $\overline{OE}$ to “0”, BS2 to “0” and BS1 to “0”. The status of the Fuse Low bits can now be read at DATA (“0” means programmed).
3. Set $\overline{OE}$ to “0”, BS2 to “1” and BS1 to “1”. The status of the Fuse High bits can now be read at DATA (“0” means programmed).
4. Set $\overline{OE}$ to “0”, BS2 to “0” and BS1 to “1”. The status of the Lock bits can now be read at DATA (“0” means programmed).
5. Set $\overline{OE}$ to “1”.

Figure 30-8. Mapping between BS1, BS2 and the fuse and lock bits during read.



30.7.13 Reading the Signature bytes

The algorithm for reading the Signature bytes is as follows (refer to ”Programming the flash” on page 214 for details on Command and Address loading):

1. A: Load Command “0000 1000”.
2. B: Load Address Low Byte (0x00 - 0x02).
3. Set $\overline{OE}$ to “0”, and BS to “0”. The selected Signature byte can now be read at DATA.
4. Set $\overline{OE}$ to “1”.

30.7.14 Reading the Calibration byte

The algorithm for reading the Calibration byte is as follows (refer to ”Programming the flash” on page 214 for details on Command and Address loading):

1. A: Load Command “0000 1000”.
2. B: Load Address Low Byte, 0x00.
3. Set $\overline{OE}$ to “0”, and BS1 to “1”. The Calibration byte can now be read at DATA.
4. Set $\overline{OE}$ to “1”.

31. Operating circuit

Figure 31-1. Operating circuit, 4-cell.

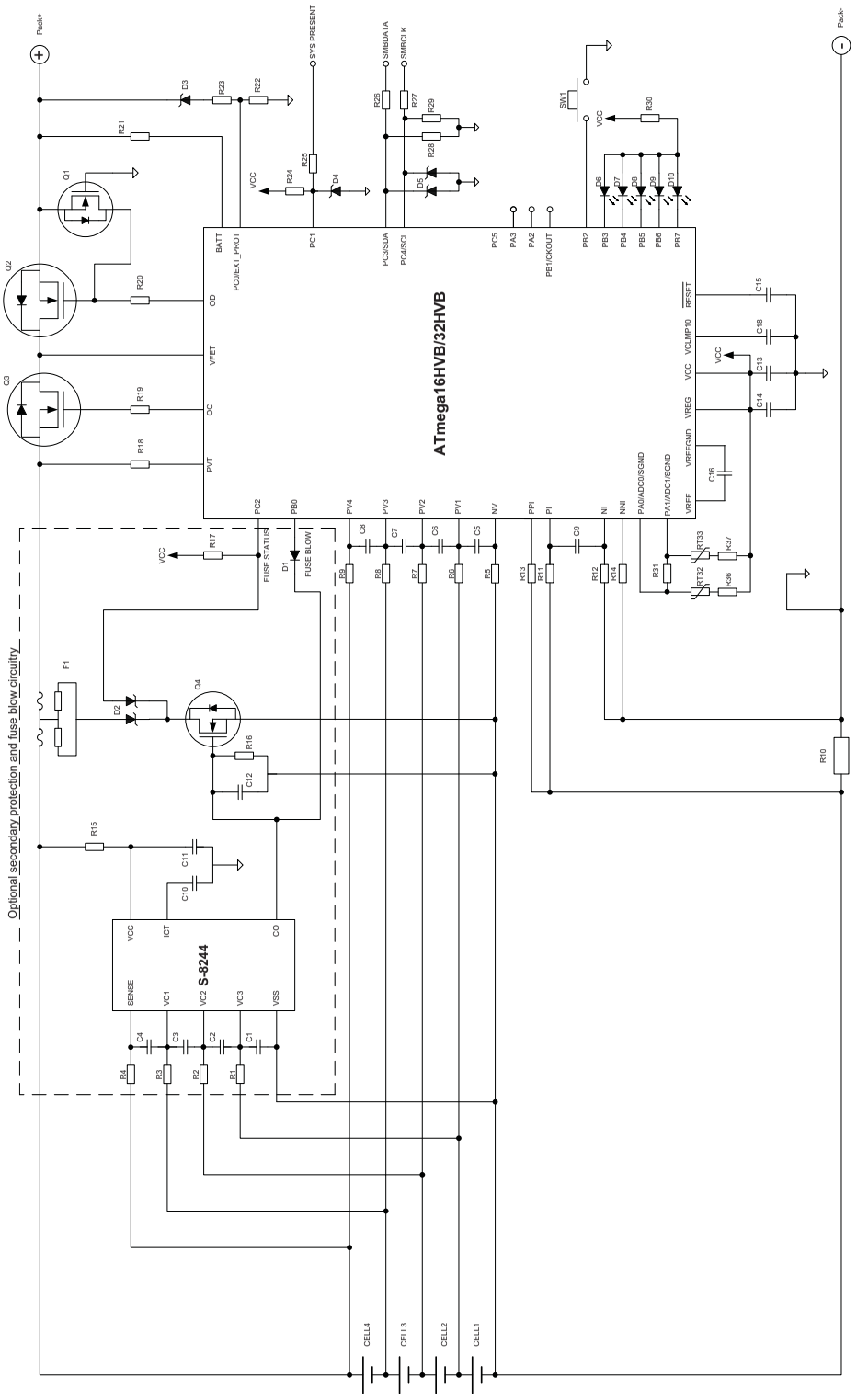


Figure 31-2. Operating circuit, 3-cell.

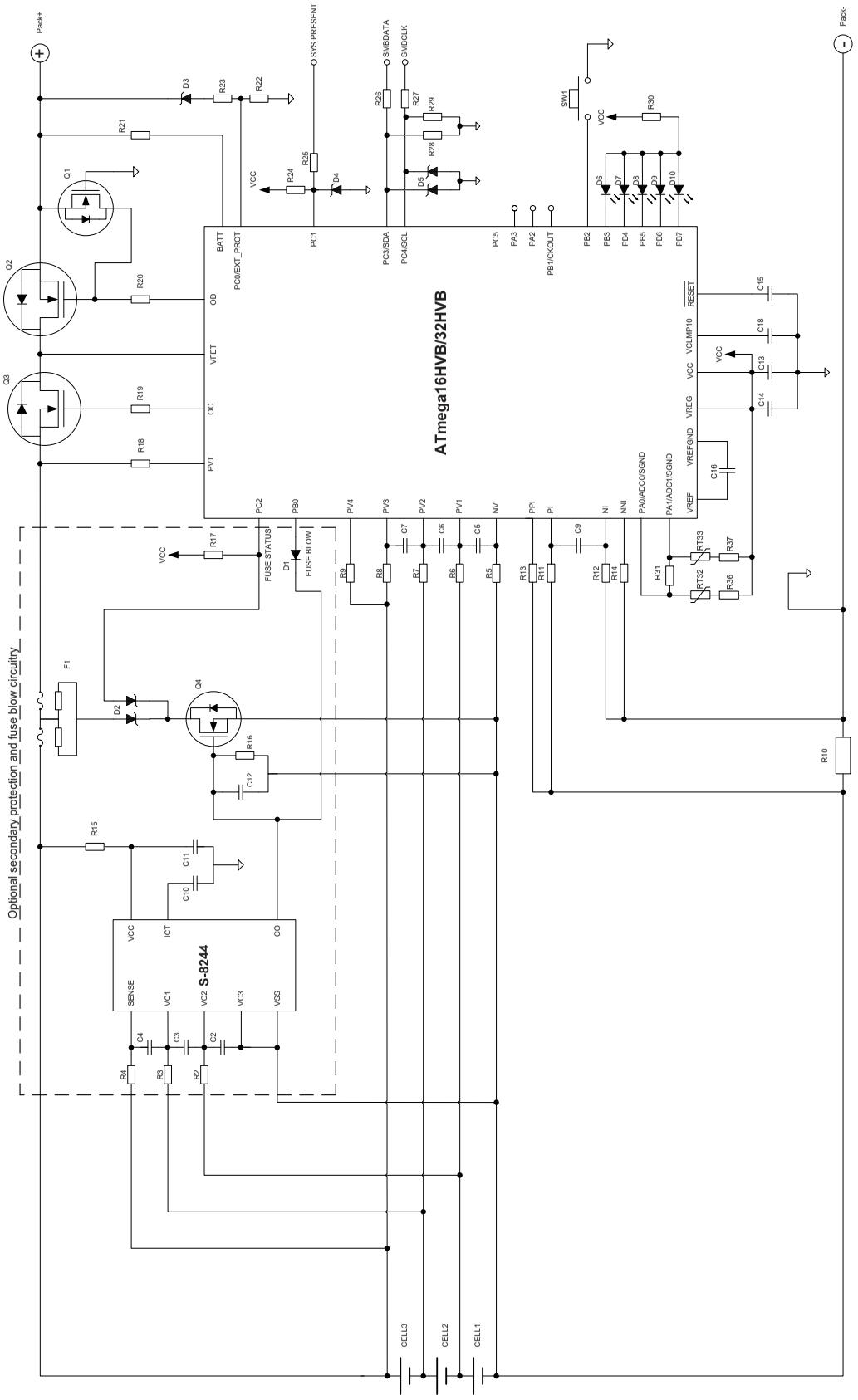


Figure 31-3. Operating circuit, 2-cell.

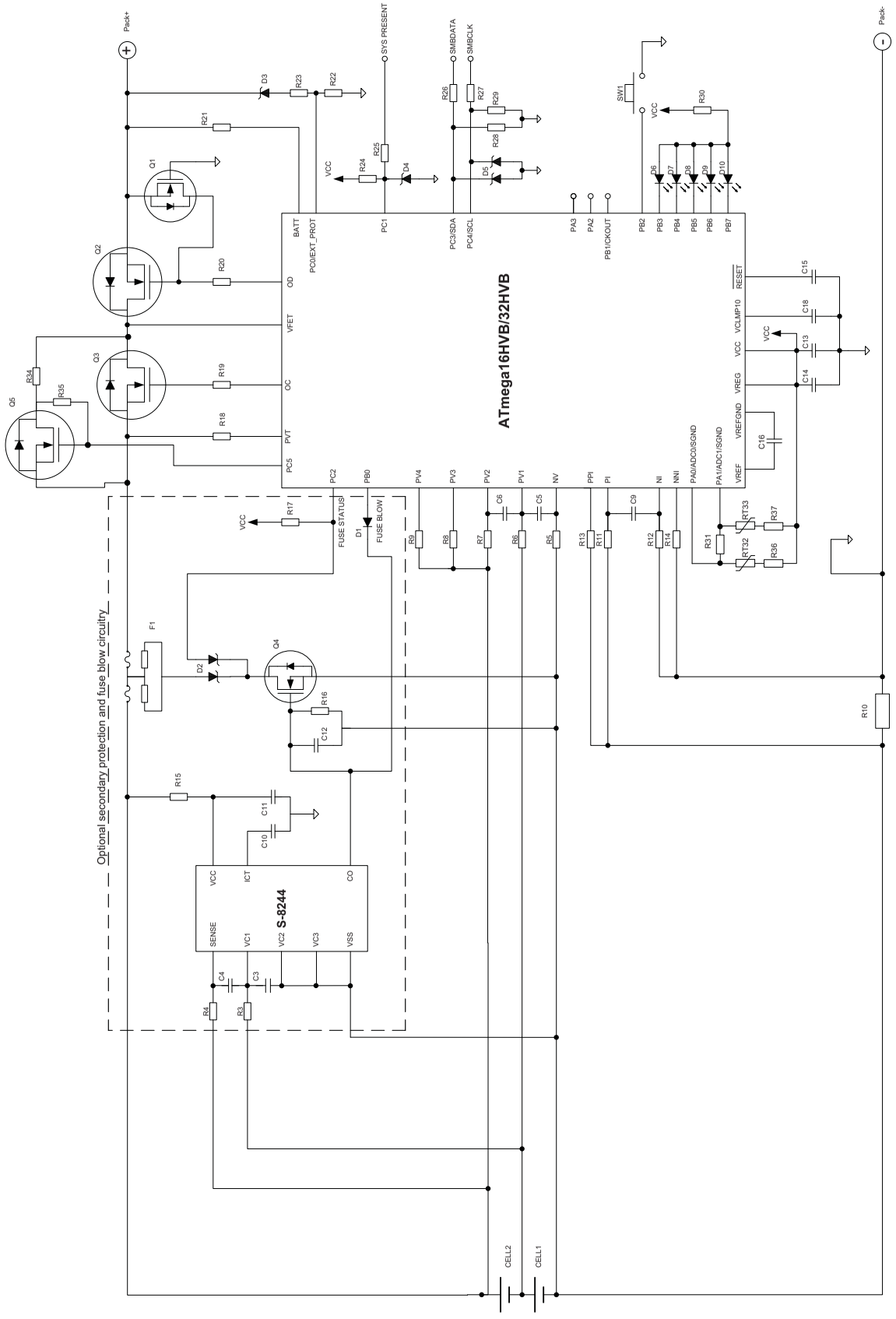


Table 31-1. Bill of materials.

Symbol	Number	Description
C1-C4, C10, C11	6	Capacitor, ceramic, 0.1µF - 1.0µF , 50V, X7R
C5-C8	4	Capacitor, ceramic, 0.01µF - 0.5µF, 50V, X7R
C9, C12, C13, C15	4	Capacitor, ceramic, 0.1µF, 50V, X7R
C14	1	Capacitor, ceramic, 2.2µF - 4.7µF, 10V, X7R
C16	1	Capacitor, ceramic, 1µF - 22µF, 10V, X7R
C18	1	Capacitor, ceramic, 22nF, 50V, X7R
D1	1	Diode, signal
D2	1	Diode, double, Shottky
D4	1	Diode, signal
D3	1	Diode, Zener, value from design considerations
D4	1	Diode, Zener, 5V6
D5	1	Diode, double, Zener, 5V6
D6-D10	5	LEDs
F1	1	Chemical fuse
Q1	1	N-FET, 50V, 0.22A
Q2, Q3	2	N-FET, 30V, 10A
Q4	1	N-FET, 20V, 1.3A
Q5	1	P-FET, 30V, 10A
R1-R4	4	Resistor, chip, 1kΩ - 10kΩ, 1/16W, 5%
R5-R9	5	Resistor, chip, 10kΩ - 1000Ω, 1/16W, 5%
R10	1	Sense resistor, 1mΩ - 10mΩ, 1W, 1%
R11, R12	2	Resistor, chip, 10Ω - 500Ω, 1/16W, 5%
R13, R14, R18, R19, R20, R21, R25	7	Resistor, chip 1kΩ, 1/16W, 5%
R15	1	Resistor, chip, 100Ω - 1000Ω, 1/16W, 5%
R16, R17	2	Resistor, chip 200kΩ, 1/16W, 5%
R22	1	Resistor, value from design considerations
R23	1	Resistor, value from design considerations
R24	1	Resistor, chip 1kΩ, 1/16W, 5%
R26, R27	2	Resistor, chip 100Ω, 1/16W, 5%
R28, R29	2	Resistor, chip 1MΩ, 1/16W, 5%
R30	1	Resistor, chip 820Ω, 1/16W, 5%
R31	1	Resistor, chip 2.4kΩ, 1/16W, 5%
R32, R33	2	NTC thermistor, 10kΩ, B = 3000 - 4000
R34	1	Resistor, value determined by battery pack and charger requirements
R35	1	Resistor, chip 1MΩ, 1/16W, 5%

Symbol	Number	Description
R36, R37	2	Resistor, chip 5.1kΩ, 1/16W, 5%
SW	1	Switch, push button
U1	1	Atmel ATmega32HVB
U2	1	S-8244 secondary protection device (Seiko Instruments)

32. Electrical characteristics

32.1 Absolute maximum ratings*

Operating temperature..... -40°C to +85°C

Storage temperature..... -65°C to +150°C

Voltage on PA0 - PA3, PI, NI, PPI and NNI with respect to ground ..... -0.5V to V_{REG} +0.5V

Voltage on PB0 - PB7 with respect to ground ..... -0.5V to VCC +0.5V

Voltage on PC0 - PC4, PV1, and NV with respect to ground.....-0.5V to +6.0V

Voltage on OC and OD with respect to ground...-0.5V to +35V

Voltage on PC5, BATT, PVT, VFET, PV4, PV3, and PV2 with respect to ground .....-0.5V to +25V

Voltage on PV4 with respect to PV3: ..... -0.5V to +10V

Voltage on PV3 with respect to PV2: ..... -0.5V to +10V

Voltage on PV2 with respect to PV1: ..... -0.5V to +10V

Voltage on PV1 with respect to NV: ..... -0.5V to +10V

Voltage on PVT with respect to VFET: 10V

Voltage on VCLMP10 and $\overline{\text{RESET}}$ with respect to ground .....-0.5V to +13V

Maximum operating voltage on VREG and VCC..... 4.5V

Maximum operating voltage on VFET 18V

*NOTICE: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

32.2 Supply current characteristics

Table 32-1. T_A= 25°C unless otherwise noted.

Symbol	Parameter	Condition	Minimum	Typical	Maximum	Units
I_{VFET}	Active current	VFET = 16V, CPU clock = 8MHz, All PRR bits set		3.75	5	mA
		VFET = 16V, CPU clock = 1MHz, All PRR bits set		760	1000	µA
	Idle current	VFET = 16V, CPU clock = 1MHz, All PRR bits set		215	293	
	ADCNRM current	VFET = 16V, CPU clock = 1MHz, All PRR bits except PRVADC are set, VADC enabled		350		
	Power-save current	VFET = 16V, Only WDT enabled, DUVR mode disabled		28	46	
		VFET = 16V, WDT, CC-ADC, OC, OD and Battery Protection enabled, DUVR mode disabled		115	170	
	Power-off current	VFET = 6V		<1	2	

32.3 NFET driver characteristics

Table 32-2. T_A= 25°C unless otherwise noted.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$V_{OC,ON}$	OC pin on voltage relative to PVT voltage	OC enabled, VFET = 16V		13		V
		OC enabled, VFET = 10V		13		
		OC enabled, VFET = 4V		6		
$V_{OD,ON}$	OD pin on voltage relative to BATT voltage	OD enabled, VFET = 16V		13		
		OD enabled, VFET = 10V		13		
		OD enabled, VFET = 4V		6		
$V_{OC,OFF}$	OC pin off voltage realtive to GND			0.0		
$V_{OD,OFF}$	OD pin off voltage realtive to GND			0.0		
$t_{r,OC}$	Rise time on OC pin	$V_{(OC-PVT)}$ = 0V to 2V, C_{eq} = 4.7nF, VFET = 16V		0.8		ms
		$V_{(OC-PVT)}$ = 0V to 2V, C_{eq} = 4.7nF, VFET = 10V		1.1		
		$V_{(OC-PVT)}$ = 0V to 2V, C_{eq} = 4.7nF, VFET = 6V		3		
		$V_{(OC-PVT)}$ = 2V to 4V, C_{eq} = 4.7nF, VFET = 16V		1		
		$V_{(OC-PVT)}$ = 2V to 4V, C_{eq} = 4.7nF, VFET = 10V		1.2		
		$V_{(OC-PVT)}$ = 2V to 4V, C_{eq} = 4.7nF, VFET = 6V		1.3		
$t_{r,OD}$	Rise time on OD pin	$V_{(OD-BATT)}$ = 0V to 2V, C_{eq} = 4.7nF, VFET = 16V		0.8		
		$V_{(OD-BATT)}$ = 0V to 2V, C_{eq} = 4.7nF, VFET = 10V		1.1		
		$V_{(OD-BATT)}$ = 0V to 2V, C_{eq} = 4.7nF, VFET = 6V		3		
		$V_{(OD-BATT)}$ = 2V to 4V, C_{eq} = 4.7nF, VFET = 16V		1		
		$V_{(OD-BATT)}$ = 2V to 4V, C_{eq} = 4.7nF, VFET = 10V		1.2		
		$V_{(OD-BATT)}$ = 2V to 4V, C_{eq} = 4.7nF, VFET = 6V		1.3		
$t_{f,OC}$	Fall time on OC pin	$V_{(OD-PVT)}$ = $V_{OC,ON}$ to 0V, C_{eq} = 4.7nF, VFET = 16V		50		ns
$t_{f,OD}$	Fall time on OD pin	$V_{(OD-BATT)}$ = $V_{OD,ON}$ to 0V, C_{eq} = 4.7nF, VFET = 16V		50		
I_{LOAD}	OC/OD drive capability (1)	V_{FET} = 9V, T_A = 85°C			3.5	µA
$V_{VFET,DUVR}$	Regulated VFET voltage in DUVR mode	DUVR enabled, VREF = 1.1V	4.1		4.9	V

Notes: 1. Measures NFET driver's ability to switch OC/OD from 0V to specified output level with constant resistive load on the pin. Loads above this limit may cause OC/OD not reaching the specified level. Drive capability is highly temperature dependent. Refer to Section 33.2 "NFET driver characteristics" on page 245 for details.

Note: The NFET drivers require a minimum total cell voltage of 6V or higher or a charger connected to turn-on the FETs. Note that this limit only applies if the FET is disabled in advance. If the FET is already enabled, the FET will be fully operational in the entire voltage range of the device (4V to 18V).

32.4 Reset characteristics

Table 32-3. T_A= -40°C to +85°C unless otherwise noted.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{POT}	Power-on threshold voltage (rising) (1)		4.5		7	V
	Power-on threshold voltage (falling) (1)(2)		4.5		6.3	
t_{RST}	Minimum pulse width on $\overline{\text{RESET}}$ Pin			900		ns
V_{BOT}	Brown-out detection (BOD) trigger level	T_A = 25°C		2.9	3.1	V
V_{HYST}	BOD level hysteresis	T_A = 25°C		50		mV

Notes:
1. The voltage at the pack + terminal will be slightly higher than V_{POT} when the chip is enabled. This is because of an internal Pull-down current on the BATT pin in the range 50µA - 150µA and the R_{BATT} resistor connected between the Pack + terminal and the BATT pin. R_{BATT} = 1k gives a voltage drop 0.05V - 0.15V.
2. The power-on reset will not work unless the voltage has been below V_{POT} (falling) after a power-off condition.

32.5 Voltage regulator characteristics

Table 32-4. T_A= -40°C to +85°C unless otherwise noted.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{VREG}	Regulator output voltage	VFET = 16.8V, I_{OUT} = 20mA	3.1			V
		VFET = 6V, I_{OUT} = 20mA	3.1			
		VFET = 4V, I_{OUT} = 7mA	3.1			
V_{RSCL}	Voltage regulator short- circuit Level at VFET pin		3.3		3.8	
V_{BLOD}	Voltage Regulator Black-out Detection Level at VREG pin	T_A = 25°C		2.65	2.75	

32.6 Voltage reference and temperature sensor characteristics

Table 32-5. T_A= -40°C to +85°C unless otherwise noted.

Parameter	Condition	Min.	Typ.	Max.	Units
Reference voltage			1.100		V
Reference voltage accuracy (1)	After factory calibration, T_A = 25°C		±0.1	±0.2	%
Temperature drift (1)(2)	T_A = -40°C to +85°C		60	90	ppm/K
	T_A = 0°C to +60°C		25	50	
VREF calibration Hold Off Time	CREG = 2.2µF, BGCCR write	2			µs
	CREG = 2.2µf, BGCRR write	5			
V_{PTAT}, voltage proportional to absolute temperature (2)			0.6		mV/K
V_{PTAT} absolute accuracy (3)				±5	K

Notes:
1. Calibration is done in Atmel factory test. Software should calibrate the VREF by writing the BGCRR and BGCCR registers with the calibration values stored in the signature row.
2. This value is not tested in production.
3. The measured V_{PTAT} voltage must be scaled with the calibration value stored in the V_{PTAT} Calibration Register to get the absolute temperature. The design target accuracy for this parameter assumes an exact calibration temperature. Actual accuracy of this parameter after calibration in Atmel factory test remains to be determined.

32.7 ADC characteristics

32.7.1 Voltage ADC characteristics

Table 32-6. T_A= -40°C to +85°C unless otherwise noted.

Parameter	Condition	Min.	Typ.	Max.	Units
Conversion time	clk_{VADC} = 1MHz		519		µs
Resolution			12		Bits
Gain ADC0/1 (un-scaled)			263		µV/LSB
Gain cell inputs (x0.2)			1.42		mV/LSB
INL (2)	ADC0, ADC1		±1	±3	LSB
	CELL1, CELL2, CELL3		±1	±3	
	CELL4		±2	±5	
Input voltage range ADC0, ADC1, VTEMP		0		1	V
Input voltage range CELL1		1.8		5	
Input voltage range CELL2	$V_{PV1-GND}$>1.8V	0		5	
Input voltage range CELL3	$V_{PV2-GND}$>1.8V	0		5	
Input voltage range CELL4	$V_{PV3-GND}$>1.8V	0		5	
Offset drift (1)(2)	ADC0, ADC1		1		LSB
	CELL1, CELL2, CELL3		1		
	CELL4		5		
Gain drift (1)(2)	ADC0, ADC1		6		LSB
	CELL1, CELL2, CELL3		7		
	CELL4		15		

Notes:
1. Value is after Atmel factory offset and gain compensation in production (for details, see Table 29-3, “Signature row addressing.,” on page 196) and it includes drift over the whole temperature range.
2. Value not tested in production but guaranteed by design and characterization.

32.7.2 Coulomb counter ADC characteristics

Table 32-7. T_A= -40°C to +85°C unless otherwise noted.

Parameter	Condition	Min.	Typ.	Max.	Units
Conversion time	Instantaneous conversion, clk_{CC-ADC} = 32kHz		3.9		ms
	Accumulated conversion CADAS = 11, clk_{CC-ADC} = 32kHz		1		s
Resolution	Instantaneous conversion		13		Bits
	Accumulated conversion		18		
Gain	Accumulated conversion, CADVSE=0		1.67		µV/LSB
	Accumulated conversion, CADVSE=1		0.84		
	Instantaneous conversion, CADVSE=0		53.7		
	Instantaneous conversion, CADVSE=1		26.9		
Input voltage range	CADVSE = 0	-200		200	mV
	CADVSE = 1	-100		100	
INL (1)	T_A= 0°C - 60°C		±0.003	±0.005	% FSR
Offset error (2)	Accumulated conversion, T_A = 25°C		-7		µV
Offset error drift (1)(2)	Accumulated conversion		30		nV/°C
Gain error (1)(3)			±0.4	±1	%
Gain error drift (1)			0.1		

Notes:
1. Values based on characterization data.
2. After software offset compensation, using the polarity switching (CADPOL) feature.
3. Value includes drift over the whole temperature range.

32.8 Clock characteristics

Table 32-8. T_A= -40°C to +85°C unless otherwise noted.

	Parameter	Condition	Min.	Typ.	Max.	Units
Calibrated fast RC oscillator	Frequency	After factory calibration at T_A = 25°C	7.92	8	8.08	MHz
	Frequency drift (2)	With run-time calibration with OSI interface and slow RC oscillator as calibration clock			3	%
Slow RC oscillator (1)	Frequency (3)		91	131	171	kHz
	Frequency prediction error (4)			0.2		%
Ultra low power RC oscillator (1)	Frequency (3)		89	128	167	kHz
	Frequency drift (2)			6		%

Notes:
1. The frequency is stored in the Value after factory calibration at 85°C.
2. Value not tested in production, but is guaranteed by design and characterization over the whole temperature range.
3. The actual oscillator frequency is measured in production and store in the device signature row (for detailes, see "Reading the signature row from software" on page 195.
4. T_A = 0°C to +85°C.

32.9 Cell balancing characteristic

Table 32-9. T_A= 25°C unless otherwise noted.

Parameter	Condition	Min.	Typ.	Max.	Unit
Balancing current	Battery cell voltage V_{CELL} = 4.2V, V-ADC filter resistance = 470Ω		4		mA

32.10 Battery protection characteristics

Table 32-10. T_A= -40°C to +85°C unless otherwise noted.

Parameter	Condition	Min.	Max.	Unit
Short circuit detection level error (1)	V_{SCD}, V_{COCD}, V_{DOCD}, V_{CHCD}, and V_{DHCD} from 20mV to 70mV (2)	-10	+10	mV
Charge/discharge over current detection level error (1)	V_{SCD}, V_{COCD}, V_{DOCD}, V_{CHCD}, and V_{DHCD} from 80mV to 140mV (2)	-15	+15	
	V_{SCD}, V_{COCD}, V_{DOCD}, V_{CHCD}, and V_{DHCD} from 150mV to 270mV (2)	-35	+35	
Charge/discharge high current detection detection level error (1)	V_{SCD}, V_{COCD}, V_{DOCD}, V_{CHCD}, and V_{DHCD} at 310mV (2)	-50	+50	

Notes: 1. Levels in charge and discharge direction can be configured independent of each other.
2. $V_{SCD} = V_{NNI} - V_{PPI}$, $V_{COCD} = V_{PPI} - V_{NNI}$, $V_{DOCD} = V_{NNI} - V_{PPI}$, $V_{CHCD} = V_{PPI} - V_{NNI}$, $V_{DHCD} = V_{NNI} - V_{PPI}$

32.11 External interrupt characteristics

Table 32-11. Asynchronous external interrupt characteristics.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
t_{INT}	Minimum pulse width for asynchronous external interrupt			50		ns

32.12 General I/O lines characteristics

32.12.1 Port A and B characteristics

Table 32-12. T_A = -40°C to +85°C, V_{CC} = 3.3V (unless otherwise noted).

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{IL}	Input low voltage, Except RESET pin		-0.5		$0.3V_{CC}$ (1)	V
V_{IL1}	Input low voltage, RESET pin				$0.3V_{CC}$ (1)	
V_{IH}	Input high voltage, Except RESET pin		$0.6V_{CC}$ (2)		V_{CC} + 0.5	
V_{IH1}	Input high voltage, RESET pin		$0.9V_{CC}$ (2)		V_{CC} + 0.5	
V_{OL}	Output low voltage	I_{OL} = 5mA			0.5	
V_{OH}	Output high voltage	I_{OH} = 2mA	2.3			
I_{IL}	Input leakage current I/O Pin	Pin low (absolute value)			1	µA
I_{IH}	Input leakage current I/O Pin	Pin high (absolute value)			1	
R_{RST}	Reset pull-up resistor		30		60	kΩ
R_{PU}	I/O pin pull-up resistor		20		50	

Notes:
1. “Max” means the highest value where the pin is guaranteed to be read as low.
2. “Min” means the lowest value where the pin is guaranteed to be read as high.
3. Although each I/O port can sink more than the test conditions (5mA at V_{CC} = 3.3V) under steady state conditions (non-transient), the following must be observed:
   - The sum of all IOL should not exceed 20mA
   If IOL exceeds the test condition, VOL may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test condition.
4. Although each I/O port can source more than the test conditions (2mA at V_{CC} = 3.3V) under steady state conditions (non-transient), the following must be observed:
   - The sum of all IOH should not exceed 2mA
   This restriction is put because the device should be within spec throughout the whole operation range. The integrated voltage regulator could have problems providing this output when supplying high currents at low VFET voltages.
5. The typical hysteresis on V_{IL}/V_{IH} is 300mV on all PA and PB pins except PA3. PA3 has a typical hysteresis of 50mV.

32.12.2 Port C characteristics

Table 32-13. PC0-PC4 characteristics.

Symbol	Parameter	Condition	Min.	Max.	Unit
V_{IL}	Input low-voltage		-0.5	0.8	V
V_{IH}	Input high-voltage		2.1	5.5	
V_{OL} (1)	Output low-voltage	350µA sink current	0	0.4	

Note: 1. This values is based on characterization and is not tested in production.

Table 32-14. PC5 characteristic.

Symbol	Parameter	Condition	Min.	Max.	Unit
V_{OL}	Output low-voltage	500µA sink current	0	0.2	V

32.13 2-wire serial interface characteristics

Table 32-15 describes the requirements for devices connected to the Two-wire Serial Bus. The Atmel ATmega16HVB/32HVB Two-wire Serial Interface meets or exceeds these requirements under the noted conditions.

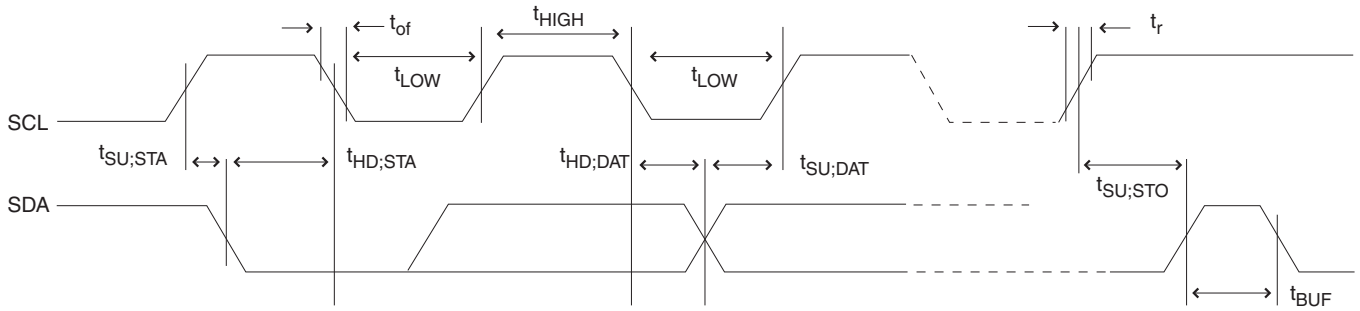
Timing symbols refer to Figure 32-1 on page 233.

Table 32-15. Two-wire serial bus requirements.

Symbol	Parameter	Condition	Minimum	Maximum	Units
V_{IL}	Input low-voltage		-0.5	0.8	V
V_{IH}	Input high-voltage		2.1	5.5	
V_{OL} (1)	Output low-voltage	350µA sink current	0	0.4	
$_{tr}$ (1)	Rise time for both SDA and SCL			300	ns
$_{tof}$ (1)	Output fall time from V_{IHmin} to V_{ILmax}	C_b < 400pF (2)		250	
$_{tSP}$ (1)	Spikes suppressed by input filter		0	50	
I_i	Input current each I/O pin	$0.1V_{BUS} < V_i < 0.9V_{BUS}$	-5	5	µA
C_i (1)	Capacitance for each I/O pin		–	10	pF
f_{SCL}	SCL clock frequency	f_{CK} (3) > max(16f_{SCL}, 450Hz) (4)	0	100	kHz
Rp	Value of pull-up resistor	f_{SCL} ≤100Hz	$\frac{V_{BUS} - 0.4V}{350\mu A}$	$\frac{V_{BUS} - 0.4V}{100\mu A}$	Ω
$t_{HD;STA}$	Hold time (repeated) START condition	f_{SCL} ≤100kHz	4.0	–	µs
t_{LOW}	Low period of the SCL clock	f_{SCL} ≤100kHz	4.7	–	
t_{HIGH}	High period of the SCL clock	f_{SCL} ≤100kHz	4.0	–	
$t_{SU;STA}$	Set-up time for a repeated START condition	f_{SCL} ≤100kHz	4.7	–	
$t_{HD;DAT}$	Data hold time	f_{SCL} ≤100kHz	0.3	3.45	
$t_{SU;DAT}$	Data setup time	f_{SCL} ≤100kHz	250	–	
$t_{SU;STO}$	Setup time for STOP condition	f_{SCL} ≤100kHz	4.0	–	
t_{BUF}	Bus free time between a STOP and START condition	f_{SCL} ≤100kHz	4.7	–	

Notes:
1. In ATmega16HVB/32HVB, this parameter is characterized and not tested.
2. C_b = capacitance of one bus line in pF.
3. f_{CK} = CPU clock frequency.
4. This requirement applies to all ATmega16HVB/32HVB Two-wire Serial Interface operation. Other devices connected to the Two-wire Serial Bus need only obey the general f_{SCL} requirement.

Figure 32-1. Two-wire serial bus timing.



32.14 SPI timing characteristics

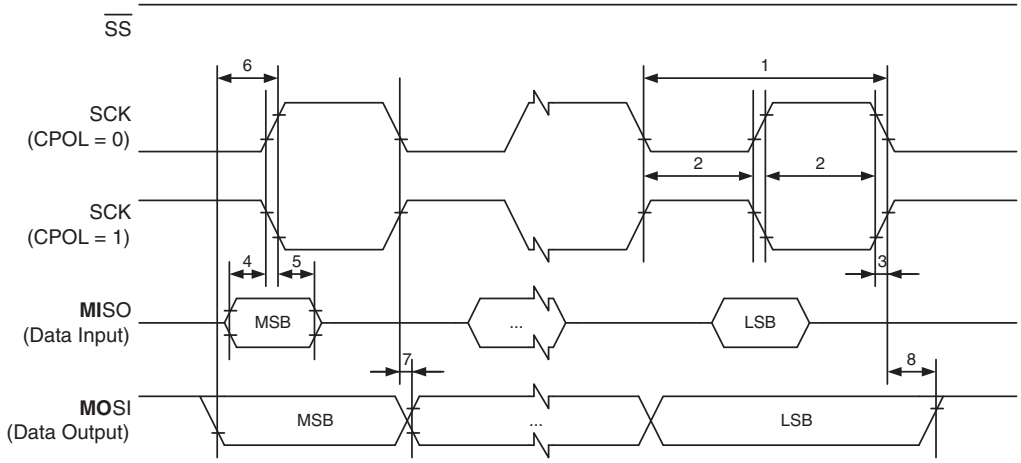
See Figure 32-2 on page 234 and SPI interface timing requirements (Slave mode).234 for details.

Table 32-16. SPI timing parameters.

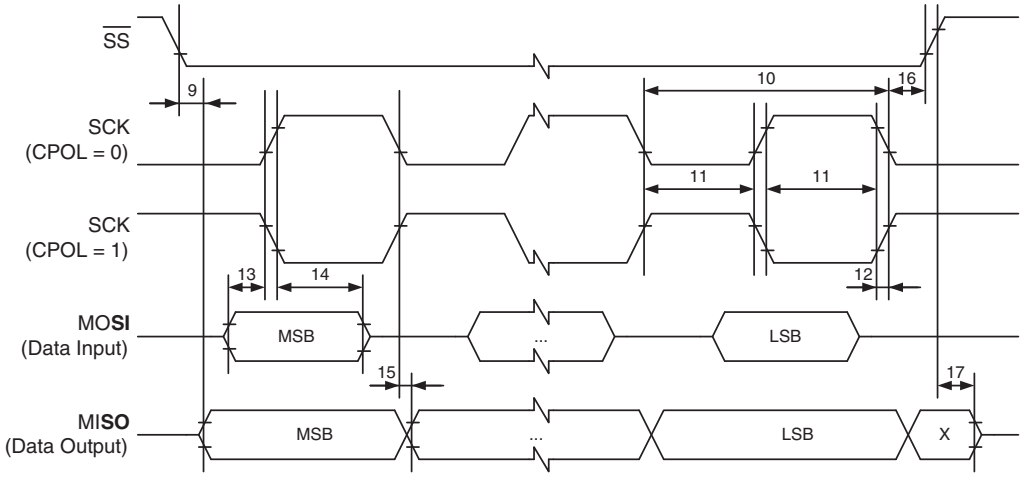
	Description	Mode	Minimum	Typical	Maximum	Units
1	SCK period	Master		See Figure 18-5 on page 106		ns
2	SCK high/low	Master		50% duty cycle		
3	Rise/fall time	Master		3.6		
4	Setup	Master		10		
5	Hold	Master		10		
6	Out to SCK	Master		0.5 • t_{sck}		
7	SCK to out	Master		10		
8	SCK to out high	Master		10		
9	$\overline{SS}$ low to out	Slave		15		
10	SCK period	Slave	4 • t_{ck} + 40ns			
11	SCK high/low (1)	Slave	2 • t_{ck} + 20ns			
12	Rise/fall time	Slave		1.6		µs
13	Setup	Slave	10			ns
14	Hold	Slave	t_{ck}			
15	SCK to out	Slave		15		
16	SCK to $\overline{SS}$ high	Slave	20			
17	$\overline{SS}$ high to tri-state	Slave		10		
18	$\overline{SS}$ low to SCK	Slave	20			

Note: 1. Refer to "Serial programming" on page 207 for serial programming requirements.

Figure 32-2. SPI interface timing requirements (Master mode).



SPI interface timing requirements (Slave mode).



32.15 Serial programming characteristics

Figure 32-3. Serial programming timing.

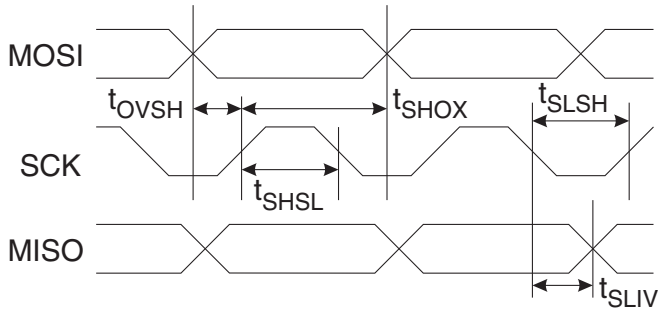


Figure 32-4. Serial programming waveforms.

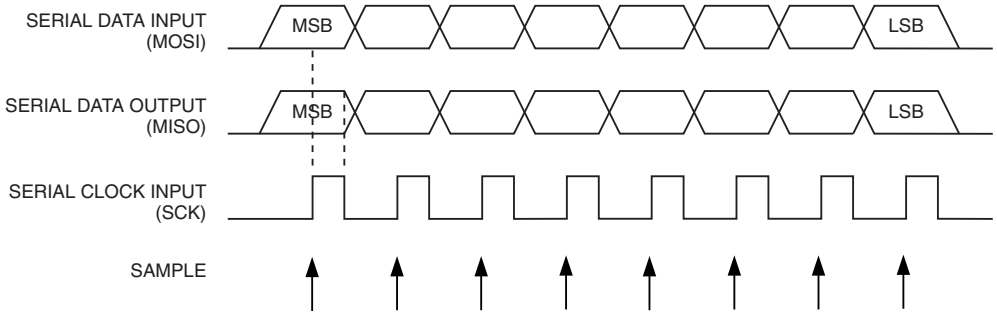


Table 32-17. Serial programming characteristics, T_A = -40°C to +85°C, V_{CC} = 3.3V (unless otherwise stated).

Symbol	Parameter	Min.	Typ.	Max.	Units
$1/t_{CLCL}$	Oscillator frequency (the Atmel ATmega16HVB/32HVB)	0		8	MHz
t_{CLCL}	Oscillator period (ATmega16HVB/32HVB)	125			ns
t_{SHSL}	SCK pulse width high	2.2 t_{CLCL} (1)			
t_{SLSH}	SCK pulse width low	2.2 t_{CLCL} (1)			
t_{OVSH}	MOSI setup to SCK high	t_{CLCL}			
t_{SHOX}	MOSI Hold after SCK High	2 t_{CLCL}			
t_{SLIV}	SCK Low to MISO Valid		15		

Note: 1. 2.2 t_{CLCL} for f_{ck} < 12MHz, 3 t_{CLCL} for f_{ck} >= 12MHz.

32.16 Parallel programming characteristics

Figure 32-5. Parallel programming timing, including some general timing requirements.

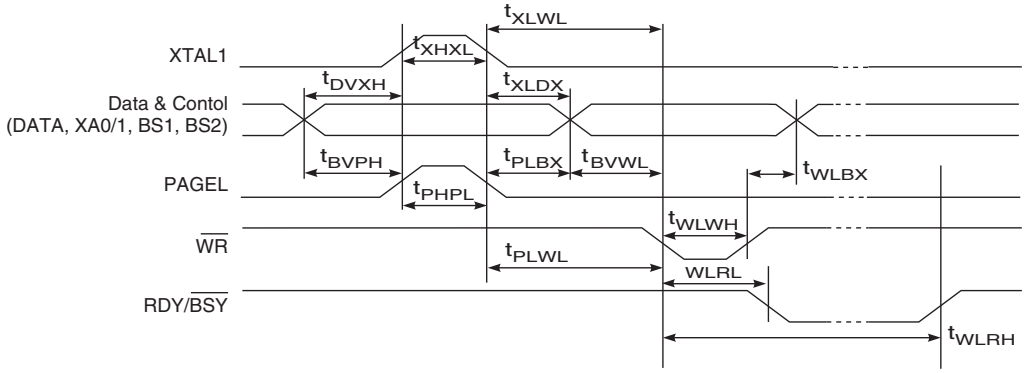
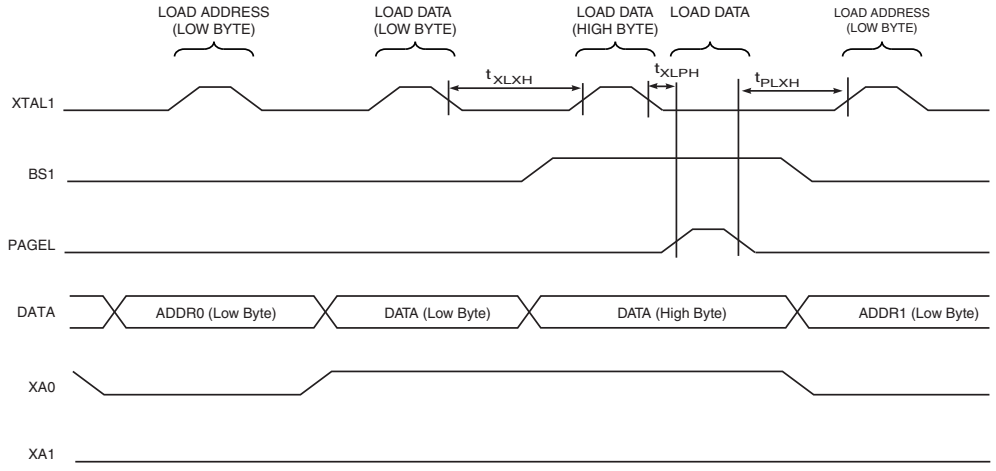
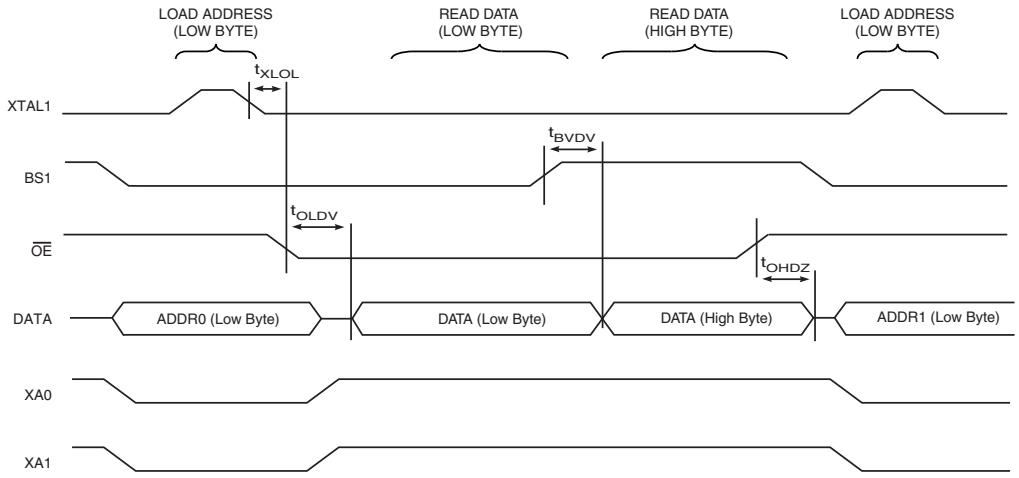


Figure 32-6. Parallel programming timing, loading sequence with timing requirements[1].



Note: 1. The timing requirements shown in Figure 32-5 on page 235 (that is, t_{DVXH}, t_{XHXL}, and t_{XLDX}) also apply to loading operation.

Figure 32-7. Parallel programming timing, reading sequence (within the same page) with timing requirements [1].



Note: 1. The timing requirements shown in Figure 32-5 on page 235 (that is, t_{DVXH}, t_{XHXL}, and t_{XLDX}) also apply to reading operation.

Table 32-18. Parallel programming characteristics.

Symbol	Parameter	Min.	Typ.	Max.	Units
V_{PP}	Programming enable voltage (RESET input)	11.5		12.5	V
I_{PP}	Programming enable current			250	µA
t_{DVXH}	Data and control valid before XTAL1 high	67			ns
t_{XLXH}	XTAL1 low to XTAL1 high	200			
t_{XHXL}	XTAL1 pulse Width high	150			
t_{XLDX}	Data and control hold after XTAL1 low	67			

Table 32-18. Parallel programming characteristics. (Continued)

Symbol	Parameter	Min.	Typ.	Max.	Units
t_{XLWL}	XTAL1 low to $\overline{WR}$ low	0			ns
t_{XLPH}	XTAL1 low to PAGEL high	0			
t_{PLXH}	PAGEL low to XTAL1 high	150			
t_{BVPH}	BS1 valid before PAGEL high	67			
t_{PHPL}	PAGEL pulse width high	150			
t_{PLBX}	BS1 hold after PAGEL low	67			
t_{WLBX}	BS2/1 hold after $\overline{WR}$ low. (Fuse programming)	3200			
	BS2/1 hold after $\overline{WR}$ low. (All other operations)	67			
t_{PLWL}	PAGEL low to $\overline{WR}$ low	67			
t_{BVWL}	BS1 valid to $\overline{WR}$ low	67			
t_{WLWH}	$\overline{WR}$ pulse Width low	150			
t_{WLRL}	$\overline{WR}$ low to RDY/$\overline{BSY}$ low	0		1	µs
t_{WLRH}	$\overline{WR}$ low to RDY/$\overline{BSY}$ high (1)	3.7		4.5	ms
t_{WLRH_EE}	$\overline{WR}$ low to RDY/$\overline{BSY}$ high (2)	2.8		3.6	
t_{WLRH_CE}	$\overline{WR}$ low to RDY/$\overline{BSY}$ high for chip erase (3)	7.5		9.1	
t_{XLOL}	XTAL1 low to $\overline{OE}$ low	0			ns
t_{BVDV}	BS1 valid to DATA valid	0		250	
t_{OLDV}	$\overline{OE}$ low to DATA Valid			250	
t_{OHDZ}	$\overline{OE}$ high to DATA Tri-stated			250	

Notes:
1. t_{WLRH} is valid for the Write Flash, Write Fuse bits and Write Lock bits commands.
2. is valid for the Write EEPROM command.
3. t_{WLRH_CE} is valid for the Chip Erase command.

33. Typical characteristics

All Typical Characteristics contained in this data sheet are based on characterization of the Atmel ATmega16/32HVB.

33.1 Supply current characteristics

33.1.1 Active supply current characteristics

Active mode current measurements with all bits in the PRR registers set and all I/O modules turned off.

Figure 33-1. Active supply current vs. V_{VFET}, internal RC oscillator, 8MHz.

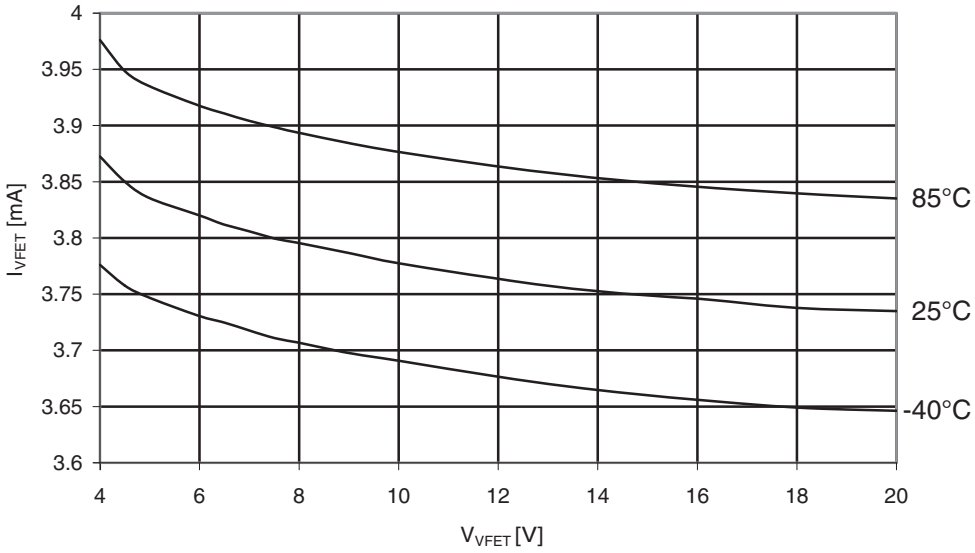


Figure 33-2. Active supply current vs. V_{VFET}, internal RC oscillator, 4MHz.

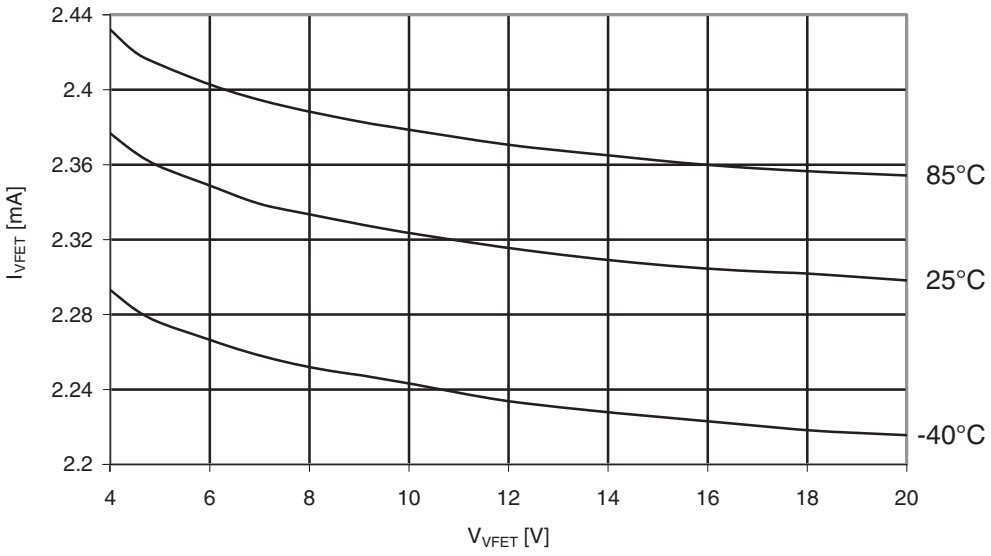


Figure 33-3. Active supply current vs. V_{VFET}, internal RC oscillator, 2MHz.

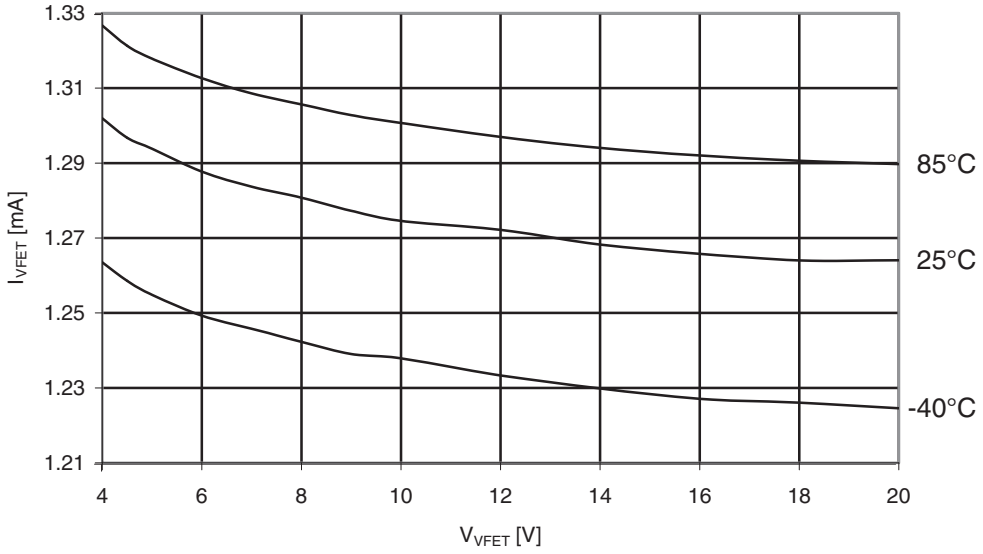
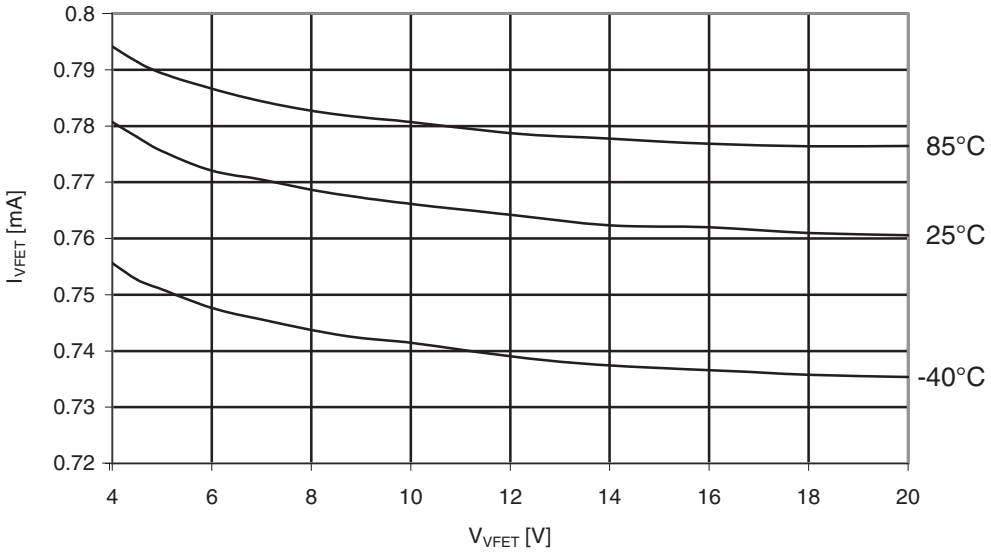


Figure 33-4. Active supply current vs. V_{VFET}, internal RC oscillator, 1MHz.



33.1.2 Idle supply current characteristics

Idle current consumption measurements with all bits in the PRR registers set and all I/O modules are turned off.

Figure 33-5. Idle supply current vs. V_{VFET}, internal RC oscillator, 8MHz.

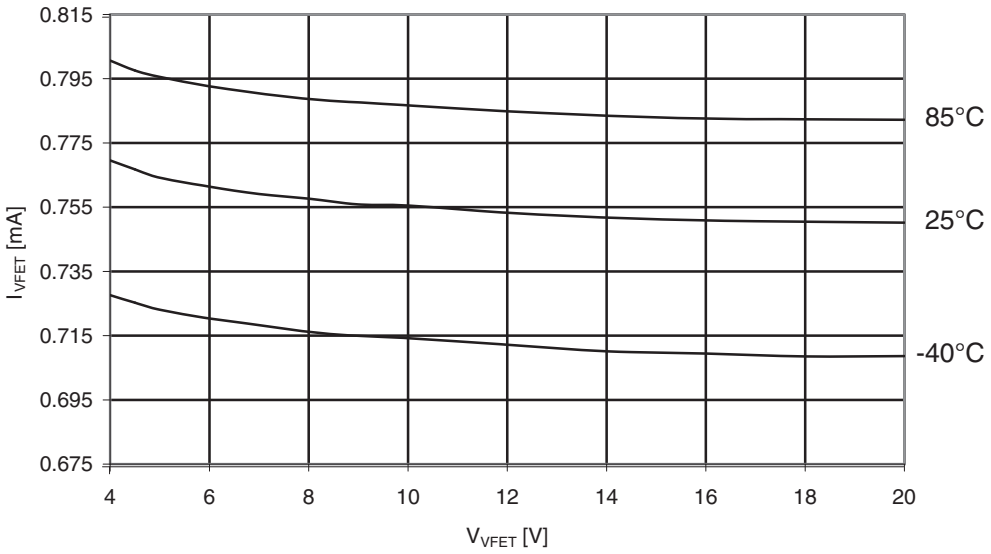


Figure 33-6. Idle supply current vs. V_{VFET}, internal RC oscillator, 4MHz.

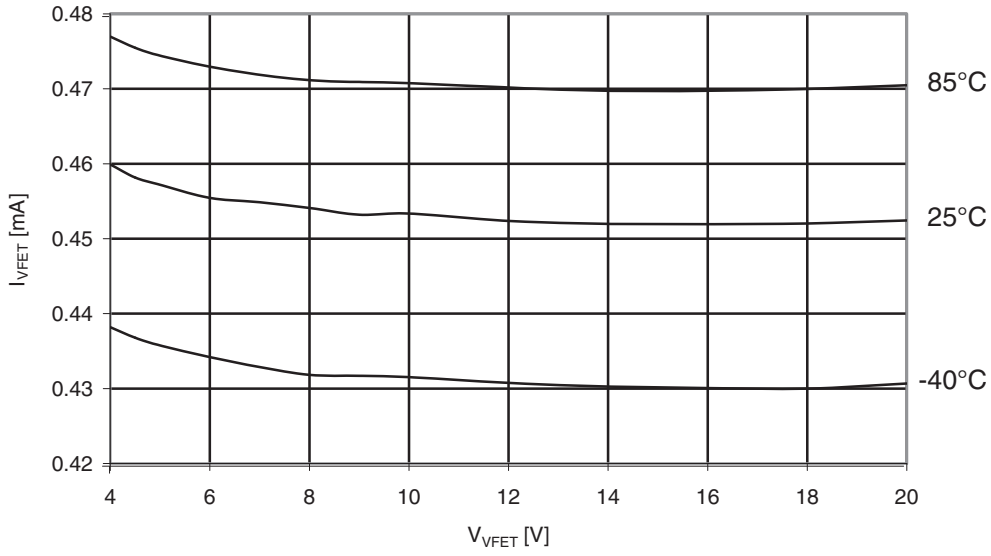


Figure 33-7. Idle supply current vs. V_{VFET}, internal RC oscillator, 2MHz.

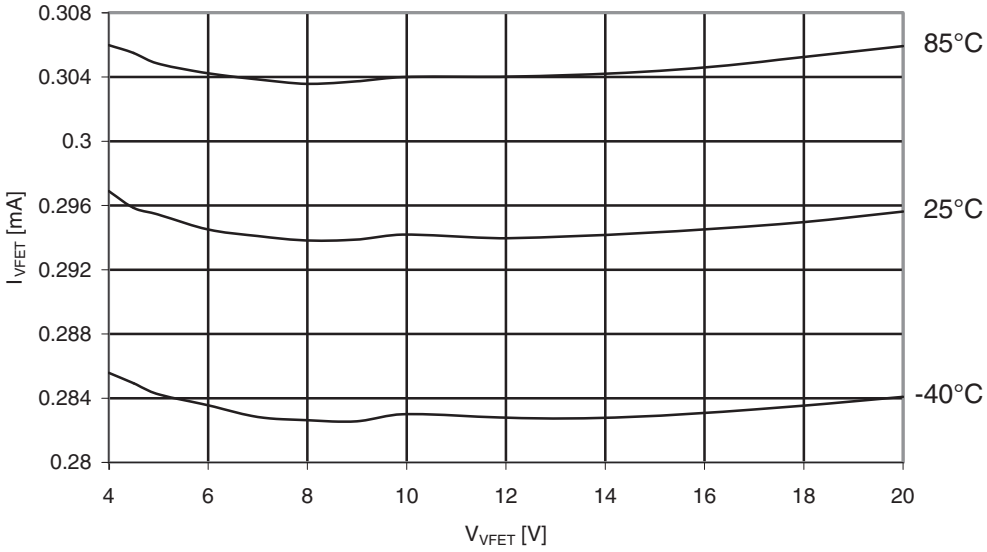
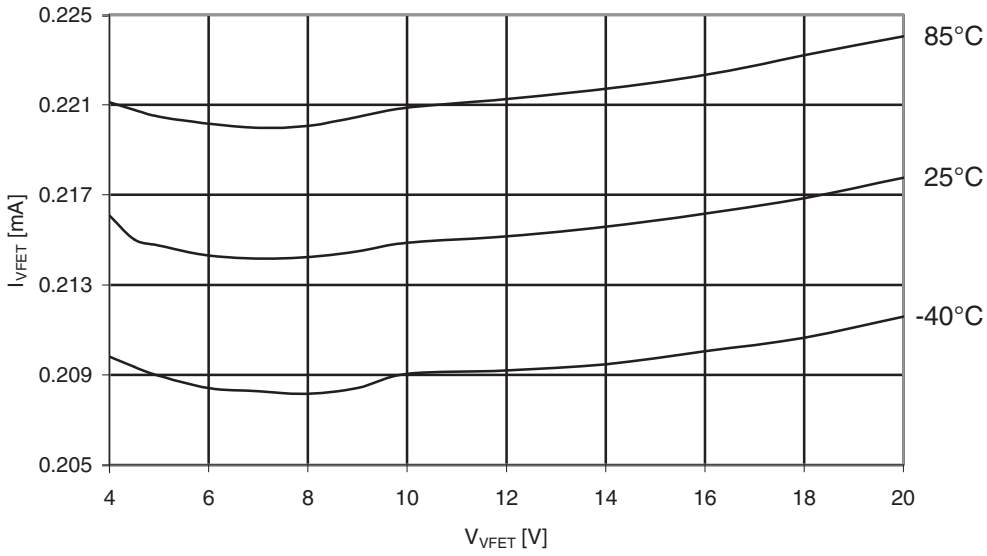


Figure 33-8. Idle supply current vs. V_{VFET}, internal RC oscillator, 1MHz.



33.1.3 Power-save current characteristics

Power-save current consumption with External Interrupt and SMBus connect/disconnect functionality enabled. The Watchdog Timer, CC-ADC, Current Battery Protection (CBP), VREF, and OC/OD are disabled.

Figure 33-9. Power-save supply current vs. V_{VFET}, external interrupt and SMBus enabled, all other modules disabled.

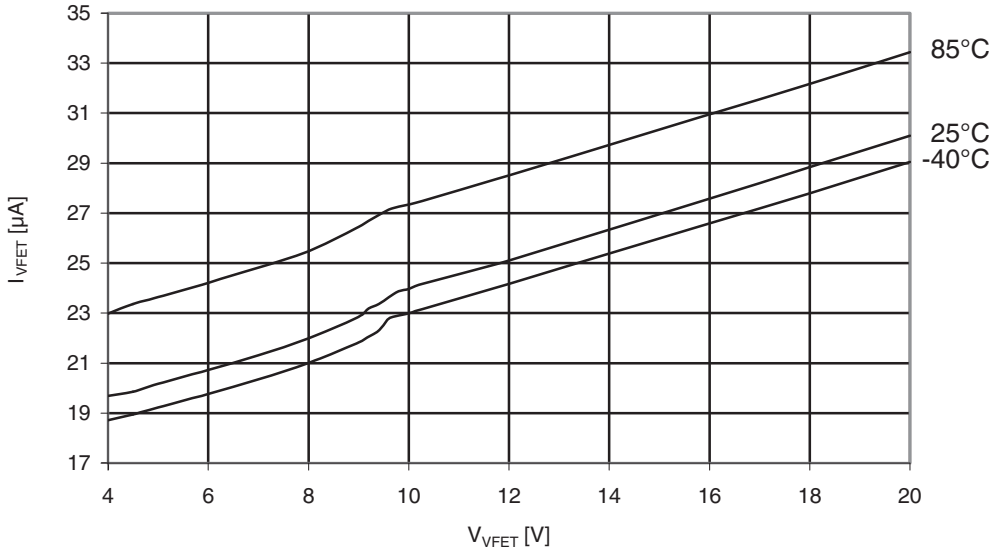


Table 33-1 shows additional current consumption that needs to be added to the total power-budget when additional modules are enableds.

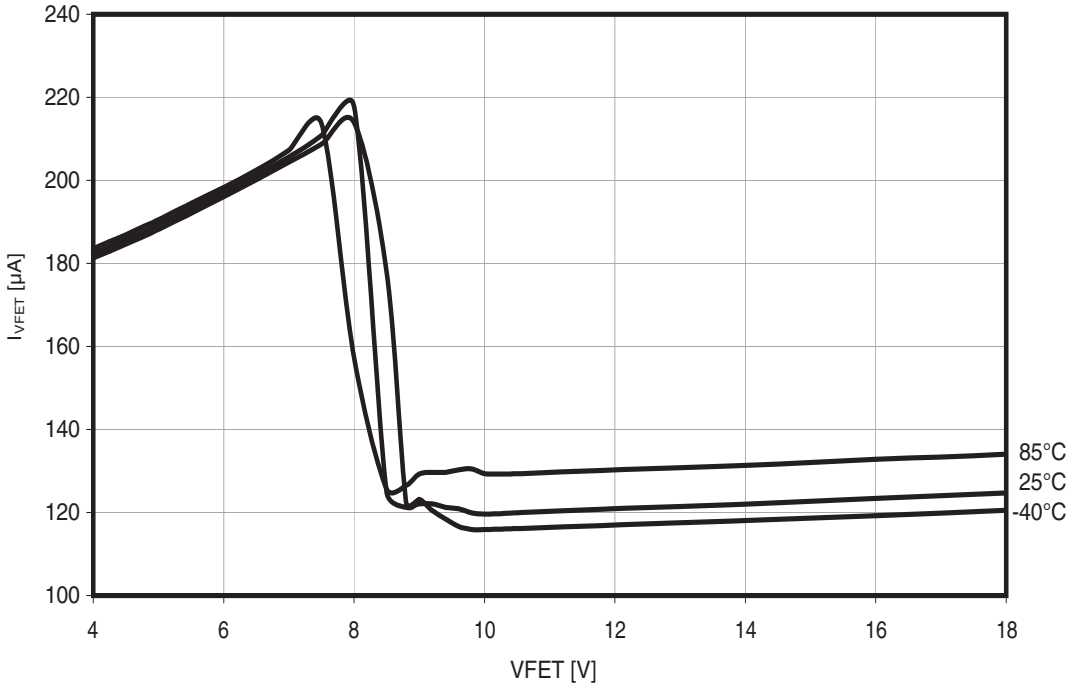
Table 33-1. Typical additional I/O modules current consumption in power-save.

I/O modules enabled					Typical current consumption
WDT	VREF	CBP (1)	OC/OD (2)	CC-ADC	(T_A = 25°C and V_{VFET} = 12V)
X					0.8µA
X	X				12µA
X	X	X	X		41µA
X	X	X	X	X	85µA

Note: 1. Default I/O register configuration used. PPI and NNI connected to GND.
2. Measurements done with Fairchild FDS6690A N-Channel MOSFET.

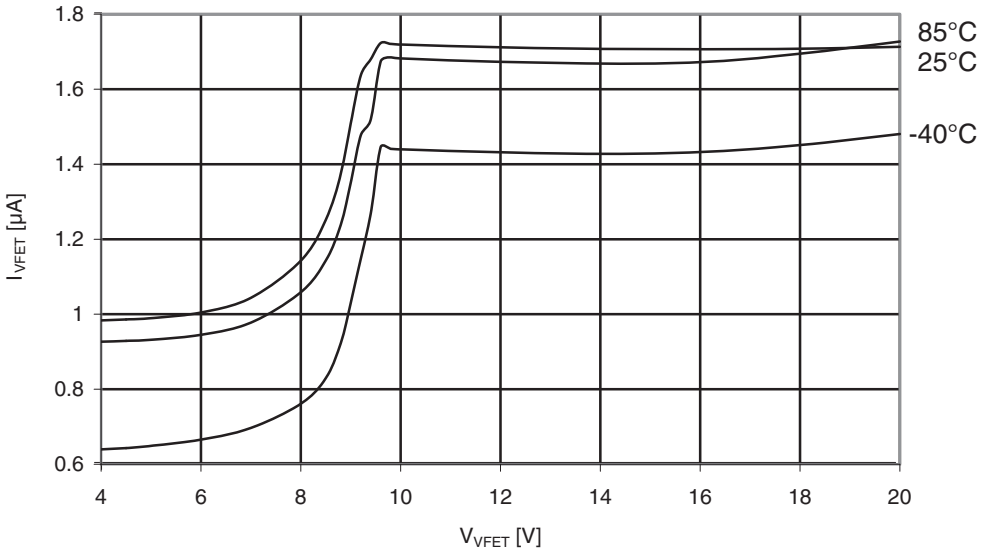
Figure 33-11 on page 245 shows Power-Save current consumption vs VFET with all modules listed in Table 33-1 enabled. The increased power consumption for low VFET voltage is caused by the NFET driver operation described in Section 25.3 ”Operation and usage” on page 146.

Figure 33-10. Power-save supply current vs. V_{VFET}, WDT, V_{REF}, CBP, OC/OD, and CC-ADC enabled.



33.1.4 Power-off current characteristics

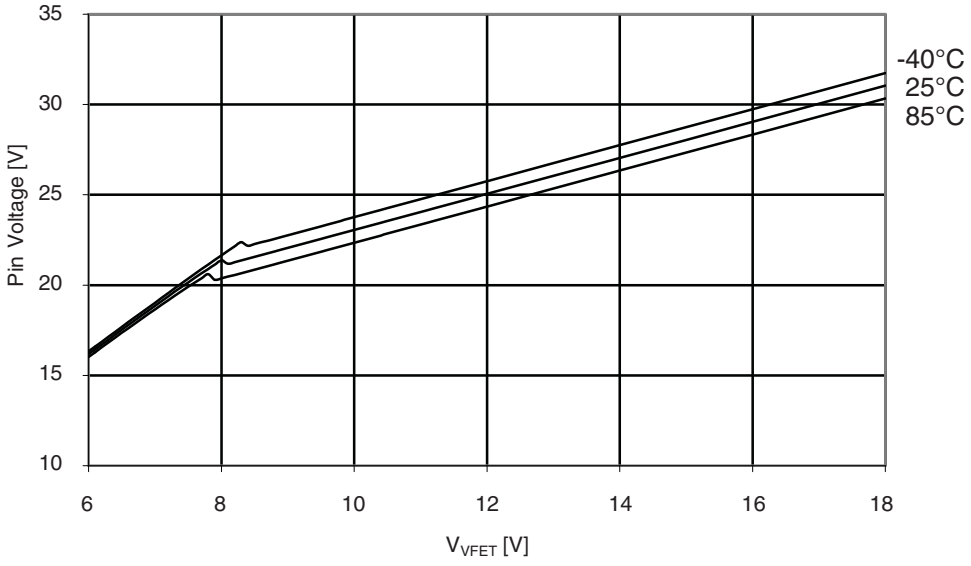
Figure 33-11. Power-off supply current vs. $V_{VFET.}$



33.2 NFET driver characteristics

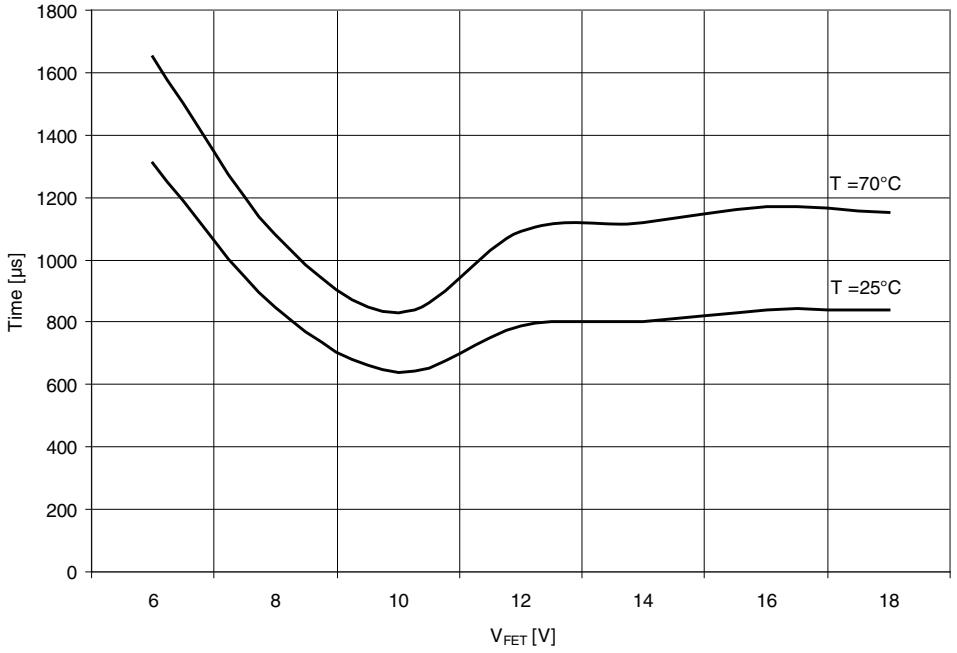
33.2.1 OC/OD levels

Figure 33-12. OC/OD pin voltage vs. V_{VFET} .



33.2.2 OC/OD rise time from 0V to 2V gate-source voltage with 4.7nF load

Figure 33-13. OC/OD rise time, V_{GS} = 0V to 2V vs. V_{VFET} .



33.2.3 OC/OD rise time from 2V to 4V gate-source voltage with 4.7nF load

Figure 33-14. OC/OD rise time, V_{GS} = 2V to 4V vs. V_{VFET} .

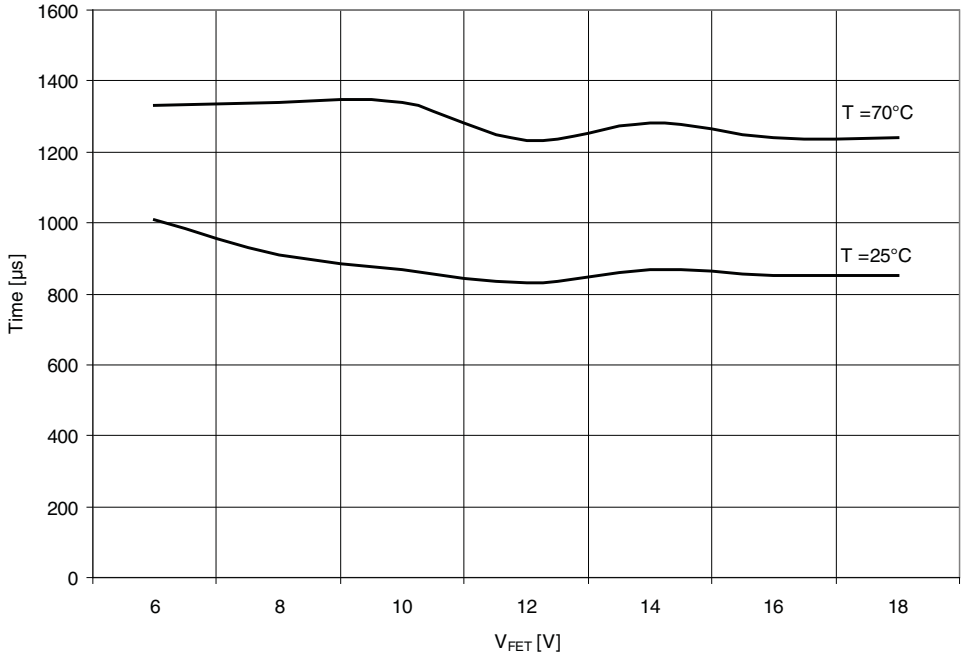
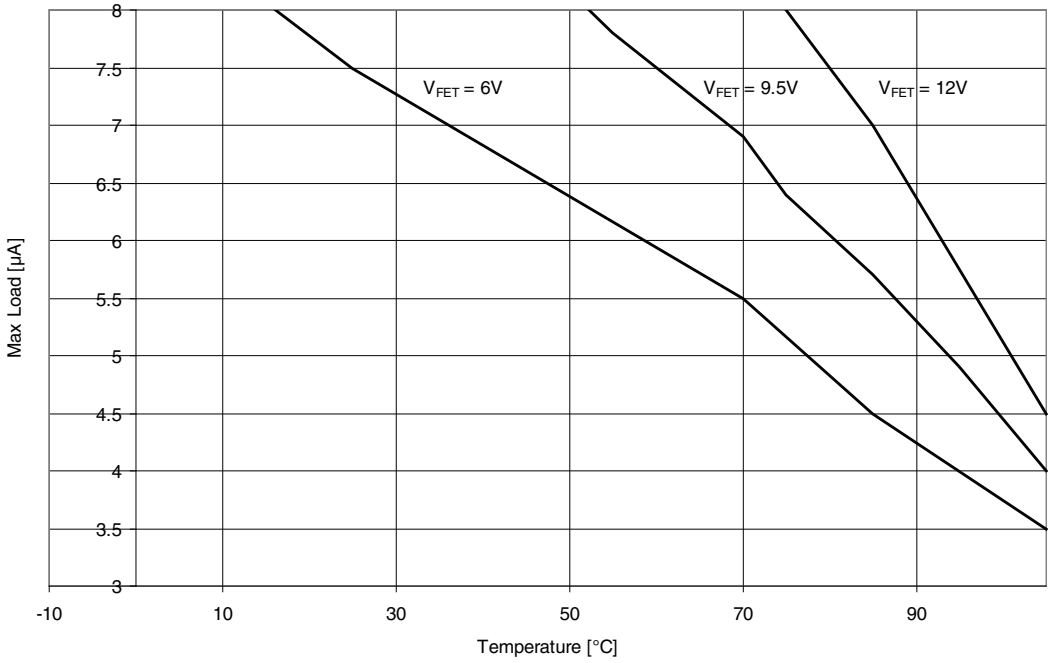
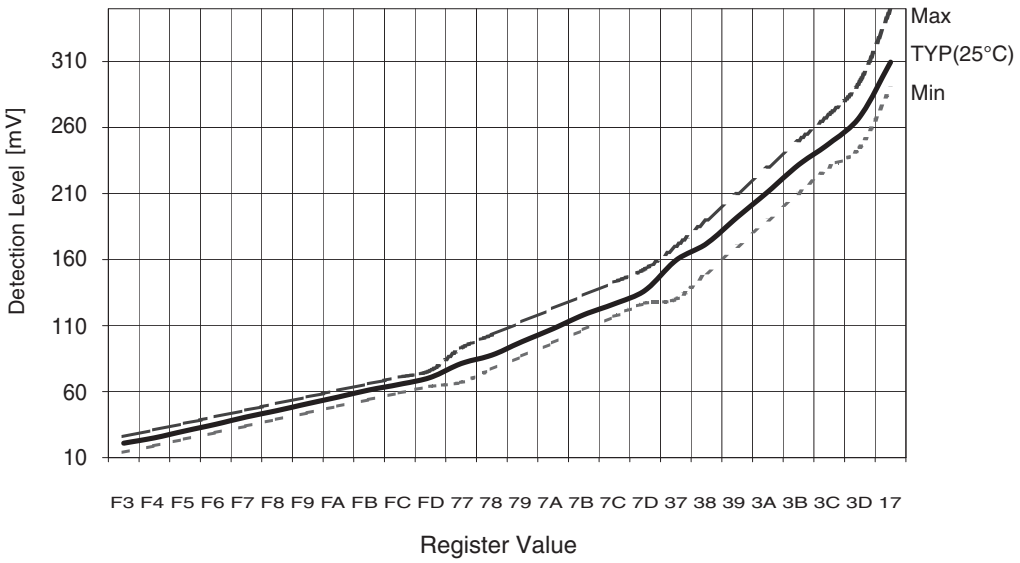


Figure 33-15. OC/OD drive capability vs temperature



33.3 Battery protection characteristics

Figure 33-16. Battery protection level.



33.4 Clock characteristics

33.4.1 Fast RC oscillator characteristics

Figure 33-17. Fast RC oscillator frequency vs. temperature (after factory calibration).

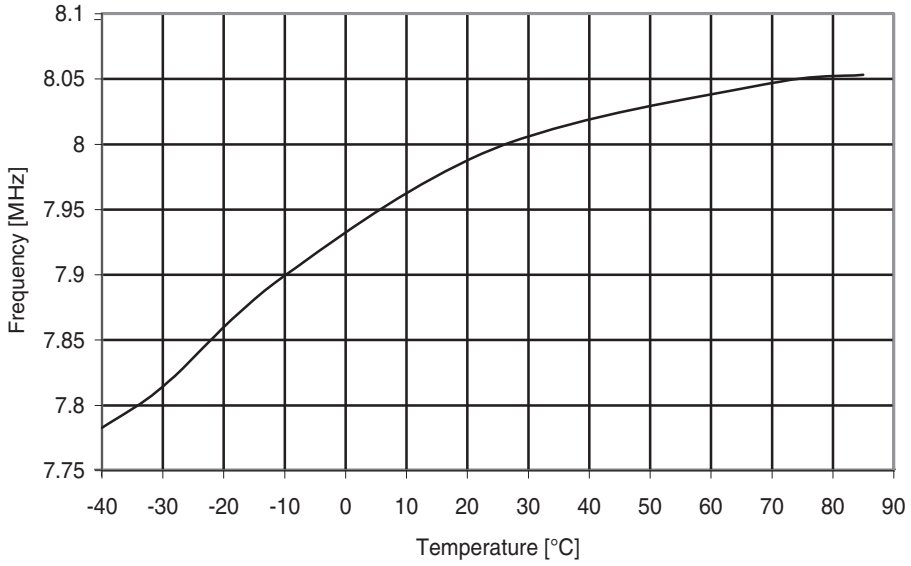
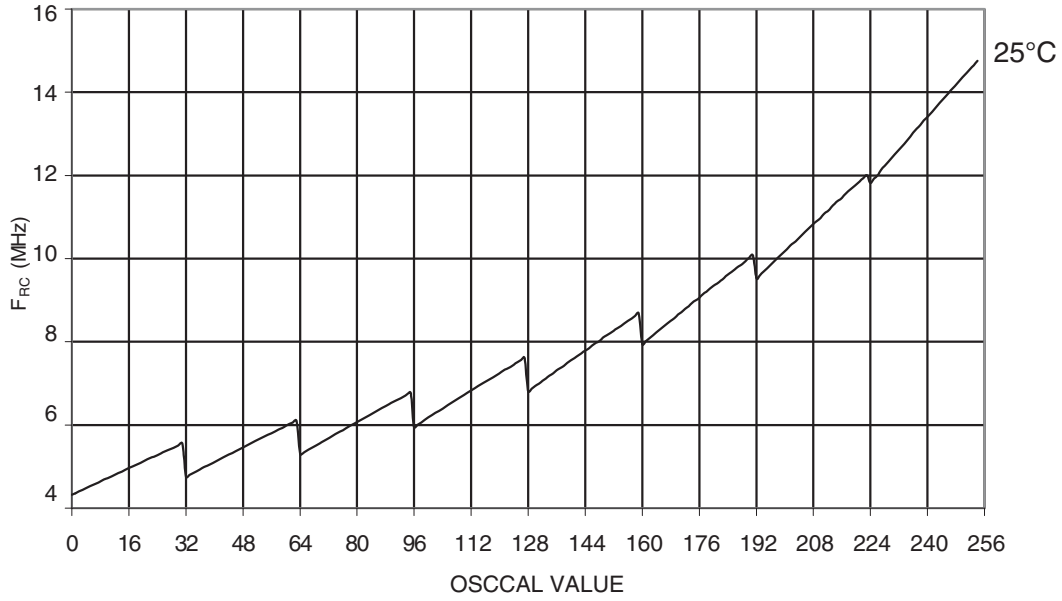
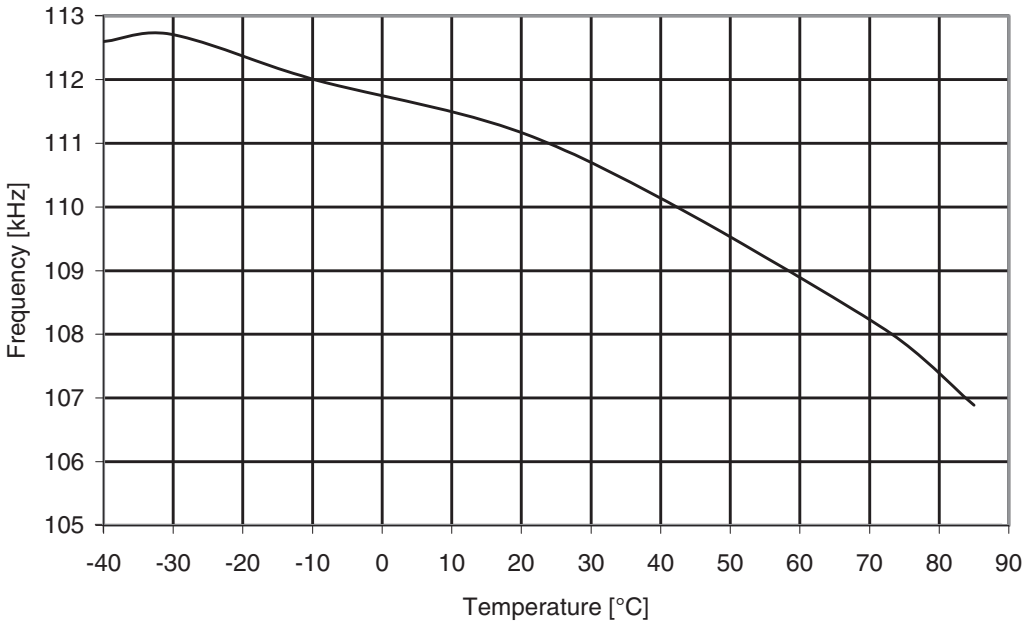


Figure 33-18. Calibrated fast RC oscillator frequency vs. OSCCAL value.



33.4.2 Ultra low power RC oscillator characteristics

Figure 33-19. ULP RC oscillator frequency vs. temperature.



33.4.3 Slow RC oscillator characteristics

Figure 33-20. Slow RC oscillator frequency vs. temperature.

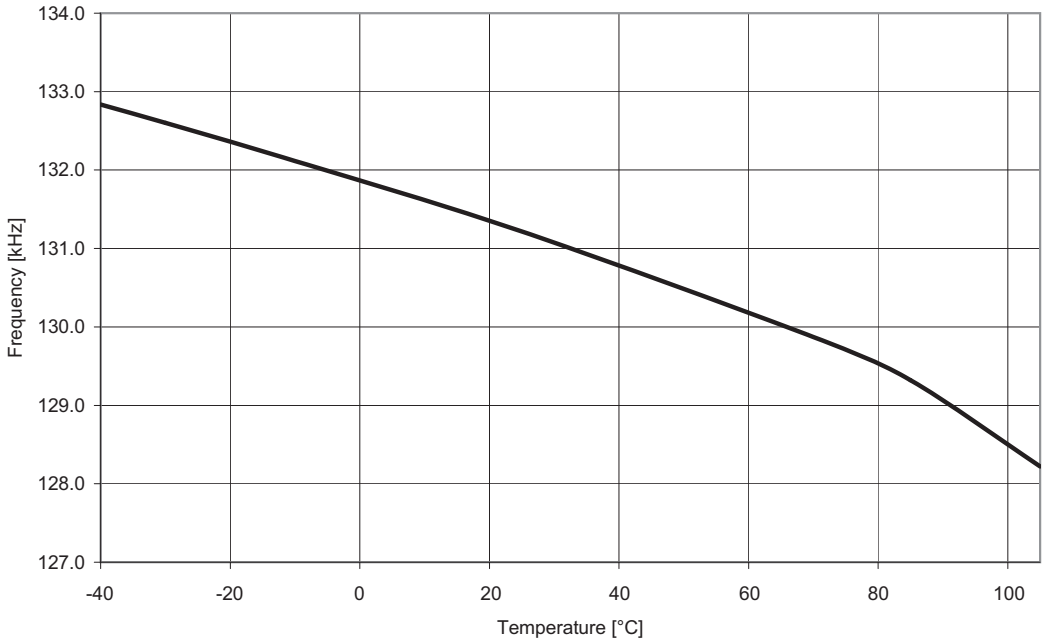
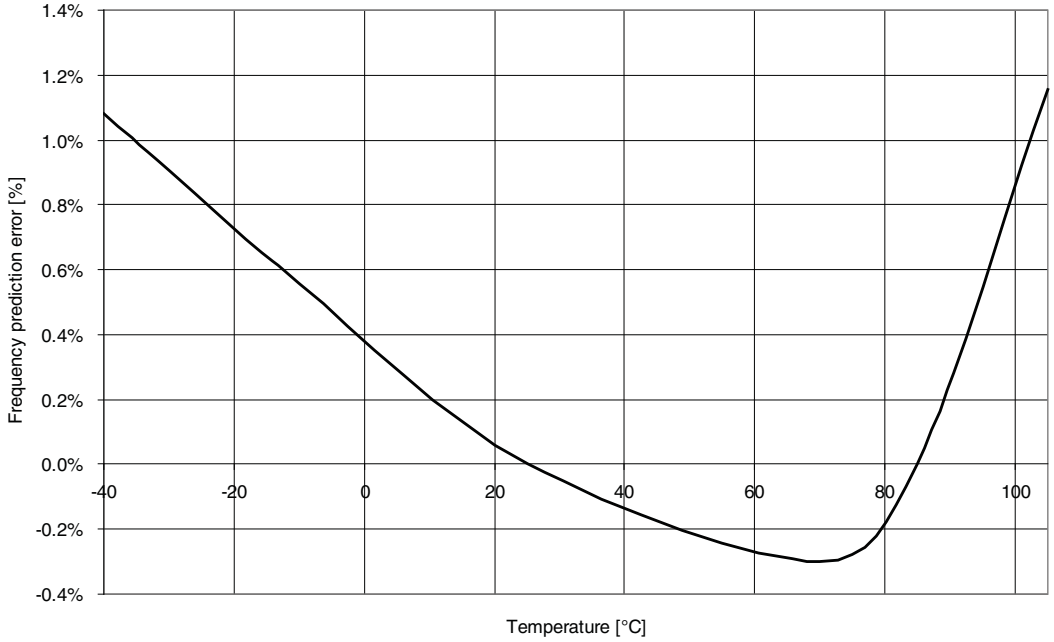


Figure 33-21. Typical SlowRC frequency frequency prediction error based on algorithm in Section 9.2.2 on page 27.



33.5 Voltage reference characteristics

Figure 33-22. Typical VREF curve with Atmel factory calibration at 25°C and 85°C.

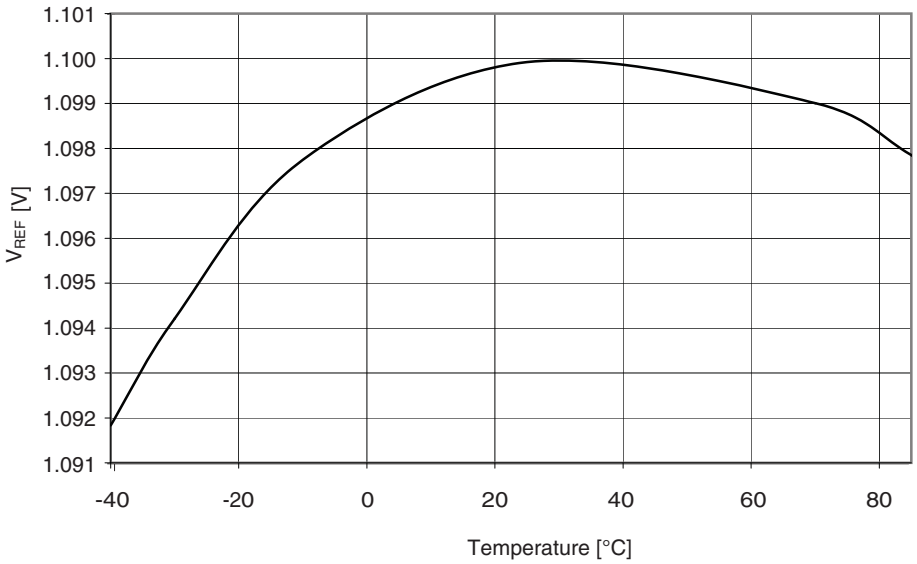
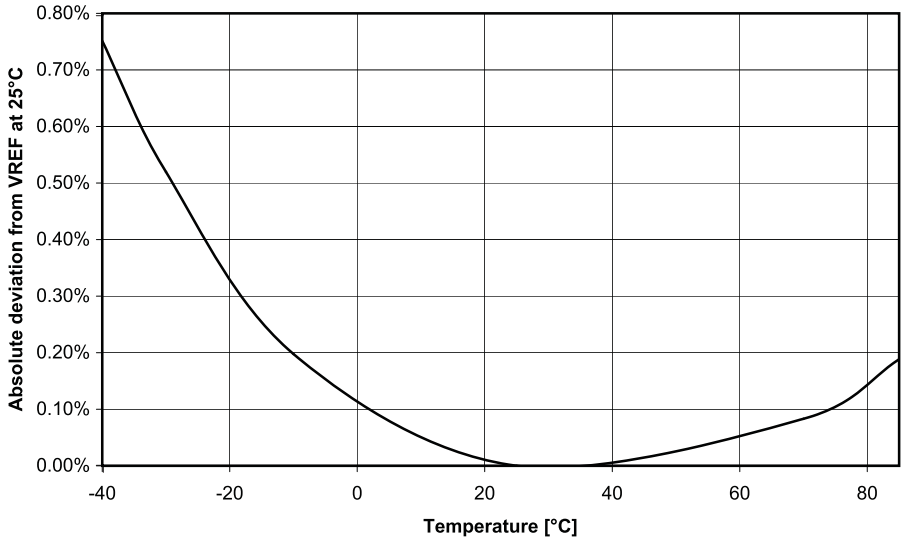


Figure 33-23. Typical VREF deviation curve with Atmel factory calibration at 25°C and 85°C.



33.6 Voltage regulator characteristics

Figure 33-24. Voltage regulator vs. V_{VFET}, I_{LOAD} = 10mA.

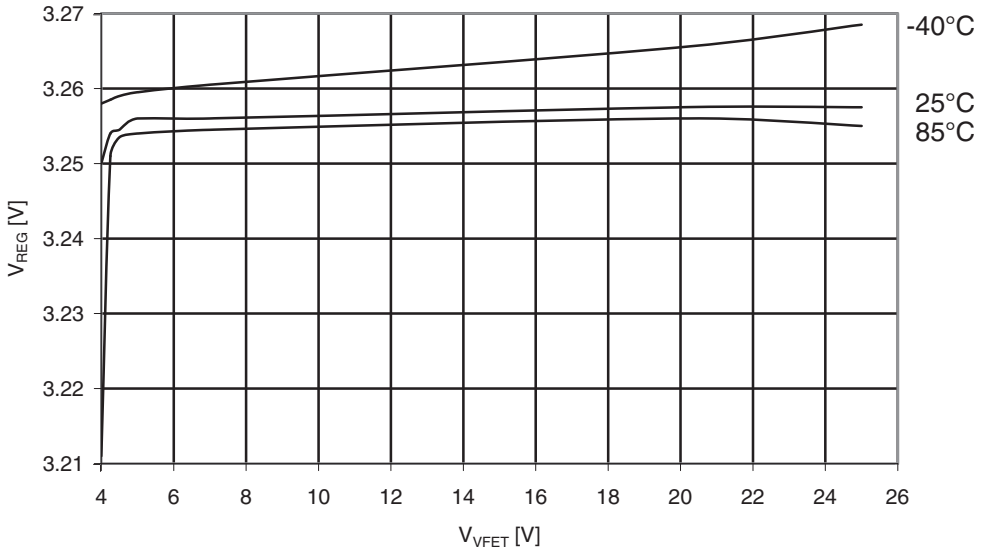


Figure 33-25. Voltage regulator vs. V_{VFET}, I_{LOAD} = 20mA.

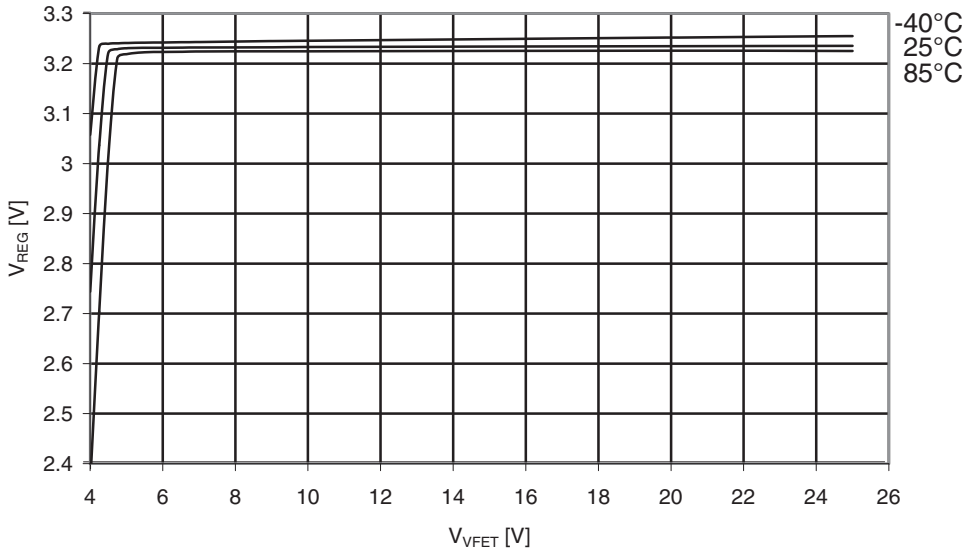


Figure 33-26. Voltage regulator short-circuit level at V_{VFET} pin vs. temperature.

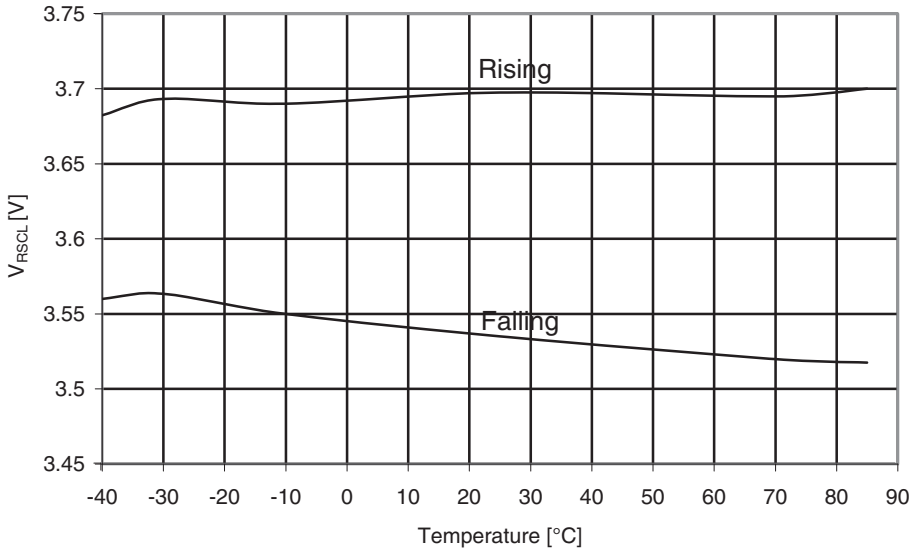
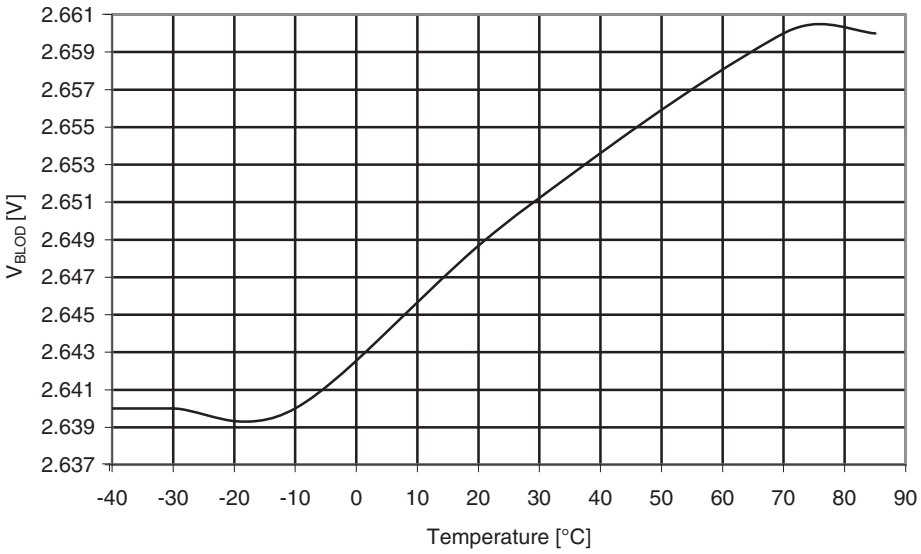
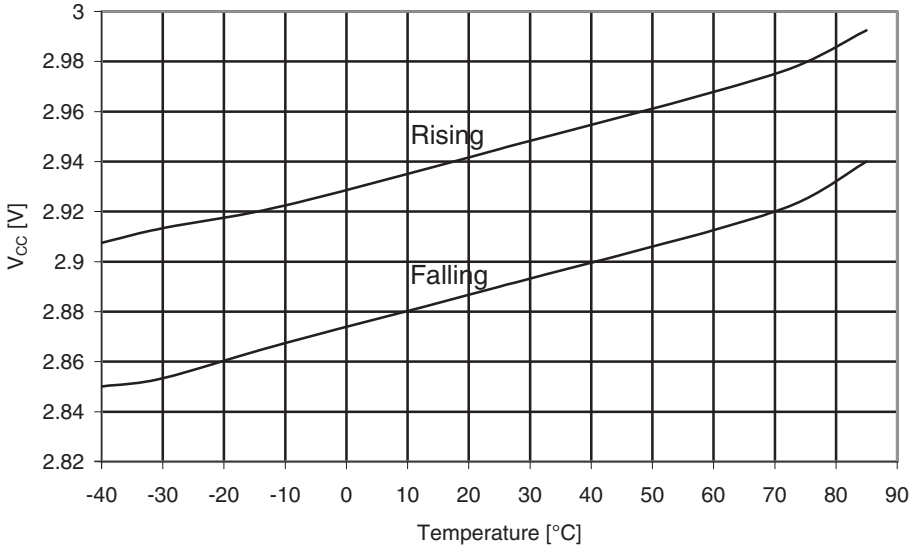


Figure 33-27. BLOD level.



33.7 BOD threshold characteristics

Figure 33-28. BOD level.



34. Register summary

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
(0xFF)	Reserved	–	–	–	–	–	–	–	–	
(0xFE)	BPPLR	–	–	–	–	–	–	BPPLE	BPPL	137
(0xFD)	BPCR	–	–	EPID	SCD	DOCD	COCD	DHCD	CHCD	138
(0xFC)	BPHCTR	–	–	HCPT[5:0]						140
(0xFB)	BPOCTR	–	–	OCPT[5:0]						139
(0xFA)	BPSCTR	–	SCPT[6:0]							139
(0xF9)	BPCHCD	CHCDL[7:0]								142
(0xF8)	BPDHCD	DHCDL[7:0]								142
(0xF7)	BPCOCD	COCDL[7:0]								142
(0xF6)	BPDOCD	DOCDL[7:0]								141
(0xF5)	BPSCD	SCDL[7:0]								141
(0xF4)	Reserved	–	–	–	–	–	–	–	–	
(0xF3)	BPIFR	–	–	–	SCIF	DOCIF	COCIF	DHCIF	CHCIF	144
(0xF2)	BPIMSK	–	–	–	SCIE	DOCIE	COCIE	DHCIE	CHCIE	143
(0xF1)	CBCR	–	–	–	–	CBE4	CBE3	CBE2	CBE1	152
(0xF0)	FCSR	–	–	–	–	DUVRD	CPS	DFE	CFE	149
(0xEF)	Reserved	–	–	–	–	–	–	–	–	
(0xEE)	Reserved	–	–	–	–	–	–	–	–	
(0xED)	Reserved	–	–	–	–	–	–	–	–	
(0xEC)	Reserved	–	–	–	–	–	–	–	–	
(0xEB)	Reserved	–	–	–	–	–	–	–	–	
(0xEA)	CADRDC	CADRDC[7:0]								115
(0xE9)	CADRCC	CADRCC[7:0]								114
(0xE8)	CADCSRC	-	-	-	-	-	-	-	CADVSE	114
(0xE7)	CADCSRB	–	CADACIE	CADRCIE	CADICIE	–	CADACIF	CADRCIF	CADICIF	112
(0xE6)	CADCSRA	CADEN	CADPOL	CADUB	CADAS[1:0]		CADSI[1:0]		CADSE	111
(0xE5)	CADICH	CADIC[15:8]								114
(0xE4)	CADICL	CADIC[7:0]								114
(0xE3)	CADAC3	CADAC[31:24]								114
(0xE2)	CADAC2	CADAC[23:16]								114
(0xE1)	CADAC1	CADAC[15:8]								114
(0xE0)	CADAC0	CADAC[7:0]								114
(0xDF)	Reserved	–	–	–	–	–	–	–	–	
(0xDE)	Reserved	–	–	–	–	–	–	–	–	
(0xDD)	Reserved	–	–	–	–	–	–	–	–	
(0xDC)	Reserved	–	–	–	–	–	–	–	–	
(0xDB)	Reserved	–	–	–	–	–	–	–	–	
(0xDA)	Reserved	–	–	–	–	–	–	–	–	
(0xD9)	Reserved	–	–	–	–	–	–	–	–	
(0xD8)	Reserved	–	–	–	–	–	–	–	–	
(0xD7)	Reserved	–	–	–	–	–	–	–	–	
(0xD6)	Reserved	–	–	–	–	–	–	–	–	
(0xD5)	Reserved	–	–	–	–	–	–	–	–	
(0xD4)	CHGDCSR	–	–	–	BATTPVL	CHGDISC1	CHGDISC1	CHGDIF	CHGDIE	128
(0xD3)	Reserved	–	–	–	–	–	–	–	–	
(0xD2)	BGCSR	–	–	BGD	BGSCDE	–	–	BGSCDIF	BGSCDIE	125
(0xD1)	BGCRR	BGCR[7:0]								124
(0xD0)	BGCCR	–	–	BGCC[5:0]						255
(0xCF)	Reserved	–	–	–	–	–	–	–	–	
(0xCE)	Reserved	–	–	–	–	–	–	–	–	
(0xCD)	Reserved	–	–	–	–	–	–	–	–	
(0xCC)	Reserved	–	–	–	–	–	–	–	–	
(0xCB)	Reserved	–	–	–	–	–	–	–	–	
(0xCA)	Reserved	–	–	–	–	–	–	–	–	
(0xC9)	Reserved	–	–	–	–	–	–	–	–	
(0xC8)	ROCR	ROCS	–	–	ROCD	–	–	ROCWIF	ROCWIE	131
(0xC7)	Reserved	–	–	–	–	–	–	–	–	
(0xC6)	Reserved	–	–	–	–	–	–	–	–	
(0xC5)	Reserved	–	–	–	–	–	–	–	–	
(0xC4)	Reserved	–	–	–	–	–	–	–	–	
(0xC3)	Reserved	–	–	–	–	–	–	–	–	
(0xC2)	Reserved	–	–	–	–	–	–	–	–	
(0xC1)	Reserved	–	–	–	–	–	–	–	–	
(0xC0)	Reserved	–	–	–	–	–	–	–	–	

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
(0xBF)	Reserved	–	–	–	–	–	–	–	–	
(0xBE)	TWBCSR	TWBCIF	TWBCIE	–	–	–	TWBDT1	TWBDT0	TWBCIP	184
(0xBD)	TWAMR	TWAM[6:0]							–	184
(0xBC)	TWCR	TWINT	TWEA	TWSTA	TWSTO	TWWC	TWEN	–	TWIE	181
(0xBB)	TWDR	2–wire Serial Interface Data Register								183
(0xBA)	TWAR	TWA[6:0]							TWGCE	183
(0xB9)	TWSR	TWS[7:3]					–	TWPS1	TWPS0	182
(0xB8)	TWBR	2–wire Serial Interface Bit Rate Register								181
(0xB7)	Reserved	–		–	–	–	–	–	–	
(0xB6)	Reserved	–	–	–	–	–	–	–	–	
(0xB5)	Reserved	–	–	–	–	–	–	–	–	
(0xB4)	Reserved	–	–	–	–	–	–	–	–	
(0xB3)	Reserved	–	–	–	–	–	–	–	–	
(0xB2)	Reserved	–	–	–	–	–	–	–	–	
(0xB1)	Reserved	–	–	–	–	–	–	–	–	
(0xB0)	Reserved	–	–	–	–	–	–	–	–	
(0xAF)	Reserved	–	–	–	–	–	–	–	–	
(0xAE)	Reserved	–	–	–	–	–	–	–	–	
(0xAD)	Reserved	–	–	–	–	–	–	–	–	
(0xAC)	Reserved	–	–	–	–	–	–	–	–	
(0xAB)	Reserved	–	–	–	–	–	–	–	–	
(0xAA)	Reserved	–	–	–	–	–	–	–	–	
(0xA9)	Reserved	–	–	–	–	–	–	–	–	
(0xA8)	Reserved	–	–	–	–	–	–	–	–	
(0xA7)	Reserved	–	–	–	–	–	–	–	–	
(0xA6)	Reserved	–	–	–	–	–	–	–	–	
(0xA5)	Reserved	–	–	–	–	–	–	–	–	
(0xA4)	Reserved	–	–	–	–	–	–	–	–	
(0xA3)	Reserved	–	–	–	–	–	–	–	–	
(0xA2)	Reserved	–	–	–	–	–	–	–	–	
(0xA1)	Reserved	–	–	–	–	–	–	–	–	
(0xA0)	Reserved	–	–	–	–	–	–	–	–	
(0x9F)	Reserved	–	–	–	–	–	–	–	–	
(0x9E)	Reserved	–	–	–	–	–	–	–	–	
(0x9D)	Reserved	–	–	–	–	–	–	–	–	
(0x9C)	Reserved	–	–	–	–	–	–	–	–	
(0x9B)	Reserved	–	–	–	–	–	–	–	–	
(0x9A)	Reserved	–	–	–	–	–	–	–	–	
(0x99)	Reserved	–	–	–	–	–	–	–	–	
(0x98)	Reserved	–	–	–	–	–	–	–	–	
(0x97)	Reserved	–	–	–	–	–	–	–	–	
(0x96)	Reserved	–	–	–	–	–	–	–	–	
(0x95)	Reserved	–	–	–	–	–	–	–	–	
(0x94)	Reserved	–	–	–	–	–	–	–	–	
(0x93)	Reserved	–	–	–	–	–	–	–	–	
(0x92)	Reserved	–	–	–	–	–	–	–	–	
(0x91)	Reserved	–	–	–	–	–	–	–	–	
(0x90)	Reserved	–	–	–	–	–	–	–	–	
(0x8F)	Reserved	–	–	–	–	–	–	–	–	
(0x8E)	Reserved	–	–	–	–	–	–	–	–	
(0x8D)	Reserved	–	–	–	–	–	–	–	–	
(0x8C)	Reserved	–	–	–	–	–	–	–	–	
(0x8B)	Reserved	–	–	–	–	–	–	–	–	
(0x8A)	Reserved	–	–	–	–	–	–	–	–	
(0x89)	OCR1B	Timer/Counter1 – Output Compare Register B								95
(0x88)	OCR1A	Timer/Counter1 – Output Compare Register A								95
(0x87)	Reserved	–	–	–	–	–	–	–	–	
(0x86)	Reserved	–	–	–	–	–	–	–	–	
(0x85)	TCNT1H	Timer/Counter1 (8 Bit) High Byte								95
(0x84)	TCNT1L	Timer/Counter1 (8 Bit) Low Byte								95
(0x83)	Reserved	–	–	–	–	–	–	–	–	
(0x82)	Reserved	–	–	–	–	–	–	–	–	
(0x81)	TCCR1B	–	–	–	–	–	CS12	CS11	CS10	81
(0x80)	TCCR1A	TCW1	ICEN1	ICNC1	ICES1	ICS1	–	–	WGM10	94
(0x7F)	Reserved	–	–	–	–	–	–	–	–	
(0x7E)	DIDR0	–	–	–	–	–	–	PA1DID	PA0DID	121

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(0x7D)	Reserved	–	–	–	–	–	–	–	–	
(0x7C)	VADMUX	–	–	–	–	VADMUX[3:0]				119
(0x7B)	Reserved	–	–	–	–	–	–	–	–	
(0x7A)	VADCSR	–	–	–	–	VADEN	VADSC	VADCCIF	VADCCIE	119
(0x79)	VADCH	–	–	–	–	VADC Data Register High byte				120
(0x78)	VADCL	VADC Data Register Low byte								120
(0x77)	Reserved	–	–	–	–	–	–	–	–	
(0x76)	Reserved	–	–	–	–	–	–	–	–	
(0x75)	Reserved	–	–	–	–	–	–	–	–	
(0x74)	Reserved	–	–	–	–	–	–	–	–	
(0x73)	Reserved	–	–	–	–	–	–	–	–	
(0x72)	Reserved	–	–	–	–	–	–	–	–	
(0x71)	Reserved	–	–	–	–	–	–	–	–	
(0x70)	Reserved	–	–	–	–	–	–	–	–	
(0x6F)	TIMSK1	–	–	–	–	ICIE1	OCIE1B	OCIE1A	TOIE1	96
(0x6E)	TIMSK0	–	–	–	–	ICIE0	OCIE0B	OCIE0A	TOIE0	96
(0x6D)	Reserved	–	–	–	–	–	–	–	–	
(0x6C)	PCMSK1	PCINT[15:8]								60
(0x6B)	PCMSK0	–	–	–	–	PCINT[3:0]				61
(0x6A)	Reserved	–	–	–	–	–	–	–	–	
(0x69)	EICRA	ISC31	ISC30	ISC21	ISC20	ISC11	ISC10	ISC01	ISC00	58
(0x68)	PCICR	–	–	–	–	–	–	PCIE1	PCIE0	60
(0x67)	Reserved	–	–	–	–	–	–	–	–	
(0x66)	FOSCCAL	Fast Oscillator Calibration Register								32
(0x65)	Reserved	–	–	–	–	–	–	–	–	
(0x64)	PRR0	–	PRTWI	PRVRM	–	PRSPI	PRTIM1	PRTIM0	PRVADC	40
(0x63)	Reserved	–	–	–	–	–	–	–	–	
(0x62)	Reserved	–	–	–	–	–	–	–	–	
(0x61)	CLKPR	CLKPCE	–	–	–	–	–	CLKPS1	CLKPS0	32
(0x60)	WDTCSR	WDIF	WDIE	WDP3	WDCE	WDE	WDP2	WDP1	WDP0	49
0x3F (0x5F)	SREG	I	T	H	S	V	N	Z	C	10
0x3E (0x5E)	SPH	SP15	SP14	SP13	SP12	SP11	SP10	SP9	SP8	13
0x3D (0x5D)	SPL	SP7	SP6	SP5	SP4	SP3	SP2	SP1	SP0	13
0x3C (0x5C)	Reserved	–	–	–	–	–	–	–	–	
0x3B (0x5B)	Reserved	–	–	–	–	–	–	–	–	
0x3A (0x5A)	Reserved	–	–	–	–	–	–	–	–	
0x39 (0x59)	Reserved	–	–	–	–	–	–	–	–	
0x38 (0x58)	Reserved	–	–	–	–	–	–	–	–	
0x37 (0x57)	SPMCSR	SPMIE	RWWSB	SIGRD	CTPB	RFLB	PGWRT	PGERS	SPMEN	202
0x36 (0x56)	Reserved	–	–	–	–	–	–	–	–	
0x35 (0x55)	MCUCR	–	–	CKOE	PUD	–	–	IVSEL	IVCE	78/32
0x34 (0x54)	MCUSR	–	–	–	OCDRF	WDRF	BODRF	EXTRF	PORF	49
0x33 (0x53)	SMCR	–	–	–	–	SM[2:0]			SE	39
0x32 (0x52)	Reserved	–	–	–	–	–	–	–	–	
0x31 (0x51)	DWDR	debugWIRE Data Register								187
0x30 (0x50)	Reserved	–	–	–	–	–	–	–	–	
0x2F (0x4F)	Reserved	–	–	–	–	–	–	–	–	
0x2E (0x4E)	SPDR	SPI Data Register								107
0x2D (0x4D)	SPSR	SPIF	WCOL	–	–	–	–	–	SPI2X	106
0x2C (0x4C)	SPCR	SPIE	SPE	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	105
0x2B (0x4B)	GPIOR2	General Purpose I/O Register 2								24
0x2A (0x4A)	GPIOR1	General Purpose I/O Register 1								24
0x29 (0x49)	OCR0B	Timer/Counter0 Output Compare Register B								95
0x28 (0x48)	OCR0A	Timer/Counter0 Output Compare Register A								95
0x27 (0x47)	TCNT0H	Timer/Counter0 (8 Bit) High Byte								95
0x26 (0x46)	TCNT0L	Timer/Counter0 (8 Bit) Low Byte								95
0x25 (0x45)	TCCR0B	–	–	–	–	–	CS02	CS01	CS00	81
0x24 (0x44)	TCCR0A	TCW0	ICEN0	ICNC0	ICES0	ICS0	–	–	WGM00	94
0x23 (0x43)	GTCCR	TSM	–	–	–	–	–	–	PSRSYNC	
0x22 (0x42)	EEARH	–	–	–	–	–	–	EEPROM High byte		20
0x21 (0x41)	EEARL	EEPROM Address Register Low Byte								20
0x20 (0x40)	EEDR	EEPROM Data Register								20
0x1F (0x3F)	EECR	–	–	EEPM1	EEPM0	EERIE	EEMPE	EEPE	EERE	21
0x1E (0x3E)	GPIOR0	General Purpose I/O Register 0								24
0x1D (0x3D)	EIMSK	–	–	–	–	INT3	INT2	INT1	INT0	59
0x1C (0x3C)	EIFR	–	–	–	–	INTF3	INTF2	INTF1	INTF0	59

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
0x1B (0x3B)	PCIFR	–	–	–	–	–	–	PCIF1	PCIF0	60
0x1A (0x3A)	Reserved	–	–	–	–	–	–	–	–	
0x19 (0x39)	Reserved	–	–	–	–	–	–	–	–	
0x18 (0x38)	Reserved	–	–	–	–	–	–	–	–	
0x17 (0x37)	OSICSR	–	–	–	OSISEL0	–	–	OSIST	OSIEN	33
0x16 (0x36)	TIFR1	–	–	–	–	ICF1	OCF1B	OCF1A	TOV1	96
0x15 (0x35)	TIFR0	–	–	–	–	ICF0	OCF0B	OCF0A	TOV0	96
0x14 (0x34)	Reserved	–	–	–	–	–	–	–	–	
0x13 (0x33)	Reserved	–	–	–	–	–	–	–	–	
0x12 (0x32)	Reserved	–	–	–	–	–	–	–	–	
0x11 (0x31)	Reserved	–	–	–	–	–	–	–	–	
0x10 (0x30)	Reserved	–	–	–	–	–	–	–	–	
0x0F (0x2F)	Reserved	–	–	–	–	–	–	–	–	
0x0E (0x2E)	Reserved	–	–	–	–	–	–	–	–	
0x0D (0x2D)	Reserved	–	–	–	–	–	–	–	–	
0x0C (0x2C)	Reserved	–	–	–	–	–	–	–	–	
0x0B (0x2B)	Reserved	–	–	–	–	–	–	–	–	
0x0A (0x2A)	Reserved	–	–	–	–	–	–	–	–	
0x09 (0x29)	Reserved	–	–	–	–	–	–	–	–	
0x08 (0x28)	PORTC	–	–	PORTC5	PORTC4	PORTC3	PORTC2	PORTC1	PORTC0	66
0x07 (0x27)	Reserved	–	–	–	–	–	–	–	–	
0x06 (0x26)	PINC	–	–	–	PINC4	PINC3	PINC2	PINC1	PINC0	66
0x05 (0x25)	PORTB	PORTB7	PORTB6	PORTB5	PORTB4	PORTB3	PORTB2	PORTB1	PORTB0	78
0x04 (0x24)	DDRB	DDB7	DDB6	DDB5	DDB4	DDB3	DDB2	DDB1	DDB0	78
0x03 (0x23)	PINB	PINB7	PINB6	PINB5	PINB4	PINB3	PINB2	PINB1	PINB0	78
0x02 (0x22)	PORTA	–	–	–	–	PORTA3	PORTA2	PORTA1	PORTA0	78
0x01 (0x21)	DDRA	–	–	–	–	DDA3	DDA2	DDA1	DDA0	78
0x00 (0x20)	PINA	–	–	–	–	PINA3	PINA2	PINA1	PINA0	78

Notes:
1. For compatibility with future devices, reserved bits should be written to zero if accessed. Reserved I/O memory addresses should never be written.
2. I/O registers within the address range $00 - $1F are directly bit-accessible using the SBI and CBI instructions. In these registers, the value of single bits can be checked by using the SBIS and SBIC instructions.
3. Some of the status flags are cleared by writing a logical one to them. Note that the CBI and SBI instructions will operate on all bits in the I/O register, writing a one back into any flag read as set, thus clearing the flag. The CBI and SBI instructions work with registers 0x00 to 0x1F only.
4. When using the I/O specific commands IN and OUT, the I/O addresses $00 - $3F must be used. When addressing I/O registers as data space using LD and ST instructions, $20 must be added to these addresses. The Atmel ATmega16HVB/32HVB is a complex microcontroller with more peripheral units than can be supported within the 64 location reserved in Opcode for the IN and OUT instructions. For the Extended I/O space from $60 - $FF in SRAM, only the ST/STS/STD and LD/LDS/LDD instructions can be used.

35. Instruction set summary

Mnemonics	Operands	Description	Operation	Flags	#Clocks
ARITHMETIC AND LOGIC INSTRUCTIONS					
ADD	Rd, Rr	Add two Registers	Rd ← Rd + Rr	Z, C, N, V, H	1
ADC	Rd, Rr	Add with Carry two Registers	Rd ← Rd + Rr + C	Z, C, N, V, H	1
ADIW	Rdl, K	Add Immediate to Word	Rdh:Rdl ← Rdh:Rdl + K	Z, C, N, V, S	2
SUB	Rd, Rr	Subtract two Registers	Rd ← Rd - Rr	Z, C, N, V, H	1
SUBI	Rd, K	Subtract Constant from Register	Rd ← Rd - K	Z, C, N, V, H	1
SBC	Rd, Rr	Subtract with Carry two Registers	Rd ← Rd - Rr - C	Z, C, N, V, H	1
SBCI	Rd, K	Subtract with Carry Constant from Reg.	Rd ← Rd - K - C	Z, C, N, V, H	1
SBIW	Rdl,K	Subtract Immediate from Word	Rdh:Rdl ← Rdh:Rdl - K	Z, C, N, V, S	2
AND	Rd, Rr	Logical AND Registers	Rd ← Rd • Rr	Z, N, V	1
ANDI	Rd, K	Logical AND Register and Constant	Rd ← Rd • K	Z, N, V	1
OR	Rd, Rr	Logical OR Registers	Rd ← Rd v Rr	Z, N, V	1
ORI	Rd, K	Logical OR Register and Constant	Rd ← Rd v K	Z, N, V	1
EOR	Rd, Rr	Exclusive OR Registers	Rd ← Rd ⊕ Rr	Z, N, V	1
COM	Rd	One's Complement	Rd ← 0xFF − Rd	Z, C, N, V	1
NEG	Rd	Two's Complement	Rd ← 0x00 − Rd	Z, C, N, V, H	1
SBR	Rd, K	Set Bit(s) in Register	Rd ← Rd v K	Z, N, V	1
CBR	Rd, K	Clear Bit(s) in Register	Rd ← Rd • (0xFF - K)	Z, N, V	1
INC	Rd	Increment	Rd ← Rd + 1	Z, N, V	1
DEC	Rd	Decrement	Rd ← Rd − 1	Z, N, V	1
TST	Rd	Test for Zero or Minus	Rd ← Rd • Rd	Z, N, V	1
CLR	Rd	Clear Register	Rd ← Rd ⊕ Rd	Z, N ,V	1
SER	Rd	Set Register	Rd ← 0xFF	None	1
MUL	Rd, Rr	Multiply Unsigned	R1:R0 ← Rd x Rr	Z, C	2
MULS	Rd, Rr	Multiply Signed	R1:R0 ← Rd x Rr	Z, C	2
MULSU	Rd, Rr	Multiply Signed with Unsigned	R1:R0 ← Rd x Rr	Z, C	2
FMUL	Rd, Rr	Fractional Multiply Unsigned	R1:R0 ← (Rd x Rr) << 1	Z, C	2
FMULS	Rd, Rr	Fractional Multiply Signed	R1:R0 ← (Rd x Rr) << 1	Z, C	2
FMULSU	Rd, Rr	Fractional Multiply Signed with Unsigned	R1:R0 ← (Rd x Rr) << 1	Z, C	2
BRANCH INSTRUCTIONS					
RJMP	k	Relative Jump	PC ← PC + k + 1	None	2
IJMP		Indirect Jump to (Z)	PC ← Z	None	2
JMP	k	Direct Jump	PC ← k	None	3
RCALL	k	Relative Subroutine Call	PC ← PC + k + 1	None	3
ICALL		Indirect Call to (Z)	PC ← Z	None	3
CALL	k	Direct Subroutine Call	PC ← k	None	4
RET		Subroutine Return	PC ← STACK	None	4
RETI		Interrupt Return	PC ← STACK	I	4
CPSE	Rd, Rr	Compare, Skip if Equal	if (Rd = Rr) PC ← PC + 2 or 3	None	1/2/3
CP	Rd, Rr	Compare	Rd − Rr	Z, N, V, C, H	1
CPC	Rd, Rr	Compare with Carry	Rd − Rr − C	Z, N, V, C, H	1
CPI	Rd, K	Compare Register with Immediate	Rd − K	Z, N, V, C, H	1
SBRC	Rr, b	Skip if Bit in Register Cleared	if (Rr(b) = 0) PC ← PC + 2 or 3	None	1/2/3
SBRS	Rr, b	Skip if Bit in Register is Set	if (Rr(b) = 1) PC ← PC + 2 or 3	None	1/2/3
SBIC	P, b	Skip if Bit in I/O Register Cleared	if (P(b) = 0) PC ← PC + 2 or 3	None	1/2/3
SBIS	P, b	Skip if Bit in I/O Register is Set	if (P(b) = 1) PC ← PC + 2 or 3	None	1/2/3
BRBS	s, k	Branch if Status Flag Set	if (SREG(s) = 1) then PC←PC+k + 1	None	1/2
BRBC	s, k	Branch if Status Flag Cleared	if (SREG(s) = 0) then PC←PC+k + 1	None	1/2
BREQ	k	Branch if Equal	if (Z = 1) then PC ← PC + k + 1	None	1/2
BRNE	k	Branch if Not Equal	if (Z = 0) then PC ← PC + k + 1	None	1/2
BRCS	k	Branch if Carry Set	if (C = 1) then PC ← PC + k + 1	None	1/2
BRCC	k	Branch if Carry Cleared	if (C = 0) then PC ← PC + k + 1	None	1/2
BRSH	k	Branch if Same or Higher	if (C = 0) then PC ← PC + k + 1	None	1/2
BRLO	k	Branch if Lower	if (C = 1) then PC ← PC + k + 1	None	1/2
BRMI	k	Branch if Minus	if (N = 1) then PC ← PC + k + 1	None	1/2
BRPL	k	Branch if Plus	if (N = 0) then PC ← PC + k + 1	None	1/2
BRGE	k	Branch if Greater or Equal, Signed	if (N ⊕ V= 0) then PC ← PC + k + 1	None	1/2
BRLT	k	Branch if Less Than Zero, Signed	if (N ⊕ V= 1) then PC ← PC + k + 1	None	1/2
BRHS	k	Branch if Half Carry Flag Set	if (H = 1) then PC ← PC + k + 1	None	1/2
BRHC	k	Branch if Half Carry Flag Cleared	if (H = 0) then PC ← PC + k + 1	None	1/2
BRTS	k	Branch if T Flag Set	if (T = 1) then PC ← PC + k + 1	None	1/2
BRTC	k	Branch if T Flag Cleared	if (T = 0) then PC ← PC + k + 1	None	1/2
BRVS	k	Branch if Overflow Flag is Set	if (V = 1) then PC ← PC + k + 1	None	1/2
BRVC	k	Branch if Overflow Flag is Cleared	if (V = 0) then PC ← PC + k + 1	None	1/2

35. Instruction set summary (Continued)

Mnemonics	Operands	Description	Operation	Flags	#Clocks
BRIE	k	Branch if Interrupt Enabled	if (I = 1) then PC ← PC + k + 1	None	1/2
BRID	k	Branch if Interrupt Disabled	if (I = 0) then PC ← PC + k + 1	None	1/2
BIT AND BIT-TEST INSTRUCTIONS					
SBI	P, b	Set Bit in I/O Register	I/O(P,b) ← 1	None	2
CBI	P, b	Clear Bit in I/O Register	I/O(P,b) ← 0	None	2
LSL	Rd	Logical Shift Left	Rd(n+1) ← Rd(n), Rd(0) ← 0	Z, C, N, V	1
LSR	Rd	Logical Shift Right	Rd(n) ← Rd(n+1), Rd(7) ← 0	Z, C, N, V	1
ROL	Rd	Rotate Left Through Carry	Rd(0)←C,Rd(n+1)← Rd(n),C←Rd(7)	Z, C, N, V	1
ROR	Rd	Rotate Right Through Carry	Rd(7)←C,Rd(n)← Rd(n+1),C←Rd(0)	Z, C, N, V	1
ASR	Rd	Arithmetic Shift Right	Rd(n) ← Rd(n+1), n=0..6	Z, C, N, V	1
SWAP	Rd	Swap Nibbles	Rd(3..0)←Rd(7..4),Rd(7..4)←Rd(3..0)	None	1
BSET	s	Flag Set	SREG(s) ← 1	SREG(s)	1
BCLR	s	Flag Clear	SREG(s) ← 0	SREG(s)	1
BST	Rr, b	Bit Store from Register to T	T ← Rr(b)	T	1
BLD	Rd, b	Bit load from T to Register	Rd(b) ← T	None	1
SEC		Set Carry	C ← 1	C	1
CLC		Clear Carry	C ← 0	C	1
SEN		Set Negative Flag	N ← 1	N	1
CLN		Clear Negative Flag	N ← 0	N	1
SEZ		Set Zero Flag	Z ← 1	Z	1
CLZ		Clear Zero Flag	Z ← 0	Z	1
SEI		Global Interrupt Enable	I ← 1	I	1
CLI		Global Interrupt Disable	I ← 0	I	1
SES		Set Signed Test Flag	S ← 1	S	1
CLS		Clear Signed Test Flag	S ← 0	S	1
SEV		Set Twos Complement Overflow.	V ← 1	V	1
CLV		Clear Twos Complement Overflow	V ← 0	V	1
SET		Set T in SREG	T ← 1	T	1
CLT		Clear T in SREG	T ← 0	T	1
SEH		Set Half Carry Flag in SREG	H ← 1	H	1
CLH		Clear Half Carry Flag in SREG	H ← 0	H	1
DATA TRANSFER INSTRUCTIONS					
MOV	Rd, Rr	Move Between Registers	Rd ← Rr	None	1
MOVW	Rd, Rr	Copy Register Word	Rd+1:Rd ← Rr+1:Rr	None	1
LDI	Rd, K	Load Immediate	Rd ← K	None	1
LD	Rd, X	Load Indirect	Rd ← (X)	None	2
LD	Rd, X+	Load Indirect and Post-Inc.	Rd ← (X), X ← X + 1	None	2
LD	Rd, - X	Load Indirect and Pre-Dec.	X ← X - 1, Rd ← (X)	None	2
LD	Rd, Y	Load Indirect	Rd ← (Y)	None	2
LD	Rd, Y+	Load Indirect and Post-Inc.	Rd ← (Y), Y ← Y + 1	None	2
LD	Rd, - Y	Load Indirect and Pre-Dec.	Y ← Y - 1, Rd ← (Y)	None	2
LDD	Rd, Y+q	Load Indirect with Displacement	Rd ← (Y + q)	None	2
LD	Rd, Z	Load Indirect	Rd ← (Z)	None	2
LD	Rd, Z+	Load Indirect and Post-Inc.	Rd ← (Z), Z ← Z+1	None	2
LD	Rd, -Z	Load Indirect and Pre-Dec.	Z ← Z - 1, Rd ← (Z)	None	2
LDD	Rd, Z+q	Load Indirect with Displacement	Rd ← (Z + q)	None	2
LDS	Rd, k	Load Direct from SRAM	Rd ← (k)	None	2
ST	X, Rr	Store Indirect	(X) ← Rr	None	2
ST	X+, Rr	Store Indirect and Post-Inc.	(X) ← Rr, X ← X + 1	None	2
ST	- X, Rr	Store Indirect and Pre-Dec.	X ← X - 1, (X) ← Rr	None	2
ST	Y, Rr	Store Indirect	(Y) ← Rr	None	2
ST	Y+, Rr	Store Indirect and Post-Inc.	(Y) ← Rr, Y ← Y + 1	None	2
ST	- Y, Rr	Store Indirect and Pre-Dec.	Y ← Y - 1, (Y) ← Rr	None	2
STD	Y+q, Rr	Store Indirect with Displacement	(Y + q) ← Rr	None	2
ST	Z, Rr	Store Indirect	(Z) ← Rr	None	2
ST	Z+, Rr	Store Indirect and Post-Inc.	(Z) ← Rr, Z ← Z + 1	None	2
ST	-Z, Rr	Store Indirect and Pre-Dec.	Z ← Z - 1, (Z) ← Rr	None	2
STD	Z+q, Rr	Store Indirect with Displacement	(Z + q) ← Rr	None	2
STS	k, Rr	Store Direct to SRAM	(k) ← Rr	None	2
LPM		Load Program Memory	R0 ← (Z)	None	3
LPM	Rd, Z	Load Program Memory	Rd ← (Z)	None	3
LPM	Rd, Z+	Load Program Memory and Post-Inc	Rd ← (Z), Z ← Z+1	None	3
SPM		Store Program Memory	(Z) ← R1:R0	None	-
IN	Rd, P	In Port	Rd ← P	None	1

35. Instruction set summary (Continued)

Mnemonics	Operands	Description	Operation	Flags	#Clocks
OUT	P, Rr	Out Port	P ← Rr	None	1
PUSH	Rr	Push Register on Stack	STACK ← Rr	None	2
POP	Rd	Pop Register from Stack	Rd ← STACK	None	2
MCU CONTROL INSTRUCTIONS					
NOP		No Operation		None	1
SLEEP		Sleep	(see specific descr. for Sleep function)	None	1
WDR		Watchdog Reset	(see specific descr. for WDR/timer)	None	1
BREAK		Break	For On-chip Debug Only	None	N/A

36. Ordering information

36.1 The Atmel ATmega16HVB

Speed (MHz)	Power supply	Ordering code	Package	Operation range
1MHz - 8MHz	4V - 18V	ATMEGA16HVB-8X3	44X1	-40°C to 85°C

Package type	
44X1	44-lead, 4.4mm body width, plastic thin shrink small outline package (TSSOP)

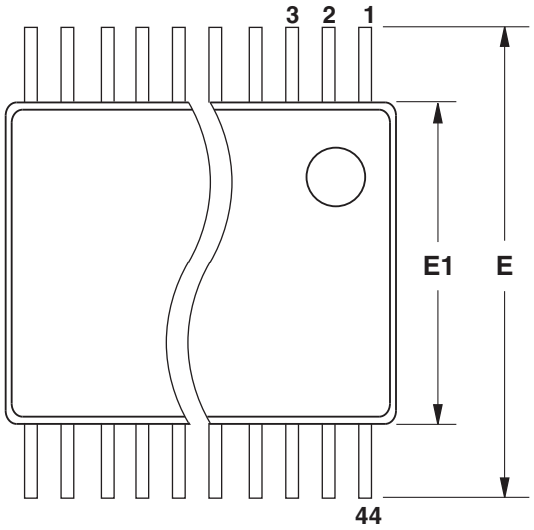
36.2 The Atmel ATmega32HVB

Speed (MHz)	Power supply	Ordering code	Package	Operation range
1MHz - 8MHz	4V - 18V	ATMEGA32HVB-8X3	44X1	-40°C to 85°C

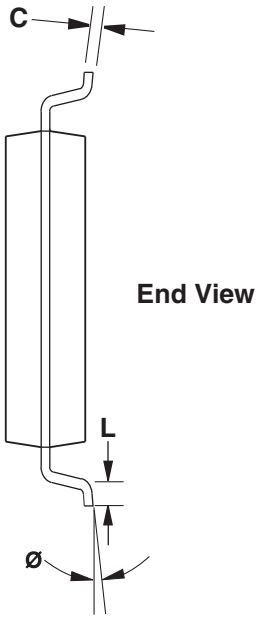
Package type	
44X1	44-lead, 4.4mm body width, plastic thin shrink small outline package (TSSOP)

37. Packaging information

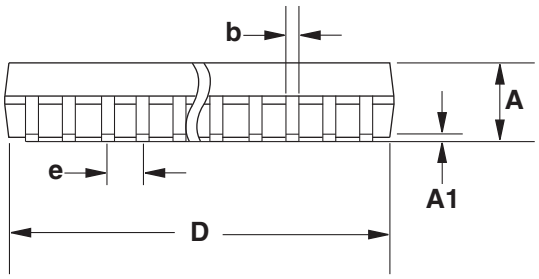
37.1 44X1



Top View



End View



Side View

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
b	0.17	–	0.27	
C	0.09	–	0.20	
D	10.90	11.00	11.10	
E1	4.30	4.40	4.50	
E	6.20	6.40	6.60	
e		0.50 TYP		
L	0.50	0.60	0.70	
Ø	0°	–	8°	

Note: These drawings are for general information only. Refer to JEDEC Drawing MO-153BE.

5/16/07

2325 Orchard Parkway San Jose, CA 95131	**TITLE** **44X1**, 44-lead, 4.4mm Body Width, Plastic Thin Shrink Small Outline Package (TSSOP)	**DRAWING NO.** 44X1	**REV.** A

38. Errata

38.1 The Atmel ATmega16HVB

38.1.1 Rev. B

Stack pointer initial value

The stack pointer in ATmega16HVB is incorrectly initialized to 0x08ff instead of 0x04ff.

Problem fix/workaround

Initialize the stack pointer in software before the stack is used. Most C-compilers does initialize the stack pointer without manual intervention.

Assembly Code Example:

ldi r16,high(RAMEND) ; Main program start out SPH,r16 ; Set Stack Pointer to top of RAM ldi r16,low(RAMEND) out SPL,r16 C Code Example (if required): SP = RAMEND;

38.1.2 Rev. A

Not sampled.

38.1.3 All revisions

TWI bus can get stuck if TWI STOP condition bit is set in slave mode

If the TWSTO bit in TWCR is set while the TWI starts to receive data in slave mode, it can result in pulling the SCL pin low and then the TWI bus will get stuck. To release the SCL pin and get out of this situation the TWI module needs to be disabled and then re-enabled.

Problem fix/workaround

While in slave mode the TWSTO bit should be written only to recover from an error condition and then cleared before a data transfer starts.

38.2 The Atmel ATmega32HVB

38.2.1 Rev. A

Not sampled.

38.2.2 All revisions

TWI bus can get stuck if TWI STOP condition bit is set in slave mode

If the TWSTO bit in TWCR is set while the TWI starts to receive data in slave mode, it can result in pulling the SCL pin low and then the TWI bus will get stuck. To release the SCL pin and get out of this situation the TWI module needs to be disabled and then re-enabled.

Problem fix/workaround

While in slave mode the TWSTO bit should be written only to recover from an error condition and then cleared before a data transfer starts.

39. Revision history

Please note that the referring page numbers in this section are referring to this document. The referring revision in this section are referring to the document revision.

39.1 Rev. 8042D-10/11

1. Operating voltage has been changed from 4V - 25V to 4V - 18V
2. The methods for determing the actual clock period of the ULP Oscillator i Section 9.2.3 on page 27 have been changed
3. In "Bit 1:0 – CLKPS[1:0]: Clock Prescaler select Bit[1:0]" on page 33 new text has been inserted in and the text "If CKDIBV8 is programmed" has been corrected to "If CKDIV8 is programmed"
4. Note 2 in "Bit 0 – OSIEN: Oscillator sampling interface enable" on page 34 has been deleted
5. Figure 11-1 on page 43 has been corrected
6. New Note 2 has been added below Table 11-2 on page 51
7. The last sentence in Section 21.5 on page 123 has been corrected
8. The text in Section 25.3.1 on page 146 below Figure 25-2 has been corrected several places
9. V_{CC} in Figure 28-1 on page 186 has been corrected
10. Bit no 4 in Table 30-3 on page 205 has been corrected
11. Note 1 below Table 30-3 on page 205 has been corrected
12. The text in point 4 and 5 in Section 30.6.1 on page 208 has been corrected
13. The V_{FET} value in Figure 30-3 on page 212 has been corrected
14. The table in Section 32.1 on page 225 hase been updated with several new values
15. I_{LOAD} in Table 32-2 on page 226 has been added
16. Note 1 below Table 32-2 on page 226 has been added
17. The maximum value for V_{BOT} in Table 32-3 on page 227 has been added
18. In Table 32-4 on page 227 the maximum value for V_{RSCL} has been corrected and the maximum value for V_{REG} pin has been added
19. In Table 32-7 on page 229 the typical and maximum values for INL has been corrected
20. In Table 32-8 on page 229 the typical value for frequency prediction error (slow RC oscillator) has been corrected
21. In Table 32-10 on page 230 the text below "Parameter" has been corrected
22. In Table 32-12 on page 231 Note 5 has been added
23. In Table 32-18 on page 236 the maximum value for t_{WLRH_CE} has been corrected
24. The former figure "Active supply current vs. V_{VFET}, WDT, V_{REF}, CBP, OC/OD and CC-ADC enabled" on page 238 has been removed
25. In Table 33-1 on page 243 the text "CC-OD" has benn changed to "OC-OD" and below "Typical current consumption" the value "55µA" has been changed to "85µA"
26. New text is added below the two notes for Table 33-1 on page 243
27. New Figure 33-11 on page 245 "Power-save supply current vs. V_{VFET}, WDT, V_{REF}, CBP, OC/OD, and CC-ADC enabled" is added

28. The plot in Figure 33-13 on page 246 has been updated
29. The plot in Figure 33-14 on page 246 has been updated
30. New Figure 33-15 on page 247 has been added
31. New Figure 33-21 on page 250 has been added
32. Heading in Figure 33-27 on page 253 has been corrected
33. The power supply voltage in the table in Section 36.1 on page 262 has been corrected
34. The power supply voltage in the table in Section 36.2 on page 263 has been corrected
35. The Section 38. on page 265 has been corrected by adding an errata for “all revisions”
36. The text “...clock period of the Slow RC Oscillator...” in point 2 in Section 9.2.3 on page 27 has been corrected to “...clock period of the ULP RC Oscillator...”
37. Note 1 below Table 19-1 on page 112 has been corrected
38. Note 1 below Table 19-2 on page 112 has been corrected
39. Figure 31-1 on page 220 has been updated
40. Figure 31-2 on page 221 has been updated
41. Figure 31-3 on page 222 has been updated
42. Table 31-1 on page 223 has been updated according to the changes in Figure 31-1 on page 220, Figure 31-2 on page 221, and Figure 31-3 on page 222

39.2 Rev. 8042C-06/11

1. The columns “Minimum” and “Maximum” in Table 24-5 on page 142 are deleted
2. A new row (“Device lot ID and position”) in Table 29-3 on page 196 is added
3. A new note (“Note 16”) in Table 29-3 on page 196 is added
4. In ”Absolute maximum ratings*” on page 225 the following values have been changed: “Voltage on OC and OD with respect to ground”, “Voltage on PC5, BATT, PVT, VFET, PV4, PV3, and PV2 with respect to ground”, and “Maximum operating voltage on VFET”
5. In Table 32-1 on page 225 the values for “Typical” and “Maximum” in the row “VFET = 16V, WDT, CC-ADC, OC, OD, and battery protection enabled, DUVR mode disabled” are added
6. “Frequency drift” for “Slow RC oscillator” in Table 32-8 on page 229 is deleted
7. A new note (“Note 4”) in Table 32-8 on page 229 is added
8. Table 32-10 on page 230 is updated and corrected
9. The text “C_{EQ} = 4.7nF, VFET = 16V” is added to “Condition” for t_f,OC and t_f,OD in Table 32-2 on page 226
10. New Figure 33-1 on page 238 is added
11. Corrected formula in Table 32-15 on page 232
12. Corrected and added some short-cuts in addition to general update and some minor corrections in text

39.3 Rev. 8042B-06/10

1. Removed direction arrow in Figure 17-1 on page 82.
2. Updated ”Configuring PA1 and PA0 for V-ADC operation” on page 117.
3. Updated ”Operating circuit” on page 220, with correct naming convention for thermistors RT32 and RT33.

39.4 Rev. 8042A-08/09

1. Initial revision

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